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This chapter describes the T-Spice documentation conventions and user interface, and provides a simple tutorial on basic T-Spice usage.

## Documentation Conventions

This section contains information about the typographical and stylistic conventions used in this user guide.

## Special Fonts

The following references in the text are represented by a bold font:

- Menu and simulation commands (For example: .print tran v(out).)
- Literal user input (For example: Enter 14.5.)
- Program output (For example: S-Edit generates names for the ports on the symbol based on the PAD string.)
- All dialog elements—fields, checkboxes, drop-down menus, titles, etc. (For example: Click Add.)

Freestanding quotations of input examples, file listings, and output messages are represented by a constant-width font-for example:
.ac DEC 5 1MEG 100 MEG
Variables for which context-specific substitutions should be made are represented by bold italics-for example, myfile.tdb.

Sequential steps in a tutorial are set off with a checkbox ( $\boxed{\square}$ ) in the margin.
References to mouse buttons are given in all capitals-for example, MOVE/EDIT. When a key is to be pressed and held while a mouse button is used, the key and button are adjoined by a plus sign (+). For example, Shift+SELECT means that the Shift key is pressed and held while the SELECT mouse button is used.

The terms "left-click," "right-click," and "middle-click" all assume default mappings for mouse buttons.

## Menu Commands and Dialog Titles

Elements in hierarchical menu paths are separated by a > sign. For example, File $>$ Open means the Open command in the File menu.

Tabs in dialog boxes are set off from the command name or dialog box title by a dash. For example, Setup > Layers-General and Setup Layers-General both refer to the General tab of the Setup Layers dialog.

## Special Keys

Special keys are represented by the following abbreviations:

| Key | Abbreviation |
| :--- | :--- |
| Shift | Shift |
| Enter | Enter |
| Control | Ctrl |
| Alternate | Alt |
| Backspace | Back |
| Delete | Del |
| Escape | Esc |
| Insert | Ins |
| Tab | Tab |
| Home | Home |
| End | End |
| Page Up | PgUp |
| Page Down | PgDn |
| Function Keys | F1 F2 F3 $\ldots$ |
| Arrow Keys | $\downarrow, \leftarrow, \uparrow$ |

When keys are to be pressed simultaneously, their abbreviations are adjoined by a plus sign (+). For example, $\mathbf{C t r l}+\mathbf{R}$ means that the $\mathbf{C t r l}$ and $\mathbf{R}$ keys are pressed at the same time.

When keys are to be pressed in sequence, their abbreviations are separated by a space ( ). For example, Alt+E R means that the Alt and E keys are pressed at the same time and then released, immediately after which the $\mathbf{R}$ key is pressed.

Abbreviations for alternative key-presses are separated by a slash (/). For example, Shift+ $\uparrow / \downarrow$ means that the Shift key can be pressed together with either the up $(\uparrow)$ arrow key or the down $(\downarrow)$ arrow key.

## User Interface

The T-Spice user interface consists of the following elements:

- Title bar
- Menu bar
- Toolbars
- Status bar
- Simulation Manager
- Simulation Status window

Commands on the View menu toggle display of the last four items.
Text windows in the display area display the contents of input and output files.


## Menu Bar

The menu bar contains the names of the T-Spice command menus. The Edit and Window menus are only available when the active window contains a text file.


Commands for accessing online documents

## Toolbars

The Standard toolbar contains buttons with icons representing the most commonly used menu commands.


The Simulation toolbar contains buttons with icons representing simulation commands.


## Status Bar

When the pointer is positioned over a button in the toolbar, the left side of the status bar contains a short description of the button's function. When a text window in the display area is active, the status bar provides information useful for editing.


## Display Area

The display area consists of the entire T-Spice window not occupied by the title, menu bar, toolbars, Simulation Manager, Simulation Status window, or status bar. In this area, input files are viewed and edited and simulation status information is displayed.

## Simulation Manager

The Simulation Manager allows you to control and monitor all T-Spice simulations. Use View > Simulation Manager to display or hide the Simulation Manager. You can use the Simulation Manager to monitor multiple simulations at one time. Each simulation occupies one row, and each row has five attributes.

| Status | Input file | Output file | Start Date/Time | Elapsed Time |
| :---: | :---: | :---: | :---: | :---: |
| failed | Y:\My Documentş]...\|InverterDC.sp | InverterDC.out | March 12, 2008 16:29:44 | 00:00:02 |
| failed | Y:'My Documents'....Inverterop.sp | InverterOP.out | March 12, 2008 16:30:12 | 00:00:03 |
| failed | Y:'My Documents)...\|InverterOP.sp | InverterOP.out | March 12, 2008 16:30:27 | 00:00:02 |
| firished | Y:'My Documentş....\InverterTRAN.sp | InverterTRAN.out | March 12, 2008 16:30:47 | 00:00:02 |
| running | Y:My Documents,...(RingOscillatorTRAN.sp | RingOscillator TRAN. out | March 12, 2008 16:31:05 | 00:00:03 |

## Simulation Status

The Simulation Status window displays output messages from the T-Spice simulation engine. When you select a simulation in the Simulation Manager, the Simulation Status window displays the results for that simulation.


## Command Tool

T-Spice also provides a Command Tool, which presents a categorized listing of T-Spice simulation commands and options. You can use this tool as a guide in composing commands for the input file.


## Simulating a Design-a Simple Example

This section illustrates some basic principles of T-Spice operation using a simple example.

## Creating a New Input File

Create a new input file by clicking the New File button ( $\square$ ) or selecting File $>$ New.
When you click the New File button, T-Spice opens a new text window with the default filename T-Spice1. T-Spice increments the default name for additional new files, assigning them T-Spice2, T-Spice3, etc.

When you select File > New, a dialog appears that prompts you to specify the type of file you wish to create:


The extension shown in parentheses will be the default file format.

- SPICE Netlist (.sp)
- C Macro (.c)
- Text (.txt)

Selecting T-Spice enables color-coding for T-Spice commands and comments. An empty active window appears in the display area; it is provisionally called T-Spice1 (or T-Spice2, T-Spice3, etc.). Change the name to test.sp as follows:

- Use the File > Save command (or click $\square_{\text {- }}$ in the toolbar).
- Type test.sp under File name in the Save As dialog.
- Press Return or click OK.

T-Spice will change the window title accordingly.

## Entering the Circuit Description

## Device Statements

Type the following text in the test.sp window, pressing Enter after each line:

| Eplest.sp | -IV] |
| :---: | :---: |
|  |  |

The first line is a comment. (T-Spice always treats the first line of an input file as a comment, whether or not it begins with a comment symbol.) The next three lines, beginning with $\mathbf{v v}, \mathbf{r} 1$, and $\mathbf{r} \mathbf{2}$, are device statements comprising a SPICE description of the elementary voltage divider schematically represented below.


For information on comments, see "Input Conventions" on page 51. For information on device statements, see "Device Statements" on page 151.

## Simulation Commands

With the blinking cursor at the beginning of the next blank line in the test.sp window, use the Edit > Insert Command command (shortcut Ctrl+M or use the toolbar icon $\overline{\bar{\xi}}$ ) to open the Command Tool.

The first category on the left is Analysis. Expand that category and select the Transient command. T-Spice displays the appropriate options in the right-hand pane of the Command Tool.


In the Command Tool:

- For Maximum Time Step enter 5n.
- For Simulation Length enter 500n (nanoseconds).
- Click Insert Command.

The full command is placed as a line of highlighted text into test.sp, and the Command Tool closes.

Click at the end of this line to deselect it, then press Enter to create another blank line. Open the Command Tool again, and select the Output category and the Transient results command.


In the Command Tool:

- For Plot type, select Voltage.
- For Node name enter top. Then click the Add button.
- Replace the name top with the name out, and click the Add button again.
- Click the Insert Command button.
test.sp now looks like this:

| Pisp test.sp | - |
| :---: | :---: |
| $*$ Test circuit vv top gnd $S I N(0$ 1 1OMEG) r1 top out 1 r2 out gnd 2 .tran/op $5 n 500 n$ method=bdf .print tran $v$ (top) $v$ (out) |  |

The last two lines (beginning with .tran and .print) are the simulation command sequence, directing T-Spice to perform a transient analysis for 500 nanoseconds with a maximum time step of 5 nanoseconds, and to report the results of the transient analysis for the voltages at nodes top and out.

Alternatively, simulation commands can be incorporated directly into a circuit schematic. Then the commands will be present in the netlist when it is exported.

For information on the commands used in this example, see "Simulation Commands" on page 59.
Save test.sp. The circuit description is now complete and the simulation can be run.

## Running the Simulation

Use the Simulation $>$ Run Simulation command (or click $\bar{\square}$ in the toolbar) to initiate simulation.
The status of the simulation is shown in the Simulation Status window.


Text within the scrolling portion of the Simulation Status window can be copied for pasting into another input window.

At the same time, the output of the simulation is shown graphically in a separate W-Edit window. For information on W-Edit, see the W-Edit User Guide.


The voltage at node out is, correctly, two-thirds of the voltage at node top.

## Simulation Queueing

You can submit multiple simulations... they will run in the order they were submittedr.
You can also run batch simulations from a DOS or Unix command-line using T-Spice's -batch option, which passes the simulation commands listed in a text batch file to the T-Spice engine. See "CommandLine Options" on page 24 for a description of command-line options.

## Setup Options

The three tabs in Setup > Application control global options in T-Spice.

## T-Spice Server

An internal http server in T-Spice allows other Tanner applications to launch it and run a simulation. This setup tab indicates the status of the server, the port on which it is active and whether to log simulation jobs sent to the server.

When a remote request is sent to launch T-Spice, it initiates a sequence of checks to determine whether T-Spice is installed on the local PC, whether the user has a current license and whether the version of the remote application is compatible with the version of T-Spice.


Status

Network protocol settings
Logging

Indicates the status of the internal T-Spice server. Use the Start, Pause and Stop buttons to control the simulation job.

Enter the port to use to search for the T-Spice executable.
When Enable logging is checked, you can enter a name in the Log file field and location (using the browse button) for a log file.

## Text Editor

Determines T-Spice behavior in file saving operations. The most recently used settings are kept as defaults.


## Auto-Load

Modified text files

When checked, T-Spice automatically loads changes whenever a text file is modified outside T-Spice. No warning will be provided.

Controls how files modified within T-Spice will be saved prior to simulation operations. Options are:

- Save all changes-automatically saves all active windows when one of the above operations is invoked.
- Prompt to save changes-T-Spice will display a prompt when there are unsaved changes in the simulation input file. Select Yes to save the input file and proceed with simulation. If you select No, the Run Simulation command is ignored.
- Don't save changes-modified files will not be saved and the operation will use the stored version of those files.

When Auto-Load is disabled, T-Spice will open a checklist of all the files open in the text editor that have been modified elsewhere. You will have the option to reload modified files (checked) or not.

Files that have also been modified in the text editor will be highlighted. Similarly, when Prompt to save changes is selected, T-Spice will open a checklist of the modified files associated with the operation you are running. For example, you might open a text file in T-Spice, then later overwrite it by
reexporting a netlist. In such a case, T-Spice will display the following message to warn you that the file on disk has changed since you opened it in T-Spice:


If you click Yes, T-Spice updates the file in memory.

## Text Style

Use this tab to define the types of text (keyword groups) that will be highlighted when displayed in the T-Spice text editor, and their formatting. You can set text formats for SPICE netlists, C macro and text files.


Each file type has a set of predefined keyword groups that cannot be edited or deleted. Use this tab to view those settings, and to add or remove your own keyword groups with customized characteristics.

File Type
A drop down list of the file types for which keywords are or can be defined.

Font

## Paragraph

## Groups

Keyword Group

Allows you to set the typeface (Face Name) and point Size in which a given keyword group will appear.

Allows you to set the increment, in spaces, of the Tab Size used by the text editor.

Displays the keyword groups defined for the active file type. Use Add to enter the name of a new keyword group. Use Edit to enter the keywords belonging to a group. Use Remove to delete a keyword group.

- Use Add to enter the name of a new keyword group.
- Use Edit to enter the keywords belonging to a group.
- Use Remove to delete an entire keyword group.

Colors
Use Foreground and Background to set the respective colors for a keyword group.

## Adding Keywords to a Group

Edit keyword groups opens the Keywords dialog, which allows you to enter keywords and to specify whether the case is evaluated (Case sensitive keyords checkbox enabled) when highlighting is applied.


## External Programs

This tab is used to configure external executables used by T-Spice. In particular, the diff program that can compare two (or three) text files is specified here.


## Command-Line Options

T-Spice supports command-line options that allow you to alter simulation commands or options without changing the input netlist. There are two ways to use command-line options in T-Spice:

- You can use any command-line option in conjunction with the tspomd.exe executable to run simulations in a command-line environment, such as DOS or Unix.
- Most command-line options are also available within the T-Spice user interface; you can type them in the Simulation > Run Simulation dialog before you begin a simulation.

Command descriptions follow these conventions:

- Variables to be replaced by actual names, numbers, or expressions are indicated by italics.
- Square brackets [ ] enclose items that are not required. The brackets should not be typed on the command line.

Some command-line options allow you to specify an included or referenced file. Use the following rules to specify filenames in the command line:

- Specify filenames relative to the working directory, or using a fully qualified pathname. The working directory is the one that contains the main input file.
- Filenames containing spaces must be enclosed in single or double quotes.

T-Spice supports the following command-line options:

| Option | When on | When off (default) |
| :---: | :---: | :---: |
| -batch batchfile <br> (Not available in T-Spice GUI.) | Processes the simulations listed in the text file batchfile in series. See "Running T-Spice From the Command-Line" on page 26 for batchfile syntax. This option is only available with the tspomd.exe executable. | - |
| -c | Estimate MOSFET drain and source areas and perimeters from MOSFET lengths and widths. Equivalent to ".options" (page 106) moscap=1. | Set drain and source areas (if not specified in MOSFET statements) to zero. |
| -C | Disable the connectivity check. | Enable the connectivity check. |
| -d [probefile] | Turns on probing and optionally specifies the binary output filename. This option is equivalent to adding the following commands to the input netlist: <br> . probe <br> . probe noise dn (*,tot) <br> [.options <br> probefilename=filename] | No probing commands are specified, unless explicitly stated in the input netlist. |
|  | If a filename is specified, it will override the command .options probefilename in the netlist. |  |
| -dll dllfile <br> (Not available in T-Spice GUI.) | Runs the current simulation using the specified DLL dllfile. See "Running T-Spice From the Command-Line" on page 26 for a description. This option is only available with the tspemd.exe executable. | Use the default DLL (recommended). |
| -h headerfile | Specify a header file to be processed at the start of T-Spice simulation. | Parse only the contents of the current T-Spice input file. |
| -i "TSCommand" | Executes the T-Spice command enclosed in double quotes. Input commands added with -i are parsed after the header file, but before other input files. | - |
| -1 | Echoes all parsed input lines to the Simulation Status window or stderr output. This is equivalent to setting .options echo=1. | Input lines are not shown in simulation output. |


| Option | When on | When off (default) |
| :---: | :---: | :---: |
| -m modelfile | Include model definitions from mfile. Equivalent to the .model mfile command. | Use model parameters specified in the input file, if available. |
| -n | Disables splash screen. | Splash screen appears on application startup. |
| -o outfile | Print results to ofile. | Print results to standard output (the screen or the Simulation Window). |
| -P parameter = value | Assign a value (a plain number or an expression enclosed by single quotes) to parameter. Parameter assignments made with this option override assignments made with the ".param" (page 113) command in the input file. This option can be used as many times as desired. | Use parameters specified in the input file, if any. |
| -q | "Quiet" mode: disable the simulation status display. | Enable the simulation status display. |
| -U | Print a usage message and quit. | - |
| -V | Print the version number and acknowledgments and quit. | - |
| netlistfile | Use netlistfile as the circuit description. Netlists generally have the extension .sp or .cir. | [The argument is required when running tspomd.exe.] |

## Running T-Spice From the Command-Line

The tspomd.exe executable file allows you to run the T-Spice engine, without a graphical interface, from a command-line environment such as DOS or Unix. To run T-Spice from a command-line, use the following syntax:

```
tspcmd [-aqlCUV] [-dll dllfile] [-batch batchfile]
    [-d [probefile]] [-P parameter=value]
    [-m modelfile] [-o outfile] [-i "command"] netlistfile
```

The options -batch and -dII, are available only in command-line environments; you cannot use these options in the T-Spice Run Simulation dialog.

## Batch Simulations from the Command Line

The command-line option:

```
-batch batchfile
```

allows you to pass a list of simulations to T-Spice for serial execution. The batchfile specifies a text file that contains a list of simulations and accompanying command-line options. Each simulation and its associated options must be listed on a separate line, using the following syntax:
[-acqruCMTUV] [-dll dllfile] [-d probefile]
[-P param=value][-m modelfile][-o outfile]
[-i "TScommand"] netlistfile

## 2 Simulation Concepts

## Simulation Algorithms

T-Spice is designed to solve a wide variety of circuit problems. Its flexibility is due to robust algorithms which can be optimized by means of user-adjustable parameters. This chapter contains an overview of T-Spice's algorithms and parameters.

In what follows, when reference is made to an "option" (such as the numnd option) it means that the corresponding quantity is controlled with the .options command. For information on the .options command, see "Simulation Commands" on page 59.

## Kirchoff's Current Law

T-Spice uses Kirchoff's Current Law (KCL) to solve circuit problems. To T-Spice, a circuit is a set of devices attached to nodes. The circuit's state is represented by the voltages at all the nodes. T-Spice solves for a set of node voltages that satisfies KCL (implying that the sum of the currents flowing into each node is zero).

In order to evaluate whether a set of node voltages is a solution, T-Spice computes and sums all the currents flowing out of each device into the nodes connected to it (its terminals). The relationship between the voltages at a device's terminals and the currents through the terminals is determined by the device model. For example, the device model for a resistor of resistance $R$ is $i=\Delta v / R$, where $\Delta v$ represents the voltage difference across the device.

## DC Analysis

Most T-Spice simulations start with a DC operating point calculation. A circuit's DC operating point is its steady state, which would in principle be reached after an infinite amount of time if all inputs were held constant. In DC analysis, capacitors are treated as open circuits and inductors as short circuits.

Because many devices, such as transistors, are described by nonlinear device models, the KCL equations that T-Spice solves in DC analysis are nonlinear and must therefore be solved by iteration. On each iteration, T-Spice tries to find a set of node voltages that satisfies KCL more closely than the previous set. When the KCL equations are satisfied "well enough" (the sums of currents into nodes are small enough), the process stops.

The abstol and reltol options determine how closely KCL must be satisfied. The numnd option imposes a limit on the number of iterations. If numnd iterations are reached without a solution being found, then nonconvergence is declared.

T-Spice sometimes uses a technique called source stepping to find a circuit's DC operating point. In source stepping, all voltage and current sources are ramped up from zero to their final values. This allows T-Spice to find the DC operating points of difficult-to-converge circuits. Source stepping is used only in non-converging cases of initial DC operating point calculations, and not during DC analysis sweeps. The smallest source step that T-Spice will take is controlled by the minsrcstep option.

## $g_{\text {min }}$ Stepping

Some non-convergence errors can be eliminated by ensuring a sufficient conductance across capacitors. The option gmindc specifies a conductance that is added in parallel with all pn junctions during DC analysis. T-Spice applies the gmindc conductance to various elements as follows:

- diode-conductance is added across the positive/negative terminals.
- BJT-conductance is added across the base/emitter and the base/collector terminals.
- MOSFET-conductance is added across the source/bulk, drain/bulk, and the source/drain terminals.
- MESFET-conductance is added across the source/gate, drain/gate, and source/drain terminals.

The default value for gmindc is $10^{-12}$.
When a DC operating point non-convergence occurs, T-Spice can begin a $g_{\min }$ stepping algorithm to find the minimum conductance that yields a convergent solution. . The $g_{\min }$ stepping algorithm is triggered when a non-convergence occurs and the value of option gramp is greater than zero. Together, the options gmindc and gramp specify a search range for the minimum required conductance, $g_{\text {min }}$ :
gmindc $\leq g_{\text {min }} \leq$ gmindc $\cdot 10^{\text {gramp }}$
T-Spice's $g_{\text {min }}$ stepping algorithm searches the specified conductance range in two steps. First, T-Spice performs a binary search between gmindc and gmindc•10gramp. T-Spice searches for the smallest value of $g_{\text {min }}$ that results in a converged solution. T-Spice automatically ends the binary search when it reaches a $\Delta g_{\min }$ that is less than or equal to a factor of 10 .

Starting with binary search results, T-Spice then begins reducing the value of $g_{\text {min }}$ by a factor of 10 in each iteration. Once a non-convergence occurs, the previous convergent iteration provides the final solution.

## Transient Analysis

In transient analysis, T-Spice solves for a circuit's behavior over some time interval. In this mode, T-Spice takes small time steps, solving for the circuit's state at each step. At each time step, two approximations are made.

First, a small error - the discretization error - is introduced because T-Spice cannot take infinitely small time steps. The chargetol and relchargetol options determine the acceptable limits of discretization error. In general, taking smaller time steps decreases the discretization error, so tightening the tolerances has the effect of higher accuracy at the expense of smaller time steps and therefore longer simulation times and larger output files. The discretization error is also affected by the order of the time integration method used, adjusted with the maxord option.

Second, just as in DC analysis, T-Spice solves the nonlinear KCL equations iteratively at each time step. The accuracy is affected by an iteration stopping criterion. The same tolerances as in DC analysis - abstol and reltol -affect this solution process. The iteration count limit for a transient analysis time step is numnt, which is typically much smaller than numnd; the previous time step always provides a good initial guess for a transient analysis Newton iteration, so that fewer iterations are typically required than for DC analysis, where a good initial guess is usually not available. Another iteration limit, numntreduce, affects time step selection after a successful time step. If T-Spice took less than numntreduce iterations to find the solution at a time step, the next time step is adjusted (often increased) according to the discretization error tolerances chargetol and relchargetol. But if the number of iterations required is between numntreduce and numnt, then the time step is always decreased on the next step (even if the step was successful).

As in DC analysis, some non-convergence errors can be avoided by adding a small conductance across capacitors. For transient analysis, the option gmin specifies a conductance that is added in parallel with all $p n$ junctions. The default value of gmin is $10^{-12}$.

## Trapezoidal Integration Method

T-Spice's default method for transient analysis uses trapezoidal integration with the lvltim=1 delta-voltage time step control algorithm.

The trapezoidal formula calculates the average slope of the present and next time point to approximate the value of the integral of the differential equations used in the time range calculations, as follows in simplified form. The following approximation is used to discretize the differential equation:

$$
\begin{equation*}
V_{n+1}=V_{n}+\frac{h}{2}\left(\frac{d V_{n+1}}{d t}+\frac{d V_{n}}{d t}\right) \tag{0.1}
\end{equation*}
$$

where

$$
\begin{align*}
V_{n+1} & =\text { present unknown voltage value } \\
V_{n} & =\text { previous time-point solution }  \tag{0.2}\\
h & =\text { time step length } \\
n & =\text { time interval }
\end{align*}
$$

## Gear's BDF Method

T-Spice's alternate method for transient analysis uses Gear's backward differentiation formulas (BDF). In this method, the time derivative of charge in the KCL equations is replaced by an approximation involving the solution at the last few time points. The first-order BDF method uses only one previous time point, and it is equivalent to the well-known Backward Euler method. In this method, the discretization error is a linear function of the step size. The second order method uses two previous time points, and its discretization error is proportional (for small time step sizes) to the time step size squared. In general, the $k$ th order BDF method uses $k$ previous time points.

T-Spice uses a variable-step-size, variable-order, and variable-coefficient implementation of the BDF method. T-Spice automatically adjusts the time step size and BDF order (between 1 and 4) to minimize the number of time steps required to meet the given error tolerances. The maximum order used can be adjusted with the maxord option. The variable-coefficient implementation was chosen over the fixedcoefficient and fixed-leading-coefficient methods because it offers the best stability properties, especially with frequently varying time step sizes.

At each time step, the BDF discretization results in a nonlinear system of equations (representing KCL) which is solved iteratively as described above. If the iteration succeeds, the discretization error is examined (by comparison with an explicit predictor). For example, in the order 1 case, the difference between the Forward Euler predictor and the computed BDF (Backward Euler) solution provides a bound on the discretization error. If the error is within the prescribed tolerance (defined by chargetol and relchargetol), the step is accepted, and the error is used to adjust the step size for the next time step. If the error is too large, the time step is rejected and reattempted with a smaller step size. This will produce answers which approach a more stable numerical solution. Gear integration often produces superior results for power circuitry simulations, due to the fact that high frequency ringing and long simulation periods are often encountered.

## Small-Signal Analysis

Some of T-Spice's analysis commands use small-signal models. Small-signal analysis linearizes the KCL equations about an operating point. Subsequent computations are performed on the linearized circuit, which can be solved in one matrix-vector operation. In AC analysis, for example, one matrixvector solve is done at each frequency point to find the AC solution; no iteration is necessary. The linearized small-signal model is valid only locally, so if the operating point changes, then a new linearized model has to be computed.

## Tolerances

T-Spice's simulation speed and accuracy are controlled by various tolerance values. Computer-based simulators like T-Spice solve circuit equations using finite precision arithmetic. This means that numerical approximations are made at several steps of the solution process. The errors introduced by these approximations in T-Spice are bounded by tolerance settings.

Each approximation is controlled by a relative tolerance trel and an absolute tolerance tabs. In most cases, the relative tolerance is used - the approximation error may not exceed trel $\times|v|$, where $v$ is the value of the quantity to be approximated. The absolute tolerance is used when the approximated quantity's value is close to zero; in that case, the error may not exceed tabs. In general, the error must be less than the maximum of trel $\times|v|$ and tabs.

## abstol - reltol

Corresponding to each node in a circuit is an equation which expresses Kirchoff's Current Law (KCL), according to which the branch currents flowing into the node must be zero. The actual sum of these branch currents at a node is called the "residual current" for that node, and it is a function of all node voltages. In a sense, then, the value of this current at a given node is a measure of how well KCL holds at that node. T-Spice attempts to find a solution (a set of node voltages) that causes KCL to be satisfied at all nodes. The correctness of the solution is measured by the norm of the vector of residual currents at all nodes.

In general, the KCL equations are complicated and nonlinear, and T-Spice solves them by numerical iteration. Each iteration results in an improved approximation of the true solution of the KCL equation, in the sense that the norm of the residual currents decreases with each iteration. However, it is often impossible to make the residual current exactly zero, because of the finite precision arithmetic used. Even if infinite precision arithmetic were available, it might take infinitely many iterations to make the residual current zero. Therefore, the iteration is considered to have converged to a solution when the residual current is within the tolerances defined by abstol and reltol. Thus, abstol and reltol control how small the residual currents must be - how far from satisfying KCL the nodes can be - before the system is considered solved.

To be more precise, reltol and abstol are applied as relative and absolute tolerances, as described above, to the residual currents at each node. The tolerance used at a particular node is max(abstol, reltol×imax), where imax is the largest branch current (in absolute value) flowing into the node in question. The abstol and reltol tolerances are used whenever T-Spice solves the KCL equations for a DC solution or a transient analysis time step.

The default value for reltol is $1 \times 10^{-4}$, or $0.01 \%$. The default value of abstol is 0.5 nanoamps. These values should be reduced for sensitive analog designs.

## numnd - numnt - numntreduce

numnd defines the maximum number of iterations allowed during the solution of the KCL equations during a DC analysis. If, after numnd iterations, the abstol/reltol tolerances have not been satisfied, the iteration is considered to have failed and nonconvergence is declared. T-Spice then stops the iteration and reacts appropriately:

- On initial DC operating point calculations, source stepping is invoked.
- During DC transfer analysis, the transfer step size is reduced.

During source stepping, the maximum number of iterations for each source step is numnd $/ 10$. If numnd $/ 10$ iterations are exceeded during source stepping, the source step size is reduced. If the minimum source step size (minsrcstep option) is violated, then nonconvergence is declared for the DC operating point computation.

If the initial DC operating point computation fails at the beginning of a transient analysis, T-Spice attempts a powerup simulation. In a powerup simulation, all voltage and current sources are slowly ramped up from zero to their actual values. The default ramp period is $0.1 \%$ of the transient simulation final time, and it can be overridden using the poweruplen option.
numnt determines the maximum number of iterations allowed during the solution of the KCL equations for a transient analysis time step. Another option, numntreduce, is used in the time step size after a successful time step. Together, numnt and numntreduce work as follows. If a time step requires more than numnt iterations, the iteration is considered to have failed, and the same time step is reattempted with a smaller step size. If fewer than numntreduce iterations are needed for a time step, the next time step is adjusted (often increased) according to the discretization error tolerances (chargetol and relchargetol). If the number of iterations required is between numntreduce and numnt, the step size for the next time step is always reduced.

The number of iterations it takes to converge to a circuit solution depends heavily on the circuit to be simulated. Stable circuits with well-defined, steady-state conditions generally require fewer iterations, whereas circuits with poorly defined or unstable steady-state conditions require more iterations. Convergence is also sensitive to the starting point (initial guess) of the iteration. If the starting point is close enough to the operating point, then the iteration will eventually converge (although it might take many iterations in some cases). But if the starting point is not close to the solution, then the iteration may not converge at all. Different starting points (initial guesses) may be specified with the .nodeset command. For information on the .nodeset command, see "Simulation Commands" on page 59.

## chargetol - relchargetol

Kirchoff's Law contains a term that represents the time derivative (rate of change) of charge. In transient simulations, T-Spice must replace this derivative by a divided difference approximation. The approximation becomes more accurate as the time step size decreases. T-Spice chooses its time step size so that the error caused by this approximation remains below another tolerance called the "charge tolerance." You can specify both an absolute and a relative charge tolerance with the chargetol and relchargetol options. By decreasing (or increasing) these tolerances, you can force T-Spice to take smaller (or larger) time steps if you believe that the results of transient simulation are not accurate enough (or too accurate for your time constraints).

The value of relchargetol is by default the same as reltol, so that reltol controls the overall relative simulation accuracy. For example, if you would like $0.001 \%$ accuracy, simply set reltol to $1 \times 10^{-5}$; this also sets relchargetol to $1 \times 10^{-5}$. The relchargetol option should be used only to override the general relative tolerance reltol.

In general, the KCL tolerances abstol and reltol, as well as the charge tolerances chargetol and relchargetol, trade off speed for accuracy such that tightening these tolerances increases simulation accuracy at the expense of speed. However, if the KCL tolerances are too loose relative to the charge tolerances, the simulator may take small time steps because of numerical noise introduced by residual currents. These residual currents exist only because the KCL equations are not being solved exactly, but they may cause the charge tolerances to be violated, leading to excessively small time steps. If this happens, reducing abstol and/or reltol will result in larger time steps and faster (as well as more accurate) simulation.

## Device Model Evaluation

T-Spice can evaluate device models with any of the folowing methods. Direct model evaluation is the default.

## Evaluation Methods

- In direct model evaluation, data points (the charges and currents at device terminals) are computed "directly" at each step from terminal voltages using analytical model equations. This method typically produces the most accurate results, but also typically takes the most time, because values must be repeatedly recomputed from very complex equations.
- In table-based model evaluation, data points are read or interpolated from precomputed tables stored in memory. When the simulation requires the charge or current value (output) corresponding to a given voltage (input) for a particular device, T-Spice uses the voltage to look up the appropriate value in the device table, interpolating if necessary to arrive at the needed charge or current. This method is considerably faster than direct model evaluation. By default, T-Spice uses analytical models to generate cached, or internal, tables for use during a simulation. At the conclusion of the simulation these internal tables are discarded. Large circuits with many equally-sized devices benefit most from table-based evaluation.
- Another mode of table-based evaluation is external tables (see "External Tables" on page 499). In this mode, "external" tables are generated and stored prior to running a simulation. External tables can be used in multiple simulations without having to be regenerated each time; they can be constructed from existing analytical models or associated with macromodel elements to simulate

The tables are internal because T-Spice creates and maintains them during the course of a simulation and discards them at the end, without user intervention. When a simulation begins, T-Spice starts to construct charge and current tables point by point. By default, tables are computed at resolutions predefined for various device types, but these default resolutions may be overridden by .gridsize commands in the input file. T-Spice requires separate tables for devices of different types, devices of the same type with different physical characteristics, or devices of the same type using different models. As T-Spice requires device charges and currents during simulation, it looks them up (or interpolates them from nearby data) in the charge and current tables.

## Table Resolution

Table resolution is measured by the number and spacing of the table's grid points. Grid point spacing is adjusted dynamically, with new values computed analytically when necessary, and other values interpolated between existing ones. However, it is possible to force an inappropriate number of grid points or equal spacing between grid points, or to use externally generated tables over whose resolution and accuracy T-Spice has no control. Poorly chosen table parameters can result in inaccurate interpolation and degraded simulation results.

A simple example of the differences in results obtained from various table resolutions is shown in the figure below. The input file described a current mirror and used a Level $2 n$-channel MOSFET model. The DC operating point was computed by direct evaluation to provide a standard against which the table-based results were compared. Each bar in the figure represents the percentage difference between the table-simulated result (at a given number of grid points) and the direct-evaluation standard - in every case, well under one-quarter of one percent.


## Parametric Analysis

Under many circumstances, T-Spice will be required to study the effects on circuit performance of variations in parameter values. For example, parametric analysis can be used to evaluate multidimensional trends in the output over defined ranges of input values, or the sensitivity of circuit behavior to random fluctuations in fabrication conditions.

A large range of parameters may be systematically and automatically varied:

- External parameters (such as temperature)
- Simulation parameters (such as tolerances)
- Device parameters (such as input voltage level)
- Model parameters (such as transistor length)

Three types of parametric analysis are made possible by T-Spice: parameter sweeping, Monte Carlo analysis, and optimization. Discussions of T-Spice syntax and corresponding examples are included for all three analysis types in the chapter titled "Parametric Analysis" on page 510

In a parameter sweep, a specified parameter is held or initialized at a given value, on the basis of which all analyses requested by the input file are performed, and the results recorded. Then the parameter is incremented by a set amount, and the same analyses are repeated. This cycle is continued while the parameter is incremented through a defined range of values.

Parameter values may be swept linearly - in identical increments, typically through a limited range or logarithmically - in exponential increments, typically through a range spanning multiple orders of magnitude.

An example illustrating T-Spice input for parameter sweeping is given in "Parameter Sweeps" on page 511.

## Monte Carlo Analysis

Monte Carlo analysis generates "random" variations in parameter values by drawing them probabalistically from a defined distribution. For each value thus chosen, all analyses requested by the input file are performed, and the results recorded. Monte Carlo analysis is performed using the keyword sweep; syntax is described in ".step" (page 138).

Parameter values may be drawn from tunable uniform, Gaussian, or random limit distributions.
For a more detailed description of Monte Carlo analysis, see "Monte Carlo Analysis" on page 514.
If an aspect (or aspects) of the desired circuit performance can be specified quantitatively, T-Spice can search through a multidimensional "space" of parameters - that is, vary several parameters systematically and simultaneously - to determine the combination of parameter values that optimizes the specified performance measure (or set of measures).

Each run, using a particular combination of parameter values, produces a new value for each performance measure studied. Optimization is achieved by varying parameters in an attempt to minimize

$$
\begin{equation*}
\sum_{i}\left[w_{i} \frac{\left(G_{i}-R_{i}\right)}{G_{i}}\right]^{2} \tag{0.3}
\end{equation*}
$$

where $G_{i}$ is the goal or desired value of the $i$ th performance measure; $R_{i}$ is the result or actual value of the $i$ th performance measure, for a particular combination of parameters; and $w_{i}$ is the weight or importance assigned to the $i$ th performance measure relative to the other measures used. The quantity $w_{i}\left(G_{i}-R_{i}\right) / G_{i}$ is also called the error.

The choice of the next combination of parameters to test after each run, on the basis of the current total error, is the heart of the optimization algorithm. The algorithm employs gradient descent; that is, it attempts to find the steepest (fastest) "path" through the "space" of parameters that will lead to the minimum, by estimating the gradient in various directions.

For a description of T-Spice input needed to set up and invoke optimization, see "Optimization" on page 517. This section also includes a tutorial example illustrating optimization (see "Example 3: Optimization" on page 518).

## Error Types and Correction

The highly compressed, text-based nature of the SPICE circuit description language, while rendering it efficient, portable, and flexible, also makes it prone to user errors of various kinds - errors that, while they will seldom crash the program, often result in wrong answers or problems with convergence.

T-Spice makes some corrections automatically, replacing improbable values with default ones or ignoring improper commands and specifications. In other cases, the Simulation Window shows the line number of the input file on which the error was found, or the name of the device whose specification

T-Spice could not parse properly, and a brief description of the error. The most common errors can be divided into several categories.

## Syntax Errors

- Unsupported commands or statements.
- Wrong spelling of commands, statements, or options.
- Failure to abide by conventions for names, comments, line continuation, numeric formats, unit abbreviations, or expressions.
- Wrong number or order of arguments on a simulation command or device statement.
- Numbers out of range.


## Connectivity Errors

- Floating (unconnected) nodes.
- Nodes connected to only one device (except power supply and output nodes).
- Identical nodes referenced by different names.
- Different nodes referenced by identical names.
- Devices referred to that have not been previously defined.

Unless naming inconsistencies interfere with proper connectivity - producing floating nodes or devices with unconnected terminals - they will not be caught by T-Spice; it will simply assume that what is written is what is meant, and will produce misleading, implausible, or impossible results.

## Convergence Errors

- Wrong metric prefix (order-of-magnitude error). For example, forgetting the pon a number intended to represent picofarads will not be caught by the syntax or connectivity checks but will probably lead to wildly wrong results.
- Ill-chosen tolerances.

To help prevent errors, use a schematic export tool to automate part of the process of writing a circuit description. These translate a graphical description of the circuit into a textual (SPICE-format) description. As long as the schematic has been drawn consistently (and this is easier to do graphically than textually), connections will be specified and nodes and devices named properly.

In addition, use comments liberally. Take advantage of the multiple ways by which comments can be indicated in a T-Spice input file to add structure and clarity to the circuit description. This will make later use of the file, whether for further study or for debugging, much simpler.

To deal with a syntax error, note the line number or device name in the input file at which T-Spice found the error, and check the syntax there.

To deal with a connectivity error, check the structure of the circuit, as described in the input file, carefully against the original schematic or plan. (This will be easier if T-Spice's own connectivity checker detected the error and provided the appropriate line number or device name.)

To deal with a convergence error, check the input file carefully, making sure that any metric prefixes used are plausible. Adjust the tolerances if necessary.

For information on comments, see "Input Conventions" on page 51. For information on syntax specifications, see "Simulation Commands" on page 59 and "Device Statements" on page 151.

## Multi-Threaded Processing

T-Spice offers multi-threading options to provide accelerated performance on shared memory multiprocessor or multiple core computers.

Traditional SPICE simulation runtimes are dominated by two major computational areas: first, the transistor and device model evaluations, in which all terminal currents, charges, and derivatives are computed as a function of the device terminal voltages. Secondly, a sparse linear system is formed and solved, in order to compute iterates to the Newton-Raphson solution of the overall nonlinear algebraic circuit equations.

The model evaluations and linear system solutions comprise well over $95 \%$ of the solution time for T-Spice. For medium size circuits, the model evaluation time will be greater than the linear system solution time, but with larger circuits the linear solution component will grow to dominate the overall solution time. The multi-threading feature of T-Spice provides for computational operations to be decomposed and solved in parallel during both stages of processing.

Model evaluation parallel processing is controlled via a single option, option threads=0|1. When the threads option is enabled, T-Spice will automatically decompose the workload into small tasks, and dynamically distribute these tasks to multiple threads for processing. The number of threads and size of the tasks are controlled via internal variables, and are outside of user control. The linear system solution, or matrix factorization and solve, is performed using a multi-threaded sparse linear solver.

## 3 Running Simulations

## Input Files

At the heart of T-Spice's operation is the input file (also known as the circuit description, the netlist, or the input deck). This is a plain text file that contains the device statements and simulation commands, drawn from the SPICE circuit description language, with which T-Spice constructs a model of the circuit to be simulated. Input files can be created and modified with any text editor, though the text editor integrated with T-Spice is ideal as it includes default and fully-customized syntax highlighting.

Input files can be very long and complex, but they do not have to be written from scratch; they can be efficiently created using the export facility of a schematic editor (such as S-Edit ${ }^{\mathrm{TM}}$ ), or the extraction facility of a layout editor (such as L-Edit ${ }^{\mathrm{TM}}$ ). In addition, T-Spice includes a "Command Tool" (page 15) that automates error-free SPICE language entry.

Any number of text files can be open at once, each in its own window in the display area. However, only one window can be "active" at any given time, and only an input file displayed in an active window can be edited and simulated.

## File Synchronization

T-Spice has file synchronization features that allow you to control how files are saved and updated.
For input files, you can set an application-level default (auto-load) so that text files open within T-Spice are automatically reloaded if they are modified outside of T-Spice. You can also set a default for text files that have been modified inside T-Spice so that prior to being used they are automatically saved (or not, or with a prompt). Similarly, you can set a gobal default for output files so that they will always be overwritten without a prompt (see "Setup Options" on page 20).

If the file synchronization feature poses an inconvenience due to a network configuration or other issues, you can disable it by starting T-Spice with the -y command-line flag (see "Command-Line Options" on page 24).

## Opening SPICE Files

You can use File＞New or File＞Open to launch the text editor window in T－Spice．There is also a special command File＞Open Folder Containing \｛filename\}, that opens a browser window directly to the folder containing the result files for the active SPICE file as well as the folder path．．

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## Editing Text Files

When the pointer is in an active text window，it becomes an I－beam．The position in the input file at which text is to be added is marked by a blinking cursor，and the status bar displays the cursor position， editing mode，and other information as described in＂Status Bar＂on page 13．You can toggle between the two editing modes by pressing the Ins key．In Insert mode，text is added between the characters separated by the blinking cursor．In Overwrite mode，text is added in place of the character to the right of the blinking cursor．

The cursor can be moved by clicking the pointer at the desired location．Sections of text can be selected by clicking and dragging the pointer．Double－clicking selects a word．

Alternatively，all these functions are accessible from the keyboard，as follows．

| Keys | Functions |
| :--- | :--- |
| $\uparrow \downarrow \leftarrow \rightarrow$ | Move the cursor in the indicated direction |
| Home／End | Move the cursor to the beginning or end of the line |
| PgUp $/ \mathbf{P g D n}$ | Move the cursor up or down one page（scrolling the window with it） |
| $\mathbf{S h i f t}+\uparrow \downarrow \leftarrow \rightarrow$ | Extend the selection in the indicated direction |
| $\mathbf{S h i f t}+\mathbf{H o m e} /$ End | Extend the selection to the beginning or end of the line |
| $\mathbf{S h i f t}+\mathbf{P g U p} / \mathbf{P g D n}$ | Extend the selection up or down one page |
| Shift $+\mathbf{C t r l}+$ Home $/$ End | Extend the selection to the beginning or end of the file |

Selections of text can be manipulated with the Cut, Copy, Paste, and Clear commands in the Edit menu (or, in the case of the first three, by clicking 差, 舄, and in the toolbar). The Cut and Copy commands put deleted or duplicated text onto the clipboard, and from there the text can be placed elsewhere with the Paste command. The Clear command simply deletes text without adding it to the Clipboard.

## Comment Delimiters

T-Spice allows several different characters to be used as comment delimiters, including the asterisk (*), dollar sign (\$), semicolon (;), and C-language style slash (/* or */). However, the T-Spice text editor will only color-code comment text when:

- An asterisk $\left(^{*}\right)$ used as delimiter is placed in the first column of the text editor
- A dollar sign (\$) is used as delimiter in any column of the text editor

C-style comments delimited by */ or / $*$ and midline comments delimited by an asterisk will not be colorcoded. The T-Spice simulation engine will correctly interpret them as comments, however.

## Undo and Redo

The Edit > Undo command $(\mathbf{C t r l}+\mathbf{Z}$ or $\llbracket)$ ) reverses changes made to the text of the input file.
Undo reverses the most recent of the editing operations stored in the undo buffer. The previous 100 editing operations are stored in the undo buffer; they are of the following types:

- Typing, including delete and backspace keystrokes.
- Edits made with the Cut, Copy, Paste, or Clear commands.
- Edits made with Insert Command (see "Simulation Commands" on page 17).

Undo is unavailable under the following circumstances:

- Immediately after T-Spice is launched.
- Immediately after an input file is created or opened.

The Edit > Redo command (Ctrl+Y or $\mathbf{\Gamma} \mathbf{~ ) ~ r e s t o r e s ~ c h a n g e s ~ r e v e r s e d ~ w i t h ~ a ~ p r e v i o u s ~ U n d o ~ c o m m a n d . ~}$ Each of the events stored in the undo buffer can be redone one at a time in reverse order.

## Search and Replace

The T-Spice text editor supports string and regular expression search and replace operations.

## Edit > Goto Line

Prompts for a line number, then places the cursor at the beginning of the corresponding line in the active window.


Edit > Find

The Edit > Find (Ctrl+F) command opens the Find dialog which prompts for text to be searched for (the target string)

| Find |  |  |
| :---: | :---: | :---: |
| Find what: capacitorarr | ode | Find Next |
| 「 Match whole word only Match case Regular Expression | Direction $\bigcirc \mathrm{Up}$ Jp Down | Cancel |


| Find what | String to be searched for in the text file. Use the <br> the special character codes used to search for a manual line break, tab <br> break, white space, or the carat (^) character. |
| :--- | :--- |
| Match whole word only | T-Spice searches only for whole words that match the specified <br> search string. |
| Match case | Causes T-Spice to find only strings whose case matches that of the <br> search string. |
| Regular expression | Activates Unix-style regular expression searching in the target string. <br> The Match whole word only option is not available in Regular <br> expression mode. See "Regular Expression Rules," below for <br> further information. |
| Opens a submenu of special character codes that can be inserted in |  |
| (Special) | Une target string. These codes are prefixed by the caret character (^) <br> unless they are UNIX-style regular expressions. Options include: <br> - Manual Line Break |
| - Tab Break |  |

## Regular Expression Rules

The Regular expression option in the Find Item or Replace dialogs causes T-Spice to interpret the search string as a Unix-style regular expression. Instead of interpreting the caret combinations $\boldsymbol{\wedge} \mathbf{t}, \boldsymbol{\wedge}$, and ${ }^{\wedge} \mathbf{w}$ as special sequences, T-Spice replaces them with Unix-style combinations that use the backslash ( $(\backslash)$ escape character.

The following table lists the rules T-Spice will follow when searching in regular expression mode:

| Syntax | Description | Example |
| :---: | :---: | :---: |
| In | Line break. |  |
| \t | Tab character. |  |
| $\wedge$ | Beginning of line. |  |
| \$ | End of line. |  |
| - | Any character except line break. | p.n matches pin and pan. |
| [] | One of the characters enclosed in the brackets. | p[ai]n matches pin and pan but not pun. |
| [^set] | Any character not enclosed in square brackets. | $\mathrm{p}{ }^{\text {^i] }}$ ] matches pan but not pin. |
| [set] | A set of characters including any character from the set enclosed in square brackets. | [0-9] matches any digit. [spice] matches any of the characters (s pice). |
| [set] ${ }^{\text {* }}$ | Zero or more occurrences of the set enclosed in square brackets. | [0-9]*1 matches 1 and 11 and 381. |
| [set]+ | One or more occurrences of the set enclosed in square brackets. | [0-9]+ matches 2 and 4532. |
| - | Optional match. | 12- matches 1 and 12. |
| I( | Begin tag. | $\mathbf{A} \backslash([0-9]+\backslash)$ matches A123 and substitutes 123 for the first tag ( 11 ) in the replacement string. |
| 1) | End tag. |  |
| $\backslash n$ | Text matching the $n$th parenthesized component of the regular expression, where $n$ is a single digit. | If the search string is $\backslash(\mathbf{a b} \backslash) \backslash(\mathbf{c d} \backslash)$ and the replacement string is $\backslash \mathbf{2} \backslash \mathbf{1}$, T-Spice will replace abcd with cdab. |
| \& | The entire matched regular expression. | If the search string is Windows and the replacement string is MS-\&, T-Spice will replace Windows with MS-Windows. |
| 10 | The entire matched regular expression. |  |
| 11 | Literal backslash | $\mathbf{a} \backslash \backslash \mathbf{n}$ matches $\mathbf{a} \backslash \mathbf{n}$. |
| 1\& | Literal ampersand, to avoid expression substitution | If the search string is $\mathbf{1 2 3}$ and the replacement string is $\boldsymbol{\&} \backslash \boldsymbol{\&} \boldsymbol{\&}$, T-Spice will replace 123 with 123\&123. |

## Edit > Replace

Prompts for text to be searched for (the target string) and replaced (the replace string) in the active window. The Replace dialog provides one input field and two options additional to the fields in the Find dialog (see "Edit > Find" (page 41)):


Replace with

## Replace

Replace All
Replace in

The replace string, which can include character codes from the $\downarrow$ submenu.

Replaces the next instance of the search string with the replace string.
Replaces every instance of the search string with the replace string.

- Selection replaces only the instances of the search string in the text that is selected.
- Whole file replaces all instances of the search string in the file.


## Command Tool

The Command Tool automates the insertion of T-Spice commands and device statements, in correct SPICE format, into the active window. You also can use it to specify filenames and command-line options before launching a T-Spice simulation.


## Edit > Insert Command

This command opens the T-Spice Command Tool, which lists the T-Spice simulation commands in a hierarchical arrangement, with general categories that expand into individual commands for each category.

You expand or collapse a category by double-clicking it or clicking the plus or minus sign next to the category. When you click on a category name in the left-hand tree, fields representing individual commands open in the right-hand pane of the dialog.

Commands are inserted to the right of the cursor position or replacing highlighted text (above the current line if nothing is selected and below the current line if something is selected.)

## Setting Simulation Options

## Simulation > Simulation Settings

Also accessible from the toolbar button $(\sqrt{5})$, the Simulation Settings command allows the user to specify options that will be used for all subsequent simulations. A multi-tab dialog is used to configure these options:

## Options



Command line arguments Use this field to enter command-line options, which modify a simulation without altering the input file. You can enter as many options as desired, separating each with a space. Refer to "Command-Line Options" on page 24 for a description of available options and their proper syntax.

A semicolon-separated list of folders, used to search for include files, model files, and subcircuit definitions.

Commands that are prepended to the user's spice deck. These are often useful for setting simulator options, and/or including specific header files

A semicolon-separated list of folders, used to search for Verilog-A model source code

## Output



## Output folder

The output file(s) are created in the specified directory. This directory can be an absolute path, or a path relative to the input file

## Automatically create a subfolder...

Always overwrite T-Spice
output files without
promptin
promptin

If this option is selected, each simulation run creates a new subfolder in the output folder; output files for that simulation run are placed in this subfolder. The subfolder name is based on the input file name, and includes additional timestamp information.

This option allows the user to preserve all results from every simulation. A copy of the input file is also kept in this subfolder

This option is available if the "create subfolder" option is not enabled. If this option is selected, preexisting output files will be overwritten without asking for confirmation from the user.

## W-Edit

| Simulation Settings | X |
| :---: | :---: |
| Options \| Output w-Edit | |  |
| -W-Edit waveform display |  |
| - Show during simulation |  |
| $\bigcirc$ Show after simulation completes |  |
| $\bigcirc$ Do not show |  |

## W-Edit waveform display Options for displaying simulation progress in W-Edit. Check an option to make it active.

- Show during simulation-displays traces in W-Edit while the simulation is running.
- Show after simulation completes-displays traces in W-Edit once the simulation is complete.
- Do not show-does not open W-Edit.


## Launching a Simulation

Simulation $>$ Run Simulation

The Simulation > Run Simulation command (shortcut F5 or toolbar button $\quad \mathbf{\nabla}$ ), launches a T-Spice simulation on the currently active document. If a simulation is already in progress, the new simulation is added to the queue of jobs awaiting simulation. This queue is displayed in the Simulation Manager window.

## Simulation Manager

The Simulation Manager allows you to control and monitor all T-Spice simulations. It queues files for simulation, displays their processing status, and allows you to stop or pause a simulation. You can also highlight one or more files in this window to view simulation results in the Simulation Status window or the W-Edit waveform viewer.

You can right-click ion any simulation entry to access the pop-up menu with shortcuts to the controls described above, as well as additional menu items that open a new file (New), specify whether the Simulation Manager will be visible (Hide) and whether it will be docked (Docking view).

There is only one Simulation Status window, and all simulations display their output in this window. When you select a simulation in the Simulation Manager, the Simulation Status window displays the results for that simulation.

## View > Simulation Manager

Use View > Simulation Manager to display or hide the Simulation Manager. This window can be displayed using a docked or undocked view (see "Docking and Undocking the Simulation Manager" on page 47.) Each simulation occupies one row, and each row has fiveattributes.

| Status | Input file | Output file | Start DatelTime | Elapsed Time |
| :---: | :---: | :---: | :---: | :---: |
| failed | Y:'My Documents'...'InverterDC.sp | InverterDC.out | March 12, 2008 16:29:44 | 00:00:02 |
| failed | Y:'My Documents'... , InverterOP.sp | InverterOP.out | March 12, 2008 16:30:12 | 00:00:03 |
| failed | Y:'My Documents', ..'InverterOP.sp | InverterOP.out | March 12, 2008 16:30:27 | 00:00:02 |
| finished | Y:'My Documents',..\|InverterTRAN.sp | InverterTRAN.out | March 12, 2008 16:30:47 | 00:00:02 |
| running | Y:My Documents\}..., RingoscillatorTRAN.sp $^{\text {a }}$ | RingOscillatorTRAN.out | March 12, 2008 16:31:05 | 00:00:03 |

## Status

Simulation status. Possible states include:

- Queued-the simulation is in the queue and will run when the simulation engine is available.
- Running-the simulation is underway.
- Paused-simulation has been suspended by the user.
- Finished-the simulation ran and output is available.
- Stopped-the simulation was stopped by the user.
- Failed-the simulation failed to run.

Input file
Full pathname of the input file
Output file
Full pathname of the output file

## Start Date/Time

The date and time at which the simulation began execution.
Elapsed Time
The total simulation run time in hh:mm:ss format. Pausing a simulation will not interrupt the measurement of elapsed time.

## Docking and Undocking the Simulation Manager

The Simulation Manager can also be docked or undocked by right-clicking in any field and checking or unchecking Docking view in the pop-up menu. When it is docked, you can double-click on any edge of the dialog box or click-and-drag one of the sides to undock it.

## Simulation Manager Commands

When the Simulation Manager is undocked, the following commands are available to control queued simulations.


Run Simulation

Stop

Pause/Resume

Delete

## Empty List

Show Waveform

Show Netlist

Show Output

Invokes "Edit > Replace" (page 43). If a file is highlighted, the appropriate file and path names will automatically populate the Input file and Output file fields.

Stops simulation processing for the highlighted file. Once a simulation is stopped, it cannot be resumed.

Pauses simulation when the status of the highlighted file is Running, and resumes simulation when the status of the highlighted file is Paused.

Removes the highlighted file from the simulation queue. If the simulation is running or paused, you will be prompted to stop processing on the file before it is deleted.

Removes all files from the simulation queue. If any simulations are running or paused, you will be prompted to stop processing before they are deleted.

Invokes the W-Edit waveform viewer for the selected simulation. If the active window is a file that has been previously simulated and the file is still in the Simulation Manager queue, the corresponding .out file will be displayed when W-Edit opens.

Opens a window with the selected input file. If the selected file is already open, makes that window active.

Opens a window with the output file (.out) corresponding to the selected simulation. If already open, makes that window active.

## Simulation Manager Context Menu

Right-clicking in any field of the Simulation Manager (either docked or undocked) opens a pop-up menu with the following options:

New...
Creates a new file

| Setup Simulation... | Brings up the Setup Simulation dialog. Options selected here will <br> apply to subsequent simulation jobs. <br> Removes the line from the Simulation Manager. No files are deleted. |
| :--- | :--- |
| Delete | Removes all lines from the Simulation Manager |
| Empty List | Show the output data file in W-Edit |
| Show Waveform... | Open the input netlist file |
| Show Netlist... | Open the output data file in a T-Spice text editor <br> Show Output... <br> Diff Copied Inputs... <br> Simulation Manager, then right-clicking on Diff Copied Inputs. This <br> option is only available if the files are located in different directories. <br> In the case where simulation output subfolders are automatically <br> created, the diff runs on the copied input files that are created in each <br> folder. |
| Fiff Output... | For this option to work, either two or three lines must be selected in <br> the Simulation Manager, and a Diff program must have been <br> specified in the Setup... Application... External Programs dialog. |
| Hide | Textually compare the output files of two simulations. |
| Docking view | For this option to work, either two or three lines must be selected in <br> the Simulation Manager, and a Diff program must have been <br> specified in the Setup... Application... External Programs dialog. |
| Show the Simulation Manager |  |

## Simulation Status

The Simulation Status window shows simulation statistics and progress information, as well as any warnings or error messages, for the currently running or most recently completed simulation

## View > Simulation Status

Use View > Simulation Status to toggle visibility of the Simulation Status window.


| Input file | Name of the input file. |
| :--- | :--- |
| Output file | Name of the output file. |
| Progress | The type of simulation, duration in nanoseconds, and percentage of <br> the simulation completed. |
| Total nodes | Total number of nodes simulated. |
| Total devices | Total number of devices simulated. |
| Active devices | Total number of active devices simulated. |
| Passive devices | Total number of passive devices simulated. |
| Independent sources | Total number of independent sources simulated. |
| Controlled sources | Total number of controlled sources simulated. |

## 4 Input Conventions

When a simulation is run, the input file is interpreted by the T-Spice parser. For T-Spice to function efficiently and as compatibly as possible with other versions of SPICE, the parser must enforce a number of language conventions. This chapter summarizes those conventions. (For more information, see "Simulation Commands" on page 59 and "Device Statements" on page 151.)

All nodes and devices in the circuit must be identified uniquely by their names. Node and device names have the following features.

- Their length is unlimited (except by hardware constraints).
- They can include all characters except tabs, spaces, semicolons (;), single quotes ('), curly braces ( $\}$ ), parentheses, forward slashes (/), and equal signs ( $=$ ).
- The dollar sign (\$) can appear in names, but cannot be a name by itself.
- They are case sensitive. For example, the name VDD is different from Vdd and vdd.

Model names cannot start with digits.
The following examples are all valid names:
in Alpha16 ONE[21]3_72

## Reserved Names

T-Spice uses reserved node names for the default system ground: gnd, GND, Gnd, and $\mathbf{0}$ (zero). All instances of these nodes are connected and treated as the same node, which is fixed at a potential of 0.0 volts.

The following keywords (in any combination of uppercase and lowercase letters) cannot be used as names:

| ac | bit | biti | bus |
| :--- | :--- | :--- | :--- |
| busi | dc | exp | inoise |
| off | onoise | params | pie |
| piei | pwl | pwlfile | poly |
| pulse | r | repeat | round |
| rounding | sffm | sin | sini |
| transfer |  |  |  |

## Device Names

Most device statements are of the form

ZXXX ...
where the variable $\boldsymbol{Z}$ represents the required key letter which uniquely specifies the device type, and the variable $\boldsymbol{x} \boldsymbol{x} \boldsymbol{x}$ represents a user-supplied alphanumeric string.

For example, MOSFET statements have a form following this example:

```
mtran1 d g s b nmos l=2um w=2um
```

In this example, $\mathbf{m}$ is the required key letter and tran1 is the user-supplied string. The device's name is mtran1 (not tran1).

A particular device may be indicated in the input file by either case, for example, $\mathbf{m}$ or $\mathbf{M}$, of the key letter - but the case must remain constant for the same device throughout the file.

## Hierarchical Names

Hierarchical node names are used to refer to nested subcircuit nodes. Each level in the name of a node is separated by a period (.).

For example, the internal node ing in the xnand subcircuit contained in the xadder subcircuit is specified as

```
xadder.xnand.ing
```


## Subcircuit Pin Name Aliasing

T-Spice recognizes subcircuit pin node names by their internal names as well as their global names.
For example, the netlist

```
.subckt test a b
r1 a c 100
r2 c b }10
.ends
x1 a1 b1 test
```

creates three nodes: $\mathbf{a 1}, \mathbf{b 1}$, and $\mathbf{x 1 . c}$ a1 and $\mathbf{b 1}$ are globally recognized node names; but they may also be referred to by aliases $\mathbf{x 1 . a}$ and $\mathbf{x 1 . b}$, respectively -for example, within a command such as .print dc $\mathrm{v}(\mathrm{x} 1 . \mathrm{a})$.

## Comments

Comments provide information about the circuit, but are not processed as part of the formal circuit description. Comments are generally indicated by the presence of special characters called delimiters.

However, T-Spice always treats the first line of the input file as a comment, even without comment delimiters.

Other comments may be placed anywhere in the circuit description.
Several comment styles are allowed, for compatibility with other versions of SPICE:

- An asterisk (*), dollar sign (\$), or semicolon (;) in the first column of a line indicates that the entire line is a comment.
- A dollar sign or semicolon, but not an asterisk, anywhere in a line other than in the first column indicates that the rest of the line is a comment.
- C-style comments, enclosed by the delimiters /* and */, can be used anywhere, except in the middle of multi-word commands (such as .print tran) or arguments. A C-style comment is not restricted to one line.

The comments in the following examples are highlighted:

```
* Lines beginning with asterisks,
$ or dollar signs,
; or semicolons are ignored.
r1 node1 node2 4k $ This comment can follow a command
c2 node3 node4 100f ; This is like a '$' comment
v1 node5 GND /* This is a
    C-style comment */ 3volt
```

A C-style comment that interrupts a command or argument may cause an error message. However, comments may appear between arguments.

The first two lines in the following examples would cause error messages:

```
.print /* wrong */ tran v(1)
.options prtdel /* wrong */ = 0.01
.options abstol=1e-8 /* OK */ reltol=1e-4
```


## Line Continuation

Input file lines may be of any length; however, it is often convenient to break up long lines for readability.

A plus sign (+) in the first column denotes line continuation. For example:

```
.model nmes NMF
+ vto=-2.5 rs=100 rd=200 pb=0.7
+ alpha=2.0 cgs=500.0f cgd=100.0f
```


## Comments in Continued Lines

Comments may appear between continued lines. However, blank lines may not appear between continued lines.

A continued line may include a dollar sign (\$) or semicolon (;) comment symbol, in which case the rest of the line is ignored.

No plus sign is needed for a comment line, a line continuing a C-style comment, or a line continuing an expression (see "Parameters" on page 55).

For example:
. options

* now we declare several options, continuing the line
+ prtdel $=10 \mathrm{~ms}$ \$ (; would work too)
+ abstol $=1 e-10 / *$ we can put a
C-style comment here */


## Expressions and Continued Lines

Plus signs cannot be used to indicate addition in the first column within multi-line expressions.
For example:

```
.options numnd = '7 +
log(10.1) $ will be added to previous term
+ 2' $ will NOT be added - '+' is ignored
```


## Numbers and Units

Some commands and statements require arguments representing physical quantities with attached units (such as seconds or volts). Such numbers can be expressed in floating point, scientific, or fixed-point notation, and can be followed by metric abbreviations indicating order of magnitude.

The base units ( $\mathbf{s}, \mathbf{v}, \mathbf{a}, \mathbf{f}, \mathbf{h}$ ) are implicit from the context and are optional.
For example, the following expressions can all specify 12 nanoseconds in the appropriate context:

$$
12 \mathrm{~ns} \quad 12 \mathrm{e}-9 \quad 12000 \mathrm{p}
$$

Acceptable metric abbreviations are as follows.

| Abbreviation | Prefix | Meaning |
| :--- | :--- | :--- |
| $\mathbf{t}$ or $\mathbf{T}$ | tera- | $10^{12}$ |
| $\mathbf{g}$ or $\mathbf{G}$ | giga- | $10^{9}$ |
| $\mathbf{m e g}$ or $\mathbf{M E G}$ | mega- | $10^{6}$ |
| $\mathbf{x}$ or $\mathbf{X}$ | mega- | $10^{6}$ |
| $\mathbf{k}$ or $\mathbf{K}$ | kilo- | $10^{3}$ |
| $\mathbf{m}$ or $\mathbf{M}$ | milli- | $10^{-3}$ |
| 'u or $\mathbf{U}$ | micro- | $10^{-6}$ |
| $\mathbf{n}$ or $\mathbf{N}$ | nano- | $10^{-9}$ |
| $\mathbf{p}$ or $\mathbf{P}$ | pico- | $10^{-12}$ |
| $\mathbf{f}$ or $\mathbf{F}$ | femto- | $10^{-15}$ |

The abbreviation $\mathbf{f}$ is ambiguous because it can mean either the scale indicator "femto-" or the unit "farad." T-Spice employs the following convention: $\mathbf{f}$ by itself means "femto-." Thus $\mathbf{1 0 0 f}$ means "100 femto-," where the unit is clear from the context. Where $\mathbf{f}$ precedes a base unit, as in $\mathbf{f f}$ and $\mathbf{f s}$, or follows a metric abbreviation, as in uf, there is no ambiguity. When "farad" by itself is meant, no unit should be used.

A commonly used unit abbreviation is mil (or MIL), representing $10^{-3}$ inch.

## Parameters

You can declare parameters and assign them values with the .param command. Parameters cannot be reassigned values within an input file.

Parameter names can contain any characters except tabs, spaces, commas, curly braces, parentheses, single quotes, square brackets, equal signs, and algebraic operators (+-*/^).

## Expressions

Any number in a command or statement may be replaced by an algebraic expression. Expressions must conform to the following conventions.

- They must be enclosed by single quotes (').
- They may span several lines. The plus sign (+) is ignored if it appears in the first column of a continued expression.
- They may include comments that do not interrupt numeric values or parameter names.

Expressions may involve any valid combination of numbers, parameters (".param" (page 113)), operations, algebraic functions, and user-defined functions. T-Spice evaluates expressions according to a standard mathematical operator precedence, shown below. Level 1 has the highest operator precedence, and level 10has the lowest.

| Priority | Operation | Description |
| :--- | :--- | :--- |
| Level 1 | $(\boldsymbol{x})$ | Parentheses |
| Level 2 | $\boldsymbol{f}(\boldsymbol{x})$ | Function call |
| Level 3 | $\boldsymbol{x}^{\wedge} \boldsymbol{y}$ | Exponentiation |
| Level 4 | $-\boldsymbol{x}$ | Unary negation |
| Level 5 | $\boldsymbol{x} \times \boldsymbol{y}$ | Multiplication |
|  | $\boldsymbol{x} / \boldsymbol{y}$ | Division |
| Level 6 | $\boldsymbol{x}+\boldsymbol{y}$ | Addition |
|  | $\boldsymbol{x}-\boldsymbol{y}$ | Subtraction |
| Level 7 | $<,<=,>,>=$ | Relational operators |
| Level 8 | $==,!=$ | equality and inequality |
| Level 9 | $\mathrm{x} \& \& \mathrm{y}$ | logical AND |
| Level 10 | $\mathrm{x} \\| \mathrm{y}$ | logical OR |

The operations and functions available in T-Spice are summarized in the following tables (in which the variables $\boldsymbol{x}$ and $\boldsymbol{y}$ represent numbers, parameter names, or subexpressions). All angles are in radians.

| Operation | Description |
| :---: | :---: |
| ( $x$ ) | Parentheses - to override operator precedence |
| $x+y$ | Addition |
| $x-y$ | Subtraction |
| $x^{*} y$ | Multiplication |
| $x / y$ | Division |
| $x^{\wedge} y, x^{\star *} y$ | Exponentiation ( $x^{y}$ ) |
| -X | Unary negation |
| $x<y, x<=y, x>y, x>=y$ | Relational operators - return 1 if the relation is true, otherwise 0 |
| $x==y, x!=y$ | Equality operators - return 1 if the (in)equality is true, otherwise 0 |
| $x \& \& y$ | Logical AND - returns 1 if $x$ and $y$ are true (non-zero), otherwise 0 |
| $\mathbf{x} \\| \mathrm{y}$ | Logical OR - returns 1 if x or y is true (non-zero), otherwise 0 |

## Built-in Functions

Function

## $\operatorname{abs}(x)$

$\operatorname{acos}(x)$
$\operatorname{asin}(x)$
$\operatorname{atan}(x)$
$\operatorname{atan} 2(x, y)$
$\operatorname{ceil}(x)$
$\cos (x)$
$\cosh (x)$
$\mathrm{db}(x)$
$\operatorname{err}(x, y)$
$\exp (x)$
fabs( $x$ )
floor $(x)$
fmod $(x, y)$
if $(c, a, b)$
or
c ? a : b
$\operatorname{int}(x)$
$\operatorname{Idexp}(x, y)$

## Description

Absolute value of $x$ (same as fabs)
inverse cosine of $x$ (error if $|x|>1$ )
Inverse sine of $x$ (domain error if $|x|>1$ )
Inverse tangent of $x$ (range: $[-\pi / 2, \pi / 2]$ )
Inverse tangent of $y / x$ (range: $[-\pi, \pi]$ )
Smallest integer not less than $x$
Cosine of $x$
Hyperbolic cosine of $x$
$x$ in decibels: (sign of $x) \cdot 20 \cdot \log _{10}(|x|)$
error analysis; $\operatorname{abs}(x-y) / \max (x, y)$
$\mathrm{e}^{x}$
Absolute value of $x$ (same as abs)
Largest integer not greater than $x$
Remainder of $x y$ (error if $y=0$ )
conditional statement, if $\boldsymbol{c}$ is true, then $\boldsymbol{a}$, else $\boldsymbol{b}$.
Two syntax variations are supported for the conditional statement the if() function call, and the C style of conditional expression

Convert $x$ to an integer, removing the fractional portion
$x \times 2 y$ for integer $y$

| Function | Description |
| :---: | :---: |
| $\log (x)$ | Natural logarithm of $x$ (error if $x \leq 0$ ) |
| $\log 10(x)$ | Logarithm (base 10) of $x$ (error if $x \leq 0$ ) |
| $\log 2(x)$ | Logarithm (base 2) of $x$ (error if $x \leq 0$ ) |
| $\max (x 1, x 2)$ | Evaluates to the maximum of the two arguments. |
| $\min (x 1, x 2)$ | Evaluates to the minimum of the two arguments. |
| pow(x,y) | Exponentiation ( $x^{y}$ ) |
| pwr $(x, y)$ | In HSPICE compatibility mode (default): <br> $(\operatorname{sign}$ of $x) \cdot\|x\|^{y}$ <br> In PSPICE compatibility mode (.option spice=pspice) exponentiation $\left(x^{y}\right)$, equivalent to $\operatorname{pow}(\mathbf{x}, \mathbf{y})$ |
| pwrs( $x, y$ ) | signed power function, (sign of $x$ ) $\cdot\|x\|^{y}$ |
| $\operatorname{sgn}(x)$ | $\begin{aligned} & \text { Sign of } x:-1 \text { if } x<0 \\ & 0 \text { if } x=0 \\ & 1 \text { if } x>0 \end{aligned}$ |
| $\operatorname{sign}(x, y)$ | $($ sign of $y) \cdot\|x\|$ |
| $\boldsymbol{\operatorname { s i n }}(x)$ | Sine of $x$ |
| $\sinh (x)$ | Hyperbolic sine of $x$ |
| sqrt( $x$ ) | Square root of $x(-\operatorname{sqrt}(\|x\|)$ if $x<0)$ |
| $\mathbf{s t p}$ (expression) <br> or <br> stp(expression1, <br> expression2) | The first syntax evaluates to 0 if expression is negative, and 1 otherwise. The second syntax evaluates to 0 if expression 1 is less than -expression2, to 1 if expression1 is greater than expression2, and to (expression $1+$ expression 2$) /(2$ expression 2$)$ otherwise. The second syntax thus provides a continuous approximation to a step function. |
| $\begin{aligned} & \text { table(x, x1, y1, x2, y2, } ., \\ & \text { xn, yn) } \end{aligned}$ | All arguments of the table function may themselves be subexpressions. The table function evaluates the piecewise linear function defined by the points $x 1, y 1, x 2, y 2, \ldots, x n, y n$, connected by straight lines. The function value is the $y$-value of that function at $x$. The points are automatically sorted in ascending order of $x$ values to form the piecewise linear function. If $x$ is less than the smallest $x_{k}$, then the return value is the $y$-value corresponding to the smallest $x_{k}$. Similarly, if $x$ is greater than the largest $x_{k}$, then the return value is the $y$-value corresponding to the largest $x_{k}$. |
| $\boldsymbol{\operatorname { t a n }}(x)$ | Tangent of $x$ |
| $\tanh (x)$ | Hyperbolic tangent of $x$ |

## Differentiation and Integration functions

In addition to the Standard math library functions, T-Spice provides a set of functions for computing integrals and derivatives of data.

The $\operatorname{ddt}(f), \mathbf{d} \mathbf{2 d t}(f)$, and $\operatorname{idt}(f)$ (aka $\mathbf{s d t}(f)$ ) functions compute the time derivatives and integrals of transient simuation data.

The $\operatorname{ddx}(\boldsymbol{f}, \boldsymbol{x}), \mathbf{d} \mathbf{2 d x}(\boldsymbol{f}, \boldsymbol{x})$, and $\mathbf{i d x}(\boldsymbol{f}, \boldsymbol{x})$ (aka $\mathbf{s d x}(\boldsymbol{f}, \boldsymbol{x})$ ) functions compute the derivatives and integrals of the variable or expression $f$ with respect to the independent variable or expression $\boldsymbol{x}$.

The time-based integration and differentiation functions, and the generic $\boldsymbol{x}$ dependent forms of the functions, both use polynomial fits to the data for computing the integrals and derivatives. In the case of the transient functions, the order of the polynomial tracks that of the transient simulation engine, which is controled by the "maxord" (page 244) option. The generic $\boldsymbol{x}$ dependent functions use a second-order polynomial fit, by default.

The order of the function equations can be changed using the const_dt_maxord, and const_dx_maxord options:
. options const_dt_maxord=[0-4] ; default value is 0 , selecting transient order . options const_dx_maxord=[1-4] ; default value is 2

Note:
The quality of integrals is highly dependent upon the order of the fitting polynomial. It is important to select an order of equations which is an appropriate fit to the data. If the dependent function $f$ is highly irregular or is a square-shaped digital signal, then a 1st or 2 nd order integration is best. Higher order equations should only be used for very smooth data.
If the integration solutions are suspicious, perhaps containing very large integral values, then the solutions should be verified by re-running the simulation with the function integral order set to 1 , which results in a piecewise summation of integrands, without higher order effects.

| Function | Description |
| :--- | :--- |
| $\boldsymbol{\operatorname { d d t } ( \boldsymbol { f } )}$ | Derivative of $\boldsymbol{f}$ with respect to time |
| $\mathbf{d 2 d t}(\boldsymbol{f})$ | Second derivative of $\boldsymbol{f}$ with respect to time |
| $\mathbf{\operatorname { i d t } ( \boldsymbol { f } ) \| \mathbf { s d t } ( \boldsymbol { f } )}$ | Integrate $\boldsymbol{f}$ in time |
| $\mathbf{d d x}(\boldsymbol{f}, \boldsymbol{x})$ | Derivative of $\boldsymbol{f}$ with respect to $\boldsymbol{x}$ |
| $\mathbf{d 2 d x}(\boldsymbol{f}, \boldsymbol{x})$ | Second derivative of $\boldsymbol{f}$ with respect to $\boldsymbol{x}$ |
| $\mathbf{i d x}(\boldsymbol{f}, \boldsymbol{x}) \mid \mathbf{s d x}(\boldsymbol{f}, \boldsymbol{x})$ | Integrate $\boldsymbol{f}$ in $\boldsymbol{X}$ |

## 5 Simulation Commands

## Introduction

This chapter describes features, outlines syntax, and gives examples for the simulation commands of the T-Spice circuit description language.

The commands are listed in alphabetical order. Many commands have options, which branch to different modes, and arguments, which indicate expressions, nodes, or devices to be operated on. Options and arguments must be separated by spaces or new lines (with line continuation).

The Syntax sections follow these conventions:

- Italics indicate variables to be replaced by actual names, numbers, or expressions.
- Curly braces \{ \} indicate alternative values for the same option or argument.
- Square brackets [ ] enclose items that are not required.
- Vertical bars | separate alternative values for the same option or argument.
- Ellipses ... indicate items that may be repeated as many times as needed.

Brackets, vertical bars, and ellipses are not typed in the input file. All other characters are typed as shown. For further information, see: "Input Conventions" on page 51; "Device Statements" on page 151.

Performs AC analysis to characterize the circuit's dependence on small-signal input frequency: the DC operating point is computed, a linearized small-signal model is constructed at the DC operating point, and the circuit's response over a range of frequencies is measured.

- Small-signal parameters are reported to the main simulation output file. You can disable this reporting or specify a different output file using the command ".acmodel" (page 63). Reporting is automatically disabled if the simulation contains more than 1000 nodes.
- AC analysis results can be reported with the commands .print ac, .probe ac (for binary output), or .measure ac. For additional information on these commands, see ".print" (page 119), ".probe" (page 133), and ".macro /.eom" (page 88).
- The frequency can be varied linearly, by octaves, or by decades, by specifying a total number of test points, or by listing specific test frequencies.


## Syntax

```
.ac {lin|oct|dec} num start stop [sweep swinfo] [analysisname=name]
or
    .ac list f1 f2 ...fn [sweep swinfo] [analysisname=name]
or
    .ac poi num fl f2 ...fn [sweep swinfo][analysisname=name]
```


## Parameters

lin | oct $\mid$ dec
list
poi
num
start
stop
sweep
analysisname

Frequency variation mode.

- lin: linear sweep.
- oct: logarithmic sweep by octaves.
- dec: logarithmic sweep by decades.

Using the list keyword with .ac allows the user to specify a list of frequencies (values) for which the analysis is to be performed.

Using the poi keyword with .ac allows the user to specify a list of frequencies (values) for which the analysis is to be performed. The poi mode of processing is the same as the list mode, except that the syntax for poi requires that the number of frequencies, $\boldsymbol{N}$, be specified next.

Frequency count.

- Linear mode: Number of frequencies between start and stop.
- Octave mode: Number of frequencies per octave between start and stop.
- Decade mode: Number of frequencies per decade between start and stop.
- poi mode: Total number of frequency values.

First frequency. (Unit: Hertz.)
Last frequency. (Unit: Hertz.)
Specifies the parameter values of the sweep for which analysis will be performed. The sweep keyword is equivalent to ".step" (page 138) and uses the same parameter syntax. However, sweep applies only to one analysis command, while .step applies to all analysis commands in the input file. If sweep is specified on an analysis command and .step is present, the sweep sweep is nested inside the .step sweep. The parameter sweep may be used to specify a parametric sweep, Monte Carlo analysis, or optimization.

Specifies an analysis name that will be referenced by an .optimize simulation command. For further information, see ".optimize" (page 104).

## Examples

.ac DEC 5 1MEG 100MEG
Defines a frequency sweep from 1 MHz to 100 MHz by decades, with 5 points per decade.

```
.ac LIN 100 10K 100MEG
```

Defines a linear frequency sweep from 10 kHz to 100 MHz with 100 equally spaced points.

```
.ac list 5 50 500 5000 sweep rval dec 10 1 1000
```

Performs a logarithmic sweep of the parameter rval from 1 to 1000 , using 10 points per decade; also performs an AC analysis at the four specified frequencies for each value of rval.

## .acmodel

Modifies reporting of small-signal model parameters and operating points for specified devices in conjunction with AC analysis or DC operating point analysis. Small-signal parameters are automatically reported to the main simulation output file with the use of either .ac or .op in the input file.
" If ".ac" (page 60) and ".op" (page 102) are missing from the input file, .acmodel is ignored.

- No small-signal data is reported if the simulation model has more than 1000 nodes.
- Small-signal data are available for diodes, resistors, BJTs, JFETs, MESFETs, MOSFETs, and devices modeled with user-defined external models.


## Syntax

```
.acmodel [output file ] {[device [[,] device ...]]}
```

output file $\quad$ Output filename. If no filename is specified, then the output will be reported to the main simulation output file.
device $\quad$ Device(s) for which small-signal model parameters and operating points are to be given. If no devices are specified, then no smallsignal data is reported.

## Examples

$$
. \text { acmodel }\{\text { mt1 mt2\} }
$$

Prints data for devices $\mathbf{m t} \mathbf{1}$ and $\mathbf{m t}$.
.acmodel \{\}
Turns off all small-signal parameter reporting.

## .alter

Causes a simulation to be repeated with slight changes as specified after the .alter command. Multiple .alter commands can appear in the same netlist. T-Spice performs the first simulation with all commands that occur before the first .alter command; the second simulation incorporates changes between the first and second .alter commands; the third simulation incorporates changes between the second and third .alter commands, and so on. The optional altername string identifies the .alter block that follows and is used to identify the corresponding simulation output in output files.

A .alter block can contain any legal T-Spice statement. This command occurs at the end of a complete input file.

- Elements, option values, parameter values, and ".connect" (page 66) and ".model" (page 96) statements in a .alter block replace equivalent statements in the main netlist if the name of the element, parameter, option, data set, or model parameter set matches. If no name match can be made, the statement in the .alter block is simply added to the simulation.
- Statements are cumulative and progressive from one .alter block to the next such that any additions or changes made in block $\boldsymbol{N}$ will also occur (unless superseded) in block $\boldsymbol{N + 1}$.
- Initial conditions (".hdl" (page 79)) and ".nodeset" (page 100) replace equivalent commands that operate on the same nodes or devices. If no equivalent command is found in the main netlist, the command is simply added.
- If a .alter block contains a ".temp" (page 145) command, any .temp commands in the original netlist are replaced with the new .temp command.
- The commands ".lib" (page 85) and ".if ... / .elseif ... / .else / .endif" (page 82) can be used within ".alter" (page 64) blocks to include command and element statements.
- The ".del lib" (page 70) command can be used to delete a library section included in the original input file. All commands and elements in the library section are ignored during the "altered" simulation.
- Simulation commands such as ".ac" (page 60), ".tran" (page 147), and ".step" (page 138) do not replace commands in the original input file, but are simply added on as new commands.


## Syntax

```
.alter [altername]
```


## Examples

```
v1 1 0 1
r1 1 2 1k
r2 2 0 1k
.op
.alter
r1 1 2 2k
.alter r2_4k
r2 2 0 4k
.end
```

This performs three simulations:


The third uses $\mathbf{r} \mathbf{1}=\mathbf{2 k}, \mathbf{r} \mathbf{2}=\mathbf{4 k}$, and is identified by alter=r2_4k; the output is $\mathbf{v}(\mathbf{2})=\mathbf{0 . 6 6 6 6 6 7}(\mathbf{2} / \mathbf{3})$.
The abbreviated output would be:

```
*SEDIT: Alter=0
*SEDIT: Analysis types DCOP 1 ACMODEL 0 AC 0 TRANSIENT O TRANSFER 0 NOISE 0
* BEGIN NON-GRAPHICAL DATA
DC ANALYSIS - alter=0
v(2) = 5.0000e-001
v(1) = 1.0000e+000
i(v1) = -5.0000e-004
* END NON-GRAPHICAL DATA
*SEDIT: Alter=1
*SEDIT: Analysis types DCOP 1 ACMODEL 0 AC 0 TRANSIENT O TRANSFER 0 NOISE 0
* BEGIN NON-GRAPHICAL DATA
DC ANALYSIS - alter=1
v(2) = 3.3333e-001
v(1) = 1.0000e+000
i(v1) = -3.3333e-004
* END NON-GRAPHICAL DATA
*SEDIT: Alter=2
*SEDIT: Analysis types DCOP 1 ACMODEL 0 AC 0 TRANSIENT O TRANSFER 0 NOISE 0
* BEGIN NON-GRAPHICAL DATA
DC ANALYSIS - alter=r2_4k
v(2) = 6.6667e-001
v(1) = 1.0000e+000
i(v1) = -1.6667e-004
* END NON-GRAPHICAL DATA
```


## .connect

This command will connect two nodes in your circuit, so that the two nodes will be simulated as only one node. In essence, one node name becomes an alias for another node name.

Both nodes must be at the same level in the circuit design that you are simulating: you cannot connect nodes that belong to different subcircuits

## Syntax

.connect node1 node2

If you connect node 2 to node 1 , you can then refer to either node 1 or node 2 in other simulation commands, and it will refer to the same node.

## Examples

```
vcc 0 cc 5v
r1 0 1 5k
r2 1 cc 5k
.tran 1n 10n
.print i(vcc) v(1)
.alter
.connect cc 1
.end
```

The first .tran simulation includes two resistors. Later simulations have only one resistor, because r 2 is shorted by connecting cc with 1 .

You may also use multiple .connect statements to connect several nodes together:

```
.connect node1 node2
```

.connect node2 node3
connects both node 2 and node 3 to node1. The T-Spice simulation evaluates node voltages and related terms only for node1; node2, and node3 are the same node as node1.

Note: If you set .option node, T -Spice prints out a node connection table.

Used to incorporate external numerical data into simulations. The data can be used to specify reference data for error measurements, which is often used in conjunction with optimization for model parameter extraction. Also used to specify parametric sweeps in which several variables are swept simultaneously.

## Syntax

```
.data dataname
+ colname [colname [...]]
+ value [value [...]]
+ value [value [...]]
.enddata
```

The number of columns is equal to the number of values per row.

```
dataname Name assigned to the data set.
colname Name assigned to a column of data within the data set.
value Numeric parameter value. These values may be expressions, but
    must not depend on other parameter values.
```

A data set can be used with the ".macro /.eom" (page 88) command to compute differences between simulation output curves and corresponding external data.

A data set can also be used to define a parameter sweep on an ".ac" (page 60), ".dc" (page 69), ".step" (page 138), or ".tran" (page 147) command.

The syntax for the sweep parameter on those commands is as follows:

```
data=dataname
```

where dataname refers to a .data statement of the same name. Each row of numbers in the data statement corresponds to a sweep step, and each column refers to a sweep parameter (which must be a global parameter defined using .param) and the values which the parameter takes on. The colname strings identify the parameters to be swept. For each sweep step, the sweep parameters take on the values listed in a row of data.

## Examples

```
.data idsdata
+ time v1dat
+ 0 0
+ 1u 0
+ 1.1u 5
+ 2u 5
.enddata
.tran 0.1u 2u
.measure tran v1fit err1 v1dat v(1)
```

This example computes the difference between the externally supplied data curve v1dat and the simulated transient analysis response voltage $\mathbf{v}(1)$.

```
.data idsdata
+ vds ids
+ 0.0000e+00 0
+ 5.0000e-01 4.8565e-10
+ 1.0000e+00 2.2752e-06
+1.5000e+00 1.2558e-05
+2.0000e+00 3.1509e-05
+ 2.5000e+00 5.9462e-05
+ 3.0000e+00 9.6027e-05
+ 3.5000e+00 1.4135e-04
+ 4.0000e+00 1.9569e-04
+4.5000e+00 2.5978e-04
+5.0000e+00 3.2942e-04
.enddata
.param vds=0 ids=0
vd drain source vds
m1 drain gate source bulk nmos 1=2u w=2u
.dc data=idsdata
.measure dc idsfit err1 ids id(m1)
```

This example computes the (relative) difference between the externally supplied data curve ids and the simulated MOSFET drain current id(m1). This is particularly useful in conjunction with optimization for model parameter extraction, where the purpose of the simulation is to select model parameter values which yield the best match between simulated and measured data curves.

Performs DC transfer analysis to study the voltage or current at one set of points in a circuit as a function of the voltage or current at another set of points. Can also be used for linear or logarithmic sweeps of DC voltage or current; for sweeps of parameters other than voltage and current source values; and for Monte Carlo analysis or optimization.

- Transfer analysis is done by sweeping the source variables over specified ranges, and recording the output.
- Up to three parameters can be specified per .dc command.
- When two or more sources are specified, the last-named source "controls" the sweeping process (see "Examples," below).
- The specified current or voltage sources must exist-that is, be defined by $\mathbf{i}$ or $\mathbf{v}$ device statements elsewhere in the input file.
- DC transfer analysis results can be reported with the ".print" (page 119) dc, ".probe" (page 133) dc, and ".macro /.eom" (page 88) dc commands.


## Syntax

```
.dc swinfo [[sweep] swinfo [[sweep] swinfo]]
```

Refer to ".step" (page 138) for a syntax description of swinfo.

## Examples

```
.dc isrc 0 1e-6 0.1e-6
```

Current source isrc is swept from 0 to 1 microampere in 0.1-microampere steps.

```
.dc vin 0 5 0.05 VCC 4 6 0.5
```

Names two voltage sources: vin, to be swept from 0 to 5 volts in 0.05 -volt steps, and VCC, to be swept from 4 to 6 volts in 0.5 -volt steps. The second source "controls" the sweep: VCC is initially set to 4 volts, while vin is swept over its specified range. Then VCC is incremented to 4.5 volts, and vin is again swept over its range. This process is repeated until VCC reaches the upper limit of its specified range.

| .data sweep_params |  |  |
| :--- | :--- | :--- |
| + vds | r 2 | length |
| +0.0 | 1 k | 10 u |
| +1.0 | 500 | 12 u |
| +2.0 | 100 | 14 u |
| .enddata |  |  |
| .dc data=sweep_params |  |  |

This example performs a DC sweep defined using a data statement. There are three sweep steps, and the parameters $\mathbf{v d s}, \mathbf{r} \mathbf{2}$, and length are varied in the sweep. On the first sweep step, $\mathbf{v d s} \mathbf{=} \mathbf{0}, \mathbf{r} \mathbf{2}=\mathbf{1 0 0 0}$, and length=10u; on the second sweep step, $\mathbf{v d s}=\mathbf{1}, \mathbf{r} \mathbf{2}=\mathbf{5 0 0}$, and length=12u; on the third sweep step, vds=2, r2=100, and length=14u.

## .del lib

Used to delete a section from a library file previously included using the ".lib" (page 85) command. The .del lib command is used in ".alter" (page 64) blocks, typically to replace a library section with a different one.

## Syntax

.del lib filename section

| filename | Name of the referenced library file. If the referenced filename or path <br> contains a space, enclose the entire path in single or double quotation <br> marks. |
| :--- | :--- |
| section | Name of the library section in filename that is to be deleted. |

## Examples

```
.lib bsim3model.md typical
.alter
.del lib bsim3model.md typical
.lib bsim3model.md fast
.alter
.del lib bsim3model.md fast
.lib bsim3model.md slow
. end
```

T-Spice input such as shown above might be used to run a simulation three times, first with typical, then with fast, and finally with slow model parameters. First, the library section called typical is loaded for the first simulation. The second simulation incorporates changes between the first and second .alter commands, so that the typical library section is deleted and replaced with the fast library section. Similarly, the third simulation replaces the fast library section with the slow one.

## .end

Signifies the end of the circuit description.

- Any text in the input file after the .end command is ignored.
- The .end command is optional in T-Spice but is included for compatibility with generic SPICE.


## Syntax

```
.end [comment]
```


## .enddata

Signifies the end of a .data statement.

- The .enddata command must accompany a ".data" (page 67) command.


## Syntax

.enddata [comment]

## .endl

Signifies the end of a library definition.

- The .endl command must accompany a ".lib" (page 85) command.


## Syntax

.endl [comment]

## .ends

Signifies the end of a subcircuit definition.

- The .ends command must accompany a ".subckt" (page 142) command.


## Syntax

.ends [comment]

## .four

Performs Fourier analysis on transient analysis data.

- Fourier components (magnitude and phase) are computed for a given fundamental frequency and corresponding to a specified number of integer multiples of the fundamental frequency.
- The DC Fourier component is computed, as well as the total harmonic distortion, defined as

$$
\begin{equation*}
\frac{1}{R_{1}} \cdot\left(\sum_{m=2}^{n f r e q s} R_{m^{2}}\right) \tag{0.4}
\end{equation*}
$$

where $R m$ is the magnitude of the $m$ th Fourier component.

- The .four command is ignored if no .tran command is found.


## Syntax

| .four F list [nfreqs= $N$ ] | [npoints= $P$ ] [interpolate= $T$ ] |
| :---: | :---: |
| $F$ | Fundamental frequency. |
| list | Output variables for which the analysis is to be performed. Each of these can be any valid output item from a ".print" (page 119) tran command, including output expressions. |
| $N$ | Number of frequencies for which Fourier components are determined. (Default: 9.) |
| P | Number of points over which transient analysis data is interpolated to fit. These points equally divide the analysis interval $(T-J, T)$, where $T$ is the final time specified on the corresponding ".tran" (page 147) command, and $J=1 / \boldsymbol{F}$. Increasing $\boldsymbol{P}$ improves accuracy but increases simulation time and memory use. (Default: 100.) |
| I | If $0, T$-Spice inserts an actual computed time point at each place where a Fourier analysis time point is needed without interpolating transient data to fit on $n p$. If 1, Fourier analysis is based on interpolated data. (Default: 1.) |

## Examples

```
v1 2 0 sin (4 10 9e6 0 0 20)
v2 1 2 sin (0 3 3e6 0 0 -50)
.tran 1u 10u
.four 3e6 v(1) npoints=1000
```

The formula for $\mathrm{v}(1)$ is:

$$
\begin{align*}
& v(1)=4+  \tag{0.5}\\
& 10 \sin \left[2 \pi\left(9 \times 10^{6} t+20 / 360\right)\right]+ \\
& 3 \sin \left[2 \pi\left(3 \times 10^{6} t-50 / 360\right)\right]
\end{align*}
$$

The analytic Fourier response for this formula is as follows:

- The DC component is 4 .
- The first harmonic (at a frequency of 3 MHz ) has a magnitude of 3 and a phase of -50 degrees.
- The third harmonic (at a frequency of 9 MHz ) has a magnitude of 10 and a phase of 20 degrees.
- All other harmonics have a zero Fourier component.

The output will be:

```
* BEGIN NON-GRAPHICAL DATA
FOURIER ANALYSIS RESULTS
Fourier components of transient response v(1)
DC component = 4.0011e+000
Harmonic no Frequency<Hz> Fourier comp Normalized FC Phase<deg> Normalized phase
    3.0000e+006 2.9989e+000 1.0000e+000 -4.9651e+001 0.0000e+000
    6.0000e+006 2.4224e-002 8.0777e-003 3.5132e+001 8.4783e+001
    9.0000e+006 9.9949e+000 llll
    1.2000e+007 3.4401e-002 1.1471e-002 -1.6494e+002 -1.1529e+002
    1.5000e+007 1.8803e-002 6.2701e-003 -1.6786e+002 -1.1821e+002
    1.8000e+007 1.3374e-002 
    2.1000e+007 1.0534e-002 3.5126e-003 -1.7085e+002 -1.2120e+002
    2.4000e+007 8.7570e-003 2.9201e-003 -1.7169e+002 -1.2204e+002
    2.7000e+007 7.5266e-003 2.5098e-003 -1.7229e+002 
Total harmonic distortion = 333.3 percent
* END NON-GRAPHICAL DATA
```

where the DC component is $4.0011 \mathrm{e}+000$, the first harmonic has a magnitude of 2.9989 and a phase of $4.9651 \mathrm{e}+001$, the third harmonic has a magnitude of $9.9949 \mathrm{e}+000$ and a phase of $2.0564 \mathrm{e}+.001$.

Note that harmonics one and three have the exponent e+000, while the magnitude of the other harmonics-e-002 or even e-003-is quite small in comparison.

## .global

Specifies nodes with global scope.

- Global node names refer to the same nodes both inside and outside subcircuit definitions.
- Ground ( $\mathbf{0}$, gnd, Gnd, or GND) is automatically defined to be a global node.


## Syntax

.global node1 [[,] node2 ...]

## .gridsize

Specifies the number of gridpoints contained in each dimension of a device type's internal tables. (See "Evaluation Methods" on page 33, and also ".vrange" on page 150 regarding internal tables.)

- Charge and current tables for a given device type have the same gridsize.
- All devices of the same type within a simulation have the same gridsize.
- Increasing gridsize tends to increase time and memory requirements as well as accuracy.


## Syntax

.gridsize type $A$ [ $B$ [C]]
type $\quad$ Device type (see below).
ABC Numbers of gridpoints in all table dimensions (see below). All dimensions for a given device must be included. Extra values are ignored.

Each device type has a certain number of dimensions, an order in which the dimensions must be listed, and a default gridsize if the .gridsize command is not given for that type. The possible values of type, with the corresponding dimension orders and default number of gridpoints (in parentheses), are as follows:

| Device | type | $\boldsymbol{A}$ | $\boldsymbol{B}$ | $\boldsymbol{C}$ |
| :--- | :--- | :--- | :--- | :--- |
| MOSFET | mos | $V d s(64)$ | $\operatorname{Vgs}(128)$ | $V b s(10)$ |
| MESFET | mes | $V d s(30)$ | $\operatorname{Vgs}(60)$ | $V b s(6)$ |
| JFET | jfet | $V d s(20)$ | $V g s(20)$ | - |
| Diode | diode | $V p n(35)$ | - | - |

Loads a Verilog-A module into the simulator, and optionally declares that the module will be used to simulate all devices of a specified type, level, and version.

When the type, level, and version parameters are used in the .hdl command, T-Spice will use the Verilog-A module as the modeling code for all matching devices, i.e. devices of the specified type which reference a .model of the specified level and version. This capability may be used to either introduce new model levels and versions into T-Spice, or to replace the existing built-in T-Spice models with your own.

## Syntax

| filename | The Verilog-A file to be loaded. It must exist in the current directory or in the T-SpiceVerilog-A search path. Absolute or relative path names (according to the conventions of the operating system) can be used. If the referenced filename or path contains a space, enclose the entire path in single or double quotation marks. |
| :---: | :---: |
| modulename | The name of a specific module within the file. Only this one module will be loaded into the simulator, and other modules within the file will be ignored. |
| type | The type of devices that will use this module |
| level | The level number of the models that will use this module |
| version | The version number of the models that will use this module |

The device type keyword is limited to the following:

| Type keyword | Device |
| :--- | :--- |
| C or capacitor | Capacitors |
| D or diode | Diodes |
| J or jfet | JFETs |
| R or resistor | Resistors |
| M or mosfet | MOSFETs |
| Q or bipolar | BJTs |
| Z or mesfet | MESFETs |

## Examples

.hdl pll.va
.hdl bsim3v34.va bsim3 type=mosfet level=49 version=3.4

The second of the above examples demonstrates how a Verilog-A module can be used instead of the built-in device evaluation code. In this case, a Verilog-A representation of the BSIM3 model will be used instead of T-Spice's internal BSIM3 analysis code for those MOSFETs which reference a model that is level 49 and version 3.4.

Note:
If the level or version is not specified or has a value of zero, then all levels and versions will be matched and simulated using the Verilog-A module

Sets node voltages or inductor currents for the duration of a DC operating point calculation.

- DC operating points are calculated by the ".ac" (page 60), ".dc" (page 69), ".op" (page 102), ".tf" (page 146), and ".tran" (page 147) commands.
- The .ic command adds a voltage source present only in DC (not transient) simulations.
- The specified nodes are allowed to float if a transient analysis is subsequently requested in the input file. For further information on transient analysis, see ".tran" (page 147).
- Nodes and devices within subcircuits can be accessed with hierarchical notation in the form xinstance.xinstance.node.
- To set initial guesses for node voltages, use the ".nodeset" (page 100) command.
- ic commands within subcircuit definition (".subckt" (page 142)/".ends" (page 74)) blocks are replicated for each subcircuit instance.


## Syntax

```
.ic node=X [[,] node=X ...]
.ic v(node [,node]) \(=X\) [[,] v(node [,node]) \(=X . .\).
.ic i(inductor) \(=X\) [[,] i(inductor) \(=X\)...]
node \(\quad\) Node whose voltage is to be initialized. (Default reference node:
    ground.)
inductor Inductor whose current is to be initialized.
\(\boldsymbol{X} \quad\) Node-to-node or node-to-ground voltage or inductor current value.
    (Unit: volts or amperes.)
```


## Examples

.ic $a=5, b=5, c=5$
Assigns initial voltages of 5 volts (relative to ground) to nodes $\mathbf{a}, \mathbf{b}$, and $\mathbf{c}$.
.ic $v(a, b)=5$
Sets the initial voltage between nodes $\mathbf{a}$ and $\mathbf{b}$ to 5 .

## .if ... / .elseif ... / .else / .endif

The .if, .elseif, .else, and .endif conditional statements may be used in a netlist to control which simulation commands, device statements, and device models will be included in the simulation.

The .if and .elseif commands have required conditional statements which will be evaluated to either true or false (non-zero or zero). Processing will then proceed, according to the conditional value. The first condition block which evaluates to true will be the selected block, or the .else block will be evaluated if no other blocks are true.

- Conditional statements may be nested.
- You can have an unlimited number of .elseif statements in your conditional.
- Parameter assignments that are contained within a condition's statement block do not effect the condition evaluation.
- Statements that are part of a condition statement block are only evaluated if and when the containing condition statement is evaluated to true.


## Syntax

```
.if condition1
    < statement block1 >
[ .elseif condition2 ]
    < statement block2 >
[ .elseif condition3 ]
    < statement block3 >
[ .elseif ... ]
            ...
[ .else ]
    < statement blockn >
.endif
```


## condition

statement block

A value or an expression, enclosed in parentheses or quotes, which will be evaluated to control the selection of one of the statement blocks.
Any non-zero expression value will be considered true, and a zero value is false.

Any valid T-Spice statements

## Examples

The simplest example of a conditional statement has a single conditional if block:

```
.param debug=1
.if (debug)
    .options echo=1
    .options verbose=2
    .options list nomod=0 node
.endif
```

An example which demonstrates all types of conditional statements:

```
.if (technology==49 && fast)
    .lib mos49.md FF
.if (technology==49 && fast==0)
    .lib mos49.md TT
.elseif (technology==53)
    .lib mos53.md TT
.else
    .lib mos2.md TT
.endif
```


## .include

Includes the contents of the specified file in the input file.

- The include command can be nested (included files can include other files, and so on) as deeply as hardware and operating system constraints permit.


## Syntax

.include filename

## filename

The file to be included. It must exist in the current directory or in the T-Spice search path. Absolute or relative path names (according to the conventions of the operating system) can be used. If the referenced filename or path contains a space, enclose the entire path in single or double quotation marks.

Within a SPICE or included file, specifies a library file or section to be included. Within a library file, indicates the beginning of a library section.

T-Spice accepts two different library file formats. The .lib command is used to access library files of both formats. It is also used to delimit library sections within library files if the first library format is used. Specific model and subcircuit definitions are read in only if needed.

## Syntax

## Library File Format I:

The first T-Spice library file format is a sequence of library sections. Each library section begins with a .lib command and ends with a .endl command. The .lib command assigns a name to each section. Within each library section any sequence of SPICE circuit elements or commands may occur.

When .lib is used with both a file name and section name, it is equivalent to .include except that only the part of the file within the specified library section is included.
.lib filename [section]
filename
section

The file to be included. It must exist in the current directory or in the T-Spice search path. If the referenced filename or path contains a space, enclose the entire path in single or double quotation marks.

## Examples

A file test.lib might contain:

```
.lib sub1
.subckt s1 a b
r1 a b 1k
.ends
.endl
.lib sub2
.subckt s2 a b
r1 a b 2k
.ends
.endl
.lib sub3
.subckt s3 a b
r1 a b 3k
. ends
.endl
```

The command:

```
.lib test.lib sub2
```

would cause T-Spice to include the library section sub2 and therefore the definition for subcircuit s2.

## Library file format II:

The second T-Spice library file format consists simply of a sequence of .model commands and .subckt definition blocks. A library file of this second format may be included in a simulation by using the .lib command in a main input file or included file. T-Spice will search the specified file for device model and subcircuit definitions if they are not found in the main input file or included files, and read in only those that are needed.

```
.lib filename
```


## filename

The library file to be searched for ".model" (page 96), ".param" (page 113), and ".subckt" (page 142) definitions. The file must exist in the current directory or in the T-Spice search path. If the referenced filename or path contains a space, enclose the entire path in single or double quotation marks.

## Examples

## A file test2.lib might contain:

```
.subckt s1 a b
r1 a b 1k
. ends
.subckt s2 a b
r1 a b 2k
.ends
.subckt s3 a b
r1 a b 3k
.ends
```

Suppose the main input file contains:

```
.lib test2.lib
x1 1 0 s3
```

The .lib command would cause the file test2.lib to be searched for model and subcircuit definitions. The instance $\mathbf{x 1}$ references subcircuit $\mathbf{s 3}$, causing T-Spice to read and include the subcircuit definition for s3 in test2.lib. Assuming that subcircuits s1 and s2 are not referenced elsewhere, their definitions in test2.lib would not be read in.

## .load

Input the contents of the specified file. The file presumably was created using the ".save" (page 135) command, and contains either ".hdl" (page 79) or ".nodeset" (page 100) commands for restoring the bias point of the circuit. The save and .load commands can be used in combination to reduce simulation time by performing a compute-intensive operating point calculation once, saving the bias information, and then using the load command in subsequent simulations to initialize the circuit to that state.

## Syntax

.load [file=filename]
filename $\quad$ Name of the file to be read. If the file parameter is not entered, then the filename is derived from the simulation input filename, with a .ic file extension.

## Examples

.load file=baseline.ic

## .macro /.eom

.macro is synonymous with .subckt, and .eom is synonymous with .ends.
The .macro ... .eom naming convention for defining subcircuits is provided for compatibiliity with other simulators which use this syntax rather than .subckt ... .ends.

Note:
Prior to version 10.0 of T-Spice, the .macro command was used for creating table-based devices.
This usage of the .macro command is no longer supported.
Old circuit files which contain .macro table-based device definitions can be converted to the new syntax by replacing .macro statements with xname statements so that, for example,
.macro mname tablename node1 node 2 node 3 ... noden
becomes:
xmname node1 node2 node3 ... noden tablename

## .measure

Used to compute and print electrical specifications of a circuit, such as delay between signals, rise and fall times, and minimum and maximum values of a signal. Also used for optimization in conjunction with the following commands:

- ".ac" (page 60)
- ".dc" (page 69)
- ".connect" (page 66)
- ".step" (page 138)
- ".tran" (page 147)

For parameter sweeps, T-Spice generates a separate output section plotting measurement results versus swept parameter values. A data set can be used with the error measurement syntax of .measure to compute differences between simulation output curves and corresponding external data. In this case, out1 or out2 in the error function measurement syntax may refer to a column name of a .data statement.

A .measure command within a .subckt block is replicated for each instance of the subcircuit.
For optimization, you can use .optgoal instead of .measure with the goal and minval parameters to set the minimum value for the denominator in the error expression and the scalar value that specifies the relative importance of two or more measurements.

Note:
When the ".options" (page 106) autostop field is set to 1, T-Spice automatically terminates any transient analysis when all .measure results have been found. The autostop option does not affect preview transient analyses.

## Syntax

The .measure command syntax has several formats, each of which is described below. Each .measure command should be used in conjunction with DC transfer, AC, data, step, or transient analysis.

The general syntax of the .measure command is:

```
.measure {dc|ac|tran} result list [goal=goal]
    + [minval=minval] [weight=weight] [off]
```

$\mathbf{d c}|\mathbf{a c}| \operatorname{tran} \quad$ Denotes the analysis type (dc, ac, or tran) for which the measurement is to be done. For dc analysis, the independent variable is a swept parameter. For ac analysis, the independent variable is frequency. For transient analysis (tran), the independent variable is time.

Name of the measurement result. This name is used to identify the measurement result in the output file, and it can also be used in subsequent equation evaluation measurements.
list
List of keywords and parameters whose syntax depends on the type of measurement to be made. Possible measurement types include:

- "Trigger/Target Measurements" on page 90
- "Signal Statistics Measurements" on page 91
- "Find-When and Derivative Measurements" on page 92
- "Expression Evaluation Measurements" on page 94
- "Error Function Measurements" on page 94

Minimum value for the denominator in the error expression above. Default: 1.0e-12.
weight
off
Desired value of the measurement, for use in optimization. In optimization, T-Spice attempts to minimize the relative error, (goalresult)/goal. For error measurement optimizations, T-Spice minimizes simply (goal-result), because in that case result is itself a relative value, and goal is usually zero. Default value: zero.

Scalar value that is multiplied by the relative error. This value is used to specify the relative importance of two or more measurements in optimization. Default: 1.

Optional keyword that prevents T-Spice from printing output from this .measure command.

## Note: $\quad$ The .measure keyword can be abbreviated to .meas.

## Trigger/Target Measurements

The trigger/target format of the .measure command is used to make independent variable (time, frequency, or swept parameter) difference measurements. The trigger and target specifications determine the beginning and end, respectively, of the measurement. The value of the measurement is the difference in the independent variable value between the trigger and the target. Common examples of trigger/target measurements include delay time, rise time, fall time, and bandwidth measurements.

The syntax of the parameters field for trigger/target measurements is:

```
trig outvar val=val [td=td] {cross=cross | rise=rise |
    fall=fall}
+ targ outvar val=val [td=td] {cross=cross | rise=rise | fall=fall}
or
trig at=at_value targ outvar val=val [td=td] {cross=cross | rise=rise |
    fall={all}
at_value Specifies an explicit independent variable value for the trigger.
```

| outvar |  |
| :--- | :--- |
| val |  |
| td |  |
| cross | Specifies an output signal on which the trigger or target measurement <br> is performed. This can be any output plot item that is legal on a .print <br> command for the appropriate analysis type. For .measure ac <br> commands, .print noise plot items are allowed. outvar may be an <br> output expression enclosed in single quotes. |
| Specifies the value of outvar at which the trigger or target counter |  |
| for cross, rise, or fall is incremented. |  |
| Specifies a time delay before the measurement is enabled and |  |
| crossings, rises, and falls are counted. Default: 0. |  |

Note: $\quad$ For a particular trigger or target, only one of cross, rise, or fall may be specified.

Trigger/target measurement output reports the independent variable value difference between the trigger and the target, as well as the independent variable values at the trigger and target. The measurement result may be negative if the target independent variable value is less than the trigger independent variable value.

For syntax examples, see "Trigger/Target Example" on page 95.

## Signal Statistics Measurements

Signal statistics measurements are used to perform data reduction operations on signals. T-Spice can compute average, RMS (root-mean-square), minimum, maximum, and peak-to-peak values for a signal. In addition, T-Spice can report the independent variable (argument) value at the minimum or maximum of a signal.

The syntax of the parameters field for signal statistics measurements is:
type outvar [from=from] [to=to] [output=output]
type $\quad$ Specifies the type of measurement, and is one of the following:

- amax computes the independent variable value at the point where the signal's maximum value is reached.
outvar
from
to
output
- amin computes the independent variable value at the point where the signal's minimum value is reached. If the minimum value occurs more than once, amin reports the first instance.
- avg computes the average value of the signal, defined as the integral of the signal divided by the length of the measurement interval.
- integral computes the integral of the signal over the measurement interval. Can be abbreviated to integ.
- max computes the maximum value of the signal.
- min computes the (global) minimum value of the signal. The computation is independent of signal derivative (i.e., min may be a signal endpoint).
- pp reports the difference between the maximum and minimum values of the signal (peak-to-peak measurement).
- rms computes the root-mean-square value of the signal, defined as the square root of the integral of the signal squared, divided by the length of the measurement interval.

Specifies the output signal on which the measurement is to be performed. It can be any output plot item that is legal on a .print command for the appropriate analysis type. For .measure ac commands, .print noise plot items are allowed. outvar may be an output expression enclosed in single quotes.

Specifies the value of the independent variable (time, frequency, or sweep parameter) at the beginning of the measurement. The default is the beginning of the analysis.

Specifies the value of the independent variable (time, frequency, or sweep parameter) at the end of the measurement. The default is the end of the analysis.

For max and min type measurements, specifies the output signal to be evaluated at the point at which the maximum or minimum is reached.

For syntax examples, see "Signal Statistics Example" on page 95.

## Find-When and Derivative Measurements

Find-when measurements are used to measure values of dependent or independent output variables when some specific event occurs. The event specification is similar to the trigger specification in trigger/target measurements: the event occurs when a signal crosses a value, or a signal crosses another signal, or when a certain independent variable "at" value is reached. If a "find" signal is specified, the measurement output is the value of the find signal at the event. If no "find" signal is given, then the measurement result is the independent variable value at the event.

Find-when measurements can also be used to compute derivatives of functions. If the find keyword is replaced with derivative, the derivative of outvar1 is computed as the measurement result.

The syntax of the list field for find-when measurements is:

```
[find outvarl | derivative outvarl] when outvar2=val [td=td] {cross=cross |
    rise=rise | fall=fall}
Or
[find outvar1 | derivative outvarl] when outvar2=outvar3 [td=td]
    {cross=cross | rise=rise | fall=fall}
or
{find outvarl | derivative outvarl} at=at_value
```

Note: $\quad$ For a particular trigger or target, only one of cross, rise, or fall may be specified.

| at_value | Specifies an explicit independent variable value for the event. <br> outvar1 <br> Specifies the output signal to be evaluated as the measurement result <br> at the event of interest. This can be any output plot item that is legal <br> on a .print command for the appropriate analysis type. For .measure <br> ac commands, .print noise plot items are allowed. outvar1 may be <br> an output expression enclosed in single quotes. |
| :--- | :--- |
| Specifies an output signal to be evaluated for locating the |  |
| measurement event. This can be any output plot item that is legal on |  |
| a .print command for the appropriate analysis type. For .measure ac |  |
| commands, .print noise plot items are allowed. outvar2 may be an |  |
| output expression enclosed in single quotes. |  |$\quad$| Specifies the value of outvar2 at which the event counter for |
| :--- |
| crossings, rises, or falls is incremented. |
| val |
| outvar3 |
| Specifies a second output signal to be evaluated for locating the |
| measurement event. This can be any output plot item that is legal on |
| a .print command for the appropriate analysis type. For .measure ac |
| commands, .print noise plot items are allowed. outvar3 may be an |
| output expression enclosed in single quotes. |

For syntax examples, see "Find-When and Derivative Example" on page 95.

## Expression Evaluation Measurements

T-Spice can compute expressions that are functions of previous .measure command results. The syntax of the parameters field for expression evaluation measurements is:

```
param=' expression'
```

where expression is an algebraic expression involving .param parameter values, subcircuit parameter values, and previous .measure result names. The expression may not contain plot items such as node voltages or branch currents. The expression may contain the same operators and functions as used in .print output expressions.

## Error Function Measurements

The error function measurement reports a relative difference between two output variables. Four methods for calculating this error are available.

The syntax of the parameters field for error function measurements is:
errtype out1 out2 [from=from] [to=to]

errtype | Specifies the method of computing the total error. Must be one of |
| :--- |
| err, err1, err2, err3. |

| Specifies the output signals to be compared. These can be any output |
| :--- |
| plot items that are legal on a .print command for the appropriate |
| analysis type. For .measure ac commands, .print noise plot items |
| are allowed. out1 and out2 may be output expressions enclosed in |
| single quotes. |

from

to $\quad$| Specifies the value of the independent variable (time, frequency, or |
| :--- |
| sweep parameter) at the beginning of the measurement. The default |
| is the beginning of the analysis. |

| Specifies the value of the independent variable (time, frequency, or |
| :--- |
| sweep parameter) at the end of the measurement. The default is the |
| end of the analysis. |

The error computation depends on the errtype and is as follows:

| err, err1 | The error is the RMS value of the relative difference between the two <br> signals, normalized to the length of the measurement interval. |
| :--- | :--- |
| err2 | The error is the integral over the measurement interval of the <br> absolute value of the relative difference of the two signals. |
| err3 | The error is the integral over the measurement interval of the relative <br> difference of the logs of the two signals. |

The relative difference of the two signals is defined as:
(out1-out2)/max(minval, |out1|+|out2|)

The relative difference of their logs is defined as the absolute value of:

```
log(|out1|/max(minval, |out2|))/log(max(minval, |out1|+|out2|))
```

For syntax examples, see "Error Function Example" on page 95.

## Examples

## Trigger/Target Example

```
.measure tran delaytime trig v(1) val=2.5 fall=3
+ targ v(2) val=2.5 rise=3
```

measures the time delay from the third falling edge of signal $\mathbf{v}(\mathbf{1})$ to the third rising edge of signal $\mathbf{v}(\mathbf{2})$. The measurement begins when $\mathbf{v}(\mathbf{1})$ falls through 2.5 V for the third time, and ends when $\mathbf{v}(\mathbf{2})$ rises through 2.5 V for the third time.

```
.measure tran risetime trig v(1) val=0.5 rise=1
+ targ v(1) val=4.5 rise=1
```

measures the first rise time of the voltage at node 1.

## Signal Statistics Example

. measure ac maxgain max vm(out)
measures the maximum value of vm(out) over the frequency range covered during an AC analysis.

```
.measure ac resfreq amax vm(out)
```

measures the frequency at which the maximum value of vm(out) is achieved.
.measure ac phase_at_resonance max vm(out) output=vp(out)
measures the phase $\mathbf{v p}$ (out) at the frequency where vm(out) is at its maximum.

## Find-When and Derivative Example

```
.measure tran v1 find v(1) when v(2)=2 cross=1
```

measures the voltage at node $\mathbf{1}$ when the voltage at node $\mathbf{2}$ crossed 2 V for the first time.

```
.measure ac f1 when vm(out)=1
```

measures the frequency at which the voltage gain at node out is 1 .

```
.measure tran d1 derivative v(1) at=100ns
```

measures the derivative of $\mathbf{v}(1)$ with respect to time at 100 ns .

## Error Function Example

```
.measure tran v1v2 err1 v(1) v(2)
```

measures the difference between the signals $\mathbf{v}(\mathbf{1})$ and $\mathbf{v}(\mathbf{2})$.

## .model

Specifies device model parameters to be used by one or more devices.

## Syntax

```
.model modelname type [level=L][parameter=value [parameter=value [...]]]
    [ako: akomodel]
modelname Model name.
type Device type (see below).
L Model level, required for device models with multiple levels.
parameter The parameter list is predefined for each standard device model.
    (See the chapter "Device Models" on page 332.)
```

type is one of the following:
c
cpl
csw
d
npn
pnp
njf
pjf
nmf
opt
pmf
nmos
pmos
r
sw

Capacitor
Coupled transmission line.
Current-controlled switch element.
$\mathrm{P}-\mathrm{N}$ diode.
NPN-type BJT.
PNP-type BJT.
N-type JFET.
P-type JFET.
N-type MESFET.
Controls the optimization algorithm. For additional information, see "Optimization Algorithm Parameters," below.

P-type MESFET.
N-type MOSFET.
P-type MOSFET.
Two-terminal resistor (or three-terminal resistor if a capacitance is specified).

Voltage-controlled switch element.
external External model. The parameter list of a .model command of type external must specify the name of the file that contains the external model. These special model parameters vary according to platform and take the following form:

- winfile=file (Windows)
- solfile=file (Solaris 2.x)
- sunfile=file (SunOS 4.x)
- sgifile=file (SGI IRIX)
- hpfile=file (HPUX)

If the external model filename has a .c extension, T -Spice will interpret the model file. If it has any other extension, T-Spice will treat it as a compiled DLL or shared library.

External model parameters can be numbers or strings. Strings and filenames must be enclosed in double quotes (" ").

## Optimization Algorithm Parameters

The T-Spice optimization algorithm is controlled using the .model command with a model type of opt. The syntax is:
.model name opt [parameter=value [parameter=value [...]] [ako: akomodel]
modelname
parameter

value | Model name matched with the model name specified in an analysis |
| :--- |
| command |

akomodel

Model parameter name $\quad$| Value assigned to the model parameter |
| :--- |

Valid alternatives for value are listed below:

| Parameter | Description | Default |
| :--- | :--- | :--- |
| cendif | Gradient value below which <br> more accurate derivative <br> computation methods are used to <br> compute the gradient. | 1e-9 |
| close | Estimate of how close the <br> optimization parameters' initial | 0.001 |
|  | value estimates are to the <br> solution. close is a multiplier for <br> computing new parameter <br> estimates. Larger values result in |  |
|  |  |  |
|  |  |  |
| larger steps toward the solution. |  |  |


| cut | Modifies close from one iteration to the next. If an iteration was unsuccessful, close is divided by cut; if an iteration is successful, close is multiplied by cut squared. | 2 |
| :---: | :---: | :---: |
| difsiz | Determines the increment in a parameter value used to compute numerical derivatives. The increment used is <br> difsiz*max(value, parmin), where value is the parameter value. If delta is specified on the .param command, then delta is used as the increment. | 1e-3 |
| grad | Convergence tolerance for the gradient. If the gradient is less than grad, then convergence may have been achieved, depending on the outcome of the additional relin and relout tests. | 1e-6 |
| itropt | Maximum number of optimization loop iterations. | 20 |
| level | Optimization method used. <br> Level=1 selects a modified <br> Levenberg-Marquardt algorithm. | 1 |
| max | Upper limit for close | 600,000 |
| parmin | Used in increment selection for derivative computation; see difsiz parameter, above | 0.1 |
| relin | Relative input parameter variation for convergence. If all optimization parameters (defined with .param) vary by less than this amount ( $0.1 \%$ by default) from one iteration to the next, convergence is declared | 0.001 |
| relout | Relative output parameter variation for convergence. If the total error defined by measurement results varies by less than this amount from one iteration to the next, convergence is declared. | 0.001 |

Note:
When no model parameters are specified, all models take on their default values.

## Examples

| + Level=2 | $\mathrm{Ld}=0.0 \mathrm{u}$ | Tox $=225.00 \mathrm{E}-10$ |
| :---: | :---: | :---: |
| + Nsub=1.066EV+16 | $\mathrm{Vto}=0.622490$ | $\mathrm{Kp}=6.326640 \mathrm{E}-05$ |
| + Gamma=. 639243 | Phi=0.31 | $\mathrm{Uo}=1215.74$ |
| + Uexp=4.612355E-2 | Ucrit=1746677 | Delta=0.0 |
| + Vmax $=177269$ | $\mathrm{Xj}=.9 \mathrm{u}$ | Lambda=0.0 |
| $+\mathrm{Nfs}=4.55168 \mathrm{E}+12$ | Neff=4.68830 | $\mathrm{Nss}=3.00 \mathrm{E}+10$ |
| $+\mathrm{Tpg}=1.000$ | Rsh=60 | Cgso=2.89E-10 |
| + Cgdo $=2.89 \mathrm{E}-10$ | $\mathrm{Cj}=3.27 \mathrm{E}-04$ | $\mathrm{Mj}=1.067$ |
| + Cjsw=1.74E-10 | Mjsw=0.195 |  |

Specifies the parameters for an $n$-type MOSFET model called nmos.
.model resmodel external winfile="res.dll" solfile="res.sl" a=20 b="name"
Defines a model called resmodel that can be referred to by an instance ( $\mathbf{x}$ ) statement. In Windows, res.dII is loaded as a DLL; under Solaris res.sl is loaded as a shared library. Under all other platforms, an error message is issued because no external model name is specified. The numeric parameter $\mathbf{a}=\mathbf{2 0}$ and the string parameter $\mathbf{b}=$ "name" are passed to the external model as model parameters.

## .nodeset

Sets an "initial guess" for the iterative DC operating point calculation.

- DC operating points are calculated by the ".ac" (page 60), ".dc" (page 69), ".op" (page 102), ".tf" (page 146), and ".tran" (page 147) commands.
- DC operating points are calculated by iteration, and .nodeset sets starting points for iteration. Convergence properties can be very sensitive to the initial guess; .nodeset can be used (1) to enable convergence for difficult-to-converge circuits and (2) to cause T-Spice to converge to one particular solution if more than one solution exists.
- After numndset iterations, or when the convergence criteria have been met, the specified nodes are allowed to float.
- Nodes and devices within subcircuits can be accessed with hierarchical notation in the form xinstance.xinstance.node.
- To set node voltages for the duration of the operating point calculation, use the ".hdl" (page 79) command.
- .nodeset commands inside subcircuit definition blocks are replicated for each subcircuit instance.


## Syntax

```
.nodeset node=X [[,] node=X ...]
.nodeset v(node)= X [[,] v(node)= X ...]
node Node to be initialized.
X Node voltage relative to ground. (Unit: volts.)
```


## Examples

```
.nodeset n1=5V n2=2
.nodeset v(n1)=5V v(n2)=2
```

The two examples are identical except for syntax.

## .noise

Computes the effect of circuit noise on output voltage in conjunction with AC analysis.

- If the ".ac" (page 60) command is missing from the input file, the .noise command is ignored.
- Noise analysis is performed at the same frequencies as specified by the ".ac" (page 60) command.
- Noise models take the form of frequency-dependent mean-square currents (since the underlying phenomena are "random") generated by adding a current source to the circuit for each modeled noise source.
- Noise sources at different points in the circuit are uncorrelated.
- Noise models are available for resistors and semiconductor devices (diodes, BJTs, JFETs, MESFETs, and MOSFETs). Semiconductor device models may contain noise model parameters which affect the size of noise sources.
- External model devices may also contain noise sources.
- Noise analysis results can be reported with the ".print" (page 119) noise command.


## Syntax

.noise v(node1 [[,] node2]) source interval
node1
node2
source
Output node.

Reference node. (Default: ground.) $\quad$| Input voltage or current source, at which noise can be considered to |
| :--- |
| be concentrated for the purposes of estimating the equivalent noise |
| spectral density. |

## .op

Performs a DC operating point calculation and outputs all node voltages and voltage source currents.

- DC operating points are calculated on the assumption that there are no charge effects in the system: capacitors are open and inductors are shorted.
- The ".hdl" (page 79) command can be used to impose initial conditions on nodes. Initial conditions are represented by voltage sources present for the duration of the DC operating point calculation, and removed for transient simulations.
- The ".nodeset" (page 100) command can be used to set initial guesses for the iterative solution process for DC operating points.
- The results of the .op command are written automatically to the specified output file. Other results can be reported with the ".print" (page 119) dc command.
- Small-signal transfer function data can be reported with the ".tf" (page 146) command.
- Small-signal parameters are automatically reported to the output file. You can specify a separate output file for small-signal data with the ".acmodel" (page 63) command. The command .acmodel \{\} disables small-signal parameter reporting. Reporting is also disabled if the simulation model has more than 1000 nodes.


## Syntax

## .op [noprint]

noprint
Turns off automatic .op output.

## .optgoal

Sets optimization goals. Allows the same measurement to be used in different optimization runs with different goals and weight values.

Note that during an optimization run, all .optgoal commands with the same optname are used as optimization results, in addition to any measurements specified in the results list on the sweep optimize syntax of a .step or one of the analysis commands. (See the following example.)

If the .measure command does not exist in the netlist, an error message will be returned.
The formula for optimization functions is:

$$
\begin{equation*}
\sum_{k}\left(W_{k} \cdot \frac{\left(G_{k}-M_{k}\right)}{\max \left(\operatorname{minval},\left|G_{k}\right|\right)}\right)^{2} \tag{0.6}
\end{equation*}
$$

where $W k$ is the weight, $G k$ is the goal, and $M k$ is the measurement value.

## Syntax

$$
\begin{aligned}
& \text {.optgoal optname measname=goal [minval=minval] [weight=weight] } \\
& \text { optname Name of the optimization run. } \\
& \text { measname A .measure result to be used as the goal. } \\
& \text { goal Optimization goal value. } \\
& \text { minval The minimum denominator value for the optimization error } \\
& \text { computation. Defaults to the value in the .measure command } \\
& \text { identified by measname, or if not specified there, to1.0e-12. } \\
& \text { weight A relative importance of the optimization goal with respect to other } \\
& \text { goals for the same optimization run. Defaults to the value in the } \\
& \text {.measure command identified by measname, or if not specified } \\
& \text { there, tol. }
\end{aligned}
$$

## Examples

```
.ac dec 10 1 100k sweep optimize=opt1 results=gain model=optmod
.measure ac gain max vdb(out) goal=30
.measure ac bandwidth when vdb(out)=10
.optgoal opt1 bandwidth=5k
```

results in both the gain and bandwidth measurements contributing to the overall optimization goal.

## .optimize

Invokes an optimization run using parameters and goals specified using .paramlimits and .optgoal commands with the same optname.
.ac, .dc, .step and .tran use the parameter analysis to identify analysis commands from the .optimize command. However, it is possible to avoid assigning an analysis name. If the analysis name on the .optimize command is the name of an analysis type ("ac", "tran", "dc", or "step",) and no analysis of that name exists, T-Spice will perform the optimization on the first analysis of that type. (See "Examples" on page 104.)

## Syntax

| .optimize optname model $=$ modelname analysis=analysisname |  |
| :--- | :--- |
| optname | Name of the optimization run. |
| modelname | Refers to a .model command of type opt which specifies <br> optimization algorithm parameters such as iteration count limits and <br> convergence tolerances. |
| analysisname | Identifies a .step, .ac, .dc, or .tran command of the same name that <br> will be performed to evaluate the measurements for the optimization. |

## Examples

```
.ac dec 10 1 100k analysisname=ac1
.optimize opt1 model=optmod analysisname=ac1
```

invokes an optimization around an AC analysis. This AC analysis optimization syntax is equivalent to:

```
.ac dec 10 1 100k
.optimize opt1 model=optmod analysisname=ac
.param r=1k c=1u
r1 1 0 'r'
c1 1 0 'c'
.options autostop reltol=1e-6
.ic v(1)=1
.tran 0.1m 100m
.print tran v(1)
.measure tran decaytime when v(1)=0.5
```

Optimization commands:

```
.optimize opt1 model=optmod analysisname=tran
.model optmod opt level=1 itropt=40
.optgoal opt1 decaytime=300u
.paramlimits opt1 r minval=10 maxval=100k
.paramlimits opt1 c minval=0.01u maxval=100u
. end
```

This is a transient analysis of a simple RC circuit. The .measure command measures the amount of time it takes for the voltage at node 1 to decay to half its initial value. Theoretically, this decay time is equal to $\mathbf{R} * \mathbf{C} * \ln (2)$. The .optimize command invokes an optimization run called opt1. The .optgoal
command sets the optimization goal (300usec) for the decay time, and the .paramlimits commands specify ranges for the $\mathbf{R}$ and $\mathbf{C}$ parameters.

During the optimization run, $\mathbf{R}$ and $\mathbf{C}$ can be varied within their ranges in order to achieve the decay time goal of 300 microseconds. The output for this simulation is as follows:

Optimized parameter values:

```
    r=6.5783e+02
    c = 6.5775e-07
* END NON-GRAPHICAL DATA
*WEDIT: .tran 0.0001 0.1
TRANSIENT ANALYSIS - OPTIMIZE=opt1
Time<s> v(1)<V>
    0.0000e+00 1.0000e+00
    1.9207e-08 9.9996e-01
    1.8027e-06 9.9584e-01
    3.4447e-06 9.9207e-01
    1.7692e-05 9.5994e-01
    2.6271e-05 9.4109e-01
    3.4134e-05 9.2415e-01
    4.2453e-05 9.0655e-01
    5.3935e-05 8.8281e-01
    7.0558e-05 8.4953e-01
    8.9536e-05 8.1308e-01
    1.2194e-04 7.5440e-01
    1.5149e-04 7.0461e-01
    1.8663e-04 6.4965e-01
    2.2571e-04 5.9354e-01
    2.6455e-04 5.4257e-01
    3.0212e-04 4.9745e-01
* BEGIN NON-GRAPHICAL DATA
MEASUREMENT RESULTS - OPTIMIZE=opt1
decaytime = 3.0000e-04
* END NON-GRAPHICAL DATA
```

Note that the optimized $\mathbf{R}$ and $\mathbf{C}$ values achieve the optimization goal of $\mathbf{3 0 0} \mathbf{u}$. This is consistent with theoretical prediction: for the optimized $\mathbf{R}$ and $\mathbf{C}$ values of 657.83 Ohms and 657.75 nanofarads, the theoretically predicted decay time is 299.92 microseconds.

## .options

Sets global simulation options.

## Syntax

.options field=X [field=X ...]

Fields that toggle actions on or off can be specified as true/false, $\mathbf{t} / \mathbf{f}, \mathbf{1 / 0}$, or yes/no. Specifying a true/ false field without a value automatically sets the field to true.

Option fields are described in detail in the following chapter, "Simulation Options" on page 204. The following tables list a summary of simulation options; click on the option name for a full description.

## Accuracy and Convergence Options

| Field | Description | Default |
| :--- | :--- | :--- |
| "absi \| abstol" (page Maximum allowed RMS of residual branch currents when <br> kcltest = true. <br> "absv \| vntol" (page $1 \times 10^{-10} \mathrm{~A}$ <br> 207) Maximum absolute node voltage change allowed between <br> iterations when kvltest = true. <br> "accurate" (page 208) $1 \times 10^{-6} \mathrm{~V}$ <br> Triggers changes to other option settings to maximize  <br> simulation accuracy.  | false |  |
| "bypass" (page 209) | Controls the diode and transistor bypass algorithm | true |
| "bytol"(page 210) | Sets the relative tolerance for the bypass algorithm <br> terminal voltage values | 0.0 |
| "cshunt" (page 211) | Capacitance added from each node to ground. | 0.0 F |
| "dchomotopy" (page | Algorithm used to correct DC operating point non- <br> convergences. Can be set to none, source, gmin, <br> pseudo, or all. | all |
| "d2) | Default method for solving a DC operating point problem. <br> Can be set to standard, source, gmin, or pseudo. | standard |
| 214 ) | Controls the conductance added across the terminals of | 0.0 |
| "dcstep" (page 215) | each capacitor during DC operating point computation. <br> (g=c/dcstep, where $c$ is the device capacitance.) | $1 \times 10^{-12} \Omega^{-1}$ |
| "extraiter[ations]\| | Number of additional iterative steps to calculate after <br> convergence criteria have been met. | 0 |


| Field | Description | Default |
| :--- | :--- | :--- |
| "gramp" (page 220) | Specifies the range over which the gmindc variable is <br> swept during $g_{\text {min }}$ stepping. <br> (gmindc $\leq g_{\text {min }} \leq$ gmindc $\times$ 10gramp $)$ | 4 |
| "gshunt" (page 221) | Conductance added from every node to ground. | $0.0 \Omega^{-1}$ |
| "kcltest" (page 222) | Enables the current tolerance test for convergence. | true |
| "kvltest" (page 223) | Enables the voltage tolerance test for convergence in <br> transient analysis (always true for DC analysis). | false |

## Timestep and Integration Options

| Field | Description | Default |
| :--- | :--- | :--- |
| "absdv $\mid$ absvar" (page Threshold absolute voltage change between two <br> consecutive time steps; used to calculate voltage variance <br> when Ivltim=1\|3|4. <br>  0.5 V <br> "absq \| chgtol" (page Minimum capacitor charge or inductor flux used to <br> compute Local Truncation Error for timestep control <br> (Ivltim=2). | $1 \times 10^{-4} \mathrm{C}$ |  |
|  |  |  |


| Field | Description | Default |
| :---: | :---: | :---: |
| "ft" (page 240) | Fraction by which the timestep is reduced if a transient analysis solution does not converge within numnt iterations. | 0.4 |
| "Ivltim" (page 241) | Algorithm used to control timestep sizes in transient analysis: <br> $1=$ Iteration count algorithm with voltage variance test <br> $2=$ Local Truncation Error algorithm <br> $3=$ Iteration count algorithm with voltage variance and timestep reversal <br> $4=$ voltage variance test for timestep prediction plus Local Truncation Error algorithm for timestep reversal (hybrid of lvltim 1 and 2) | 1 |
| "maxord" (page 244) | Maximum time integration order for Gear's BDF calculation. | 2 |
| "method" (page 245) | Method of numerical integration for estimating time derivatives of charge during transient analysis. | trap |
| "mintimeratio \| rmin" (page 246) | Relative minimum timestep size for transient simulations. | $1 \times 10^{-9}$ |
| "mu \| xmu" (page 247) | Coefficient for varying integration between the backward Euler formula and the trapezoidal formula. Used when method = trap. | 0.5 |
| $\begin{aligned} & \text { "numnt \| itl4 \| imax" } \\ & \text { (page } 248 \text { ) } \end{aligned}$ | Newton iteration limit for transient analysis solutions. | 10 |
| $\begin{aligned} & \text { "numntreduce \| itl3" } \\ & \text { (page } 249 \text { ) } \end{aligned}$ | Threshold number of Newton iterations for controlling decrease or increase of the next timestep. | 3 |
| $\begin{aligned} & \text { "poweruplen" (page } \\ & 250 \text { ) } \end{aligned}$ | Length of the powerup ramp during powerup transient analysis. | $0.1 \%$ total .tran time |
| $\begin{aligned} & \text { "reldv \| relvar" (page } \\ & \text { 251) } \end{aligned}$ | Maximum relative voltage change between time steps; used to calculate the voltage variance when Ivltim $=1 \mid 3$. | 0.35 |
| $\begin{aligned} & \text { "relq \| relchgtol" (page } \\ & 252 \text { ) } \end{aligned}$ | Maximum relative error in predicted charge; used to adjust timestep sizes in the LTE algorithm (Ivltim = 2). | $5 \times 10^{-4}$ |
| "rmax" (page 253) | Maximum allowed timestep, given as a multiple of the timestep specified with .tran. | 2 |
| "trextraiter[ations] \| trnewtol" (page 254) | Number of additional iterative steps to calculate at each timestep after convergence criteria have been met | 0 |
| "trtol" (page 255) | Corrective factor for estimation of the local truncation error (LTE) when IvItim=2. | 10 |

## Model Evaluation Options

| Field | Description | Default |
| :--- | :--- | :--- |
| "dcap" (page 257) | Model selector for calculating depletion capacitances. | 2 |
| "dccap" (page 258) | Flag to compute device charge and capacitance values in <br> DC analysis | false |


| Field | Description | Default |
| :---: | :---: | :---: |
| "defad" (page 259) | Default MOSFET drain diode area. | $0.0 \mathrm{~m}^{2}$ |
| "defas" (page 260) | Default MOSFET source diode area. | $0.0 \mathrm{~m}^{2}$ |
| "defl" (page 261) | Default MOSFET channel length. | $1 \times 10^{-4} \mathrm{~m}$ |
| "defnrd" (page 262) | Default number of diffusion squares for a MOSFET drain resistor. | 0.0 |
| "defnrs" (page 263) | Default number of diffusion squares for a MOSFET source resistor. | 0.0 |
| "defpd" (page 264) | Default MOSFET drain diode perimeter. | 0.0 m |
| "defps" (page 265) | Default MOSFET source diode perimeter. | 0.0 m |
| "deftables" (page 266) | Selects use of table-based evaluation of models instead of direct model evaluation. See also modelmode. | false |
| "defw" (page 267) | Default MOSFET channel width. | $1 \times 10^{-4} \mathrm{~m}$ |
| "deriv" (page 268) | Selects the method for computing $d q / d v$ and $d i / d v$ derivatives. | 0 |
| "minresistance \| <br> resmin" (page 269) | Minimum (floor) resistance value for all resistors. | $1 \times 10^{-5} \Omega$ |
| $\begin{aligned} & \text { "modelmode" (page } \\ & 270 \text { ) } \end{aligned}$ | Model evaluation method (direct, uniform, or cache). | direct |
| "moscap" (page 271) | Enables automatic source/drain area/perimeter estimation for MOSFETs. | false |
| $\begin{aligned} & \text { "mosparasitics" (page } \\ & 272 \text { ) } \end{aligned}$ | Controls explicit modeling of diodes during table-based model evaluation mode. | true |
| "scale" (page 273) | Scales the physical dimensions of capacitors, MESFETs, MOSFETs, and resistors. | 1.0 |
| "scalm" (page 274) | Default scaling factor for resistors and capacitors. | 1.0 |
| "tnom" (page 275) | Nominal temperature. | 25 deg. C |
| "wl" (page 276) | Reverses MOSFET length and width specifications. | false |

## Linear Solver Options

| Field | Description | Default |
| :--- | :--- | :--- |
| "linearsolver" (page Selects the linear equation solver - best, sparse, or <br> superlu. best <br> $278)$ Minimum pivoting tolerance for real matrices. $1 \times 10^{-14}$ <br> "pivtol" (page 279) Minimum pivoting tolerance for complex matrices. $1 \times 10^{-6}$$.$"zpivtol" (page 280) |  |  |

## General Options

| Field | Description | Default |
| :--- | :--- | :--- |
| "autostop" (page 282) | Terminates transient analysis after all .measure results <br> have been found. | false |
| "casesensitive" (page Case sensitivity for names of models, subcircuits, library <br> sections, parameters, and nodes. <br> "compatibility" (page false <br> Specifies input syntax and option setting compatibility  <br> with other simulators - Berkeley SPICE, HSPICE, or  <br> PSPICE.  | HSPICE |  |
| "conncheck" (page | Enables connectivity checking. |  |
| "parhier" (page 286) | Establishes the scoping algorithm for selection of <br> parameter values in a hierarchical design. | local |
| "persist" (page 288) | Instructs T-Spice to continue simulation when the <br> specified levels of warnings or errors are generated. | 1 |
| "search" (page 289) | Search path for library and include files. <br> "spice" (page 290) | Changes other option settings to be compatible with <br> Berkeley SPICE. |
| "threads" (page 291) | Enables parallel processing. <br> "vasearch" (page 292) | Search path for locating Verilog-A files. |

## Output Options

| Field | Description | Default |
| :--- | :--- | :--- |
| "acct" (page 294) | Tracks and reports iteration counts and other accounting <br> statistics. | false |
| "acout" (page 295) | Calculation method for AC magnitude/phase differences. | 1 |
| "brief" (page 296) | Minimizes the amount of diagnostics printout which is <br> written to the simulation status window. | false |
| "captab" (page 297) | Lists capacitances for each node in the netlist. | false |
| "csdf"(page 298) | Generates output in CSDF mode. | false |
| "dnout" (page 299) | Selects noise spectral density units. | 0 |


| Field | Description | Default |
| :--- | :--- | :--- |
| "xref" (page 317) | Generates a listing of various circuit cross-reference <br> information: conditional statement tree, symbol <br> definitions, subcircuit listings. | false |

## Probing Options

| Field | Description | Default |
| :---: | :---: | :---: |
| "binaryoutput" (page 319) | Specifies the form of binary output created with .probe. | 3 |
| "probei" (page 320) | Includes device terminal current values in the output data from .probe and .print (when used without arguments). | false |
| "probeq" (page 321) | Includes device terminal charge values in the output data from .probe and .print (when used without arguments). | false |
| "probev" (page 322) | Includes node voltage values in the output data from .probe and .print (when used without arguments). | false |
| "probefilename" (page 323) | Filename for binary output produced by .probe. | outputfile.dat |

## .param

Defines and assigns values to parameters, or creates a user-defined function.

- Parameters can be used in expressions to replace numeric values.
- .param statements are sequential. A parameter must be defined before it is used in the expression of another parameter value.
- User-defined functions are very similar to the set of built-in algebraic functions. User-defined functions may take any number of arguments, and are defined using an algebraic expression which performs operations on the function arguments.
- The scope of defined parameters extends to files referenced by ".if ... / .elseif ... / .else / .endif" (page 82) commands.
- Parameters placed in subcircuit definition blocks are valid only within that subcircuit definition, and override global parameters of the same name.
- Parameters placed outside subcircuit definition blocks are valid globally.

Note: To view a listing of all parameters that are defined in the input files, use the command .option xref.

## Syntax

| parameter | Parameter name. |
| :---: | :---: |
| $\boldsymbol{X}$ | Any number or valid expression. Expressions must be enclosed by single quotes. |
| mc_distribution | Defines probability distributions used in Monte Carlo iterations. For additional information, see Monte Carlo Parameters, below. |
| opt_limits | Defines optimization parameters. For additional information, see "Optimization Parameters" on page 115. |

## User-Defined Functions

The syntax for defining a function is:


## Monte Carlo Parameters

For each Monte Carlo iteration, T-Spice will report the values of all expressions evaluated using probability distributions defined by the following syntax:

| or |  |
| :---: | :---: |
| .param parameter=aunif(nominal_val, abs_variation [, multiplier]) |  |
| or |  |
| . param parameter=gauss(nominal_val, rel_variation, sigma [, multiplier]) |  |
| or |  |
| .param parameter=agauss(nominal_val, abs_variation, sigma [, multiplier]) |  |
| or |  |
| . param parameter=limit(nominal_val, abs_variation) |  |
| parameter | Name of the parameter to be varied in the Monte Carlo analysis. |
| unif | Selects a uniform distribution with relative variation specification. |
| aunif | Selects a uniform distribution with absolute variation specification |
| gauss | Selects a Gaussian distribution with relative variation specification. |
| agauss | Selects a Gaussian distribution with absolute variation specification. |
| limit | Selects a random limit distribution function using absolute variation. The result is either nominal_val-abs_variation or nominal_val+abs_variation, with 50\% probability for each. |
| nominal_val | Nominal value for the parameter. |
| abs_variation | Largest deviation from nominal_val that can be obtained from a uniform or limit distribution, or the standard deviation multiplied by sigma for a Gaussian distribution. |
| rel_variation | Relative variation specification. The corresponding absolute variation is rel_variation*nominal_val. |
| sigma | Sigma-level at which the absolute or relative variation is specified for a Gaussian distribution. For example, if sigma=3, the standard deviation is abs_variation/3. |
| multiplier | Number of times the distribution function is evaluated. The largest deviation from the nominal value of all evaluations is the one that is used as the result. The resulting distribution is bimodal. (Default: 1.) |

Note:
Multiple parameters can be assigned on the same .param command. Probability distributions are reevaluated with every use of paramname in expressions.

## Optimization Parameters

When .param is used to define optimization parameters, the parameter argument uses the following syntax:

```
.param parameter=optname(guess, min, max [, delta])
parameter Global parameter name.
name References a particular optimization run name.
guess Initial (nominal) value for the parameter.
min}\quad\mathrm{ Minimum values the parameter can take on.
max Maximum values the parameter can take on.
delta Used for discrete optimization. The final parameter values must
differ from the initial guess by an integer multiple of delta. This is
useful for optimizing quantities that can only take on discrete values,
such as transistor lengths and widths.
```

Note: Multiple optimization parameters can be assigned on the same .param command.

The parameter parameter is allowed to vary within its range when an optimization of the appropriate name is invoked on an analysis command. During such an optimization, the parameter is initially assigned its guess value, but is allowed to vary within its range (defined by min and max) during subsequent optimization iterations.

For additional information on the optimization syntax for individual analysis commands, see ".ac" (page 60), ".dc" (page 69), or ".tran" (page 147).

## Examples

```
.param pi='4*atan(1)' tf='1E-6*sin(pi/2))'
.tran 'tf*0.01' 'tf'
```

The .param command defines and assigns a value to parameter $\mathbf{t f}$, which is subsequently used (enclosed by single quotes) in place of a numeric value in the ".tran" (page 147) command.

```
.param res=agauss (100, 10, 1)
```

Specifies that the resistance is chosen from a normal distribution of mean 100 and standard deviation 10.
.param w1=opt1 (10u, 2u, 20u, 0.25u)
Specifies that $\mathbf{w} \mathbf{1}$ is to be varied in optimization run opt1 within the limits $2 \times 10^{-6}$ and $20 \times 10^{-6}$. The initial guess for $\mathbf{w 1}$ in the optimization is $10 \times 10^{-6}$, and the final value will be a multiple of $0.25 \times 10^{-6}$.

```
.param safedivision(a,b)='if(abs(b)<1e-100, le100, a/b)'
.print tran impedance='safedivision(v(n1), i1(dev1))'
```

Creates a function named safedivision which divides one number by another without a division by zero error. This function is then used in a print expression.

## .paramlimits

Sets optimization parameter ranges. Allows the same parameter to be varied in multiple optimizations with different optimization run names.

This command specifies that the parameter paramname (specified using .param elsewhere) is to be varied and optimized during an optimization run optname. Multiple instances of .paramlimits may not exist in the netlist for the same optimization run and the same parameter name, but are allowed for the same optname but for different paramname values.

## Note:

T-Spice supports sequential optimization-multiple optimizations may be performed in series from one input file, and the optimization results used in subsequent optimizations.

## Syntax

```
.paramlimits optname paramname [guessval=guess] minval=min maxval=max
    [delta=delta]
optname Name of the optimization run.
paramname References a particular parameter.
guess Initial (nominal) parameter value for the optimization. If not used,
    the initial value defaults to the value specified in the .param
    command.
min}\quad\mathrm{ Minimum value of the range in which the parameter may vary.
max Maximum value of the range in which the parameter may vary.
delta
    If specified, the parameter can change only in integer multiples of
        this value. This is useful for optimizing quantities which can only
    take on discrete values, such as transistor lengths and widths.
```


## Examples

```
.paramlimits opt1 r minval=10 maxval=100k
.paramlimits opt1 m1width minval=1u maxval=10u delta=0.25u
```


## .power

Computes power dissipation in conjunction with transient analysis.

- If the ".tran" (page 147) command is missing from the input file, the .power command is ignored.
- The average power consumption, the instantaneous maximum power, and the instantaneous minimum power (in watts) and the times of maximum and minimum power consumption (in seconds) are reported at the end of the transient simulation.
- The instantaneous power $P(t)$ dissipated by a voltage source at time $t$ is the current through the source multiplied by the voltage drop across the source. The average power $P$ for a time interval $(t 1, t 2)$ is computed by using the trapezoidal rule approximation to evaluate the integral

$$
\begin{equation*}
\bar{P}\left(t_{1}, t_{2}\right)=\frac{1}{t_{1}-t_{2}} \int_{t_{1}}^{t_{2}} P(\tau) d \tau \tag{0.7}
\end{equation*}
$$

- Multiple .power commands can be used in a single simulation.
- Power results can also be reported with the ".print" (page 119) tran command.


## Syntax

```
.power source [A [Z]]
```

| source | Voltage source whose power consumption is to be computed. |
| :--- | :--- |
| $\boldsymbol{A}$ | Time at which power recording begins. (Unit: seconds. <br> Default: simulation start time.) |
| $\boldsymbol{Z}$ | Time at which power recording ends. (Unit: seconds. <br> Default: simulation end time.) |

## Examples

```
.power vtest 3e-7
```

Computes the power dissipated by voltage source vtest between the given time ( 0.3 microsecond) and the end of the simulation. It might produce the following sample output:

```
Power Results
vtest from time 0 to 3e-007
Average power consumed -> 1.249948e-002 watts
Max power 2.490143e-002 at time 9.76e-006
Min power 2.282279e-030 at time 1e-005
```


## .print

Reports simulation results.

- If an output filename is not specified, the output file specified in the Start Simulation dialog is used. (If that file cannot be opened, the results are written to the Simulation Window.)
- Multiple .print commands can be used to direct different types of output to separate files.
- Transient analysis results are printed in columns, with time values in the first column.
- AC and noise analysis results are printed in columns, with frequency values in the first column.
- DC transfer analysis results are printed in columns, with sweep values from the first source listed on the ".dc" (page 69) command in the first column.
- DC operating point analysis results are printed line by line, each argument to a line.
- Expressions can be printed by themselves, with or without reference to physical quantities at specific nodes.
- Nodes and devices within subcircuits can be accessed with hierarchical notation in the form xinstance.xinstance.node.
- .print commands inside subcircuit definition blocks are replicated for each instance.
- If no arguments are given, all node voltages and source currents are printed. If neither mode or arguments are given, .print applies to all analysis types. If arguments are given, a mode must also be specified.
- Wildcards may be entered as part of the .print command node names, devices names, terminal names, or terminal numbers. Wildcards are expanded to match any available elements which match the name specification.
- Device State print statements are a means of obtaining very detailed information about devices and device internal states. Data such as the current, charge, capacitance, and voltage values can be listed, as well as certain model evaluation variable (threshold voltage, beta, etc.).


## Syntax

```
.print [mode ] ["filename"] [arguments ]
mode Analysis mode (see below).
filename Output filename. Must be enclosed by double quotes.
arguments Information to be printed (see below). arguments may include valid
    expressions involving other arguments or global parameters.
```

mode is one of the following:

| tran | Print results from transient analysis. |
| :--- | :--- |
| dc | Print results from DC transfer analysis and DC operating point <br> analysis. |
| ac | Print results from AC analysis. |
| noise | Print results from noise analysis. |

arguments take one or more of a number of values, depending on mode. When no arguments are given, all node voltages and source currents are printed.

When an argument includes an expression, the expression must be enclosed by single quotes (' '). A string can also be used as a column heading in the output file, and the string can be followed by an optional unit specifier, enclosed by angle brackets ( $<\gg$ ). The unit is then displayed on the W-Edit $y$ axis.

Some entries in the argument tables below involve the variable $\boldsymbol{z}$, to be replaced by a key letter or number representing a device terminal. The key letters and numbers corresponding to particular device terminals are as follows (alternatives are separated by slashes):

- Diodes: anode $=\mathbf{P} / \mathbf{1}$; cathode $=\mathbf{N} / \mathbf{2}$.
- BJTs: collector $=\mathbf{C} / \mathbf{1}$; base $=\mathbf{B} / \mathbf{2}$; emitter $=\mathbf{E} / \mathbf{3}$; substrate $=\mathbf{S} / \mathbf{4}$.
- JFETs/MESFETs: drain = D/1; gate $=\mathbf{G} / \mathbf{2}$; source $=\mathbf{S} / \mathbf{3}$.
- MOSFETs: drain $=\mathbf{D} / \mathbf{1}$; gate $=\mathbf{G} / \mathbf{2}$; source $=\mathbf{S} / \mathbf{3}$; bulk $=\mathbf{B} / \mathbf{4}$.

Wildcards provide an easy and compact method of printing a large number of node or device values which have related names. The T-Spice .print command supports several types of wildcards in the specification of the node name, device name, terminal number, and terminal name. The ' ${ }^{*}$, character (asterisk) will be expanded to match any combination of alpha-numeric characters. The '?' character (question mark) will be expanded to match any single alpha-numeric character. And, '[...]' will be expanded to match any single character enclosed within the square brackets.

The arguments for transient, transfer, and DC analysis (.print tran, .print dc) are as follows.

| $\mathbf{n}$ | Voltage at node $\boldsymbol{n}$ relative to ground. |
| :--- | :--- |
| $\mathbf{i}(\boldsymbol{d}, \boldsymbol{n})$ | Current at node $\boldsymbol{n}$ of device $\boldsymbol{d}$ (inward current positive). |
| $\mathbf{i z ( \boldsymbol { d } )}$ | Current at terminal $\boldsymbol{z}$ of device $\boldsymbol{d}$ (inward current positive). |
| $\mathbf{p}(\boldsymbol{d})$ | Power consumed by voltage source $\boldsymbol{d}$. This result can also be <br> reported with the .power command. |
| $\mathbf{q ( d , \boldsymbol { n } )}$ | Charge at node $\boldsymbol{n}$ of device $\boldsymbol{d}$. |
| $\mathbf{q z ( \boldsymbol { d } )}$ | Charge at terminal $\boldsymbol{z}$ of device $\boldsymbol{d}$. |
| $\mathbf{v ( n 1 [ [ , ] \boldsymbol { n 2 ] } )}$ | Voltage at node $\boldsymbol{n} 1$ relative to node $\boldsymbol{n} \mathbf{2}$. (Default reference node: <br> ground.) |
| 'time()' | Simulation time. Must be or be part of an expression enclosed by <br> single quotes. (Transient analysis only.) |

The arguments for AC analysis mode (.print ac) are as follows.

| $\mathbf{i d b}(\boldsymbol{d}, \boldsymbol{n})$ | Current magnitude at node $\boldsymbol{n}$ of device $\boldsymbol{d}$. (Unit: decibels.) |
| :--- | :--- |
| $\mathbf{i d b z}(\boldsymbol{d})$ | Current magnitude at terminal $\boldsymbol{z}$ of device $\boldsymbol{d}$. (Unit: decibels.) |
| $\mathbf{i i}(\boldsymbol{d}, \boldsymbol{n})$ | Imaginary component of the complex current at node $\boldsymbol{n}$ of device $\boldsymbol{d}$. |
| $\mathbf{i i z}(\boldsymbol{d})$ | Imaginary component of the complex current at terminal $\mathbf{z}$ of device <br>  <br> $\boldsymbol{d}$. |


| im(d,n) | Current magnitude at node $\boldsymbol{n}$ of device $\boldsymbol{d}$. |
| :---: | :---: |
| $\operatorname{imz}(d)$ | Current magnitude at terminal $\boldsymbol{z}$ of device $\boldsymbol{d}$. |
| ip(d,n) | Current phase at node $\boldsymbol{n}$ of device $\boldsymbol{d}$. |
| $i p z(d)$ | Current phase at terminal $\boldsymbol{z}$ of device $\boldsymbol{d}$. |
| $\operatorname{ir}(d, n)$ | Real component of the complex current at node $\boldsymbol{n}$ of device $\boldsymbol{d}$. |
| irz(d) | Real component of the complex current at terminal $\boldsymbol{z}$ of device $\boldsymbol{d}$. |
| vdb(n1[[,]n2]) | Voltage magnitude at node $\boldsymbol{n 1}$ relative to node $\boldsymbol{n} 2$ (Unit: decibels. Default reference node: ground.) |
| vi( $n 1[[] n 2]$, | Imaginary component of the complex voltage at node $\boldsymbol{n 1}$ relative to node n2. (Default reference node: ground.) |
| vm( $n 1[[] n 2]$, | Voltage magnitude at node $\boldsymbol{n} \mathbf{1}$ relative to node $\boldsymbol{n} 2$. (Default reference node: ground.) |
| vp(n1[[,]n2]) | Voltage phase at node $\boldsymbol{n 1}$ relative to node n2. (Default reference node: ground.) |
| $\operatorname{vr}(\underline{n 1[[,] n 2])}$ | Real component of the complex voltage at node $\boldsymbol{n} 1$ relative to node n2. (Default reference node: ground.) |
| 'frequency()' | AC frequency. Must be or be part of an expression enclosed by single quotes. |

The arguments for noise analysis mode (.print noise) include any of the arguments for AC analysis mode in addition to the following:

| $\boldsymbol{d n}(\boldsymbol{d}[, \boldsymbol{t}])$ | Output noise spectral density contributions corresponding to the <br> noise sources associated with device $\boldsymbol{d}$. If the noise type $\boldsymbol{t}$ (see below) <br> is not specified, then results for all applicable noise types are printed. |
| :--- | :--- |
| inoise | Equivalent input noise spectral density magnitude. <br> (Unit: volts $/ \sqrt{H e r t z})$. |
| inoise(db) | Equivalent input noise spectral density magnitude. (Unit: decibels.) <br> inoise(tot) <br> Total input noise—the integral of the input noise spectral densities <br> over the analysis frequency interval. (Unit: volts.) |
| onoise | Output noise spectral density magnitude (Unit: volts $/ \sqrt{H e r t z})$. |
| onoise(tot) | Output noise spectral density magnitude. (Unit: decibels.) |
| transfer | Total output noise—the integral of the output noise spectral densities <br> over the analysis frequency interval. (Unit: volts.) |
|  | AC transfer function between input and output. As the frequency <br> approaches zero, this value approaches the result from the .tf <br> command. (Unit: volts/ampere, for transresistance; or no unit, for <br> voltage gain.) |

The units for the .print noise $\mathbf{d n}(\boldsymbol{d}, \boldsymbol{t})$ command are volts $/ \sqrt{\text { Hertz }}$ by default. However, this can be chabged to Volts ${ }^{2} /$ Hertz by use of the option "dnout" (page 299).

The noise types $\boldsymbol{t}$ available for the .print noise $\mathbf{d n}(\boldsymbol{d}, \boldsymbol{t})$ command vary according to the device type (BJT, Diode, JFET, etc.) as shown in the following tables:

| noise type | BJT (Gummel-Poon) Noise Types <br> description |
| :--- | :--- |
| FN | Flicker noise due to base current |
| IB | Shot noise due to base current. |
| IC | Shot noise due to collector current. |
| RB | Thermal noise due to base resistance. |
| RC | Thermal noise due to collector resistance. |
| RE | Thermal noise due to emitter resistance. |
| RX | Transresistance from flicker noise source to output. |
| TOT | Total device output noise. |


| noise type | BJT (VBIC) Noise Types <br> description |
| :--- | :--- |
| IBE | Base-Emitter shot noise |
| IBEFN | Base-Emitter flicker noise |
| IBEP | Parasitic base-emitter shot noise |
| IBEPFN | Parasitic base-emitter flicker noise |
| ICCP | Parasitic base-collector shot noise |
| ITZF | Forward transport current shot noise |
| RBI | Thermal noise due to intrinsic base resistance |
| RBP | Thermal noise due to parasitic base resistance |
| RBX | Thermal noise due to extrinsic base resistance |
| RCI | Thermal noise due to intrinsic collector resistance |
| RCX | Thermal noise due to emitter resistance |
| RE | Thermal noise due to source resistance |
| RS | Transresistance from flicker noise source to output. |
| RX | Total device output noise. |
| TOT |  |


| noise type | description |
| :--- | :--- |
| FN | Flicker noise Noise Types |
| ID | Shot noise. |
| RX | Transresistance from flicker noise source to output. |
| TOT | Total device output noise. |


| noise type | JFET and MESFET Noise Types <br> escription |
| :--- | :--- |
| FN | Flicker noise. |
| ID | Thermal noise due to channel. |
| RD | Thermal noise due to drain resistance. |
| RG | Thermal noise due to gate resistance. |
| RS | Thermal noise due to source resistance. |
| RX | Transresistance from flicker noise source to output |
| TOT | Total device output noise. |


| noise type | MOSFET Noise Types <br> description |
| :--- | :--- |
| FN | Flicker noise. |
| ID | Thermal noise due to channel. |
| RD | Thermal noise due to drain resistance. |
| RG | Thermal noise due to gate resistance. |
| RS | Thermal noise due to source resistance. |
| RX | Transresistance from channel or flicker noise source to output. |
| TOT | Total device output noise. |

## Examples

.print tran in out il(r2) id(M2)
Prints transient analysis results: the voltages at nodes in and out and the currents into terminal $\mathbf{1}$ of device $\mathbf{r 2}$ and the drain terminal of device M2.
.print dc I10/in, I10/out, I11/in, I11/out

Prints DC analysis results at various subcircuit nodes.
.print ac "acdata" im(M2,g1) vm(out) vdb(out)
Writes AC analysis results to output file acdata: the magnitude of the current flowing into node $\mathbf{g 1}$ of device M2, the magnitude of the voltage at node out, and the same magnitude expressed in decibels.
.print noise inoise transfer $d n(m n 1)$ onoise(tot)
Prints noise analysis results: the equivalent input noise spectral density, the input/output transfer function, all noise information corresponding to device mn1, and the total output noise.

```
.print tran 'v(out)*sin(time()*sf)'
```

Prints the transient value of an expression involving the voltage at node out, the simulation time time(), and parameter $\boldsymbol{s f}$ (defined elsewhere with a .param command).

```
.print tran diff<V>='v(2)-v(1)'
```

Prints the transient value of an expression subtracting the voltage at node $\mathbf{1}$ from the voltage at node 2. The string diff is used as a column heading with the letter V as a unit designation.

```
.print
```

Prints all node voltages and voltage source currents for all analyses to a text file.

```
.print tran
```

Prints all node voltages and voltage source currents for transient analysis to a text file.

```
.print v(n*)
```

Prints the voltages for all nodes whose name begins with the letter ' $n$ '.

```
.print i[12](m*) i?(q*)
```

Prints the drain and gate currents (terminals 1 and 2) for every MOSFET device, and each terminal current for every BJT.

Device State variables are not available for all types of analysis or for all devices. In general, the state plots are only relevant to DC and transient analysis.

The format of the device state plot request is always state(d), where state is the state data identifier, and $\boldsymbol{d}$ is the device name.

The device state data which is available for each device type is as follows:

## BJT (Gummel-Poon) Device State printout identifiers description

state identifier
cap_be
cap_ibc
cap_sbe
cap_xbe
cbo
cbe capacitance
internal base-collector capacitance
csc/csb substrate-collector/substrate-base capacitance
external base-collector capacitance
base current
collector current
base-collector equivalent current
current due to the base-collector charge
current due to the base-emitter charge
current due to the base-internal base charge
current due to the collector-substrate charge
วic/avce
วic/Ovbe
$\partial \mathrm{ib} / \partial \mathrm{vbe}$
$\partial \mathrm{ib} / \partial \mathrm{vbc}$
substrate current
base-collector charge
base-emitter charge
base-internal base charge
collector-substrate charge
base resistance
operating region: $-2=$ inverse, $-1=$ saturation, $0=$ off, $1=$ on
base-collector voltage
vbci
rb and rc offset internal base-collector voltage
vbe base-emitter voltage
vbei rb and re offset internal base-emitter voltage
vsub substrate voltage

| state identifier | BJT (VBIC) Device State printout identifiers description |
| :---: | :---: |
| cbco | parasitic Base-Collector overlap capacitance (fixed) |
| cbeo | parasitic Base-Emitter overlap capacitance (fixed) |
| cqbe | Base-Collector charge current |
| cqbco | currents from Cbco charge |
| cqbep | currents from Cbcp charge |
| cqbex | currents from Cbcx charge |
| cqbe | Base-Emitter charge current |
| cqbeo | currents from Cbeo charge |
| cqbep | currents from Cbep charge |
| cqbex | currents from Cbex charge |
| cqcxf | currents from Ccxf charge |
| flxf | Excess phase circuit flux |
| ibc | intrinsic Base-Collector current |
| ibcp | parasitic Base-Collector current |
| ibe | intrinsic Base-Emitter current |
| ibep | parasitic Base-Emitter current |
| ibex | extrinsic Base-Emitter current |
| igc | weak avalanche current |
| irbi | intrinsic Base resistor modulated current |
| irbp | parasitic Base resistor modulated current |
| irbx | external Base resistor current |
| irci | intrinsic Collector resistor modulated current |
| ircx | external Collector resistor current |
| ire | external Emitter resistor current |
| ith | thermal (heat generation) source, power dissipation |
| itxf | forward transport current, with excess phase |
| itzf | forward transport current, zero phase |
| itzr | reverse transport current, zero phase |
| ixxf | forward transport current, with excess phase |
| ixzf | forward transport current, with excess phase |
| qbe | Base-Collector charge |
| qbco | parasitic Base-Collector charge (depletion) |


| state identifier | BJT (VBIC) Device State printout identifiers |
| :---: | :---: |
| qbep | parasitic Base-Collector charge (depletion) |
| qbex | parasitic Base-Collector charge (depletion) |
| qbe | Base-Emitter charge |
| qbeo | parasitic Base-Emitter charge (depletion and diffusion) |
| qbep | parasitic Base-Emitter charge (depletion and diffusion) |
| qbex | extrinsic Base-Emitter charge (depletion) |
| qexf | Excess phase circuit capacitance |
| rbi | intrinsic Base resistance (modulated) |
| rbip | parasitic Base resistance (modulated) |
| rbx | extrinsic Base resistance (fixed) |
| rci | intrinsic Collector resistance (modulated) |
| rex | extrinsic Collector resistance (fixed) |
| re | Emitter resistance (fixed) |
| rgn | operating region |
| rs | Substrate resistance (fixed) |
| vb | Base voltage |
| vbe | Base-Collector voltage |
| vbci | Rb and Rc offset internal Base-Collector voltage |
| vbe | Base-Emitter voltage |
| vbei | Rb and Re offset internal Base-Emitter voltage |
| vbi | Bi internal Base voltage |
| vbp | Bp parasitic Base voltage |
| vbx | Bx external Base voltage |
| ve | Collector voltage |
| vci | Ci internal Collector voltage |
| vex | Cx external Collector voltage |
| ve | Emitter voltage |
| vei | Ei internal Emitter voltage |
| vs | Substrate voltage |
| vsi | Si internal Substrate voltage |

## Capacitor Device State printout identifiers

 description

| ceff | effective capacitance |
| :--- | :--- |
| curr | current |
| $\mathbf{d q}$ | $\partial \mathbf{q} / \partial v$ |
| $\mathbf{q}$ | charge |
| volt | voltage potential |


| state identifier | f element (CCCS) Device State printout identifiers <br> description |
| :--- | :--- |
| curr | source current |
| di or di1 | derivative of source current w.r.t. first control |
| di2 | derivative of source current w.r.t. second control |
| di3 | derivative of source current w.r.t. third control |
| volt | voltage potential across the CCCS |


| state identifier | h element (CCVS) Device State printout identifiers <br> description |
| :--- | :--- |
| curr | source current |
| dv or dv1 | derivative of source voltage w.r.t. first control |
| dv2 | derivative of source voltage w.r.t. second control |
| dv3 | derivative of source voltage w.r.t. third control |
| volt | voltage potential across the CCVS |

## state identifier

## Diode Device State printout identifiers <br> description

## c

curr current through the diode
di
$\partial \mathrm{i} / \partial \mathrm{v}$
dq
$\partial \mathbf{q} / \partial \mathrm{v}$
conductance
gd
current, excluding the series resistor

| state identifier | Diode Device State printout identifiers <br> description |
| :--- | :--- |
| ir | current through the series resistor <br> charge |
| rgn | operating region: $-1=$ breakdown, $0=$ reverse, $1=$ forward <br> voltage potential, excluding the series resistor <br> vd |
| voltage across the diode |  |
| vr | voltage across the series resistor |
| Inductor Device State printout identifiers |  |
| description |  |

## MOSFET Device State printout identifiers

state identifier description
betaeff
cap_bd
cap_bs
cbdbo
cbdo
cbgbo
cbsbo
cbso
cddbo
cdgbo
cdo
cdsbo
cgdbo
effective beta bulk-drain capacitance bulk-source capacitance $\partial \mathrm{Qb} / 2 \mathrm{Vd}$ DC drain-bulk diode current $\partial \mathrm{Qb} / \partial \mathrm{Vg}$ $\partial \mathrm{Qb} / \partial \mathrm{Vs}$ DC source-bulk diode current $\partial \mathrm{Qd} / \partial \mathrm{Vd}$ $\partial \mathrm{Qd} / \partial \mathrm{Vg}$ DC drain current $\partial \mathrm{Qd} / \partial \mathrm{Vs}$ $\partial \mathrm{Qg} / \partial \mathrm{Vd}$

## MOSFET Device State printout identifiers

| state identifier | description |
| :---: | :---: |
| cggbo | $\partial \mathrm{Qg} / \partial \mathrm{Vg}$ |
| cgsbo | $\partial \mathrm{Qg} / \partial \mathrm{Vs}$ |
| cqb | current due to the intrinsic bulk charge |
| cqd | current due to the intrinsic drain charge |
| cqg | current due to the intrinsic gate charge |
| cqs | current due to the intrinsic source charge |
| deltal | channel length modulation |
| gammaeff | effective gamma |
| gbdo | Conductance of the drain diode |
| gbso | conductance of the source diode |
| gdso | DC drain-source transconductance |
| gmbso | DC substrate transconductance |
| gmo | DC gate transconductance |
| qbi | intrinsic bulk charge |
| qbd | bulk-drain diode charge |
| qbs | bulk-source diode charge |
| cqbd | current due to bulk-drain diode charge |
| cqbs | current due to bulk-source diode charge |
| qdi | intrinsic drain charge |
| qgi | intrinsic gate charge |
| qsi | intrinsic source charge |
| rgn | operating region: $-1=$ subthreshold, $0=$ linear, $1=$ saturation |
| ueff | effective mobility |
| vbs | bulk-source voltage |
| vbsi | Rs offset internal bulk-source voltage |
| vds | drain-source voltage |
| vdsat | saturation voltage |
| vdsi | Rd and Rs offset internal drain-source voltage |
| vfbeff | effective Vfb |
| vgs | gate-source voltage |
| vgsi | Rs offset internal gate-source voltage |
| vth | Threshold voltage |


| state identifier | Resistor Device State printout identifiers description |
| :---: | :---: |
| cap1 | capacitance of the first capacitor |
| cap2 | capacitance of the second capacitor |
| curr | current through the resistor |
| di | $\partial \mathrm{I} / \partial \mathrm{V}$ |
| g | conductance |
| ic1 | current through the first capacitor |
| ic2 | current through the second capacitor |
| qc1 | charge of the first capacitor |
| qc2 | charge of the second capacitor |
| r | effective resistance |
| vc1 | voltage across the first capacitor |
| vc2 | voltage across the second capacitor |
| volt | voltage across the resistor |
| state identifier | g element (VCCS) Device State printout identifiers description |
| curr | VCCS source current |
| di or di1 | derivative of source current w.r.t. the first control |
| di2 | derivative of source current w.r.t. the second control |
| di3 | derivative of source current w.r.t. the third control |
| dq or dq1 | derivative of source charge w.r.t. the first control |
| dq2 | derivative of source charge w.r.t. the second control |
| dq3 | derivative of source charge w.r.t. the third control |
| q | VCCS source charge |
| volt | voltage across the VCCS |
| state identifier | e element (VCVS) Device State printout identifiers description |
| curr | VCVS source current |
| dv or dv1 | derivative of source voltage w.r.t. the first control |
| dv2 | derivative of source voltage w.r.t. the second control |

## e element (VCVS) Device State printout identifiers

state identifier
dv3 derivative of source voltage w.r.t. the third control
volt
voltage across the VCVS

## .probe

Reports simulation results in binary format. .probe exactly as .print, except that output is binary instead of text. If arguments are given, the mode must be specified.

The file specified with the ".options" (page 106) probefilename command becomes the default for the .probe output file. If an output filename is not specified, T-Spice uses an ASCII output file name with no extension.

## Syntax

```
.probe [mode] ["filename"] [arguments]
mode Analysis type (see below). If mode is omitted, the .probe command applies to all analysis types.
filename Specifies the binary output filename. The suggested extension is .dat. Must be enclosed by double quotes.
arguments
Specifies plot variables to be included in the output file. If arguments is omitted, T-Spice includes all node voltages and voltage source currents in the output. The format and types of arguments are the same as for the ".print" (page 119) command.
```

mode is one of the following:

| tran | Print results from transient analysis. |
| :--- | :--- |
| dc | Print results from DC transfer analysis and DC operating point <br> analysis. |
| ac | Print results from AC analysis. |
| noise | Print results from noise analysis. |

## Examples

. probe
Saves all node voltages and voltage source currents for all analyses to a binary file.
.probe tran
Saves all node voltages and voltage source currents for transient analysis to a binary file.
. probe tran $\mathrm{v}(2)$
Saves the transient voltage at node 2 to a binary file.
. probe tran Output<v> $=' v(2)-v(1)^{\prime}$
Saves the transient value of an expression subtracting voltage at node 1 from voltage at node 2 and prints it in a column with the heading Output.

## .protect / .unprotect

The .protect and .unprotect commands are used for temporarily turning input file echoing off and on. Input file echoing is initially turned on with the command .option echo. Subsequent use of .protect will turn off the echoing, until the .unprotect command is encountered. In this manner sensitive data, such as model libraries, can be protected from distribution, or excessive amounts of netlist echoing can be trimmed down.

## Syntax

## - protect

. unprotect

## .save

Saves bias point information to a file. All of the non-internal node voltage values will be saved to the file using either the .ic or the .nodeset T-Spice command syntax. Subsequent simulations may use the .load command to read the file and execute the .nodeset or the .ic commmands.

## Syntax

| .save | [type=ic \| nodeset] [time=time] |
| :---: | :---: |
| filename | Name of the file to be written. If the file parameter is not entered, then the filename is derived from the simulation output filename, with a ic file extension. |
| type | Denotes the type of node initialization command which will be written to the file for each non-internal circuit node. Either ic, to have .ic commands generated, or nodeset, for nodeset commands. (Default: nodeset) |
| time | The transient analysis time at which the bias information should be saved. Ordinarily, the .save command saves the DC operating point bias information. If a time parameter has been specified, and the simulation performs a transient analysis, then the bias at the specified timepoint will be saved. |

## Examples

```
.save type=ic time=50n
```


## .savebias

Saves bias point information to a file. Node voltage values will be saved to the file using either the .ic or the .nodeset T-Spice command syntax. Subsequent simulations may use the .load command to read the file and execute the .nodeset or the .ic commmands.

## Note:

The .save and the .savebias commands perform essentially the same task, but use a different syntax and have different options.
.save is provided for HSPICE command compatibility, while .savebias provides PSPICE command compatibility.
The saved file from either command can be loaded into a subsequent simulation using the .load command.

## Syntax



## Examples

```
.savebias ring.ic tran ic time=100n repeat
.savebias dc alter=2 dc=2.5 temp=75 internal
```

Performs a parametric sweep of a sweep variable, performing all analyses in the input file for all parameter values in the sweep.

The .step command produces a separate output section for each parameter value of the sweep. For example, an input file with .step and ".tran" (page 147) produces one transient analysis output section for each parameter value in the sweep. In addition, all ".macro /.eom" (page 88) results are plotted as traces with the swept variable as the $x$-axis. The output format for this is similar to that of the ".dc" (page 69) command.

Note: The .step command can be abbreviated to .st.

## Syntax

```
.step sweep [[sweep] sweep [[sweep] sweep]]
```

where sweep is in one of the following formats:
[lin] variable start stop inc
or
dec|oct variable start stop npoints
or
variable lin|dec|oct npoints start stop
or
variable list value [value [...]]
or
list variable value [value [...]]
or

```
variable poi npoints [value [...]]
```

or
data=dataname
or
monte=mcruns [seed=seedval]
or
optimize=optname results=measname [measname [...]] model=optmodelname
variable specifies the parameter whose value is to be swept. It is one of the following:

| temp | Specifies a temperature sweep. |
| :--- | :--- |
|  | Note: Use .dc to to plot voltage/current vs. temperature, not temp <br> and .step temp. |
| param paramname | Sweeps a global parameter named paramname defined using the <br> .param command. |
| source sourcename | Sweeps the DC value of a voltage or current source value named <br> sourcename. |
| [modparam] |  |
| parname(modelname) |  |
| paramname | Sweeps the value of model parameter parname for the device model <br> modelname. |
|  | Sweeps a global parameter (as with param) or DC source value (as <br> with source). T-Spice first looks for a matching .param parameter, <br> and then for a source name. |

Other parameters include the following:

| start | Specifies the beginning of a linear or logarithmic sweep. |
| :--- | :--- |
| stop | Specifies the end of a linear or logarithmic sweep. |
| inc | Specifies the increment for a linear sweep. |
| npoints | Specifies the total number of points for a linear or poi sweep, or the <br> number of points per decade or octave for a logarithmic sweep. |
| value | Specifies a single value which variable takes on for one step of the <br> sweep. |
| mcruns | Specifies the number of runs to be performed for Monte Carlo <br> analysis. |
| seedval | An integer specifying a seed for initializing the random number <br> sequence for Monte Carlo analysis. If seedval is negative, T-Spice <br> uses the system clock to generate a different seed each time the <br> simulation is run. A seedval of zero is equivalent to not specifying a <br> seed value at all. |
| dataname | Specifies the name of a ".connect" (page 66) statement to be used <br> for the sweep. The column names in the .data statement must <br> correspond to global ".param" (page 113) parameters. For each |
| sweep step, those parameters are assigned the values found in one |  |

\(\left.$$
\begin{array}{ll}\text { oct } & \text { Specifies a logarithmic sweep by octaves. } \\
\text { list } & \text { Specifies a sweep over a list of values (P-Spice compatible syntax). } \\
\text { poi } & \text { Specifies a sweep over a list of values (HSPICE compatible syntax). } \\
\text { data } & \text { Specifies a sweep defined using a .data statement. } \\
\text { monte } & \begin{array}{l}\text { Specifies a Monte Carlo sweep. For each Monte Carlo run, random } \\
\text { circuit parameter values are generated from probability distributions. }\end{array} \\
& \begin{array}{l}\text { A Monte Carlo sweep must be the outermost sweep if sweeps are } \\
\text { nested. }\end{array} \\
\text { optimize } & \begin{array}{l}\text { Specifies an optimization sweep. During an optimization sweep, } \\
\text { T-Spice runs many analyses in an attempt to optimize a circuit }\end{array}
$$ <br>
performance objective. The user may specify a set of parameters to <br>

be varied and a set of measurements to be included in the\end{array}\right]\)| optimization goal. Optimization sweeps may not be nested within |
| :--- |
| other optimization sweeps. For further information on setting up an |
| optimization run, see "Optimization" on page 517. |

## Examples

.step vin 050.1
sweeps the DC value of voltage source vin from 0 to 5 V with 0.1 V increments.

```
.step lin param ml 2 3 0.5 sweep vdd 3 5 0.1
```

performs a nested linear sweep of the parameter $\mathbf{m l}$ and the voltage source vdd.

```
.step list temp 0 27 100 150 -50
```

sweeps the circuit operating temperature over the five values listed.

```
.step optimize=opt1 results=bandwidth, delay model=optmod
.param p1=opt1(1e-3,1e-5,1) p2=opt1(150,100,200)
.model optmod opt level=1 itropt=40
.measure ac bandwidth trig vm(out) val=0.5 cross=1
+ targ vm(out) val=0.5 cross=2
+ goal=2kHz
```

```
.measure tran delay when v(1)=2.5 goal=10ns
```

invokes an optimization of parameters p1 and p2. T-Spice will attempt to find values for p1 and p2 which result in a bandwidth of 2 kHz and a delay of 10 ns . An AC and a transient analysis would be performed for each optimization function evaluation.

## .subckt

Defines a hierarchical set of devices and nodes to be used repeatedly in a higher-level circuit.

- Subcircuits are replicated by means of the instance ( $\mathbf{x}$ ) statement.
- When invocations of the following commands appear within subcircuit definitions and refer to nodes inside the subcircuit, the commands are executed for each instance of the node: ".acmodel" (page 63), ".hdl" (page 79), ".macro /.eom" (page 88), ".nodeset" (page 100), ".noise" (page 101), ".print" (page 119), and ".probe" (page 133), and ".tf" (page 146).
- Node and device names have local scope in subcircuits unless global node names (defined elsewhere with the ".global" (page 77) command) are used.
- Subcircuit blocks cannot be nested: after one .subckt command, the ".ends" (page 74) command must appear before another .subckt command can be used.


## Syntax

```
.subckt name node1 [node2 ...] [parameter=X ...]
subcircuit
.ends
```


## name

node1 node2
parameter
subcircuit

Name of subcircuit.
Nodes used as "external" connections to the subcircuit.
Parameter(s), with default value(s) assigned. $\boldsymbol{X}$ can be a number or an expression. Subcircuit parameters have local scope. Parameters can be written in any order in both definition and instances. Parameter values specified in the definition are used as defaults when not specified in instances. Within the definition, parameter values are referenced (in place of numbers) by enclosing their names in single quotes. Alternatively, the ".param" (page 113) command may be used within the definition, with the same results. Parameters created outside the definition with the ".param" (page 113) command may be used inside the definition, but an assignment made with the .subckt command to an externally defined parameter always overrides its external value.

Subcircuit definition (may be multiple lines).

## Examples

```
.subckt inv in out Vdd length=1.25u nwidth=2u pwidth=3u
mt1 out in GND GND nmos l='length' w='nwidth'
mt2 out in Vdd Vdd pmos l='length' w='pwidth'
c2 out GND 800f
.ends inv
```

This subcircuit could be instanced as follows:

```
xinv1 al a2 Vdd inv nwidth=4u pwidth=6u
```


## .table

Links a table reference name (used by simulated devices) with external charge and current table filenames.

The table which is imported from the named file can define the behavior of a standard device, such as a MOSFET, resistor, diode, etc., and takes the place of the modelname (from a .model definition) in the device declaration.

The table data may also be used to define a generic "black box" device which is created by the xname method of instantiating a subcircuit. When the .table and the xname commands are used in combination to define a generic table-based device, the .table model takes the place of a .subckt subcircuit definition. You use the .table command instead of the .subckt command to define your device characteristics.

## Syntax

| tablename | Table reference name. |
| :---: | :---: |
| current | File containing steady-state current table. The file should have extension .f (binary) or .ftx (ASCII). If the referenced filename or path contains a space, enclose the entire path in single or double quotation marks. |
| charge | File containing charge table. The file should have extension . $\mathbf{q}$ (binary) or .qtx (ASCII). If the referenced filename or path contains a space, enclose the entire path in single or double quotation marks. |

## Examples

## MOSFET table example:

.table nmos1x3 n1x3.ftx n1x3.qtx

Establishes a relationship between the table reference name nmos1x3 and the table files $\mathbf{n} 1 \mathbf{x 3}$.ftx and $\mathbf{n 1 x 3 . q t x}$. The input file is searched for any device statements-MOSFET (m) statements or xname commands-which include the table reference name nmos1x3. The corresponding devices use the charge and current tables in n1x3.ftx and n1x3.qtx.

A table-based MOSFET device can then be created by (for example) :

```
mnmos1x3 n1 n5 GND GND nmos1x3
```


## Inverter table example:

```
xinv in out invtable
.table invtable invcirc.ftx invcirc.qtx
```

Illustrates how a CMOS inverter can be defined as a macromodel. Rather than explicitly constructing a description of the inverter with its component transistors, the circuit description names the inverter's input and output nodes. The input/output behavior of the inverter is approximated by current (invcirc.ftx) and charge (invcirc.qtx) tables that are referenced with the name invtable.

## Resistor table example:

```
v1 1 0 1000
.table an_ftx_qtx_pair resistor.ftx resistor.qtx
xr1 1 0 an_ftx_qtx_pair
. op
```

where resistor.ftx is:

```
1 2 1 0
-1 +1
-1e-3
+1e-3
```

and resistor.qtx is:

```
1 2 1 0
-1 +1
0
0
```

Illustrates a resistor defined as a macromodel where the circuit description names the resistor's input and output nodes. The input/output behavior of the resistor is approximated by a table referenced with the tablename an_ftx_qtx_pair

Specifies the temperatures at which the circuit is to be simulated.

- Changing the temperature affects the behavior of diode, resistor, BJT, JFET, MESFET, and MOSFET models. It may also affect the behavior of user-defined external models.
- The .temp command has no effect on external tables, which should be regenerated to reflect the new temperature.


## Syntax

```
.temp temperature [temperature [temperature [...]]]
```

temperature $\quad$ Temperature. (Unit: ${ }^{\circ} \mathrm{C}$. Default: 25.)

Using .TEMP and .STEP displays voltage vs. voltage plots with different temperatures displaying as different traces. For example,

```
.DC vin 0 5 0.1
.TEMP 25 30 35 40 50
```

To plot voltage vs. temperature, use the following so that the first sweep variable in the DC analysis will become the X axis:

```
.DC temp 25 40 5 VIN 0 5 0.1
```

Computes and reports the value of the small-signal DC transfer function between the specified output and input, and the corresponding input and output resistances, at the DC operating point.

- The .tf command automatically performs (but does not report the results from) a DC operating point calculation.
- Results are reported under the heading SMALL-SIGNAL TRANSFER FUNCTION (to the specified output file or in the Simulation Window).
- The transfer function value corresponds to a voltage ( $\mathrm{V} N$ ) or current (I $\Lambda$ ) gain, a transconductance ( $\mathrm{I} / \mathrm{N}$ ), or a transresistance (V/).


## Syntax

```
.tf arguments source
```

| arguments | Any arguments appropriate for the ".print" (page 119) dc command. |
| :--- | :--- |
| source | Voltage or current input source. |

## Examples

.tf i(mb1,out1) iil

Computes transfer function results between node out1 of device mb1 and current source ii1.

## .tran

Performs large-signal time-domain (transient) analysis of the circuit to determine its response to initial conditions and time-dependent stimuli.

- The time step is adaptively varied throughout the simulation to ensure accuracy.
- Results for nodes selected by the .print tran, .probe tran, and .measure tran commands will be output for every time step, unless otherwise specified by the .options prtdel command. For additional information on these commands, see ".print" (page 119), ".probe" (page 133), ".macro /.eom" (page 88) and ".options" (page 106).


## Syntax


mode takes one of the following values:

op | Performs a DC operating point calculation before simulation to |
| :--- |
| determine initial steady-state node voltages. The commands |
| ".nodeset" (page 100) or ".hdl" (page 79) can be used to impose |
| initial conditions. |

If mode is not specified, T-Spice first performs a DC operating point analysis, without printing the DC operating point analysis results.
sweep indicates the beginning of the next nested sweep variable specification. The sweep keyword can be omitted if the previous sweep is not of the list or poi type or if one of the keywords lin, dec, oct, list, poi, temp, param, source, or modparam follows immediately.

Using the sweep option with .tran or ".ac" (page 60) causes that analysis to be performed for all parameter values of the sweep. It is equivalent to ".step" (page 138), except that it applies only to one analysis command, while .step applies to all analysis commands in the input file. If sweep is specified on an analysis command and .step is present, the sweep sweep is nested inside the .step sweep. The sweep parameter may be used to specify a parametric sweep, Monte Carlo analysis, or optimization.

## Examples

.tran $0.5 n 100 n$
Defines a transient simulation lasting 100 nanoseconds, using time steps of at most 0.5 nanosecond. By default, a DC operating point calculation will first be performed to define a starting condition.
.tran/preview 4n 4000n
The input waveforms are reported for 4000 nanoseconds; the rest of the circuit is ignored.
.tran 1 ns 100 ns
Specifies a maximum time step of 1 nanosecond and a total simulation time of 100 nanoseconds.
.tran/powerup 1 ns 100 ns
Specifies a powerup simulation with no operating point computation.
.tran 1 ns 100 ns start $=50 \mathrm{~ns}$
Produces output starting at time 50 nanoseconds.
.tran 1 n $100 n$ sweep temp list $027100150-50$

Performs five transient analysis runs, one for each temperature listed. The keyword temp specifies the sweep variable, as defined in ".step" (page 138).
.tran $1 n 400 n$ sweep temp -5015050
This performs five transient analyses at temperatures -50, 0, 50, 100, and 150 degrees Celsius.
.tran $0.5 u 100 u$ sweep monte=20
This performs 20 transient simulations as part of a Monte Carlo analysis. The keyword monte defines one of the many sweep options described in ".step" (page 138)). For each of the 20 transient analyses, values are randomly chosen for circuit variables, which are assigned probability distributions according to the specified "Monte Carlo Parameters" (page 114).

For a demonstration of Monte Carlo analysis in T-Spice, see "Example 2: Monte Carlo Analysis" on page 515.
.tran $1 n 200 n$ sweep temp list 02575150
This example performs four transient analysis runs at temperatures $0,25,75$, and 150 degrees Celsius.

## .vector

Names a bus and specifies how many bits the bus will contain.

- The bus is connected to a vector-valued current or voltage source, defined by a $\mathbf{i}$ or $\mathbf{v}$ statement with the bus keyword.
- The input source generates signals composed of bit strings of the length specified in the .vector command.


## Syntax

```
.vector bus {node1 [[,] node2 ...]]}
```

bus
node1 node2

Bus name.
Input nodes. If there are $\boldsymbol{n}$ nodes in a bus, the rightmost $\boldsymbol{n}$ bits of the input waveform (a binary number) are assigned one by one to these nodes. The last-named ( $\boldsymbol{n}$ th) node is assigned the least-significant (rightmost) bit; the $(\boldsymbol{n}-1)$ th node is assigned the next bit to the left; and so on. Extra bits are discarded. Extra nodes are set to zero.

## Examples

```
.vector bus1 {b7 b6 b5 b4 b3 b2 b1 b0}
```

Defines a bus bus1 and lists its eight input nodes. The input waveform to these nodes is specified as some number or numbers, convertible to a binary string with at least eight bits, in the accompanying voltage or current source statement.

## .vrange

Sets the voltage range used for all table dimensions of a specific device type.

- Changing the voltage range of a table does not change the number of points in each dimension of the table. Increasing the voltage range will compromise accuracy unless the gridsize is also increased.


## Syntax

| .vrange type $V$ |  |
| :--- | :--- |
| type | Type of device (see below). |
| $\boldsymbol{V}$ | Maximum table voltage (volts). Only one value is required; tables <br> range from $-\boldsymbol{V}$ to $\boldsymbol{V}$. |

type is one of the following:

| diode | DIODE |
| :--- | :--- |
| jfet | JFET |
| mes | MESFET |
| mos | MOSFET |

## Examples

. vrange mos 15
Causes MOSFET tables to range, for the purposes of interpolation, from -15 to +15 V in all dimensions. (Values outside the range are extrapolated.)

## 6 Device Statements

## Introduction

This chapter documents the device statements of the T-Spice circuit description language.
The device types are listed in alphabetical order; each type is associated with a key letter (in parentheses). Many statements have "options," which branch to different modes, and "arguments," which indicate expressions, nodes, or devices to be used. In the input file, a device statement must begin with its key letter in the first column of the line containing it (no leading spaces). Options and arguments must be separated by spaces or new lines (with line continuation).

Syntax sections in this documentation follow these conventions:

- Italics indicate variables to be replaced by actual names, numbers, or expressions.
- Curly brackets $\}$ indicate alternative values for the same option or argument.
- Square brackets [ ] enclose items that are not required.
- Vertical bars | separate alternative values for the same option or argument.
- Ellipses ... indicate items that may be repeated as many times as needed.

These characters are not typed in the input file. All other characters are typed as shown.

For more information, see "Input Conventions" on page 51 and "Simulation Commands" on page 59.

## BJT (q)

A transistor with up to four terminals: collector, base, emitter, and (optional) substrate. (BJT stands for bipolar junction transistor.)

Several types of bipolar models are supported in T-Spice:
SPICE Gummel-Poon model (level 1)
Vertical Bipolar Inter-Company (VBIC) (level 9)
Philips MEXTRAM (levels 6, 503, and 504)
Philips Modella (level 10 and 500)
The substrate is optional so that both discrete and IC BJTs may be modeled correctly.

## Syntax

| Parameter | Symbol | Description | Default |
| :---: | :---: | :---: | :---: |
| name |  | BJT name |  |
| collector |  | Collector terminal |  |
| base |  | Base terminal |  |
| emitter |  | Emitter terminal |  |
| substrate |  | Substrate terminal |  |
| model |  | BJT model name. The model is specified elsewhere in the input file in the form .model name npn\|pnp [parameters]. |  |

The following device options are available for Gummel-Poon models. Note that the tables parameter default is determined by the global modelmode option, which defaults to direct mode (tables=0).

| Parameter | Symbol | Description | Default |
| :--- | :--- | :--- | :--- |
| area | A | Area scale factor | 1 |
| areab | B | Base area scale factor | A |
| areac | C | Collector area scale factor | A |
| M | M | Multiplicity - the number of devices to be <br> placed in parallel. | 1 |
| tables | T | Toggle internal tables. When internal tables are <br> on, T-Spice will build a table of current and <br> charge values to speed device evaluation. | 1 |

VBIC device statements are different from the Gummel-Poon bipolars. The VBIC model does not contain any terms for explicitly defining geometry or junction areas.

```
qname collector base emitter [substrate] [tmode] model [M=M] [SCALE=S]
[tnodeout]
```

Instead, the device SCALE parameter is provided for linearly scaling the device currents and charges. For compatibility with Gummel-Poon devices, the VBIC device statement will also accept the $\mathbf{M}$ multiplicity factor as a synonym for the SCALE parameter.

| Parameter | Symbol | Description | Default |
| :--- | :--- | :--- | :--- |
| scale | S | Scale factor | 1 |

## Examples

```
qout1 r32 r23 gnd sub1 npnmod
qout2 r32 r23 gnd sub1 npnmod area=2
```

The area factor scales the generated current; thus, qout2 generates twice as much current as qout1.

## Capacitor (c)

A two-terminal capacitor. A nonlinear capacitor can be created using the $\mathbf{g}$ - element with an expression and the chg keyword. See "Nonlinear Capacitor" on page 194.

Syntax

```
cname node1 node2 CapValue|C=CapValue[=C] [M=M] [scale=scale] [tc1=T1]
    [tc2=T2] [dtemp=dtemp]
.or
cname node1 node2 POLY c0 [c1 [...]] [M=M]
or
cname nodel node2 modelname [c=C] [M=M] [scale=scale] [tc1=T1] [tc2=T2]
    [dtemp=dtemp] [l=length] [w=width]
or
cname node1 node2 modelname C [T1 [T2 ]] [M=M] [scale=scale] [dtemp=dtemp]
    [l=length] [w=width]
```

| Parameter | Symbol | Description | Default | Units |
| :---: | :---: | :---: | :---: | :---: |
| name |  | Capacitor name. |  |  |
| node1 |  | Positive terminal |  |  |
| node2 |  | Negative terminal. |  |  |
| C | C | Capacitance. |  | F |
| POLY |  | Keyword indicating that the capacitance is a polynomial function. |  |  |
| c0, c1, .. | $\mathrm{C}_{0}, \mathrm{C}_{1}$ | Coefficients of the polynomial function for capacitance. |  |  |
| M | M | Multiplicity - the number of devices to be placed in parallel. | 1 |  |
| scale | S | Element scale factor | 1 |  |
| T1 | $\mathrm{T}_{1}$ | First temperature coefficient for capacitance. | 0 | 1/deg |
| T2 | T2 | Second temperature coefficient for capacitance. | 0 | ( $1 / \mathrm{deg}^{2}$ ) |
| dtemp | $\mathrm{D}_{\text {temp }}$ | Difference between the capacitor and the circuit temperatures. | 0 | deg |
| I | L | Length of capacitor. |  | m |
| w | W | Width of capacitor |  | m |

## Equations

If the first syntax is employed the capacitance is calculated as

$$
\begin{equation*}
C=M \cdot S\left[1+T_{1}(\Delta T)+T_{2}(\Delta T)^{2}\right] \cdot C_{0} \tag{0.8}
\end{equation*}
$$

where

$$
\begin{equation*}
\Delta T=T_{\text {circuit }}+D_{\text {temp }}-T_{n o m} \tag{0.9}
\end{equation*}
$$

where $T_{\text {circuit }}$ is set in .temp and $T_{\text {nom }}$ in .options tnom.
If the second syntax is employed, capacitance is calculated as

$$
\begin{equation*}
C=c_{0}+c_{1} V+c_{2} V^{2}+\ldots \tag{0.10}
\end{equation*}
$$

where $V$ denotes the voltage between node1 and node2.
If the third or fourth syntax is employed, there must be a matching ".model" (page 96).

Note: When the calculated capacitance is greater than $0.1 \mathrm{~F}, \mathrm{~T}$-Spice issues a warning message.

## Examples

cwire w1 gnd 82f
The example defines a capacitor with a value of 82 femtofarads. A common error is to omit the metric abbreviation on the capacitance value, which can lead to unexpected results.
cxx 10 poly $0.08 \quad 2.08 \quad 3.08$
This example defines a capacitor cxx connected between nodes $\mathbf{1}$ and $\mathbf{0}$. The capacitance of cxx is described as

$$
\begin{equation*}
C=0.08+1.08 V+2.08 V^{2}+3.08 V^{3} \tag{0.11}
\end{equation*}
$$

where $V$ is the voltage between nodes $\mathbf{1}$ and $\mathbf{0}$.
A capacitor exhibiting polynomial dependence on its applied voltage can be modeled using the POLY keyword:
$\mathrm{c} 1 \mathrm{n}+\mathrm{n}-$ POLY c0 'c0*VCc'
The waveform for this capacitor is illustrated in "Nonlinear Capacitor" on page 194.
c1 1020 capxx $0.021 .5 e-25.0 e-4$ dtemp=20

This example illustrates the fourth syntax. The capacitor is named c1. Its terminals are connected to nodes 10 and 20. Its model name is capxx. It has two temperature coefficients, $\mathbf{t c 1}=\mathbf{1 . 5 e - 2}$ and $\mathbf{t c 2}=$ $\mathbf{5 . 0 e - 4}$. Its dtemp $=\mathbf{2 0}$. As the model name is capxx, the corresponding .model statement must also contain the word capxx.

## Coupled Transmission Line (u)

A set of coupled transmission lines.
There is no limit (besides physical memory) on the number of transmission lines that can be coupled.

## Syntax

```
uname in1 [in2 [...]] in0 out1 [out2 [...]] out0 model length=L [lumps=X]
```

[lumptype $=Y$ ]

| Parameter | Symbol | Description | Default | Units |
| :---: | :---: | :---: | :---: | :---: |
| name |  | Coupled transmission line name. |  |  |
| in1 in2 ... |  | Input terminals (as many as needed). |  |  |
| out1 out2 |  | Output terminals (as many as needed); |  |  |
| ... |  |  |  |  |
| inO |  | Input reference terminal. |  |  |
| out0 |  | Output reference terminal. |  |  |
| model |  | CPL coupling model name. The model is specified elsewhere in the input file in the form <br> .model name cpl level $=1[[r]=\{$ matrix $\}]$ <br> $[\mathrm{c}]=\{$ matrix $\}[1]=\{$ matrix $\}[[\mathrm{g}]=\{$ matrix $\}]$ |  |  |
| length | L | Physical length. |  | m |
| lumps | X | Number of lumps used for iterative ladder circuit (ILC) expansion. | 1 |  |
| lumptype |  | Type of lumps used for ILC expansion. Y is one of the following: <br> $0=$ "Gamma" type lumps <br> $1=$ "Tee" type symmetric lumps <br> $2=$ "Pi" type symmetric lumps <br> 3= Hybrid RGT lumps | 3 | 1/deg |

## Examples

```
ufine in1 in2 in3 refin out1 out2 out3 refout
+ cplmod l=1m lumps=3 lumptype=1
```


## Current Source (i)

A two-terminal ideal current supply.
Exponential, pulse, piecewise linear, frequency-modulated, sinusoidal, and customizable (vectorized) waveforms can be specified.

To specify a current source with an equation, use the "Voltage-Controlled Current Source (g)" (page 191) with an expression that may involve the time() function.

## Syntax

| iname node1 node2 [ [DC] $I][$ AC $M[P]]$ [waveform] |  |
| :--- | :--- |
| name | Voltage source name. |
| node1 | Positive terminal—or bus named by an associated .vector command. |
| node2 | Negative terminal. |
| $\boldsymbol{I}$ | DC level. (Unit: A) |
| $\boldsymbol{M}$ | AC Magnitude. (Unit: A) |
| $\boldsymbol{P}$ | AC Phase (Unit: degrees. Default: 0. ) |
| $\boldsymbol{w a v e f o r m}$ | Waveform identifier and parameters (see below). |

DC, AC, and transient values can be specified independently and in any order.
waveform is one of the following:

## Exponential Waveform

$\exp (\operatorname{Ii} \operatorname{Ip}[D r[\operatorname{Tr}[D f[T f]]])$

| II | Initial current. (Unit: amperes.) |
| :--- | :--- |
| Ip | Peak current. (Unit: amperes.) |
| Dr | Rise time delay. (Unit: seconds. Default: 0.) |
| Tr | Rise time constant. (Unit: seconds. Default: 0.) |
| Df | Fall time delay. (Unit: seconds. Default: 0.) |
| $\boldsymbol{T f}$ | Fall time constant. (Unit: seconds. Default: 0.) |

The formula used is:

$$
I(t)=\begin{array}{ll}
I_{i} & 0 \leq t \leq D_{r} \\
I_{i}+\left(I_{p}-I_{i}\right)\left(1-\exp \left(\frac{-\left(t-D_{r}\right)}{T_{r}}\right)\right) & D_{r} \leq t \leq D_{f}  \tag{0.12}\\
I_{i}+\left(I_{i}-I_{p}\right)\left(1-\exp \left(\frac{-\left(t-D_{f}\right)}{T_{f}}\right)\right) & D_{f} \leq t
\end{array}
$$

## Pulse Waveform

```
pulse (Ii Ip [D [Tr [Tf [PW [Pp]]]]]) [ROUND=RND]
```

Ii Initial current. (Unit: amperes.)
Ip Peak current. (Unit: amperes.)
D Initial delay. (Unit: seconds. Default: 0.)
Tr Rise time. (Unit: seconds. Default: time step from .tran.)
$\boldsymbol{T f} \quad$ Fall time. (Unit: seconds. Default: time step from .tran.)
Pw Pulse width. (Unit: seconds. Default: stop time from .tran.)
Pp Pulse period. (Unit: seconds. Default: stop time from .tran.)
RND

Rounding half-interval. A corner at time $T$ is replaced by a smoothly differentiable polynomial in the interval ( $T-$ RND,$T+$ RND $)$. The maximum $\boldsymbol{R N D}$ is half the distance to the nearest neighboring corner. (Default: 0—no rounding.)

Note that beginning with version 11, T-Spice interprets rise time as the time to go from the initial voltage to the pulse voltage, regardless of which is larger.

## Piecewise Linear Waveform

```
pwl (T1 I1 [T2 I2 ...])[ROUND=RND] [REPEAT[=Tr]] [TD=DELAY]
```

T1 T2
I1 I2
ROUND

REPEAT

Time at corner 1, 2, and so on. (Unit: seconds.)
Current at corner 1, 2, and so on. (Unit: amperes.)
Rounding half-interval. A corner at time $T$ is replaced by a smoothly differentiable polynomial in the interval ( $T-\boldsymbol{R N D}, T+\boldsymbol{R N D}$ ). The maximum $R N D$ is half the distance to the nearest neighboring corner. (Default: 0—no rounding.)

Starting time within the specified waveform for an infinite number of repetitions of the subwaveform. If $\boldsymbol{T r}$ is not specified, the entire waveform repeats indefinitely (i.e., $\boldsymbol{T r}=0$ ). $\boldsymbol{T r}$ must be less than or equal to the duration of the waveform. Waveforms can only repeat if the start and end points match. If they do not match, the repeat option is ignored. The REPEAT keyword can be abbreviated to $\mathbf{R}$.

Time delay added to the beginning of the waveform. If you specify corners $\mathbf{T 1}, \mathbf{T 2}$, etc. and TD=DELAY, then the defined current values will actually be applied at effective corner times T1+DELAY,
T2+DELAY, etc.

## Piecewise Linear Waveform File

| filename | Input file which contains the piecewise linear waveform definition in a series of time, current pairs, one per line. |
| :---: | :---: |
| ROUND | Same meaning as with $\mathbf{p w l}$ waveforms |
| REPEAT | Same meaning as with $\mathbf{p w l}$ waveforms |
| TD | Same meaning as with $\mathbf{p w l}$ waveforms |

## Frequency-Modulated Waveform

```
sffm (Io Ip [FC [Xm [Fs]]])
```

| Io | Offset current. (Unit: amperes.) |
| :--- | :--- |
| Ip | Peak current. (Unit: amperes.) |
| Fc | Carrier frequency (Unit: Hertz. Default: $1 / T$, where $T$ is the stop <br> time from .tran.) |
| Xm | Modulation index. (Default: 0. .) |
| Fs | Signal frequency. (Unit: Hertz. Default: $1 / T$, where $T$ is the stop <br> time from .tran.) |

The formula used is:

$$
\begin{equation*}
I(t)=I_{o}+I_{p} \cdot \sin \left[\left(2 \pi \cdot F_{c} \cdot t\right)+X m \cdot \sin \left(2 \pi \cdot F_{s} \cdot t\right)\right] \tag{0.13}
\end{equation*}
$$

## Sinusoidal Waveform

$\sin (I O \operatorname{Ip}[F r \quad[D e \quad[D a \quad[P h]]]])$

| Io | Offset current. (Unit: amperes.) |
| :--- | :--- |
| Ip | Peak current. (Unit: amperes.) |
| Fr | Frequency. (Unit: Hertz. Default: $1 / T$, where $T$ is the stop time from <br> .tran.) |
| Da | Delay time. (Unit: seconds.) |
|  | Damping factor. (Unit: $1 /$ seconds.) |

The formula used is:

$$
\begin{equation*}
I(t)=I_{o}+I_{p} \cdot \sin \left(2 \pi \cdot\left(F_{r} \cdot\left(t-t_{d}\right)+\frac{P}{360}\right)\right) \cdot \exp \left(-\left(\left(t-t_{d}\right) \cdot D\right)\right) \tag{0.14}
\end{equation*}
$$

## Vectorized Waveform

```
bit|bus ({pattern} [on=A] [off=Z] [delay=D] [pw=P] [rt=R] [ft=F] [lt=L]
    [ht=H]) [ROUND=RND]
```

| pattern | An expression consisting of one or more string or string-multiplier combinations (see below). |
| :---: | :---: |
| A | On current (Unit: amperes. Default: 0.001.) |
| $Z$ | Off current. (Unit: amperes. Default: 0.) |
| D | Delay time. (Unit: seconds. Default: 0.) |
| P | Pulse width: $\boldsymbol{P}=\boldsymbol{R}+T_{\boldsymbol{A}}=\boldsymbol{F}+T_{\boldsymbol{Z}}$, where $T_{\boldsymbol{A}}$ is the time during a pulse where the current is "on" $(V=\boldsymbol{A})$ and $T \boldsymbol{Z}$ is the time during a pulse where the current is "off" $(V=\boldsymbol{Z})$. (Unit: seconds. Default: $10 \times 10^{-}$ ${ }^{9}$.) |
| $R$ | Rise time. (Unit: seconds. Default: $1 \times 10^{-9}$.) |
| F | Fall time. (Unit: seconds. Default: $1 \times 10^{-9}$.) |
| L | Low time: $\boldsymbol{L}=\boldsymbol{F}+T_{\boldsymbol{Z}}$, where $T_{\boldsymbol{Z}}$ is the time during a pulse where the current is "off" $(V=\boldsymbol{Z})$. (Unit: seconds. Default: $10 \times 10^{-9}$.) |
| H | High time: $\boldsymbol{H}=\boldsymbol{R}+T_{\boldsymbol{A}}$, where $T_{\boldsymbol{A}}$ is the time during a pulse where the current is "on" $(V=\boldsymbol{A})$. (Unit: seconds. Default: $10 \times 10^{-9}$.) |
| RND | Rounding half-interval. A corner at time $T$ is replaced by a smoothly differentiable polynomial in the interval ( $T-\boldsymbol{R N D}, T+\boldsymbol{R N D}$ ). The maximum $\boldsymbol{R N D}$ is half the distance to the nearest neighboring corner. (Default: 0—no rounding.) |

A bit pattern consists of a set of numbers (possibly associated with multiplier factors) whose binary representations sequentially specify the "on"/"off" structure of the waveform. The pattern takes the form $\boldsymbol{a}(\boldsymbol{b}(\boldsymbol{x}) \boldsymbol{c}(\boldsymbol{y}) \ldots$ ), where $\boldsymbol{a}, \boldsymbol{b}$, and $\boldsymbol{c}$ are the optional multiplier factors and $\boldsymbol{x}$ and $\boldsymbol{y}$ are the numbers.

A bus pattern consists of a set of numbers (possibly associated with multiplier factors) whose binary representations-"bit strings"-are grouped together as a waveform bus and treated as a single input. The length of the bit strings is specified by the .vector command. If there are $n$ nodes in a vector, then T-Spice assigns the first $n$ bits of each bit string to those nodes. Extra bits are discarded. If there are not enough bits, the highest-order bits are set to zero. The leftmost node name in the .vector command takes the most significant bit.

Numbers are specified on the device statement in binary, hexadecimal (suffixed by $\mathbf{h}$ ), octal (suffixed by $\mathbf{0}$ ), or decimal (suffixed by d) notation. (For decimal representations the number of lower-order bits to be collected is also given.)

## Examples

i1 a b 4.5u AC 1.0 m 0.0
i1 has a DC value of 4.5 microamps, an AC magnitude of 1 milliampere, and an AC phase shift of 0 degrees.

```
i2 n2 GND pwl (0n 0 100n 0 101n 5 300n 5 301n 0
+ 500n 0 680n 5 700n 0 880n 5 900n 0)
```

i2 generates a pwl (piecewise linear) input: a single pulse followed by a pair of sawtooth cycles.

```
i3 n3 GND bit ({01010 11011} on=5.0u off=0.0 pw=50n rt=10n ft=30n)
```

i3 generates a bit input. Enclosed in braces \{ \} are two binary-valued five-bit patterns specifying the waveform. The two patterns alternate in time. The on current value is 5.0 microamps; the off current value is zero. The pulse width (pw), 50 nanoseconds, is the time the wave is either (ramping up and) on, or (dropping down and) off. The rise time ( $\mathbf{r t}$ ), 10 nanoseconds, is the time given for the wave to ramp from off to on; and the fall time ( $\mathbf{f t}$ ), 30 nanoseconds, the time given for the wave to drop from on to off.

```
i4 n4 GND bit ({5(01010 5(1))} pw=10n on=5.0u off=0.0)
```

$i 4$ generates a repeating bit input. Two distinct patterns are given again, but now multiplier factors are included. The wave consists of two alternating patterns: the first pattern contains five bits, the second is a single bit. The five-bit pattern is followed by five successive repetitions of the single-bit pattern, and this combination is repeated five times. (The same pattern could be described by $\{5(\mathbf{3}(\mathbf{0 1 )} \mathbf{4 ( 1 ) )}\}$.) The pulse width and on and off voltages are again specified, but the rise and fall times take default values.

```
.vector bb {n5 n6 n7 n8}
ib bb GND bus ({50(Ah) 30(7d4) 20(1000)} pw=5n on=5.0u off=0.0)
```

The .vector command defines the bus waveform generated by current source ib. The command assigns the bus a name (bb) and specifies by name the number of bits the bus waveform will have (four: $\mathbf{n 5}$ through n8). The current source statement, which contains the bus keyword, specifies waveforms with one or more patterns, along with pulse width and level information.

- The first pattern is $\mathbf{A h}$ (hex) $=1010$ (binary). Thus, using the names given on the .vector command, $\mathbf{n} 5=1, \mathbf{n} 6=0, \mathbf{n} 7=1$, and $\mathbf{n} 8=0$. The pattern is repeated 50 times (that is, maintained for a time period equal to the pulse width multiplied by 50 ).
- The next pattern is 7d4—that is, 7 (decimal) $=111$ (binary), or, to four lower-order bits, 0111. So $\mathbf{n} 5=0, \mathbf{n} \mathbf{6}=1, \mathbf{n 7}=1$, and $\mathbf{n 8}=1$. The pattern is repeated 30 times.
- The last pattern is $\mathbf{1 0 0 0}$ (binary), so $\mathbf{n} \mathbf{5}=1, \mathbf{n} \mathbf{6}=0, \mathbf{n} \mathbf{7}=0$, and $\mathbf{n} 8=0$. The pattern is repeated 20 times.


## Current-Controlled Current Source (f)

A two-terminal ideal DC current supply with a level that is a function of one or more control currents.
Syntax

```
Linear
fname node1 node2 vname1 K [Options]
```

Polynomial


| fname | Current-controlled current source name. Must begin with "f". |
| :--- | :--- |
| node1 | Positive terminal. Positive current flows into node1. |
| node2 | Negative terminal. Positive current flows out of node2. |
| $\boldsymbol{K}$ | Current gain—the ratio of the output current to the control current. <br> POLY <br> Keyword indicating that the output current is a polynomial function <br> of the control currents. |
| $\boldsymbol{N}$ | Number of control currents (valid values 1-6). |
| $\boldsymbol{v n a m e} \mathbf{1}^{\text {vname2 } \ldots}$ | Name(s) of the voltage source(s) supplying the control current(s). |
| $\boldsymbol{P}_{\mathbf{0}} \boldsymbol{P}_{\mathbf{1}} \boldsymbol{P}_{\mathbf{2}} \ldots$ | Coefficients of the control polynomial. |

## Options

```
[MAX=value] [MIN=value] [ABS =[0 | 1]] [TC1=value] [TC2=value] [SCALE=value]
```

MAX Maximum output voltage value.
MIN Minimum output voltage value.
ABS Output is absolute value if $\mathrm{ABS}=1$.
TC1, TC2, First- and second-order temperature coefficients.
SCALE Element value multiplier.

Current is reckoned positive if it enters a voltage source at its first terminal. A similar convention holds for the current-controlled current source.

The first statement creates a current source with a level equal to $\boldsymbol{K}$ multiplied by the current through voltage source vname1.

The second statement creates a current source whose level is a nonlinear polynomial function of the currents through up to three voltage sources. Let:

- $x=$ current through voltage source vname1;
- $y=$ current through voltage source vname2 (if $\boldsymbol{N} \geq 2$ );
- $z=$ current through voltage source vname3 (if $\boldsymbol{N} \geq 3$ ).

Then the controlled current source's level is defined as follows:
If $\boldsymbol{N}=1$ :

$$
\begin{equation*}
P_{0}+P_{1} x+P_{2} x^{2}+P_{3} x^{3}+\ldots \tag{0.15}
\end{equation*}
$$

If $\boldsymbol{N}=2$ :

$$
\begin{equation*}
P_{0}+P_{1} x+P_{2} y+P_{3} x^{2}+P_{4} x y+P_{5} y^{2}+P_{6} x^{3}+P_{7} x^{2} y+P_{8} x y^{2}+P_{9} y^{3}+\ldots \tag{0.16}
\end{equation*}
$$

If $\boldsymbol{N}=3$ :

$$
\begin{gather*}
P_{0}+P_{1} x+P_{2} y+P_{3} z+P_{4} x^{2}+P_{5} x y+P_{6} x z+P_{7} y^{2}+P_{8} y z+P_{9} z^{2}+P_{10} x^{3}+P_{11} x^{2} y+P_{12} x^{2} z+P_{13} x y^{2}+ \\
P_{14} x y z+P_{15} x z^{2}+P_{16} y^{3}+P_{17} y^{2} z+P_{18} y z^{2}+P_{19} z^{3}+\ldots \tag{0.17}
\end{gather*}
$$

If $\boldsymbol{N}=1$ and only one polynomial coefficient is specified, it is assumed to be $P_{1}$, to facilitate the specification of linearly-controlled sources.

## Examples

ftest in gnd vin 1.0
Current-controlled current source ftest has a gain of 1 and is controlled by the current through vin.
f1 01 ventrl 2.0
This defines a current source with a level equal to $2 \times i(\mathbf{v e n t r l})$, that is, twice the current through ventrl.
f2 01 POLY(1) ventrl 1 m 02
This defines a current source with a level equal to $10^{-3}+\left(2 \times i(\mathbf{v e n t r l})^{2}\right)$.

```
f3 0 1 POLY(2) v1 v2 0 1 2 3
```

This defines a current source with a level equal to $i(\mathbf{v 1})+(2 \times i(\mathbf{v 2}))+(3 \times i(\mathbf{v 1}) \times i(\mathbf{v 2}))$.
f4 $0 \quad 1$ POLY(3) v1 v2 v3 0
This defines a current source with a level equal to $i(\mathbf{v} 1)+(3 \times i(\mathbf{v} 3))+(4 \times i(\mathbf{v} 1) \times i(\mathbf{v} \mathbf{2}))$.

## Current-Controlled Voltage Source (h)

A two-terminal ideal DC voltage supply with a level that is a function of one or more controlling currents.

Linear
hname node1 node2 vname1 $K$ [Options]

## Polynomial

hname node1 node2 POLY ( $N$ ) vname1 [vname2 [vname3 ]] $P_{0} P_{1} P_{2} \ldots$ [Options]

| hname | Current-controlled voltage source name. Must begin with "h". |
| :--- | :--- |
| node1 | Positive terminal. |
| node2 | Negative terminal. |
| K | Transresistance—the ratio of the output voltage to the control <br> current. <br> Keyword indicating that the output voltage is a polynomial function <br> of the control currents. |
| POLY | Number of control currents (valid values 1-6). |
| $\boldsymbol{N}$ | Name(s) of the voltage source(s) supplying the control current(s). |
| $\boldsymbol{P}_{\mathbf{0}} \boldsymbol{P}_{\mathbf{1}} \boldsymbol{P}_{2} \ldots$ | Coefficients of the control polynomial. Current is reckoned positive <br> if it enters a voltage source at its first terminal. |

## Options

```
[MAX=value] [MIN=value] [ABS =[0 | 1]] [TC1=value] [TC2=value] [SCALE=value]
```

MAX Maximum output voltage value.
MIN Minimum output voltage value.
ABS Output is absolute value if $\mathrm{ABS}=1$.
TC1, TC2, First- and second-order temperature coefficients.
SCALE Element value multiplier.

The first statement creates a voltage source with a level equal to $\boldsymbol{K}$ multiplied by the current through voltage source vname1.

The second statement creates a voltage source whose level is a nonlinear polynomial function of the currents through up to three voltage sources. Let

- $x=$ current through voltage source vname1;
- $y=$ current through voltage source vname2 (if $\boldsymbol{N} \geq 2$ );
- $z=$ current through voltage source vname3 (if $\boldsymbol{N} \geq 3$ ).

Then the controlled voltage source's level is defined as follows:
If $\boldsymbol{N}=1$ :

$$
\begin{equation*}
P_{0}+P_{1} x+P_{2} x^{2}+P_{3} x^{3}+\ldots \tag{0.18}
\end{equation*}
$$

If $\boldsymbol{N}=2$ :

$$
\begin{equation*}
P_{0}+P_{1} x+P_{2} y+P_{3} x^{2}+P_{4} x y+P_{5} y^{2}+P_{6} x^{3}+P_{7} x^{2} y+P_{8} x y^{2}+P_{9} y^{3}+\ldots \tag{0.19}
\end{equation*}
$$

If $\boldsymbol{N}=3$ :

$$
\begin{gather*}
P_{0}+P_{1} x+P_{2} y+P_{3} z+P_{4} x^{2}+P_{5} x y+P_{6} x z+P_{7} y^{2}+P_{8} y z+P_{9} z^{2}+P_{10} x^{3}+P_{11} x^{2} y+P_{12} x^{2} z+P_{13} x y^{2}+ \\
P_{14} x y z+P_{15} x z^{2}+P_{16} y^{3}+P_{17} y^{2} z+P_{18} y z^{2}+P_{19} z^{3}+\ldots \tag{0.20}
\end{gather*}
$$

If $\boldsymbol{N}=1$ and only one polynomial coefficient is specified, it is assumed to be $P 1$, to facilitate the specification of linearly-controlled sources.

## Examples

```
htest in gnd vin 1.23e4
```

Current-controlled voltage source htest has a transresistance of 12.3 kilohms and is controlled by the current through vin.

```
h1 0 1 ventrl 2.0
```

This defines a voltage source with a level equal to $2 \times i(\mathbf{v c n t r l})$, that is, twice the current through ventrl.
h2 01 POLY(1) ventrl 1 m 02
This defines a voltage source with a level equal to $10^{-3}+\left(2 \times i(\text { ventrl })^{2}\right)$.

```
h3 0 1 POLY(2) v1 v2 0 1 2 3
```

This defines a voltage source with a level equal to $i(\mathbf{v} 1)+(2 \times i(\mathbf{v} \mathbf{2}))+(3 \times i(\mathbf{v} 1) \times i(\mathbf{v 2}))$.

```
h4 0 1 POLY(3) v1 v2 v3 0 1 0 3 0 4
```

This defines a voltage source with a level equal to $i(\mathbf{v} 1)+(3 \times i(\mathbf{v} \mathbf{3}))+(4 \times i(\mathbf{v} 1) \times i(\mathbf{v 2}))$.

## Diode (d)

A two-terminal $p-n$ junction diode.

## Syntax

| dname |
| :---: |
| name |
| node1 |
| node2 |
| model |
| A |
| M |
| T |
| L |
| W |
| $P J$ |
| LM |
| $\boldsymbol{W} \boldsymbol{M}$ |
| $L P$ |
| WP |

## Examples

```
dpn2 n1 n2 dmodel
D3 n3 n4 dmodel 3
```

The area factor scales the diode current; thus, D3 provides three times as much current as dpn2, given the same bias conditions.

## Inductor (I)

A two-terminal inductor.

Coupled (mutual) inductors can be defined with the $\mathbf{k}$ statement.

## Syntax

| or |  |  |
| :---: | :---: | :---: |
| lname node1 node2 L [tc1[tc2]] [M=M] [scale = scale] [dtemp = dtemp] [ $\boldsymbol{r}=$ resistance] |  |  |
| or |  |  |
| Iname node1 node2 PoLy CO C1 ... [M=M] |  |  |
| Parameter | Symbol | Description |
| name |  | Inductor name. |
| node1 |  | Positive terminal. |
| node2 |  | Negative terminal. |
| L | $L_{0}$ | Inductance. (Unit: henries. Default: 0.) |
| POLY |  | Keyword indicating that the inductance is a polynomial function. |
| Co C1 ... | $c_{0}, c_{1}, c_{2}$ | Coefficients of the polynomial. The inductance is $\boldsymbol{C O}+(\boldsymbol{C 1} \times i)+\left(\boldsymbol{C 2} \times i^{2}\right) \ldots$, where $i$ is the current through the inductor. |
| M | M | Multiplicity-the number of devices to be placed in parallel. (Default: 1.) |
| scale | $S$ | Element scale factor. (Default: 1.) |
| Tc1 | $T_{c l}$ | First temperature coefficient for inductance. (Unit: (1/deg C) ${ }^{2}$ ). (Default: 0.) |
| Tc2 | $T_{c 2}$ | Second temperature coefficient for inductance. (Unit: (1/deg C)2). (Default: 0.) |
| Dtemp | $D_{\text {temp }}$ | Difference between the inductor and the circuit temperatures. (Unit: Deg C). (Default: 0.) |
| R | $R_{0}$ | Parasitic resistance of the inductor. (Unit: ohm). <br> (Default: 0.) |

The formula for inductance is:

$$
\begin{equation*}
L=M S\left[1+T_{c 1}(\Delta T)+T_{c 2}(\Delta T)^{2}\right] L_{0} \tag{0.21}
\end{equation*}
$$

where

$$
\begin{equation*}
\Delta T=T_{\text {circuit }}+D_{\text {temp }}-T_{\text {nom }} \tag{0.22}
\end{equation*}
$$

where $T_{\text {circuit }}$ is set in .temp and $T_{\text {nom }}$ in .options tnom.
The formula for parasitic resistance is:

$$
\begin{equation*}
R_{\text {parasitic }}=R_{0} / M \tag{0.23}
\end{equation*}
$$

Note:
When the calculated inductance is greater than or equal to 0.1 H , T-Spice issues a warning message.

## Examples

L1 na nb $10 u$
The example specifies an inductor with a value of 10 microhenries.

L1 a c $25 \mathrm{~m}=10$ scale=20R=10 dtemp=20 tc1=1.5e-2 tc2=5e-4

## Instance (x)

An instantiation of a subcircuit definition, a Verilog-A device, or an external model device.
Subcircuit must be defined elsewhere in the input file with a .subckt/.ends block.
Nodes several levels deep within a subcircuit hierarchy are named using hierarchical notation in the form xinstance.xinstance.node.

The $\mathbf{x}$ key letter is also used to instance devices that are defined by Verilog-A modules and by external user-defined models.

## Syntax

| xname nodel [ $\ldots] \quad[\mathbf{M}=M]$ | subcircuit \| modulename | modelname [parameter=X |
| :---: | :---: |
| name | Subcircuit instance name. |
| node1 node2 ... | Specific instance nodes. The order of nodes named corresponds to the order specified by the .subckt command. |
| parameter $=X$ | Parameter(s) from the subcircuit definition or external model whose default value(s) are to be overridden by the assignment(s) made here. $\boldsymbol{X}$ can be a number or an expression. Subcircuit parameters have local scope. Parameters can be written in any order in both definition and instances. Parameters not specified here take their default values. |
| subcircuit | Original subcircuit definition name. |
| modulename | A Verilog-A module name |
| modelname | External model name. T-Spice matches this device with a model defined using a .model command with a matching modelname and whose type is external. |
| M | Multiplicity-the number of representations of parallel instances of the subcircuit. T-Spice multiplies the subcircuit terminal currents and charges by $\boldsymbol{M} . \boldsymbol{M}$ can be any positive integer or decimal. (Default: 1.) |

## Examples

```
.subckt inv in out Vdd length=1.25u nwidth=2u pwidth=3u
mt1 out in GND GND nmos l=' length' w='nwidth'
mt2 out in Vdd Vdd pmos l=' length' w='pwidth'
c2 out GND 800f
.ends inv
xinv1 a1 a2 Vdd inv nwidth=2.5u
```

The .subckt/.ends block creates a three-terminal subcircuit (an inverter) and names it inv. The subcircuit consists of two MOSFETs (one $n$-type and one $p$-type) and an 800 -femtofarad capacitor. The instance statement defines an instance, named inv1, of the inverter subcircuit inv. Following the instance name are the three terminals of the instance (in order corresponding to that of the original
subcircuit definition); the name of the subcircuit to which it refers; and a new assignment for parameter nwidth, which overrides the default value assigned in the definition.

```
x1 1 0 resmodel res=1k
```

This statement instantiates a device with terminals attached to nodes $\mathbf{0}$ and $\mathbf{1}$ and matches it to a model defined using
.model resmodel external winfile="res.dll"

The parameter $\mathbf{r e s}=\mathbf{1 k}$ is passed to the external model.

## JFET (j)

A transistor with drain, gate, and source terminals and an optional fourth terminal. (JFET stands for junction field effect transistor.)

## Syntax

| name | JFET name. |
| :---: | :---: |
| drain | Drain terminal. |
| gate | Gate terminal. |
| source | Source terminal. |
| model | JFET model name. This is specified elsewhere in the input file in the form <br> .model name $\mathbf{n j f} \mid \mathrm{pjf}$ [parameters] |
| A | Area scale factor. (Default: 1.) |
| M | Multiplicity-the number of devices to be placed in parallel. (Default: 1.) |
| T | Toggle internal tables. When internal tables are on, T-Spice will build a table of current and charge values to speed device evaluation (Default: 0.) |

## Examples

```
jout 4 8 6 jfet2
j1 vdd in out jfet2 3
```

The area factor scales the generated currents; thus, the currents at the terminals of $\mathbf{j} \mathbf{1}$ are three times those at the terminals of jout.

## MESFET (z)

A transistor with three or four terminals: drain, gate, and source. (MESFET stands for metal semiconductor field effect transistor.)

```
zname drain gate source [bulk] model [[area=]A] [l=L] [w=W] [M=M] [tables=T]
```

For HSPICE compatibility, you can create a MESFET device in T-Spice using a device name jname instead of zname. The syntax for these MESFET device statement is the same.]

| name | MESFET name. |
| :--- | :--- |
| drain | Drain terminal. |
| gate | Gate terminal. |
| source | Source terminal. |
| bulk | Bulk terminal. |
| $\boldsymbol{m o d e l}$ | MESFET model name. This is specified elsewhere in the input file in <br> the form |
| $\boldsymbol{A}$ | .model name $\mathbf{n m f}\|\mathrm{pmf}\| \mathrm{nj} \boldsymbol{f} \mid \mathrm{pjf}$ [parameters] |
| $\boldsymbol{L}$ | Area scale factor. (Default: 1.$)$ |
| $\boldsymbol{W}$ | Device length. (Unit: meters.) <br> $\boldsymbol{M}$ |
| Device width. (Unit: meters.) <br> Multiplicity-the number of devices to be placed in parallel. <br> (Default: 1.$)$ |  |
| $\boldsymbol{T}$ | Toggle internal tables. When internal tables are on, T-Spice will <br> build a table of current and charge values to speed device evaluation. <br> (Default: 0.$)$ |

## Examples

```
zout 4 8 6 mfet2
z1 vdd in out mfet2 3
ztest drain gate source vbg nmes1 w=20u l=2u
```

The area factor scales the generated current; thus, the currents at the terminals of $\mathbf{z 1}$ are three times those at the terminals of zout. The third example shows specification of the bulk terminal and of width and length. The area is fixed by the given width and length; any area specification is overridden by this computed area.

## MOSFET (m)

A transistor with four terminals: drain, gate, source, and bulk. (MOSFET stands for metal oxide semiconductor field effect transistor.)

Refer to Additional Model Documentation for complete documentation of the model parameter variations for each MOSFET level.

Unique T-Spice device model parameters can be found in "MOSFET Levels 8, 49 and 53 (BSIM3 Revision 3.3)" on page 418, "Variables for which equations are not given here are as follows." on page 426, "MOSFET Levels 44 and 55 (EKV Revision 2.6)" on page 447, and "MOSFET Level 57 (BSIM3SOI)" on page 453.

## Syntax



| Rdc | Additional contact resistance, which overrides the rdc model <br> parameter value—drain. (Unit: Ohms. Default: 0.0 ) |
| :--- | :--- |
| Rsc | Additional contact resistance, which overrides the rsc model <br> parameter value—source. (Unit: Ohms. Default: 0.0) |
| $\boldsymbol{R s h}$ | Source-Drain sheet resistance, which overrides the rsh model <br> parameter. (Unit: Ohms/square. Default: 0.0) |
| $\boldsymbol{G e o}$ | Selector for source/drain sharing of stacked devices (Default: 0 ) <br> $\boldsymbol{M}$ |
| $\boldsymbol{T}$ | Multiplicity—the number of devices to be placed in parallel. <br> (Default: 1.) |
|  | Toggle internal tables. When internal tables are on, T-Spice will <br> build a table of current and charge values to speed device evaluation. <br> (Default: 0. .) |

Default values for $\boldsymbol{A d}, \mathbf{P d}, \boldsymbol{A s}$, and $\boldsymbol{P s}$ depend on the acm model parameter. Default value for $\boldsymbol{T}$ depends on the global modelmode option, which defaults to direct mode (tables=0).

Parasitic diodes are always addes for MOSFETs in direct model evaluation mode. For table based model evaluation, the diodes are replaced with nonlinear capacitors when the option mosparasitics is turned off. One diode is placed between the bulk and the source, and another between the bulk and the drain.

The parasitic diode characteristics are determined by the MOSFET device parameters as, ad, pd, ps, and geo, as well as the MOSFET model parameters acm, cj, cjsw, cjgate, js, jsw, is, $\mathbf{n}$, $\mathbf{n d s}$, vnds, and hdif. The quantity weff also plays a role in determining default values for source and drain areas and perimeters for some values of acm.

The parasitic diode equations have been modified from the standard diode equations, in an effort to improve compatibility with other SPICE simulators and to improve simulator convergence. The diode charge/capacitance equations are unchanged; they are the same as for regular diodes. The DC current equations for MOSFET parasitic diodes are as follows.

If the MOSFET bulk-source voltage vbs is positive (the bulk-source diode is forward-biased), then the bulk-source diode's DC current is given by

$$
\begin{equation*}
\mathbf{i b s}=\mathbf{i s a t b s} \times(\exp (\mathbf{v b s} /(\mathbf{n} \times \mathbf{v t})-1)) \tag{0.24}
\end{equation*}
$$

where $\mathbf{v t}=k T / q$ (the thermal voltage), and the diode's saturation current isatbs is

$$
\begin{equation*}
\text { isatbs }=(\mathbf{j s} \times \text { aseff })+(\mathbf{j s w} \times \mathbf{p s e f f}) \tag{0.25}
\end{equation*}
$$

if that value is positive, or is zero otherwise. The effective source area aseff and perimeter pseff are computed as described below, depending on the value of the acm parameter.

Similarly, if the MOSFET bulk-drain voltage vds is positive (the bulk-drain diode is forward-biased), the bulk-drain diode's DC current is

$$
\begin{equation*}
\mathbf{i b d}=\mathbf{i s a t b d} \times(\exp (\mathbf{v b d} /(\mathbf{n} \times \mathbf{v t})-1)) \tag{0.26}
\end{equation*}
$$

where the diode saturation current isatbd is

$$
\begin{equation*}
\text { isatbd }=(\text { js } \times \text { adeff })+(\text { jsw } \times \text { pdeff }) \tag{0.27}
\end{equation*}
$$

if that value is positive, or is otherwise. The effective drain area adeff and perimeter pdeff are computed as described below.

The exponential function in both diodes is replaced by a linear extension when the current is larger than the value of the expli model parameter. The linear extension is chosen such that the diode current function is continuously differentiable at the transition point where the diode current equals expli.

The $\boldsymbol{n}$ parameter is now supported for MOSFET parasitic diodes.

When a MOSFET parasitic diode with saturation current isat is reverse-biased with a negative voltage vdi, then its current idi behaves as follows.

If $0>$ vdi $>$ vnds:

$$
\begin{equation*}
\text { idi }=\text { isat } \times v d i \tag{0.28}
\end{equation*}
$$

If vdi < vnds:

$$
\begin{equation*}
\text { idi }=\text { isat } \times(\mathbf{v n d s}+(\mathbf{v d i}-\mathbf{v n d s}) / \mathbf{n d s}) \tag{0.29}
\end{equation*}
$$

The effective source and drain areas and perimeters are computed as in the table below, depending on the value of the acm parameter.

If $\mathbf{a c m}=3$, the geo device parameter affects these calculations. The geo parameter is used to handle stacked MOSFET devices properly, and it can have the following values:

- geo $=\mathbf{0}$ (default): the drain and the source are not shared by other devices.
- geo =1: the drain is shared with another device.
- geo = 2: the source is shared with another device.
- geo = 3: the drain and the source are shared with other devices.

The geo parameter may be specified on the MOSFET device statement, at any point after the model name.

Each parasitic diode inherits its multiplicity factor $\mathbf{m}$ from its "parent" MOSFET. The values of defas, defad, and moscap are specified using .options.

$$
\text { acm = 0 } \quad \text { acm =1 } \quad \text { acm }=2 \quad \text { acm }=3
$$

## Source area

| with as | as $\times$ wmlt $^{2}$ | weff $\times$ wmlt | as $\times$ wmlt $^{2}$ | as $\times$ wmlt $^{2}$ |
| :--- | :--- | :--- | :--- | :--- |
| without as | $\mathbf{I} \times \mathbf{w}$ <br> $($ if moscap=1) <br> defas <br> (otherwise) | weff $\times$ wmlt | $2 \times$ hdifeff $\times$ weff | $2 \times$ hdifeff $\times$ weff <br> (if $\mathbf{g e o}=0$ or 1) |
|  |  | hdifeff $\times$ weff <br> (otherwise) |  |  |

Drain area
with ad $\quad$ ad $\times$ wmlt $^{2} \quad$ weff $\times$ wmlt $\quad$ ad $\times$ wmlt $^{2} \quad$ ad $\times$ wmlt $^{2}$

|  | $\mathrm{acm}=0$ | acm $=1$ | acm $=2$ | $\mathrm{acm}=3$ |
| :---: | :---: | :---: | :---: | :---: |
| without ad | ```l < w (if moscap = 1) defad (otherwise)``` | weff $\times$ wmlt | $2 \times$ hdifeff $\times$ weff | $2 \times$ hdifeff $\times$ weff <br> (if geo $=0$ or 2 ) <br> hdifeff $\times$ weff <br> (otherwise) |
| Source perimeter |  |  |  |  |
| with ps | ps $\times$ wmlt | weff | ps $\times$ wmlt | ps $\times$ wmlt |
| without ps | $\begin{aligned} & 2 \times(I+w) \\ & (\text { if moscap }=1) \\ & \text { defps } \\ & \text { (otherwise) } \end{aligned}$ | weff | $\begin{aligned} & 4 \times \text { hdifeff }+ \\ & 2 \times \text { weff } \end{aligned}$ | $4 \times$ hdifeff + weff <br> (if geo $=0$ or 1) <br> $2 \times$ hdifeff <br> (otherwise) |
| Drain perimeter |  |  |  |  |
| with pd | pd $\times$ wmlt | weff | pd $\times$ wmlt | pd $\times$ wmlt |
| without pd | $\begin{aligned} & 2 \times(\mathbf{I}+\mathbf{w}) \\ & (\text { if moscap }=1) \\ & \text { defpd } \\ & \text { (otherwise) } \end{aligned}$ | weff | $\begin{aligned} & 4 \times \text { hdifeff }+ \\ & 2 \times \text { weff } \end{aligned}$ | $4 \times$ hdifeff + weff <br> (if geo $=0$ or 2 ) <br> $2 \times$ hdifeff <br> (otherwise) |

The parasitic drain/source diodes' sidewall capacitance now makes use of the new cjgate parameter, which describes the sidewall capacitance per unit length along the gate edge. If cjgate is specified and the MOSFET's effective width weff is not greater than the diode's perimeter, then the total sidewall capacitance is given by:

$$
\begin{equation*}
\text { csw }=\text { cjsw } \times(p-\text { weff })+(\text { cjgate } \times \text { weff }) \tag{0.30}
\end{equation*}
$$

where $\boldsymbol{p}$ is $\mathbf{p s}$ for a source diode or $\mathbf{p d}$ for a drain diode. Otherwise, if cjgate is not specified or weff > $\boldsymbol{p}$, the total sidewall capacitance is:

$$
\begin{equation*}
\operatorname{csw}=\operatorname{cjsw} \times p \tag{0.31}
\end{equation*}
$$

## Examples

$$
\text { m12 n1 n2 GND GND ndep } l=10 u \text { w=5u } a d=100 p \text { as=100p pd=40u ps=40u }
$$

## Mutual Inductor (k)

A coupled pair of inductors.

## Syntax

```
kname inductor1 inductor2 K
name Mutual inductor name.
inductor1 First inductor.
inductor2 Second inductor.
K}\quad\mathrm{ Coefficient of coupling (0<K}\leq1)
```


## Examples

k1 La Lb $10 u$

The example illustrates coupling between two inductors $\mathbf{L a}$ and $\mathbf{L b}$, defined elsewhere in the input file:

```
La node1a node2a 10m
Lb node1b node2b 20m
```

The order of node naming on the inductor statements determines the relative directions of current flow in the mutual inductor. The current flow from node1a to node2a (inductor La) is in the same direction as from node1b to node2b (inductor Lb). To reverse the current flow in either inductor, reverse the node order on the appropriate inductor statement.

## Resistor (r)

A two-terminal resistor.

The resistance $R$ is influenced by the temperature as follows:
$R=\boldsymbol{N}\left(1+\boldsymbol{A} T+\boldsymbol{B} T^{2}\right)$
$T=T a-T n$
where $\boldsymbol{N}, \boldsymbol{A}, \boldsymbol{B}$ are device parameters described below; $T a$ (the "ambient" temperature) is set by the .temp command; and $T n$ (the "nominal" temperature) is set by the .options tnom command.

Resistors can be specified using geometric and physical parameters such as l, w, and rsh. For a description of how resistance is calculated using these parameters, refer to the device model "Resistor" on page 463.

Optional capacitors may be included between the terminals and a bulk node (usually ground) to obtain a simple transmission line model.

## Syntax

```
rname node1 node2 r=r [resistor_parameters]
or
rname node1 node2 r [tc1[tc2]] [resistor_parameters]
or
rname node1 node2 modelname + [[r=r] [resistor_parameters]
or
rname node1 node2 modelname r [tc1[tc2]] [resistor_parameters]
name Resistor name.
node1 Positive terminal.
node2 Negative terminal.
modelname Name of resistor model. Must match .model name when type is r.
    For additional information, see ".model" (page 96).
r=resistance Nominal resistance. (Unit: ohms.)
```

In the first syntax and the third syntax, the resistor_parameters field is of the form:

```
[tc1=tc1] [tc2=tc2] [noise=noise] [m=mult] [scale=devscale] [ac=acres]
    [dtemp=dtemp] [l=l] [w=w] [c=c]
```

In the second syntax and the fourth syntax, the resistor_parameters field is of the form:


Note:
If T-Spice calculates the effective resistance, $R_{e f f}$, to be less than $10^{-5} \Omega$, then a warning message is issued and the effective resistance is automatically assigned a value of $10^{-5} \Omega$. See the model description "Resistor" on page 463 for calculation of $R_{e f f}$

## Examples

```
r1 2 1 30K TC=1e-2,1e-4
```

This produces a resistor of resistance 30 kilohms at the nominal temperature tnom. If the temperature T is different from tnom, the resistance is $30,000 *(1+0.01 *(T-t n o m)+0.0001 *(T-t n o m) *(T-t n o m))$. For example, if the circuit temperature is 127 degrees and tnom is 27 degrees, the resistance is $30,000 *(1+0.01 * 100+0.0001 * 100 * 100)=90,000$ Ohms.

```
r1 n1 n2 rmod l=5u w=10u
.model rmod r rsh=1k cap=10pf cratio=0.5
```

This example creates a resistor between nodes $\mathbf{n} \mathbf{1}$ and $\mathbf{n} \mathbf{2}$ of size 500 Ohms ( $\boldsymbol{r}=\boldsymbol{\Gamma} \boldsymbol{r} \boldsymbol{r} \boldsymbol{h} / \boldsymbol{w}$ ) as well as two capacitors, 5 picofarads each, one between $\mathbf{n 1}$ and Gnd, the other between $\boldsymbol{n} \mathbf{2}$ and $\mathbf{G n d}$.

## Voltage- or Current-Controlled Switch (s)

A switch is implemented as a resistor between node1 and node2, whose resistance is controlled by the controlling voltage or current. (See also the device model "Switch" on page 466.)

The general syntax for T-Spice's voltage-controlled switch element is:

```
sname node1 node2 control1 control2 modelname
```

The syntax for a current-controlled switch is:

```
sname nodel node2 vsourcename modelname
```

name

```
node1
```

node2
control1
control2
vsourcename
modelname

Switch name.
Positive terminal.
Negative terminal.
Name of the voltage source supplying the control voltage.
Name of the voltage source supplying the control voltage.
Controlling current for a current-controlled switch.
Name of resistor model. Must match .model modelname when type is sw or csw. For additional information, see ".model" (page 96).

Resistance is roff when the switch is off and ron when the switch is on. The switch is on when the control voltage or current for the switch is greater than its threshold voltage or current.

The ron, roff, and threshold values for the switch are specified in a .model statement whose model name matches the modelname on the device statement.

T-Spice switch elements can display hysteresis, so that the threshold value is different when the control voltage/current is increasing than when it is decreasing. For a voltage-controlled switch, the threshold voltage is $v \boldsymbol{t}$ when $\mathbf{v}$ (control1, control2) is increasing, and $\boldsymbol{v t}$ - $\mathbf{v h}$ when $\mathbf{v}$ (control1, control2) is decreasing. For a current-controlled switch the threshold current is it when i(vsourcename) is increasing, and it-ih when $\mathbf{i}$ (vsourcename) is decreasing. The switch is on when the control voltage or current is greater than the threshold value.

The $\boldsymbol{d} \boldsymbol{v}$ and $\boldsymbol{d i}$ parameters define a small interval around the threshold in which a smooth transition between ron and roff is made.

## Examples

## Voltage-Controlled Switch

The following two examples would both produce voltage-controlled switches:

```
s1 n1 n2 c1 c2 swmod
.model swmod sw ron=1 roff=1e12 vt=2.5
```

and

```
s1 out 0 0 in swmod
.model swmod sw vt=0 dv=0.2
```

The waveform for this switch is illustrated in "Voltage-Controlled Resistor" on page 194.

## Current-Controlled Switch

The following example demonstrates the modeling of a current-controlled switch:

```
s1 out 0 vin swmod
.model swmod csw it=0.7 di=0.1
```

This switch would produce the following waveform:


## Transmission Line ( t )

A mechanism for "lossless" or "lossy" signal propagation.
The "lossless" transmission line is described by characteristic impedance and delay; the "lossy" transmission line is described by RLCG parameters.

## Syntax

## "Lossless" Transmission Line

```
tname node1 node2 node3 node4 z0=Z [td=D] [f=F [nl=N]]
```

| name | Transmission line name. |
| :--- | :--- |
| node1 ... node4 | Terminals. node1 $(+)$ and node2 $(-)$ are at one end of the <br> transmission line, node3 $(+)$ and node4 $(-)$ at the opposite end. |
| $\boldsymbol{Z}$ | Impedance. (Unit: ohms.) |
| $\boldsymbol{D}$ | Transmission delay. The delay may instead be specified indirectly <br> from $\boldsymbol{F}$ and $\boldsymbol{N}$. (Unit: seconds.) |
| $\boldsymbol{F}$ | Line frequency. (Unit: Hertz. Default: $\left.1 \times 10^{9}.\right)$ <br> $\boldsymbol{N}$ |
| Normalized number of wavelengths. The transmission delay is the <br> ratio of the wavelength number $\boldsymbol{N}$ to the line frequency $\boldsymbol{F}$. <br> $($ Default: 0.25.$)$ |  |

"Lossy" Transmission Line
thame node1 node 2 node 3 node $4 \mathbf{r}=R \mathbf{l}=L \mathbf{c}=C \mathbf{g}=G$ length $=W$ [lumps $=X$ ] [lumptype $=Y$ ]

| name | Transmission line name. |
| :--- | :--- |
| node1 ... node4 | Terminals. node1 (+) and node2 ( - ) are at one end of the <br> transmission line, node3 (+) and $\boldsymbol{n o d e 4}(-)$ at the opposite end. |
| $\boldsymbol{R}$ | Distributed resistance. (Unit: ohms/meter.) |
| $\boldsymbol{L}$ | Distributed inductance. (Unit: henries/meter.) |
| $\boldsymbol{C}$ | Distributed capacitance. (Unit: farads/meter.) |
| $\boldsymbol{G}$ | Distributed conductance. (Unit: siemens/meter.) <br> $\boldsymbol{W}$ |
| $\boldsymbol{P}$ | Physical length. (Unit: meters.) <br> (Default: 1.) |
| $\boldsymbol{Y}$ | Type of lumps used for ILC expansion (see below). (Default: 3.) |

$\boldsymbol{Y}$ is one of the following:

0

1

2

3
"Gamma" type lumps.
"Tee" type symmetric lumps.
"Pi" type symmetric lumps.
Hybrid RGT lumps (default).

## Examples

```
tline2 pad2 GND pin2 GND z0=100 td=10ns
tline3 drive GND out GND z0=300 f=100meg nl=.1
```


## Voltage Source (v)

A two-terminal ideal voltage supply.
Exponential, pulse, piecewise linear, frequency-modulated, sinusoidal, and customizable (vectorized) waveforms are available.

Voltage sources whose waveform is described using an expression can be created using the e-element with an expression and the time() function.

## Syntax



DC, AC, and transient values can be specified independently and in any order.
waveform is one of the following:

## Exponential Waveform

| Vi | Initial voltage. (Unit: volts.) |
| :---: | :---: |
| Vp | Peak voltage. (Unit: volts.) |
| Dr | Rise time delay. (Unit: seconds. Default: 0.) |
| Tr | Rise time constant. (Unit: seconds. Default: 0.) |
| Df | Fall time delay. (Unit: seconds. Default: 0.) |
| Tf | Fall time constant. (Unit: seconds. Default: 0.) |

## Pulse Waveform

pulse (Vi $V p$ [D [Tr [Tf [Pw [Pp]]]]]) [ROUND=RND]

Vi Initial voltage. (Unit: volts.)

| $\boldsymbol{V} \boldsymbol{p}$ | Peak voltage. (Unit: volts.) |
| :--- | :--- |
| $\boldsymbol{D}$ | Initial delay. (Unit: seconds. Default: 0.) |
| $\boldsymbol{T r}$ | Rise time. (Unit: seconds. Default: time step from .tran.) |
| $\boldsymbol{T f}$ | Fall time. (Unit: seconds. Default: time step from .tran.) |
| $\boldsymbol{P w}$ | Pulse width. (Unit: seconds. Default: stop time from .tran.) |
| $\boldsymbol{P p}$ | Pulse period. (Unit: seconds. Default: stop time from .tran.) |
| $\boldsymbol{R N D}$ | Rounding half-interval. A corner at time $T$ is replaced by a smoothly <br> differentiable polynomial in the interval (T-RND,T+RND). The <br> maximum $\boldsymbol{R N D}$ is half the distance to the nearest neighboring corner. <br> (Default: 0—no rounding.) |

Note that rise time is not necessarily a 'rise' time, but is the time to go from the initial voltage to the pulse voltage, regardless of whether it's smaller or larger.

## Piecewise Linear Waveform

```
pwl (T1 V1 [T2 V2 ...])[ROUND=RND] [REPEAT[=Tr]] [TD=DELAY]
```

T1 T2
V1 V2
ROUND

REPEAT

TD

Time at corner 1, 2, and so on. (Unit: seconds.)
Voltage at corner 1, 2, and so on. (Unit: volts.)
Rounding half-interval. A corner at time $T$ is replaced by a smoothly differentiable polynomial in the interval ( $T-$ RND,$T+$ RND). The maximum $\boldsymbol{R N D}$ is half the distance to the nearest neighboring corner. (Default: 0—no rounding.)

Piecewise Linear Waveform File
pwlfile filename [ROUND=RND] [REPEAT[=Tr]] [TD=DELAY]

| filename | Input file which contains the piecewise linear waveform definition in <br> a series of time, voltage pairs, one per line. |
| :--- | :--- |
| ROUND | Same meaning as with pwl waveforms |
| REPEAT | Same meaning as with pwl waveforms |
| $\boldsymbol{T D}$ | Same meaning as with pwl waveforms |

## Frequency-Modulated Waveform

```
sffm (Vo Vp [FC [Xm [Fs]]])
```

| Vo | Offset voltage. (Unit: volts.) |
| :--- | :--- |
| Vp | Peak voltage. (Unit: volts.) |
| Fc | Carrier frequency (Unit: Hertz. Default: $1 / T$, where $T$ is the stop <br> time from .tran.) |
| Xm | Modulation index. (Default: 0. .) |
| Fs | Signal frequency. (Unit: Hertz. Default: $1 / T$, where $T$ is the stop <br> time from .tran.) |

## Sinusoidal Waveform

```
sin (Vo Vp [Fr [De [Da [Ph]]]])
Vo Offset voltage. (Unit: volts.)
Vp Peak voltage. (Unit: volts.)
Fr
    Frequency. (Unit: Hertz. Default: 1/T, where T is the stop time from
    .tran.)
De Delay time. (Unit: seconds.)
Da Damping factor. (Unit: 1/seconds.)
Ph Phase advance. (Unit: degrees.)
```


## Vectorized Waveform

```
bit|bus ({pattern} [on=A] [off=Z] [delay=D] [pw=P] [rt=R] [ft=F] [lt=L]
    [ht=H]) [ROUND=RND]
pattern An expression consisting of one or more string or string-multiplier combinations (see below).
A On voltage (Unit: volts. Default: 0.001.)
\(Z \quad\) Off voltage (Unit: volts. Default: 0.)
D
Delay time. (Unit: seconds. Default: 0.)
\(P\)
Pulse width: \(\boldsymbol{P}=\boldsymbol{R}+T_{\boldsymbol{A}}=\boldsymbol{F}+T_{\boldsymbol{Z}}\), where \(T_{\boldsymbol{A}}\) is the time during a pulse where the voltage is "on" \((V=\boldsymbol{A})\) and \(T \boldsymbol{Z}\) is the time during a pulse where the voltage is "off" \((V=\boldsymbol{Z})\). (Unit: seconds. Default: \(10 \times 10^{-}\) 9.)
\(\boldsymbol{R} \quad\) Rise time. (Unit: seconds. Default: \(1 \times 10^{-9}\).)
F
\(L\)
Fall time. (Unit: seconds. Default: \(1 \times 10^{-9}\).)
Low time: \(\boldsymbol{L}=\boldsymbol{F}+T_{\boldsymbol{Z}}\), where \(T_{\boldsymbol{Z}}\) is the time during a pulse where the voltage is "off" \((V=\boldsymbol{Z})\). (Unit: seconds. Default: \(10 \times 10^{-9}\).)
```

High time: $\boldsymbol{H}=\boldsymbol{R}+T_{\boldsymbol{A}}$, where $T_{\boldsymbol{A}}$ is the time during a pulse where the voltage is "on" $(V=\boldsymbol{A})$. (Unit: seconds. Default: $10 \times 10^{-9}$.)

RND
Rounding half-interval. A corner at time $T$ is replaced by a smoothly differentiable polynomial in the interval ( $T-$ RND,$T+$ RND $)$. The maximum $R N D$ is half the distance to the nearest neighboring corner. (Default: 0—no rounding.)

A bit pattern consists of a set of numbers (possibly associated with multiplier factors) whose binary representations sequentially specify the "on"/"off" structure of the waveform. The pattern takes the form $\boldsymbol{a}(\boldsymbol{b}(\boldsymbol{x}) \boldsymbol{c}(\boldsymbol{y}) \ldots$ ), where $\boldsymbol{a}, \boldsymbol{b}$, and $\boldsymbol{c}$ are the optional multiplier factors and $\boldsymbol{x}$ and $\boldsymbol{y}$ are the numbers.

A bus pattern consists of a set of numbers (possibly associated with multiplier factors) whose binary representations-"bit strings"-are grouped together as a waveform bus and treated as a single input. The length of the bit strings is specified by the .vector command. If there are $n$ nodes in a vector, then T-Spice assigns the first $n$ bits of each bit string to those nodes. Extra bits are discarded. If there are not enough bits, the highest-order bits are set to zero. The leftmost node name in the .vector command takes the most significant bit.

Numbers are specified on the device statement in binary, hexadecimal (suffixed by h), octal (suffixed by $\mathbf{0}$ ), or decimal (suffixed by d) notation. (For decimal representations the number of lower-order bits to be collected is also given.)

## Examples

v1 n1 GND $\sin (2.52 .5$ 30MEG 100 n$)$
$\mathbf{v 1}$ generates a $\boldsymbol{\operatorname { s i n }}$ (sinusoidal) input. It has an amplitude of 2.5 volts, a frequency of 30 MHz , an offset of 2.5 volts from system ground, and a time delay of 100 nanoseconds after the start of the simulation before the wave begins.
v2 n2 GND bit (\{01010 11011\} on=5.0 off=0.0 pw=50n rt=10n ft=30n)
v2 generates a bit input. Enclosed in braces \{ \} are two binary-valued five-bit patterns specifying the waveform. The two patterns alternate in time. The on voltage value is 5.0 volts; the off voltage value is zero. The pulse width ( $\mathbf{p w}$ ), 50 nanoseconds, is the time the wave is either (ramping up and) on, or (dropping down and) off. The rise time (rt), 10 nanoseconds, is the time given for the wave to ramp from off to on; and the fall time ( $\mathbf{f t}$ ), 30 nanoseconds, the time given for the wave to drop from on to off.

```
v3 n3 GND bit ({5(01010 5(1))} pw=10n on=5.0 off=0.0)
```

v3 generates a repeating bit input. Two distinct patterns are given again, but now multiplier factors are included. The wave consists of two alternating patterns: the first pattern contains five bits, the second is a single bit. The five-bit pattern is followed by five successive repetitions of the single-bit pattern, and this combination is repeated five times. (The same pattern could be described by $\{\mathbf{5 ( 3 ( 0 1 )} \mathbf{4 ( 1 ) )}\}$.) The pulse width and on and off voltages are again specified, but the rise and fall times take default values.

```
.vector bb {n7 n6 n5 n4}
vb bb GND bus ({50(Ah) 30(7d4) 20(1000)} pw=5n on=5.0 off=0.0)
```

The .vector command defines the bus waveform generated by voltage source vb. The command assigns the bus a name (bb) and specifies by name the number of bits the bus waveform will have (four: $\mathbf{n 7}$ through $\mathbf{n 4}$ ). The voltage source statement, which contains the bus keyword, specifies waveforms with one or more patterns, along with pulse width and level information.

- The first pattern is $\mathbf{A h}$ (hex) = 1010 (binary). Thus, using the names given on the .vector command, $\mathbf{n 7}=1, \mathbf{n 6}=0, \mathbf{n 5}=1$, and $\mathbf{n 4}=0$. The pattern is repeated 50 times (that is, maintained for a time period equal to the pulse width multiplied by 50 ).
- The next pattern is 7 d 4 -that is, 7 (decimal) $=111$ (binary), or, to four lower-order bits, 0111 . So $\mathbf{n} 7=0, \mathbf{n} 6=1, \mathbf{n} 5=1$, and $\mathbf{n} 4=1$. The pattern is repeated 30 times.
- The last pattern is $\mathbf{1 0 0 0}$ (binary), so $\mathbf{n 7 4}=1, \mathbf{n} \mathbf{6}=0$, $\mathbf{n} \mathbf{5}=0$, and $\mathbf{n 4}=0$. The pattern is repeated 20 times.


## Voltage-Controlled Current Source (g)

A two-terminal ideal DC current supply with a level that is a function of one or more controlling voltages. This device can be utilized to model a wide variety of elements, including voltage-controlled resistors, nonlinear capacitors, voltage-controlled capacitors, switch-level MOSFETs, and diodes. See "Examples" on page 193.

## Syntax

```
Linear
gname node1 node2 nal nb1 K [Options]
```

Polynomial

| LaPlace Transform |  |
| :---: | :---: |
| gname nodel node2 LAPLACE nal nbl $a_{1} \mathrm{a}_{2} \ldots \ldots \mathrm{a}_{m}\left[/ \mathrm{b}_{1} \mathrm{~b}_{2} \ldots \ldots \mathrm{~b}_{m}\right]$ [Options] |  |
| Nonlinear \| Behavioral |  |
| gname node | 'expression'] [chg='expression'] [Options] |
| gname | Voltage-controlled current source name. Must begin with "g". |
| node1 | Positive terminal. Positive current flows into node1. |
| node2 | Negative terminal. Positive current flows out of node2. |
| K | Transconductance-the ratio of the output current to the control voltage. |
| POLY | Keyword indicating that the output current is a polynomial function of the control voltages. |
| $N$ | Number of control voltages (valid values 1-6). |
| LAPLACE | Keyword indicating that the output current is described via a Laplace transform function |
| cur | Keyword indicating an expression expression that defines current flowing through the device. |
| chg | Keyword indicating an expression expression that defines terminal charges of the device. Used to define the capacitance of a nonlinear capacitor. |
| expression | Expression involving any node voltages and source currents. |
| na1 nb2... | Node pairs whose voltages control the level of the $\mathbf{g}$ element. |
| $P_{0} P_{1} P_{2} \ldots$ | Coefficients of the control polynomial. |
| $a_{0} a_{1} a_{2} \ldots a_{m}$ | Numerator of Laplace transfer function. |
| $b_{0} b_{1} b_{2} \ldots a_{n}$ | Denominator of Laplace transfer function. |

## Options

[MAX=value] [MIN=value] [ABS = [0 | 1]] [TC1=value] [TC2=value] [SCALE=value]

| MAX | Maximum output voltage value. |
| :--- | :--- |
| MIN | Minimum output voltage value. |
| ABS | Output is absolute value if $\mathrm{ABS}=1$. |
| TC1, TC2, | First- and second-order temperature coefficients. |
| SCALE | Element value multiplier. |

Current is reckoned positive if it enters the $\mathbf{g}$ element at its first terminal.

## Linear Functions

The first form of voltage-controlled current sources creates a current source with a level equal to $\boldsymbol{K}$ multiplied by the voltage across the node pair na1 nb1.

## Polynomial Functions

The second form creates a current source whose level is a nonlinear polynomial function of the voltages across one or more node pairs. Let

- $\quad x=$ voltage across node pair na1 nb1;
- $\quad y=$ voltage across node pair na2 nb2 (if $\boldsymbol{N} \geq 2$ );
- $\quad z=$ voltage across node pair na3 nb3 (if $\boldsymbol{N} \geq 3$ ).

Then the controlled voltage source's level is defined as follows:

If $\boldsymbol{N}=1$ :

$$
\begin{equation*}
P_{0}+P_{1} x+P_{2} x^{2}+p_{3} x^{3}+\ldots \tag{0.32}
\end{equation*}
$$

If $\boldsymbol{N}=2$ :

$$
\begin{equation*}
P_{0}+P_{1} x+P_{2} y+P_{3} x^{2}+P_{4} x y+P_{5} y^{2}+P_{6} x^{3}+P_{7} x^{2} y+P_{8} x y^{2}+P_{9} y^{3}+\ldots \tag{0.33}
\end{equation*}
$$

If $\boldsymbol{N}=3$ :

$$
\begin{gather*}
P_{0}+P_{1} x+P_{2} y+P_{3} z+P_{4} x^{2}+P_{5} x y+P_{6} x z+P_{7} y^{2}+P_{8} y z+P_{9} z^{2}+P_{10} x^{3}+P_{11} x^{2} y+P_{12} x^{2} z+P_{13} x y^{2}+ \\
P_{14} x y z+P_{15} x z^{2}+P_{16} y^{3}+P_{17} y^{2} z+P_{18} y z^{2}+P_{19} z^{3}+\ldots \tag{0.34}
\end{gather*}
$$

If $\boldsymbol{N}=1$ and only one polynomial coefficient is specified, it is assumed to be $P 1$, to facilitate the specification of linearly-controlled sources.

## Laplace Functions

With the Laplace keyword, the current source is implemented as a Laplace transfer function.

$$
H(s)=\frac{a_{0}+a_{1} s+a_{2} s^{2}+\ldots+a_{m} s^{m}}{b_{0}+b_{1} s+b_{2} s^{2}+\ldots+b_{n} s^{n}}
$$

## Expression-Controlled Functions

The fourth form of voltage controlled current sources uses mathematical expressions ("Expressions" (page 55)) to define the output current and charge functions. At least one of the keywords cur or chg must be specified.

## Examples

Gtest in out n10 n17 -2.314

Gtest is a $\mathbf{g}$ element. Its terminals are connected to nodes in and out. The voltage across the node pair $\mathbf{n 1 0}$ and $\mathbf{n 1 7}$ control the level of gtest. The level of gtest equals $(-2.314)\{v(n 10)-v(n 17)\}$. If this is a positive number, current flows in this direction: node in-gtest -node out.

| G1 | 0 | 1 | poly (1) |  |  |  |  |
| :--- | :--- | :--- | :--- | :--- | :--- | :--- | :--- |
| + |  | n10 | n17 |  |  |  |  |
| + |  |  |  |  | $1 m$ | 0 | 2 |

$\mathbf{g} \mathbf{1}$ is a $\mathbf{g}$ element. It terminals are connected to nodes $\mathbf{0}$ and $\mathbf{1}$. The level of $\mathbf{g} \mathbf{1}$ is a polynomial in one variable. The one variable is the voltage across the node pair $\mathbf{n} 10$ and n 17 . The level of $\mathbf{g 1}$ is computed as

$$
\begin{equation*}
g 1=10^{-3}+2\{v(n 10)-v(n 17)\}^{2} \tag{0.36}
\end{equation*}
$$

If this is a positive number, current flows in this direction: node $\mathbf{0}$-g1-node $\mathbf{1}$.

```
G3 01 poly(3)
+ nkingnkong
+ npingnpong
+ nsingnsong
+ 01 03 0
```

$\mathbf{g} \mathbf{3}$ is a $\mathbf{g}$ element. Its terminals are connected to nodes $\mathbf{0}$ and $\mathbf{1}$. The level of $\mathbf{g} \mathbf{3}$ is a polynomial in three variables. The three variables are the voltages across the three node pairs nking and nkong, nping and npong, nsing and nsong. The level of $\mathbf{g} \mathbf{3}$ is computed as

$$
\begin{align*}
g 3= & \{v(\text { nking })-v(\text { nkong })\}+3\{v(\text { nsing })-v(\text { nsong })\}  \tag{0.37}\\
& +4\{v(\text { nking })-v(\text { nkong })\}\{v(\text { nping })-v(\text { npong })\}
\end{align*}
$$

If this is a positive number, current flows in this direction: node $\mathbf{0}-\mathbf{g} 3$-node 3.

## Laplace Transforms

For examples of Laplace transforms, please refer to the analogous examples of Laplace transforms in the voltage-controlled voltage source section ("Voltage-Controlled Voltage Source (e)" (page 197)).

## Voltage-Controlled Resistor

```
gswitch out 0 cur='v(out)*table(v(in), -1,1e-12, -0.1,1e-12, 0.1,1, 1,1)'
```

The switch's resistance between nodes out and ground is controlled by the voltage at node in. The switch is off when $\mathbf{v}(\mathbf{i n})$ is less than -0.1 V , and on when $\mathbf{v}(\mathbf{i n})$ is greater than 0.1 V . The interval $0.1 \mathrm{~V}<\mathrm{v}(\mathrm{in})<0.1 \mathrm{~V}$ serves as a smooth transition between the on and off states. Note the use of the table function to describe the conductance characteristics of the switch: the conductance is $10^{-12}$ (corresponding to a resistance of $10^{+12}$ ) when the switch is off, while the conductance is 1 when the switch is on. The chart below shows the switch's output current as a function of input voltage (holding the voltage at node out fixed at 1 V ).


## Nonlinear Capacitor

The following example models a nonlinear capacitor whose capacitance is a function of applied voltage. A capacitor is described by specifying a charge function that depends on the voltage across the device. The device's capacitance is the derivative of the charge function with respect to the voltage. For example, a CMOS capacitor might be modeled as follows:

```
.param c0=10p vcc=1
gcmoscap n+ n- chg='c0*V(n+,n-) * (1 + 0.5*Vcc*V(n+,n-))'
```

The capacitance of the device gcmoscap is then given by:

$$
\begin{equation*}
\mathrm{C}=\mathrm{c} 0 *(1+\mathrm{vcc} * \mathrm{v}(\mathrm{n}+, \mathrm{n}-)) \tag{0.38}
\end{equation*}
$$

where $c 0$ represents the capacitance at zero applied voltage, and $v c c$ measures the sensitivity of the capacitance with respect to input voltage.

The capacitor's charge depends on applied voltage, as shown in the chart below.


## Voltage-Controlled Capacitor

A voltage-controlled capacitor is a two-terminal device whose capacitance is a function of node voltages elsewhere in the circuit. Such an element can be modeled in T-Spice with the expressioncontrolled g-element, using the chg parameter.

For example, the capacitance of a vertically moving parallel plate capacitor, a device used in the design of microelectromechanical systems (MEMS) might be modeled as follows:

```
gvccap n+ n- chg='v(n+,n-)*k/v(gapdistance)'
```

where gapdistance refers to a state variable which represents the distance between the capacitor's plates and $\boldsymbol{k}$ is a proportionality constant defined using ".param" (page 113).

## Switch-Level MOSFET

The T-Spice $\operatorname{stp}()$ and table() functions can be used to create a switch-level model for a MOSFET. An example of such a model for an N-type MOSFET is as follows:

```
gmos d s cur='v(d,s) * table(v(g,s)*stp(v(d,s)) + v(g,d)*(1-stp(v(d,s))),
+ 0,1e-12, 0.4,1e-12, 1,1e-7, 2,2e-5,
+ 3, 1e-4, 5, 4e-4)'
```

Note that the use of the $\boldsymbol{\operatorname { s t p }} \mathbf{( )}$ function allows for a model that is symmetric with respect to source and drain.

## Diode

The T-Spice g-element can be used to model any device for which analytic equations are available. When the equations have different forms for different regions of operation, the T-Spice stp() function can be useful. The following example models the current and capacitance of a diode. Note that the capacitance equation has different forms for the forward and reverse bias regions, but the $\boldsymbol{s t p}()$ function allows us to describe the entire model using a single charge expression.

$$
\text { . param vt }=0.02586 \text { is=1e-14 } t t=30 n \quad c j o=1 e-12 v j=1 \mathrm{~m}=0.5
$$

```
gdiode 1 2 cur='is*(exp(v(1,2)/vt)-1)'
+ chg='tt*is*(exp(v(1, 2)/vt)-1)
+
    +cjo*(2*vj*(1-sqrt(1-v(1, 2)/vj))*stp (v (1, 2)))
```

This example would produce the following waveform for current:

and the following waveform for charge:


## Voltage-Controlled Voltage Source (e)

A two-terminal ideal DC voltage supply with a level that is a function of one or more controlling voltages.

Linear
ename node1 node2 nal nb1 $K$ [Options]
Polynomial
ename node1 node2 POLY (N) na1 nb1 [na2 nb2...] $P_{0} P_{1} P_{2} \ldots$ [Options]
LaPlace Transform
ename node1 node2 LAPLACE nal nb1 $a_{1} a_{2} \ldots a_{m}\left[/ b_{1} b_{2} \ldots b_{n}\right]$ [Options]
Nonlinear | Behavioral
ename nodel node2 vol='expression' [Options]

| Parameter | Description |
| :---: | :---: |
| ename | Voltage-controlled voltage source name. Must begin with "e". |
| node1 | Positive terminal. |
| node2 | Negative terminal. |
| $K$ | Voltage gain-the ratio of the output voltage to the control voltage. |
| POLY | Keyword indicating that the output voltage is a polynomial function of the control voltages. |
| $N$ | Number of control voltages (valid values 1-6). |
| LAPLACE | Keyword indicating that the output current is described via a Laplace transform function |
| vol | Keyword indicating that the source voltage is specified by an expression. |
| expression | Expression specified by the vol keyword. |
| na1 nb2... | Node pairs whose voltages control the level of the e element. |
| $P_{0} P_{1} P_{2} \ldots$ | Coefficients of the control polynomial. |
| $a_{0} a_{1} a_{2} \ldots a_{m}$ | Numerator of Laplace transfer function. |
| $b_{0} b_{1} b_{2} \ldots a_{n}$ | Denominator of Laplace transfer function. |

## Options

[MAX=value] [MIN=value] [ABS =[0 | 1]] [TC1=value] [TC2=value] [SCALE=value]

| MAX | Maximum output voltage value. |
| :--- | :--- |
| MIN | Minimum output voltage value. |
| ABS | Output is absolute value if ABS=1. |
| TC1, TC2, | First- and second-order temperature coefficients. |
| SCALE | Element value multiplier. |

## Linear Functions

The first statement creates a voltage source with a level equal to $\boldsymbol{K}$ multiplied by the voltage across node pair na1 nb1.

## Polynomial Functions

The second statement creates a voltage source whose level is a nonlinear polynomial function of the voltages supplied by up to three voltage sources. Let

- $x=$ voltage across node pair na1 nb1;
- $\quad y=$ voltage across node pair na2 nb2 (if $\boldsymbol{N} \geq 2$ );
- $\quad z=$ voltage across node pair na3 nb3 (if $\boldsymbol{N} \geq 3$ ).

Then the controlled voltage source's level is defined as follows:
If $\boldsymbol{N}=1$ :

$$
\begin{equation*}
P_{0}+P_{1} x+P_{2} x^{2}+P_{3} x^{3}+\ldots \tag{0.39}
\end{equation*}
$$

If $\boldsymbol{N}=2$ :

$$
\begin{equation*}
P_{0}+P_{1} x+P_{2} y+P_{3} x^{2}+P_{4} x y+P_{5} y^{2}+P_{6} x^{3}+P_{7} x^{2} y+P_{8} x y^{2}+P_{9} y^{3}+\ldots \tag{0.40}
\end{equation*}
$$

If $\boldsymbol{N}=3$ :

$$
\begin{gather*}
P_{0}+P_{1} x+P_{2} y+P_{3} z+P_{4} x^{2}+P_{5} x y+P_{6} x z+P_{7} y^{2}+P_{8} y z+P_{9} z^{2}+P_{10} x^{3}+P_{11} x^{2} y+P_{12} x^{2} z+P_{13} x y^{2}+ \\
P_{14} x y z+P_{15} x z^{2}+P_{16} y^{3}+P_{17} y^{2} z+P_{18} y z^{2}+P_{19} z^{3}+\ldots \tag{0.41}
\end{gather*}
$$

If $\boldsymbol{N}=1$ and only one polynomial coefficient is specified, it is assumed to be $P 1$, to facilitate the specification of linearly-controlled sources.

## Laplace Functions

With the Laplace keyword, the current source is implemented as a Laplace transfer function. The three transform equations supported by the Laplace transform source types in T-Spice are shown in the
equation below and several of the examples ("Integrator element" on page 200, "Differentiator element" on page 200, "Single Pole / Residue" on page 201).

$$
H(s)=\frac{a_{0}+a_{1} s+a_{2} s^{2}+\ldots+a_{m} s^{m}}{b_{0}+b_{1} s+b_{2} s^{2}+\ldots+b_{n} s^{n}}
$$

## Expression-Controlled Functions

The fourth form of voltage controlled current sources uses mathematical expressions ("Expressions" (page 55)) to define the output current and charge functions. At least one of the keywords cur or chg must be specified.

## Examples

Etest in out n10 n17 -2.314

Etest is an e element. Its nodes are connected to nodes in and out. The voltage across the node pair n10 and $\mathbf{n} 17$ control the level of etest. The level of etest equals $(-2.314)\{v(n 10)-v(n 17)\}$.

| E1 | 0 | 1 | poly (1) |  |  |  |  |
| :--- | :--- | :--- | :--- | :--- | :--- | :--- | :--- |
| + |  | n10 | n17 |  |  |  |  |
| + |  |  |  |  | $1 m$ | 0 | 2 |

$\mathbf{e} \mathbf{1}$ is an e element. It terminals are connected to nodes $\mathbf{0}$ and $\mathbf{1}$. The level of $\mathbf{e} \mathbf{1}$ is a polynomial in one variable. The one variable is the voltage across the node pair $\mathbf{n 1 0}$ and $\mathbf{n 1 7}$. The level of $\mathbf{e} \mathbf{1}$ is computed as

$$
\begin{equation*}
e 1=10^{-3}+2\{v(n 10)-v(n 17)\}^{2} \tag{0.43}
\end{equation*}
$$

| E3 | 0 | poly (3) |  |  |  |  |  |
| :--- | :--- | :--- | :--- | :--- | :--- | :--- | :--- |
| + |  | nking | nkong |  |  |  |  |
| + |  | nping | npong |  |  |  |  |
| + |  | nsing | nsong |  |  |  |  |
| + |  |  |  | 0 | 1 | 0 | 304 |

$\mathbf{e} \mathbf{3}$ is an $\mathbf{e}$ element. Its terminals are connected to nodes $\mathbf{0}$ and 1. The level of $\mathbf{e} \mathbf{3}$ is a polynomial in three variables. The three variables are the voltages across the three node pairs nking and nkong, nping and npong, nsing and nsong. The level of e3 is computed as

$$
\begin{align*}
e 3= & \{v(\text { nking })-v(\text { nkong })\}+3\{v(\text { nsing })-v(\text { nsong })\}  \tag{0.44}\\
& +4\{v(\text { nking })-v(\text { nkong })\}\{v(\text { nping })-v(\text { npong })\}
\end{align*}
$$

## Ideal OpAmp

The expression-controlled e-element (voltage-controlled voltage source) can be used with the table function to model an ideal voltage amplifier. The following circuit element implements a voltage amplifier with a gain of 5 , and minimum and maximum output voltages of -5 V and 5 V , respectively.

```
eamp out 0 vol='table(v(in), -1, -5, 1, 5)'
```

This example would produce the following waveform:


## Integrator element

You can model an integrator using the e element with the Laplace transformation function.
Consider the behavior of an integrator. In the frequency domain, the integrator is modeled as:

$$
\begin{equation*}
V_{o u t}=\frac{k}{s} V_{i n} \tag{0.45}
\end{equation*}
$$

And, in the time domain the integrator is modeled as:

$$
\begin{equation*}
V_{o u t}=k \int V_{i n} d t \tag{0.46}
\end{equation*}
$$

The transfer function for the voltage gain is:

$$
\begin{equation*}
H(s)=\frac{V_{o u t}}{V_{i n}}=\frac{k}{s} \tag{0.47}
\end{equation*}
$$

This is equivalent to the Laplace transfer function with the coefficient assignments: $a_{0}=k, a_{1}=0, b_{0}=0, b_{1}=1$

The voltage-controlled voltage source element which implements this function is:

```
einteg out in laplace cpos cneg k 0.0 / 0.0 1.0
```


## Differentiator element

You can also use the e element with the Laplace transformation function to model a voltage differentiator.

Consider the behavior of a differentiator. In the frequency domain, the differentiator is defined by:

$$
\begin{equation*}
V_{o u t}=k s V_{i n} \tag{0.48}
\end{equation*}
$$

And, in the time domain the differentiator is defined by:

$$
\begin{equation*}
V_{o u t}=k \frac{d V_{i n}}{d t} \tag{0.49}
\end{equation*}
$$

The transfer function for the voltage gain is:

$$
\begin{equation*}
H(s)=\frac{V_{o u t}}{V_{\text {in }}}=k s \tag{0.50}
\end{equation*}
$$

This is equivalent to the Laplace transfer function with the coefficient assignments:
$a_{0}=0, a_{1}=k, b_{0}=1$
The voltage-controlled voltage source element to implement this function is:
ediff out in laplace cpos cneg 0.0 k / 1.0

## Single Pole / Residue

A single pole/residue element is modeled using a transfer function which is:

$$
\begin{equation*}
H(s)=\frac{a_{0}}{b_{0}+b_{1} s} \tag{0.51}
\end{equation*}
$$

A representative single pole element is:

```
epole out in laplace cpos cneg 1.0 / 0.5 3.0
```


## Zero-Delay Inverter Gate

The same technique used to produce the ideal amplifier, above, could be used to create a simple model of a zero-delay inverter:

```
einvert out 0 vol='table(v(in), 0.6, 5, 1, 4.9, 1.5, 0.1, 1.9, 0)'
```

This example would produce the following waveform:


## Zero-Delay AND Gate

The following example implements a simple model for a zero-delay digital AND gate:

```
eand out 0 vol='table( min(v(a),v(b)), 0, 0, 1, 0.5, 4, 4.5, 5, 5)'
```

This example would produce the following waveform:


Other logic gates can also be modeled using the same technique:

- NAND gate:
enand nand 0 vol='table( min(v(a),v(b)), 0, 5, 1, 4.5, 4, 0.5, 5, 0)'
- OR gate:
eor or 0 vol='table( $\max (v(a), v(b)), 0,0,1,0.5,4,4.5,5,5) '$
- NOR gate:

```
enor nor 0 vol='table( max(v(a),v(b)), 0, 5, 1, 4.5, 4, 0.5, 5, 0)'
```


## Voltage-Controlled Oscillator (VCO)

A voltage-controlled oscillator model can be built using a combination of expression-controlled sources. The following example implements a VCO whose output voltage is a sine wave of frequency $\boldsymbol{f 0} \boldsymbol{+} \mathbf{K} \boldsymbol{*}(\boldsymbol{v c o n t r o l} \boldsymbol{- v \boldsymbol { c }}$, where vcontrol is the control voltage, and $\boldsymbol{f 0}, \boldsymbol{k} \mathbf{O}$, and $\boldsymbol{v \boldsymbol { c }}$ are fixed parameters. The amplitude and offset of the VCO's output sine wave are controlled by the parameters amp and offset, respectively.

```
.param offset=2.5 amp=2.5 pi=3.141592654
.param f0=10k k0=3k vc=2.5
evco out 0 vol='offset+amp*sin(2*pi*(f0*time()+k0*v(theta)))'
gtheta theta 0 cur='vc-v(control)' chg='v(theta)'
.ic v(theta)=0
```

Note that a state variable called theta has been introduced to track the phase of the VCO. Without this additional state variable, the VCO might have been modeled using:

```
evco2 out 0 vol='offset+amp*sin(2*pi*(k0*(v(control)-vc)+f0)*time())'
```

but this would result in phase discontinuities of the VCO's output sine wave. The initial condition for theta is necessary to define a DC value for the phase, which would otherwise be arbitrary. The gtheta element implements the equation

$$
\begin{equation*}
\frac{d \theta}{d t}=v(\text { control })-v c \tag{0.52}
\end{equation*}
$$

The chart below shows the behavior of a VCO modeled as in the five SPICE lines above. The VCO's frequency ranges from 2.5 kHz when the control voltage is zero to 17.5 kHZ when the control voltage is 5 V .


## $7 \quad$ Simulation Options

This section provides a reference to the T-Spice simulation options that can be set with the ".options" (page 106) command.

Options are grouped in the following categories:

- "Accuracy and Convergence Options" (page 205)
- "Timestep and Integration Options" (page 237)
- "Model Evaluation Options" (page 256)
- "Linear Solver Options" (page 277)
- "General Options" (page 281)
- "Output Options" (page 293)
" "Probing Options" (page 318)


## Accuracy and Convergence Options

"absi | abstol" (page 206)
"accurate" (page 208)
"bytol" (page 210)
"dchomotopy" (page 212)
"dcstep" (page 215)
"fast" (page 217)
"gmindc" (page 219)
"gshunt" (page 221)
"kvltest" (page 223)
"mindcratio" (page 225)
"numnd | itl1" (page 227)
"numns | itl6" (page 229)
"numnxramp" (page 231)
"reli | reltol" (page 234)
"tolmult" (page 236)
"absv | vntol" (page 207)
"bypass" (page 209)
"cshunt" (page 211)
"dcmethod" (page 214)
"extraiter[ations] | newtol" (page 216)
"gmin" (page 218)
"gramp" (page 220)
"kcltest" (page 222)
"maxdcfailures" (page 224)
"minsrcstep" (page 226)
"numndset" (page 228)
"numnx | itl2" (page 230)
"precise" (page 232)
"relv" (page 235)

## absi | abstol

where $\boldsymbol{a b s i}>0$

## Default Value

$1 \times 10^{-10} \mathrm{~A}$

## Description

Specifies a convergence criterion that limits the total RMS (root mean square) of residual branch currents at all nodes in the circuit. The current test for convergence is applied when kcltest = true.

When the current tolerance test is applied, the system of equations is determined to be converged if:

$$
\text { reli }>\sqrt{\sum_{i=0}^{n}\left(\Delta I^{\prime}\right)^{2}} \quad \text { and } \quad \text { absi }>\sqrt{\sum_{i=0}^{n} I^{2}}
$$

where $I$ is the residual branch current at each node. The quantity $\Delta I$ ' represents the change in relative residual branch current between two consecutive iterations:

$$
\Delta I^{\prime}=\left(\frac{I_{j}}{\text { imax }_{j}}\right)-\left(\frac{I_{j-1}}{\text { imax }_{j-1}}\right)
$$

where $\operatorname{imax}_{j}$ is the largest branch current (in absolute value) flowing into the node in question in the $j^{\text {th }}$ Newton iteration.

## See Also

```
"reli | reltol" (page 234), "kcltest" (page 222)
```


## absv | vntol

```
.options absv = absv
where absv>0
```


## Default Value

$1 \times 10^{-6} \mathrm{~V}$

## Description

Specifies a convergence criterion limiting the absolute change in node voltage between two Newton iterations. The voltage test for convergence is applied when kvltest = true.

The voltage tolerance at each node is calculated as follows:
voltage tolerance $=\max (\mathbf{a b s v}, \mathbf{r e l v} \times V)$,
where $V$ is the node voltage value. If the voltage variation at each node is less than the calculated voltage tolerance for that node, then the iteration is considered to be converged.

## See Also

## accurate

```
.options accurate = { true | false }
```


## Default Value

## false

## Description

Triggers changes to other option settings to maximize simulation accuracy:

| Option | Default | Accurate |
| :--- | :--- | :--- |
| "Ivltim" (page 241) | 1 | 3 |
| "numnd \| itl1" (page 227) | 250 | 500 |
| "numndset" (page 228) | numnd / 10 (25) | numnd / 5 (100) |
| "numns \| itl6" (page 229) | 50 | 100 |
| "numnx \| itl2" (page 230) | 100 | 200 |
| "numnxramp" (page 231) | 50 | 100 |
| "reldv \| relvar" (page 251) | 0.35 | 0.3 |
| "reli \| reltol" (page 234) | $5 \times 10^{-4}$ | $1 \times 10^{-4}$ |
| "rmax" (page 253) | 2 | 1 |

Specifying any of the above fields individually will override the value set by accurate.

## See Also

[^0]
## bypass

```
.options bypass = { true | false }
```


## Default Value

true

## Description

Enables or disables the diode and transistor evaluation bypass algorithm. If the terminal voltage values for a device have a relative change that is less than or equal to bytol since the previous evaluation, then this evaluation will be skipped, and the previous solutions used.

## See Also

## bytol

.options bytol = bytol where bytol $\geq 0$
Default Value
0.0

## Description

Sets the relative tolerance for the bypass algorithm terminal voltage values.

## See Also

```
"bypass" (page 209)
```


## cshunt

```
.options cshunt = cshunt
where cshunt \(\geq 0.0 \mathrm{~F}\)
```


## Default Value

0.0 F

## Description

Adds a capacitor with the specified capacitance from each node to ground. A small cshunt value will sometimes resolve transient analysis "timestep too small" values that are caused by small, highfrequency oscillations within the circuit.

## See Also

"gmin" (page 218), "gshunt" (page 221)

## dchomotopy

```
.options dchomotopy = { none | source | gmin | pseudo | all }
```


## Default Value

all

## Description

Specifies the algorithm used to correct DC operating point non-convergences. When a non-convergence occurs during DC operating point analysis, the selected form of homotpy will be used to try to obtain a valid, converged solution.

Options include:
none Do not attempt any homotopy methods.
source Source stepping. All voltage and current sources are ramped up from zero to their final values. The smallest source step that T-Spice will take is controlled by "minsrcstep" (page 226).
gmin Gmin stepping. T-Spice uses the $g_{\text {min }}$ stepping algorithm to find the minimum conductance value that yields a convergent solution. The options gmindc and gramp specify a search range for the minimum required conductance, $g_{\text {min }}$ :

$$
\text { gmindc } \leq g_{\min } \leq \text { gmindc } \times 10 \text { gramp }
$$

pseudo
all

If a non-convergence occurs, T-Spice attempts homotopy methods in the following order:

- source stepping
- gmin stepping
- pseudotransient solution

As soon as a converged solution is achieved, the simulation completes without attempting the next homotopy algorithm.

## Note:

If you know that a specific homotopy is required to reach a convergent solution, you can reduce simulation time by setting this as the default method with dcmethod. Using demethod automatically skips the standard solution (no homotopy) and only attempts to calculate the solution using the method specified.

## See Also

"dcmethod" (page 214), "minsrcstep" (page 226), "gmindc" (page 219), "gramp" (page 220)

## dcmethod

```
.options dcmethod = {standard | source | gmin | pseudo }
```


## Default Value

standard

## Description

Specifies the default method for solving a DC operating point problem. This option is useful when you have prior knowledge that the circuit can only reach a convergent solution when a particular homotopy is required. In this case, you can reduce simulation time by setting the demethod option to the appropriate method, thus skipping attempts to solve the problem using either the standard method or the other homotopy methods. The settings for dcmethod are:
standard Default setting. If a non-convergence is reached using the standard method, T-Spice will then apply the homotopy methods specified by dchomotopy to try to reach a convergent solution.
source
gmin
pseudo
Source stepping. All voltage and current sources are ramped up from zero to their final values. The smallest source step that T-Spice will take is controlled by the minsrcstep option.

Gmin stepping. T-Spice finds the minimum conductance value that yields a convergent solution. . The options gmindc and gramp specify a search range for the minimum required conductance, $g_{\text {min }}$ :

$$
\boldsymbol{g m i n d c} \leq g_{\min } \leq\left(\boldsymbol{g m i n d c} \times 10^{\text {gramp }}\right)
$$

Pseudotransient solution. In the pseudotransient solution method, TSpice uses homotopy methods to approximate a solution, then removes the homotopies for the final solution. T-Spice obtains a pseudotransient solution as follows:

- T-Spice first enables pseudotransient simulation values for gmindc and cshunt, which are determined internally. The source values are then ramped up to their final values.
- T-Spice then performs a time-stepping simulation. When this simulation converges, T-Spice removes the homotopy devices (gmindc and cshunt), one at a time, until the final solution is reached.

Note: If you do not know the best solution method for your circuit, then do not set demethod. Instead, set dhomotopy to the default value of all. In this case, T-Spice will automatically cycle through the homotopies as necessary to achieve convergence.

## See Also

[^1]
## dcstep

$$
\text { .options dcstep }=\text { dcstep } \quad \text { where dcstep } \geq 0
$$

## Default Value

0.0

## Description

Adds a conductance across the terminals of each capacitor during DC operating point computation. If a non-zero value is specified, T-Spice computes the additional conductance for each capacitor as:

$$
g=\frac{c}{\text { dcstep }}
$$

where $g$ is the applied conductance and $c$ is the device capacitance.

## See Also

"cshunt" (page 211), "gmindc" (page 219)

## extraiter[ations] | newtol

.options extraiter = extraiter
Default Value

0

## Description

Instructs T-Spice to compute the specified number of Newton solver iterative steps after convergence criteria have been met. This option is used to improve the accuracy of the solution, and is applicable to DC operating point, DC sweep, and AC simulations. For transient analysis, use the trnewtol option.

When precise $=$ true, the default value of extraiter is 10 .

## See Also

[^2]
## fast

```
.options fast = { true | false }
```


## Default Value

## false

## Description

Triggers changes to other options settings to maximum simulation speed:

| Option | Default | Fast |
| :--- | :--- | :--- |
| "absi \| abstol" (page 206) | $1 \times 10^{-10} \mathrm{~A}$ | $5 \times 10^{-10} \mathrm{~A}$ |
| "bytol" (page 210) | 0 | $1 \times 10^{-13}$ |
| "modelmode" (page 270) | direct | cachetable |
| "reldv \| relvar" (page 251) | 0.35 | 0.4 |
| "reli \| reltol" (page 234) | $5 \times 10^{-4}$ | $1 \times 10^{-3}$ |
| "relq \| relchgtol" (page 252) | $\boldsymbol{r e l i}\left(5 \times 10^{-4)}\right.$ | $\boldsymbol{r e l i}\left(1 \times 10^{-3}\right)$ |

Specifying any of the above fields individually will override the value set by fast.

## See Also

```
"accurate" (page 208), "precise" (page 232)
```


## gmin

$$
. \text { options gmin }=\text { gmin } \quad \text { where } \text { gmin } \geq 0
$$

## Default Value

$1 \times 10^{-12} \Omega^{-1}$

## Description

Specifies a conductance added in parallel with all pn junctions during transient analaysis. When $\boldsymbol{g m i n}>0$, T -Spice generates a gmin conductance across two terminals by adding a resistor with resistance $R$

$$
R=\frac{1}{\boldsymbol{g m i n}}
$$

T-Spice applies the gmin conductance to various elements as follows:

- diode-conductance is added across the positive/negative terminals.
- -conductance is added across the base/emitter and the base/collector terminals.
- MOSFET-conductance is added across the source/bulk, drain/bulk, and the source/drain terminals.
- MESFET-conductance is added across the source/gate, drain/gate, and source/drain terminals.
- JFET-conductance is added across the source/gate, drain/gate, and source/drain terminals.


## See Also

```
"gmindc" (page 219), "gshunt" (page 221)
```


## gmindc

## .options gmindc $=$ gmindc

where $\boldsymbol{g m i n d} c \geq 0$

## Default Value

$1 \times 10^{-12} \Omega^{-1}$

## Description

Specifies a conductance that is added in parallel with all pn junctions during DC operating point analysis. When gmindc $>0$, T-Spice generates a gmindc conductance across two terminals by adding a resistor with resistance $R$

$$
R=\frac{1}{\text { gmindc }}
$$

T-Spice applies the gmindc conductance to various elements as follows:

- diode-conductance is added across the positive/negative terminals.
- -conductance is added across the base/emitter and the base/collector terminals.
- MOSFET-conductance is added across the source/bulk, drain/bulk, and the source/drain terminals.
- MESFET-conductance is added across the source/gate, drain/gate, and source/drain terminals.
- JFET-conductance is added across the source/gate, drain/gate, and source/drain terminals.

Note: $\quad$ When a DC operating point non-convergence occurs, T-Spice can begin a $g_{\min }$ stepping algorithm to find the minimum conductance that yields a convergent solution. The $g_{\min }$ stepping algorithm is triggered when a non-convergence occurs and the dchomotopy option is set to all or gmin.

## See Also

[^3]
## gramp

> .options gramp = gramp
where $0<$ gramp $<(-\log 10(100 \times$ gmind $c))$

## Default Value

4

## Description

Specifies the range over which the gmindc value will be swept in $g_{\text {min }}$ stepping for DC analysis. The $g_{\min }$ stepping algorithm is triggered when a non-convergence occurs and dchomotopy is set to all or gmin. Together, the options gmindc and gramp specify a search range for the minimum required conductance, $g_{\text {min }}$ :
gmindc $\leq g_{\text {min }} \leq \boldsymbol{g m i n d c} \cdot 10$ gramp
T-Spice's $g_{\text {min }}$ stepping algorithm searches the specified conductance range in two steps. First, T-Spice performs a binary search between gmindc and gmindc-10gramp. T-Spice searches for the smallest value of $g_{\text {min }}$ that results in a converged solution. T-Spice automatically ends the binary search when it reaches a $\Delta g_{\text {min }}$ that is less than or equal to a factor of 10 .

Starting with binary search results, T-Spice then begins reducing the value of $g_{\min }$ by a factor of 10 in each iteration. Once a non-convergence occurs, the previous convergent iteration provides the final solution.

## See Also

[^4]
## gshunt

.options gshunt = gshunt
where gshunt $\geq 0$

## Default Value

$0.0 \Omega^{-1}$

## Description

Specifies a conductance to be added between every node and ground. When gshunt $>0$, T-Spice generates a gshunt conductance from each node to ground by adding a resistor with resistance $R$

$$
R=\frac{1}{\text { gshunt }}
$$

See Also

> "cshunt" (page 211), "gmin" (page 218)

## kcltest

```
.options kcltest = {true | false }
```


## Default Value

true

## Description

Enables the current tolerance test for convergence. When the current tolerance test is applied, the system of equations is determined to be converged if:

$$
\text { reli }>\sqrt{\sum_{i=0}^{n}\left(\Delta I^{\prime}\right)^{2}} \quad \text { and } \quad \text { absi }>\sqrt{\sum_{i=0}^{n} I^{2}}
$$

where $I$ is the residual branch current at each node. The quantity $\Delta I$ ' represents the change in relative residual branch current between two consecutive iterations:

$$
\Delta I^{\prime}=\left(\frac{I_{j}}{\text { imax }_{j}}\right)-\left(\frac{I_{j-1}}{\text { imax }_{j-1}}\right)
$$

where $\operatorname{imax}_{j}$ is the largest branch current (in absolute value) flowing into the node in question in the $j^{\text {th }}$ Newton iteration.

## See Also

"absi | abstol" (page 206), "reli | reltol" (page 234), "kvltest" (page 223)

## kvItest

```
.options kvltest = { true | false }
```

Default Value

## false

## Description

Enables the voltage tolerance test for convergence during transient analysis. The voltage tolerance test is always performed during DC, DC sweep, Transfer, and AC analysis. The kvltest option is used for enabling this test during transient analysis also.

The voltage tolerance is calculated as follows:
voltage tolerance $=\max (\boldsymbol{a b s v}, \boldsymbol{r e l v} \times V)$,
where $V$ is the node voltage value. If the voltage variation at each node is less than the calculated voltage tolerance for that node, then the iteration is considered to be converged.

## See Also

"absv | vntol" (page 207), "relv" (page 235), "kcltest" (page 222)

## maxdcfailures

.options maxdcfailures $=\mathbf{n} \quad$ where $\boldsymbol{n}$ is a non-negative integer

## Default Value

4

## Description

Maximum number of non-convergence failures allowed in a DC sweep simulation before T-Spice ends processing with a "too many nonconvergences" error.

## See Also

[^5]
## mindcratio

```
.options mindcratio = mindcratio
where \(0<\boldsymbol{m i n d c r a t i o}<1\)
```


## Default Value

$1 \times 10^{-4}$

## Description

Minimum fractional step size allowed in source ramping for DC sweep analysis:

$$
\Delta d c_{\min }=\text { mindcratio } \times \Delta d c
$$

where $\Delta d c$ is the step size specified in the netlist sweep statement. If the step size falls below $\Delta d c_{\text {min }}$, TSpice will declare a non-convergence error.

T-Spice applies source ramping when a fixed source step fails to converge. In source ramping, the source variable is gradually ramped up from the previous sweep value to the next sweep value.

See Also

```
"maxdcfailures" (page 224), "numnx | itl2" (page 230)
```


## minsrcstep

```
.options minsrcstep = minsrcstep where minsrcstep > 0
```


## Default Value

$1 \times 10^{-8}$

## Description

Minimum fractional step size for source stepping:
min step size $=\boldsymbol{m i n s r c s t e p} \times($ Source value $)$
In source stepping, all voltage and current sources are ramped up from zero to their final values. This allows T-Spice to find the DC operating points of difficult-to-converge circuits. Source stepping is used only in non-converging cases of initial DC operating point computations when dchomotopy is set to source or all.

## See Also

[^6]
## numnd | itl1

$$
\text { .options numnd }=\text { numnd } \quad \text { where } \text { numnd is a positive integer }
$$

## Default Value

250

## Description

Newton iteration limit for DC operating point computation. If a solution does not converge within numnd iterations, T-Spice applies the homotopy method specified by dchomotopy to attempt to reach a convergent solution. If dchomotopy $=$ none, $T$-Spice declares a non-convergence error.

## See Also

[^7]
## numndset

.options numndset $=$ numndset $\quad$ where numndset is a positive integer

## Default Value

numnd / 10

## Description

This option is used during DC operating point computations when the user has specified node voltage guesses using the .nodeset command. Numndset is the number of Newton iterations during which the .nodeset nodes will be held at their user-specified voltage values. After numndset iterations, or when the circuit convergence criteria have been met, these node voltages are allowed to vary for the remainder of the computation

## See Also

[^8]
## numns | itl6

$$
\text { .options numns }=\text { numns } \quad \text { where } \text { numns is a positive integer }
$$

## Default Value

50

## Description

Newton iteration limit for each source stepping attempt in DC operating point analysis. In source stepping, all voltage and current sources are ramped up from zero to their final values. This allows T-Spice to find the DC operating points of difficult-to-converge circuits. Source stepping is used only in non-converging cases of initial DC operating point computations when dchomotopy is set to source or all.

## See Also

[^9]
## numnx | itl2

.options numnx = numnx
where numnx is a positive integer

## Default Value

100

## Description

Newton iteration limit for DC sweep computation. If a convergent solution is not reached within numnx iterations, T-Spice begins source ramping. In source ramping, the source variable is gradually ramped up from the previous sweep value to the next sweep value. The Newton iteration limit for source ramping is specified by numnxramp.

## See Also

[^10]
## numnxramp

.options numnxramp = numnxramp where numnxramp is a positive integer

## Default Value

50

## Description

Newton iteration limit for DC sweep computation during source ramping. T-Spice applies source ramping when a fixed source step fails to converge within numnx iterations. In source ramping, the source variable is gradually ramped up from the previous sweep value to the next sweep value.

## See Also

"numnx | itl2" (page 230), "minsrcstep" (page 226)

## precise

$$
\text { .options precise = \{true | false }\}
$$

## Default Value

## false

## Description

Triggers changes to other options for extreme simulation precision. This option should only be used for single transistor characterizations, or for very simple circuits.

The following option settings will be used:

| Option | Default | Precise |
| :---: | :---: | :---: |
| "absdv \| absvar" (page 238) | 0.5 V | 0.3 V |
| "absi \| abstol" (page 206) | $1 \times 10^{-10} \mathrm{~A}$ | $5 \times 10^{-11} \mathrm{~A}$ |
| "absq \| chgtol" (page 239) | $1 \times 10^{-14} \mathrm{C}$ | $1 \times 10^{-14} \mathrm{C}$ |
| "absv \| vntol" (page 207) | $1 \times 10^{-6} \mathrm{~V}$ | $1 \times 10^{-7} \mathrm{~V}$ |
| ```"extraiter[ations] \| newtol" (page 216)``` | 0 | 10 |
| "gmin" (page 218) | $1 \times 10^{-12} \Omega^{-1}$ | $1 \times 10^{-14} \Omega^{-1}$ |
| "gmindc" (page 219) | $1 \times 10^{-12} \Omega^{-1}$ | $1 \times 10^{-14} \Omega^{-1}$ |
| "kvltest" (page 223) | false | true |
| "Ivltim" (page 241) | 1 | 3 |
| "extraiter[ations] \| newtol" (page 216) | 0 | 10 |
| "numnd \| itl1" (page 227) | 250 | 500 |
| "numndset" (page 228) | numnd / 10 (25) | numnd / 5 (100) |
| "numns \| itl6" (page 229) | 50 | 100 |
| "numnx \| itl2" (page 230) | 100 | 200 |
| "numnxramp" (page 231) | 50 | 100 |
| "pivtol" (page 279) | $1 \times 10^{-14}$ | $1 \times 10^{-16}$ |
| "reldv \| relvar" (page 251) | 0.35 | 0.25 |
| "reli \| reltol" (page 234) | $5 \times 10^{-4}$ | $1 \times 10^{-4}$ |
| "relq \| relchgtol" (page 252) | reli $\left(5 \times 10^{-4}\right)$ | reli ( $1 \times 10^{-4}$ ) |
| "relv" (page 235) | $1 \times 10^{-3}$ | $1 \times 10^{-4}$ |
| "rmax" (page 253) | 2 | 1 |


| Option | Default | Precise |
| :--- | :--- | :--- |
| "trextraiter[ations] $\mid$ trnewtol", <br> (page 254) | 0 | 1 |

Specifying any of the above fields individually will override the value set by precise.

## See Also

```
"accurate" (page 208), "fast" (page 217)
```


## reli | reltol

where reli > 0

## Default Value

$5 \times 10^{-4}$

## Description

Specifies a convergence criterion limiting the relative change in total RMS branch current for all nodes in the circuit between consecutive iterations. The current test for convergence is applied when kcltest = true.

When the current tolerance test is applied, the system of equations is determined to be converged if:

$$
\text { reli }>\sqrt{\sum_{i=0}^{n}\left(\Delta I^{\prime}\right)^{2}} \quad \text { and } \quad \text { absi }>\sqrt{\sum_{i=0}^{n} I^{2}}
$$

where $I$ is the residual branch current at each node. The quantity $\Delta I$ ' represents the change in relative residual branch current between two consecutive iterations:

$$
\Delta I^{\prime}=\left(\frac{I_{j}}{i m a x_{j}}\right)-\left(\frac{I_{j-1}}{i m a x}\right)
$$

where $\operatorname{imax}_{j}$ is the largest branch current (in absolute value) flowing into the node in question in the $j^{\text {th }}$ Newton iteration.

## See Also

[^11]
## relv

$$
. \text { options relv }=\text { relv } \quad \text { where relv }>0
$$

## Default Value

$1 \times 10^{-3}$

## Description

Specifies a convergence criterion limiting the relative change in node voltage at any node in the circuit between consecutive iterations. The voltage test for convergence is applied when kvltest = true.

The voltage tolerance test uses both the absv and relv options to calculate tolerance:
voltage tolerance $=\max (\boldsymbol{a b s v}, \boldsymbol{r e l v} \times V)$,
where $V$ is node voltage. If the voltage change at each node is less than the voltage tolerance for that node, then the iteration is considered to be converged.

## See Also

"absv | vntol" (page 207), "kvltest" (page 223)

## tolmult

$$
\text { .options tolmult }=\text { tolmult } \quad \text { where } \text { tolmult }>0
$$

## Default Value

1.0

## Description

Multiplicative scaling factor for absolute and relative tolerance values used in the current and voltage tolerance tests for convergence. The following option values are multiplied by tolmult:

- "absi | abstol" (page 206)
- "absv | vntol" (page 207)
- "reli | reltol" (page 234)
" "relv" (page 235)


## Timestep and Integration Options

"absdv | absvar" (page 238)<br>"ft" (page 240)<br>"maxord" (page 244)<br>"mintimeratio | rmin" (page 246)<br>"numnt | itl4 | imax" (page 248)<br>"poweruplen" (page 250)<br>"relq | relchgtol" (page 252)<br>"trextraiter[ations] | trnewtol" (page 254)

"absq | chgtol" (page 239)
"Ivltim" (page 241)
"method" (page 245)
"mu | xmu" (page 247)
"numntreduce | itl3" (page 249)
"reldv | relvar" (page 251)
"rmax" (page 253)
"trtol" (page 255)

## absdv | absvar

. options absdv $=\boldsymbol{a b s d v} \quad$ where $\boldsymbol{a b s d v}>0$

## Default Value

0.5 V

## Description

For transient analysis, absdv specifies the threshold absolute voltage change between two consecutive time steps. This quantity is used with reldv to calculate the voltage variance error measurement:

$$
\text { variance }=\left|\frac{V_{n+1}-V_{n}}{\text { reldv } \cdot \max \left(\mathbf{a b s d v}, V_{n}\right)}\right|
$$

Voltage variance is used to scale time step sizes when "Ivltim" (page 241) is equal to 1,3 , or 4.

## See Also

"Ivltim" (page 241)

## absq | chgtol

```
.options absq = absq
where \(\boldsymbol{a b s q}>0\)
```


## Default Value

$1 \times 10^{-14} \mathrm{C}$

## Description

Minimum capacitor charge or inductor flux used to predict a timestep in the Local Truncation Error timestep algorithm (Ivltim =2 or 4). The absq option sets a floor on charge values to prevent the time step size from becoming too small.

The value of absq is used to calculate Local Truncation Error (LTE) as follows:

$$
L T E=\frac{Q-Q_{\text {predicted }}}{\boldsymbol{t r t o l} \times \max (\boldsymbol{a b s q},(\boldsymbol{r e l q} \times Q))}
$$

When Ivltim $=2$ or 4, and $L T E>1$, T-Spice recalculates the solution at a smaller timestep. See "Ivltim" (page 241) for a description of the LTE algorithm.

## See Also

"Ivltim" (page 241), "relq | relchgtol" (page 252)

## ft

$$
. \text { options } \mathbf{f t}=\boldsymbol{f t} \quad \text { where } 0<\boldsymbol{f t}<1
$$

## Default Value

0.25

## Description

Fraction by which the internal timestep is decreased if a transient analysis solution does not converge within numnt iterations. T-Spice recalculates the solution for a smaller timestep:

$$
\Delta t_{n}=\Delta t_{n}^{\prime}(1-\mathrm{ft})
$$

where $\Delta t_{n}{ }^{\prime}$ is the size of the failed or non-converged $\mathrm{n}^{\text {th }}$ timestep.
The ft option also determines the fraction by which the next timestep $\left(\Delta t_{n+1}\right)$ is decreased if the $\mathrm{n}^{\text {th }}$ timestep solution requires more than numntreduce iterations to converge:

$$
\Delta t_{n+1}=\Delta t_{n}(1-f t)
$$

For more information about timestep reduction algorithms, see "Ivltim" (page 241).

## See Also

"numnt | itl4 | imax" (page 248), "numntreduce | itl3" (page 249), "Ivltim" (page 241)

## Default Value

1

## Description

Specifies the algorithm used to control timestep sizes in transient analysis simulation:

$$
\left.\left.\begin{array}{ll}
\text { Ivltim = } \mathbf{1} & \text { Iteration count algorithm with voltage variance test. } \\
\text { Ivltim = } \mathbf{2} & \begin{array}{l}
\text { Local Truncation Error timestep control algorithm. } \\
\text { Ivltim = 3 }
\end{array} \\
\text { Ivltim = 4 } \\
\text { revified iteration count with voltage variance test and timestep }
\end{array}\right] \begin{array}{l}
\text { Combines lvltim=1 voltage variance test, prior to the timestep, with } \\
\text { lvltim=2 local truncation error control of timestep reversal }
\end{array}\right\}
$$

All three algorithms require that the solution at each time step converge within numnt iterations. If a convergent solution is not found within numnt iterations, T-Spice recalculates the solution at a smaller timestep:

$$
\Delta t_{n}^{\prime}=\Delta t_{n}(1-f t)
$$

where $\Delta t_{n}$ is the original size of the $\mathrm{n}^{\text {th }}$ timestep. When Ivltim $=1$, no further conditions are placed on the current timestep solution.

When Ivltim=3, the timestep solution must also have an error value less than or equal to 1 , where error is calculated as the voltage variance between time steps

$$
\text { error }=\left|\frac{V_{n+1}-V_{n}}{\max \left(\mathbf{a b s d v},\left(\boldsymbol{r e l d} \boldsymbol{v} \cdot V_{n}\right)\right)}\right|
$$

If Ivltim=3 and the error is greater than 1, T-Spice recalculates the solution for a smaller timestep. The smaller timestep is obtained by scaling the current timestep by the error (voltage variance):

$$
\Delta t_{n}^{\prime}=\Delta t_{n} \cdot\left(\frac{0.9}{\text { error }}\right)
$$

T-Spice continues the timestep reversal algorithm until it reaches a convergent solution within numnt iterations, such that error $<1$.

## Local Truncation Error Algorithm (Ivltim = 2 or 4)

The Local Truncation Error (LTE) algorithm adjusts the timestep size according to the discretization error generated by integration. The amount of truncation error introduced by integration increases with the rate-of-change in the circuit. Local truncation error is calculated as the ratio between the error in predicted charge and the charge tolerances relq and absq. The value of "trtol" (page 255) is included as a corrective factor in the LTE calculation::

$$
\text { error }=\frac{Q-Q_{\text {predicted }}}{\boldsymbol{t r t o l} \cdot \max ((\boldsymbol{r e l q} \cdot Q), \boldsymbol{a b s q})}
$$

If the calculated local truncation error $(L T E)$ is greater than 1, then T-Spice recalculates the solution for a smaller time step:

$$
\Delta t^{\prime}=\Delta t \cdot\left(\frac{0.9}{\text { error }}\right)
$$

Note:
The LTE algorithm is error-prone in high-current devices, because the rapidly changing charge values will generate large local truncation error values. This can cause T-Spice to use extremely small timesteps, leading to slow simulations and/or "timestep too small" errors. In high-current circuits, a voltage-based timestep algorithm (IvItim =1 or 3 ) is often the preferred choice.

## Determining the Next Timestep (Ivltim $=1,2,3$, or 4)

All three algorithms use both iteration count and an error measurement to determine the size of the next timestep. After a convergent solution is found at the current timestep, T-Spice applies the following rules to determine the next timestep size:

- If the solution required more than numntreduce iterations, T-Spice reduces the next timestep by the fraction ft :

$$
\Delta t_{n+1}=\Delta t_{n}(1-f t)
$$

- If the solution converged in fewer than numntreduce iterations, T-Spice uses the appropriate error measurement to scale the next timestep. (Error is equal to voltage variance when Ivltim $=1$ or 3, and LTE when Ivltim $=2$ or 4 .)

$$
\Delta t_{n+1}=\Delta t_{n} \cdot\left(\frac{0.9}{\text { error }}\right)
$$

The following chart summarizes the three timestep control algorithms:


See Also
"mintimeratio | rmin" (page 246), "numnt | itl4 | imax" (page 248), "numntreduce | itl3" (page 249),
"absdv | absvar" (page 238), "reldv | relvar" (page 251), "ft" (page 240)

## maxord

.options maxord $=\{1|2| 3 \mid 4\}$

## Default Value

2

## Description

Maximum time integration order for variable-order Gear's BDF calculation in transient analysis. Gear's BDF integration is used when method = gear.

## See Also

[^12]
## method

```
.options method = { gear | trap }
```


## Default Value

## trap

## Description

Method of numerical integration for estimating the time derivative of the system's charge components during a .tran simulation. Possible settings are:

| gear | Variable order Gear's backward differential formula (see "Gear's <br> BDF Method" on page 30).The order of integration is controlled by <br> the option maxord. |
| :--- | :--- |
| trap | Trapezoidal integration. This method is faster than gear but may <br> introduce non-physical oscillations in nodal responses. (see <br> "Trapezoidal Integration Method" on page 30). |

## See Also

"maxord" (page 244)

## mintimeratio | rmin

$$
\text { .options mintimeratio }=\text { mintimeratio } \text { where } \text { mintimeratio }>0
$$

## Default Value

$1 \times 10^{-9}$

## Description

Relative minimum timestep size for transient simulations. The minimum timestep for transient simulation is equal to mintimeratio $\times$ tstep, where tstep is the timestep size listed on the .tran statement.

If the timestep size falls below mintimeratio $\times \boldsymbol{t s t e p}, \mathrm{T}$-Spice ends processing with a "timestep too small" error.

## mu | xmu

.options $m u=m u$
where $0 \leq \boldsymbol{m u} \leq 0.5$

## Default Value

0.5

## Description

Coefficient for varying the integration between the backward Euler formula and the Trapezoidal formula. Valid values of $\mathbf{m u}$ are between 0 and 0.5 , with 0 yielding a backward Euler integration, 0.5 yielding Trapezoidal integration, and intermediate values producing a hybrid integration of the specified proportional weighting. Trapezoidal integration is used when method = trap.

## See Also

[^13]
## numnt | itl4 | imax

## .options numnt = numnt

where numnt is a positive integer

## Default Value

10

## Description

Newton iteration limit for transient analysis solutions.
If a solution does not converge within numnt iterations, T-Spice recalculates the solution for a smaller time step. The fraction by which the time step is decreased after a non-convergence is specified by "ft" (page 240).

## See Also

[^14]
## numntreduce | itl3

.options numntreduce $=$ numntreducewhere numntreduce is a positive integer

## Default Value

3

## Description

For transient analysis, the threshold number of Newton iterations that controls the next time step size.
If more than numntreduce iterations are needed to reach a convergent solution at the $\mathrm{n}^{\text {th }}$ time step, then the next time step size is reduced by the fraction $\boldsymbol{f t}$ :

$$
\Delta t_{n+1}=\Delta t_{n}(1-\mathrm{ft})
$$

If the $\mathrm{n}^{\text {th }}$ time step converges with fewer than numntreduce iterations, then T-Spice increases or decreases the next time step by scaling with a calculated error value:

$$
\Delta t_{n+1}=\Delta t_{n} \cdot\left(\frac{0.9}{\text { error }}\right)
$$

The error calculation is dependent on the algorithm specified by "Ivltim" (page 241).

## See Also

"ft" (page 240), "Ivltim" (page 241)

## poweruplen

.options poweruplen = poweruplen

## Default Value

$0.1 \%$ of the total transient simulation time.

## Description

Length of the powerup ramp (seconds) during powerup transient analysis.

## See Also

".tran" (page 147)

## reldv | relvar

$$
. \text { options reldv }=\text { reldv } \quad \text { where reldv }>1
$$

## Default Value

0.35

## Description

For transient analysis, reldv specifies the maximum relative voltage change between two consecutive time steps. This quantity is used with $\boldsymbol{a b s d v}$ to calculate the voltage variance error measurement:

$$
\text { variance }=\left|\frac{V_{n+1}-V_{n}}{\text { reldv } \cdot \max \left(\mathbf{a b s d v}, V_{n}\right)}\right|
$$

Voltage variance is used to scale time step sizes when "Ivltim" (page 241) is equal to 1,3 , or 4.

## See Also

"absdv | absvar" (page 238), "Ivltim" (page 241)

## relq | relchgtol

$$
. \text { options relq }=\text { relq } \quad \text { where } r e l q>0
$$

## Default Value

$5 \times 10^{-4}$

## Description

Maximum relative error in predicted capacitor charge or inductor flux. The error between predicted and actual charges is used to adjust timestep sizes in the Local Truncation Error timestep algorithm (Ivltim = 2 or 4).

The value of relq is used to calculate Local Truncation Error (LTE) as follows:

$$
L T E=\frac{Q-Q_{\text {predicted }}}{\boldsymbol{t r t o l} \times \max (\boldsymbol{a b s q},(\boldsymbol{r e l q} \times Q))}
$$

When Ivltim=2 or 4, and $L T E>1$, T-Spice recalculates the solution at a smaller timestep. See "Ivltim" (page 241) for a description of the LTE algorithm.

## See Also

"Ivltim" (page 241), "absq | chgtol" (page 239)

## rmax

.options rmax $=\boldsymbol{r m a x} \quad$ where $r m a x \geq 1$

## Default Value

2

## Description

Defines the maximum allowed timestep in transient simulation, specified as a ratio. The maximum timestep is defined as:

$$
\Delta t_{\max }=r \max \times \Delta t_{\operatorname{tran}}
$$

where $\Delta t_{t r a n}$ is the timestep specified in the netlist .tran statement.

## See Also

> "fast" (page 217), "accurate" (page 208), "precise" (page 232)

## trextraiter[ations] | trnewtol

```
.options trextraiter = trextraiter
where trextraiter \(\geq 0\)
```


## Default Value

0

## Description

Instructs T-Spice to compute the specified number of Newton solver iterative steps after convergence criteria have been met. This option is used to improve the accuracy of the solution, and is applicable to transient analysis only. For increasing the iterations of non-transient simulations use the newtol option.

When precise $=$ true, the default value of trextraiter is 1.

## See Also

[^15]
## trtol

.options trtol = trtol

## Default Value

10

## Description

Corrective factor for estimation of the local truncation error in the LTE algorithm:

$$
L T E=\frac{Q-Q_{\text {predicted }}}{\boldsymbol{t r t o l} \cdot \max ((\text { relq } \cdot Q), \mathbf{a b s q})}
$$

See "Ivltim" (page 241) for a description of the LTE algorithm.

## Note:

The default value of trtol has been calculated to minimize error in the estimation of LTE. Changing the value of trtol is generally not recommended.

## See Also

[^16]
## Model Evaluation Options

| "dcap" (page 257) | "dccap" (page 258) |
| :--- | :--- |
| "defad" (page 259) | "defas" (page 260) |
| "defl" (page 261) | "defnr"" (page 262) |
| "defnrs" (page 263) | "defpd" (page 264) |
| "defps" (page 265) | "defw" (page 267) |
| "deriv" (page 268) | "minresistance \| resmin" (page 269) |
| "modelmode" (page 270) | "moscap" (page 271) |
| "mosparasitics" (page 272) | "scale" (page 273) |
| "scalm" (page 274) | "tnom" (page 275) |
| "wl" (page 276) |  |

## dcap

```
.options dcap ={1|2}
```


## Default Value

2

## Description

Selects the model used to calculate depletion capacitance for BJTs, diodes, and MOS parasitic diodes. Possible settings are:

dcap $=1 \quad$ Berkeley SPICE diode equations.<br>dcap $=2$<br>Revised equations. See the device model documentation for "BJT<br>Level 1 (Gummel-Poon)" (page 338) and "Diode" (page 368).

## See Also

[^17]
## dccap

```
.options dccap = {true | false}
```


## Default Value

## false

## Description

Controls the computation of charges and capacitances in DC simulations. Charge and capacitance values are not normally computed for DC operating point, DC sweep, and DC transfer analyses. Enabling this flag will permit the user to print out charge values for capacitors, diode, and transistors, without affecting the DC solutions.

## defad

## Default Value

$0.0 \mathrm{~m}^{2}$

## Description

Default MOSFET drain diode area.

## See Also

"MOSFET (m)" (page 174)

## defas

.options defas = defas
where defas $\geq 0.0$

## Default Value

$0.0 \mathrm{~m}^{2}$

## Description

Default MOSFET source diode area.

## See Also

"MOSFET (m)" (page 174)
.options defl = defl
where defl $\geq 0.0$

## Default Value

$1 \mathrm{e}-4 \mathrm{~m}$

## Description

Default MOSFET channel length.

## See Also

"MOSFET (m)" (page 174)

## defnrd

## Default Value

0.0

## Description

Default number of diffusion squares for a MOSFET drain resistor.

## See Also

"MOSFET (m)" (page 174)

## defnrs

```
.options defnrs = defnrs
    where defnrs }\geq0.
```


## Default Value

0.0

## Description

Default number of diffusion squares for a MOSFET source resistor.

## See Also

"MOSFET (m)" (page 174)

## defpd

.options defpd = defpd
where defpd $\geq 0.0$

## Default Value

0.0 m

## Description

Default MOSFET drain diode perimeter.

## See Also

"MOSFET (m)" (page 174)

## defps

## Default Value

0.0 m

## Description

Default MOSFET source diode perimeter.

## See Also

"MOSFET (m)" (page 174)

## deftables

.options deftables $=\{$ true $\mid$ false $\}$

## Default Value

false

## Description

Enables table-based model evaluation mode instead of direct model evaluation.

Note:
deftables has been replaced with the modelmode option, and is documented and maintained only for purposes of backward compatibility.

## See Also

> "modelmode" (page 270)

## defw

$$
. \text { options defw }=\text { defw } \quad \text { where } \text { defw } \times 0.0
$$

## Default Value

$1 \mathrm{e}-4 \mathrm{~m}$

## Description

Default MOSFET channel width.

## See Also

"MOSFET (m)" (page 174)

## deriv

```
.options deriv ={0|1}
```


## Default Value

0

## Description

Selects the default method for computing all device $d q / d v$ and $d i / d v$ derivatives:

0
Computes analytical derivatives where possible. (Available for most MOSFETs, diodes, and BJTs.)

Only uses numerical, finite-difference derivatives.

## minresistance | resmin

.options minresistance $=$ minresistance

## Default Value

$1 \mathrm{e}-5 \Omega$

## Description

Minimum resistance value for all resistors, including parasitics and inductor values, as well as resistors defined in the netlist. Any resistance that is specified or computed to be less than minresistance is reset to minresistance.

## modelmode

```
.options modelmode = {direct | uniform | cache}
```


## Default Value

> direct

## Description

Specifies the model evaluation method used in T-Spice simulation:

| direct | Direct model evaluation. |
| :--- | :--- |
| uniform \| uniformtable | Table-based evaluation with uniform grid spacing. |
| cache \| cachetable | Table-based evaluation with adaptive grid generation. |

Note: Not all models support table-based evaluation.

Note: $\quad$ The modelmode option replaces the deftables and adaptivegrid options found in previous versions of T-Spice. For backward compatibility, the old options are still supported.

## moscap

.options moscap $=\{$ true | false $\}$

## Default Value

## false

## Description

Enables automatic source/drain area/perimeter estimation for MOSFETs.
When the ACM model parameter is set to 0 (default) or 10 , then:
The default AD and AS values will be $\mathbf{I} \times \mathbf{w}$
The default PD and PS values will be $2 \times(\mathbf{I}+\mathbf{w})$

## See Also

"MOSFET (m)" (page 174)

## mosparasitics

```
.options mosparasitics = { true | false }
```


## Default Value

> true

## Description

For table-mode simulations (modelmode=uniform or cache), mosparastics enables explicit addition of MOSFET source/bulk drain/bulk parasitic diodes. When mosparastics is disabled, then the diode behavior is approximated using nonlinear capacitors, for improved speed.

## See Also

[^18]
## scale

$$
\text { .options scale }=\text { scale } \quad \text { where scale } \geq 0.0
$$

## Default Value

1.0

## Description

Scales the physical dimensions of capacitors, MESFETs, MOSFETs, and resistors. Lengths and widths are multiplied by scale, and areas are multiplied by scale ${ }^{2}$.

## See Also

"scalm" (page 274), "Capacitor (c)" (page 154), "MESFET (z)" (page 173), "MOSFET (m)" (page 174), "Resistor (r)" (page 179)

## scalm

.options scalm $=\boldsymbol{s c a l m} \quad$ where $\boldsymbol{s c a l m} \geq 0.0$

## Default Value

1.0

## Description

Default scaling factor for resistors and capacitors. The scalm option is overridden by setting the model parameter scale. The scaling factor affects lengths, widths, and drawn lengths and widths.

## See Also

"scale" (page 273), "Capacitor" (page 365), "Resistor" (page 463)

## tnom

.options tnom $=$ tnom

## Default Value

$25^{\circ} \mathrm{C}$
Description

Nominal temperature in ${ }^{\circ} \mathrm{C}$. This is the temperature at which all device and model parameters are assumed to be measured.

Note:
Differences in the nominal and the simulation temperatures may account for some variations in solutions when using different SPICE simulators. Many Berkeley SPICE derivatives use $27^{\circ} \mathrm{C}$ as the baseline temperature.

## wl

.options wl = \{ true | false \}
Default Value
false

## Description

Reverses MOSFET length and width specifications. If wl = true, then length specifications apply to width, and width specifications apply to length.

## See Also

[^19]
## Linear Solver Options

> "linearsolver" (page 278) "pivtol" (page 279) "zpivtol" (page 280)

## linearsolver

$$
\text { .options linearsolver = \{best | klu | pardiso | sparse | superlu \} }
$$

## Default Value

> best

## Description

Specifies how linear equations are solved. Possible settings are:

| best | Allows T-Spice to select a solver based on the number of <br> independent nodes in the system (sparse for less than 100, klu <br> otherwise). |
| :--- | :--- |
| klu | A sparse solver for circuit simulators, developed by Tim Davis and <br> the University of Florida. This is the default solver for systems with <br> more than 100 independent nodes (equation unknowns). |
| pardiso | Intel MKL (Math Kernel Library) sparse linear solver which <br> supports multi-threading, and is appropriate for solving very large <br> linear systems. |
| sparse | The original Berkeley SPICE direct solver for a system with fewer <br> than 100 independent nodes (equation unknowns). |
| superlu | A direct solver which is typically faster than sparse for large dense <br> systems. |

## pivtol

.options pivtol = pivtol
where pivtol > 0.0

## Default Value

$1 \times 10^{-14}$

## Description

Minimum pivoting tolerance for real matrices.

## zpivtol

.options zpivtol = zpivtol
where zpivtol > 0.0

## Default Value

$1 \times 10^{-6}$

## Description

Minimum pivoting tolerance for complex matrices.
"tnom" (page 275)

## General Options

| "autostop" (page 282) | "casesensitive" (page 283) |
| :--- | :--- |
| "compatibility" (page 284) | "conncheck" (page 285) |
| "parhier" (page 286) | "persist" (page 288) |
| "search" (page 289) | "spice" (page 290) |
| "threads" (page 291) |  |

## autostop

```
.options autostop = { true | false }
```


## Default Value

## false

## Description

Instructs T-Spice to terminate transient analysis after all ".macro /.eom" (page 88) results have been found. The autostop option does not affect transient analyses run in preview mode.

## See Also

[^20]
## casesensitive

```
.options casesensitive = { true | false }
```

Default Value

## false

## Description

Controls case sensitivity for names of models, subcircuits, library sections, parameters, and nodes.

Note:
This option only controls case sensitivity for names that appear after the .options casesensitive command in the input file.

## compatibility

```
.options compatibility ={ spice | hspice | pspice }
```


## Default Value

## hspice

## Description

Selects a compatibility mode for the input netlist syntax and for simulation settings.
T-Spice can natively read about $99 \%$ of Berkeley SPICE, HSPICE, and PSPICE input statements. There are, however, some incompatibilities and some irreconcilable syntax distinctions across the various simulators. By assigning a simulator cmpatibility mode, these input syntax ambiguities can be resolved and appropriately parsed.

In addition to providing syntax parsing support, the compatibility command sets certain simulator settings in order to mimic the behavior of the target simulator. The most notable of these settings is the default temperature, which is $25^{\circ} \mathrm{C}$ in HSPICE, and $27^{\circ} \mathrm{C}$ in other simulators. Other differences, such as the default MOSFET nrd and nrs values, and output format settings, may sometimes be the source of subtle or surprising differences in simulator solutions.

HSPICE compatibility mode settings:

- HSPICE compatibility mode is the default setting. Therefore, the default T-Spice settings are used.

SPICE compatibility mode settings:

- The command for assigning Berkeley SPICE compatibility, options compat=spice, is equivalent to the options spice command, described in "spice" (page 290).

PSPICE compatibility mode settings:

- The default temperature and tnom setting are $27^{\circ} \mathrm{C}$
- The "acout" (page 295) option is set to 0
- The $\mathbf{p w r}()$ function is evaluated as a signed power function in expressions


## conncheck

```
.options conncheck = { true | false }
```

Default Value
true

## Description

Toggles connectivity checking, which tests for common connectivity problems such as "No dc path to ground from node X " and "Node X is attached to only one device."

## parhier

## .options parhier=\{local | global\}

## Default value

global

## Description

Establishes the scoping algorithm for selection of parameter values in a hierarchical design. Parameters can obtain their values in a number of different methods, and the varying methods must have an extablished precedence for resolving which value assignment to select when a parameter value is assigned in multiple ways or at multiple levels of hierarchy. The ways in which parameters can be set are:

- .param statements example:.param cap=600f
- subckt parameter declaration, which establish default values example:.subckt inverter in out v cap=800f
- subckt instances (calls) with parameter assignment example:xInverter $\mathbf{n 1} \mathbf{n 2}$ vdd inverter cap=200f
- .step and DC sweep simulations example:.step cap 200f 1000f 200 f

The parhier option controls whether global .param statements will override the local (subcircuit) parameter assignments. With global scoping the highest level (outermost) parameter assignment will be selected. With local scoping the lowest level (innermost) parameter assignment will be selected.The rules of scoping vary according to the parhier setting, as depicted in the following chart:

| parhier $=$ local | parhier $=$ global |
| :--- | :--- |
| sweep assignments | sweep assignments |
| subckt call assignment | .param assignment |
| subckt declaration <br> assignment | subckt call assignment |
| .param assignment | subckt declaration assignment |

The following example demonstrates how the parhier setting can effect the final parameter value.

```
.param cap=600f
.subckt inverter in out v cap=800f
cap1 n3 gnd C=cap
.ends
xinverter1 1 5 vdd cap=400f
```

If parhier is set to local, then xinverter.c1 will have a capacitance of 400f. If parhier is set to global, then xinverter.c1 will have a capacitance of 600 f .

Note:
To get a listing of all parameter names, values, and the type of assignment, use the xref option: .options xref=true

## persist

.options persist $=\{0|1| 2 \mid 3\}$

## Default Value

1

## Description

Instructs T-Spice to continue simulation when the specified levels of warnings or errors are generated. In the default mode, a severe warning encountered during execution causes the simulation to exit with a terminal error message.

0
Stop simulation when a warning or error occurs.
1
2
Ignore warning messages.
Ignore severe warnings.
Ignore error messages.

Fatal error messages cannot be ignored; these always cause the simulation to exit.

Note:
The persist option should be used with discretion, as some warnings or errors may cause T-Spice to generate incorrect answers or to execute for a long period of time and ultimately fail.

## search

.options search = pathname
where pathname specifies a valid directory path. If the path contains spaces, pathname must be enclosed in quotes.

## Default Value

None
Description

Sets the search path for libraries and include files. T-Spice uses the search path as follows:

- If T-Spice encounters an undefined subcircuit, it automatically searches pathname for a file named subckt.inc, where subckt is the name of the subcircuit.
- If .include or .lib statements reference files that are not in the current directory, T-Spice automatically looks for these files in the pathname directory.


## See Also

".if ... / .elseif ... / .else / .endif" (page 82), ".lib" (page 85)

## spice

```
.options spice = { true | false }
```


## Default Value

## false

## Description

Changes other option settings to be compatible with Berkeley SPICE:

| Option | Default | spice |
| :--- | :--- | :--- |
| "acout" (page 295) | 1 | 0 |
| "dcap" (page 257) | 2 | 1 |
| "defnrd" (page 262) | 0.0 | 1.0 |
| "defnrs" (page 263) | 0.0 | 1.0 |
| "ingold" (page 302) | 0 | 2 |
| "tnom" (page 275) | $25^{\circ} \mathrm{C}$ | $27^{\circ} \mathrm{C}$ |

Specifying any of the above fields individually will override the value set by spice.

## threads

$$
\text { .options threads }=\{0 \mid 1\}
$$

## Default Value

$\mathbf{0}$ on single processor computers

1 on multiprocessor and multicore computers.

## Description

Controls parallel processing of model evaluation in T-Spice simulation. When the value is set to $\mathbf{1}$, T-Spice will automatically decompose the workload into small tasks, and dynamically distribute these tasks to multiple threads for processing. The number of threads and size of the tasks are controlled via internal variables, and are outside of user control.

0
Disables threading. This is the default on single processor computers.
Enables threading. This is the default on multiprocessor and multicore computers.

## See Also

[^21]
## vasearch

.options vasearch = pathname
pathname is one or more directories. If the path contains spaces, pathname must be enclosed in quotes.
Multiple directory names should be separated with semicolons.

## Default Value

## None

## Description

Sets the search path for Verilog-A files.

## See Also

".hdl" (page 79)

## Output Options

| "acct" (page 294) | "acout" (page 295) |
| :--- | :--- |
| "brief" (page 296) | "captab" (page 297) |
| "csdf" (page 298) | "dnout" (page 299) |
| "echo" (page 300) | "expert" (page 301) |
| "ingold" (page 302) | "list" (page 303) |
| "maxmsg" (page 304) | "node" (page 305) |
| "nomod" (page 306) | "numdgt" (page 307) |
| "nutmeg" (page 308) | "opts" (page 309) |
| "outputall" (page 310) | "pathnum" (page 311) |
| "prtdel" (page 312) | "prtinterp" (page 313) |
| "statdelay" (page 314) | "tabdelim" (page 315) |
| "verbose" (page 316) | "xref" (page 317) |

.options acct $=\{$ true | false \}

## Default Value

## false

## Description

Tracks and reports simulation iteration counts and other accounting statistics. This information is written to the Simulation Window, and is also recorded in the output file.

## acout

```
.options acout ={0|1 }
```


## Default Value

1

## Description

Calculation method for AC magnitude or phase differences requested in .print and .probe statements (e.g., $\mathbf{v m}(\mathbf{x}, \mathbf{y})$ ).

- If acout $=0$, T-Spice performs subtraction first, then calculates the magnitude or phase of the difference, e.g., $\mathrm{vm}(\mathrm{x}, \mathrm{y})=\mathrm{vm}(x-y)$.
- If acout $=1, \mathrm{~T}$-Spice first calculates the magnitudes or phases and then takes the difference, e.g., $\mathrm{vm}(\mathrm{x}, \mathrm{y})=\operatorname{vm}(x)-\mathrm{vm}(y)$.

Note: $\quad$ Use acout $=0$ for compatibility with Berkeley SPICE, and acout $=1$ for compatibility with H-Spice.

## See Also

[^22]
## brief

.options brief = \{ true | false \}
Default Value
false

## Description

Turns off most of the printout which is sent to the Simulation Status window.

The brief option is equivalent to the verbose $=\mathbf{0}$ setting.

## captab

```
.options captab = { true | false }
```


## Default Value

## false

## Description

Lists the capacitances for each node in the netlist, and identifies the node with the greatest capacitance.

## csdf

```
.options csdf = { true | false }
```


## Default Value

## false

## Description

Causes T-Spice to generate output in CSDF (Common Simulation Data Format) mode for compatibility with ViewLogic Tools.

If probing has been requested in the input T-Spice netlist (see ".probe" on page 133), then the output probe file will be written in CSDF binary file format. If probing has not been requested, then the standard T-Spice output file will be written in CSDF text format.

## dnout

```
.options dnout ={0|1}
```


## Default Value

0

## Description

Selects the units that T-Spice uses to measure all input and output noise spectral density magnitudes.

T-Spice reports noise spectral density contributions in units of Volts/sqrt(Hz).

1
T-Spice reports noise spectral density contributions in units of Volts ${ }^{2} / \mathrm{Hz}$.

Note: Use dnout = 1 for compatibility with H-Spice computations.

## echo

```
.options echo = { true | false }
```


## Default Value

## false

## Description

Causes T-Spice to print each line of input to the error log as it is read. The error log is the T-Spice GUI output window, or the specified file when the -e filename commandline option is used

When echo = true, T-Spice lists each input next to the line number on which it occurs. For example:

```
Initializing parser with command line options
line 00001: .options verbose=2
End-of-input
line 00003: .param pres=100
line 00004: .param ptc1=0.1
line 00005: .param ptc2=0.4
line 00006:
line 00007: .options precise
line 00008:
line 00009: v1 1 0 0.01 sin(0.01 12 1e8)
```


## expert

.options expert = \{ true | false \}
Default Value
false
Description

Activates the printout of detailed information about non-convergent nodes and devices when a simulation, or a stage of a simulation, fails.

```
.options ingold ={0|1|2}
```


## Default Value

0
Description
Controls the format of all real numeric data which is written to the AC Small-Signal output (".acmodel" (page 63)) and to the device listings ()..

| ingold value | Format | Examples |
| :--- | :--- | :--- |
| $\mathbf{0}$ | engineering format | -2.875 u |
| $\mathbf{1}$ | g format - combined fixed and <br> exponential format | 6.234 |
| $\mathbf{2}$ | e format - constant width exponential <br> format | $-1.7428 \mathrm{e}-005$ |

For the engineering format, exponents between the value of $1 \mathrm{e}-18$ and 1 e 15 are expressed as a single character appended to the end of the real data. Numbers which are smaller then 1e-18 or greater than 1 e 15 are printed in the exponential format. The characters used to express the exponential value are:

| Character suffix | Value |
| :--- | :--- |
| T | $10^{12}$ |
| G | $10^{9}$ |
| X | $10^{6}$ |
| K | $10^{3}$ |
| m | $10^{-3}$ |
| u | $10^{-6}$ |
| n | $10^{-9}$ |
| p | $10^{-12}$ |
| f | $10^{-15}$ |
| a | $10^{-18}$ |

## list

```
.options list = { true | false }
```


## Default Value

## false

## Description

Directs T-Spice to printout detailed information about every element in the netlist. The information will include nodal connectivity, the device values (resistance, capacitance, etc.), and other pertinent device parameter and device geometry settings.

## maxmsg

.options maxmsg = maxmsg
where maxmsg is a non-negative integer

## Default Value

4

## Description

Sets the maximum number of times that a duplicate warning message will be printed. A value of 0 specifies that all warning messages should be printed an unlimited number of times.

## node

```
.options node = { true | false }
```


## Default Value

false

## Description

Prints a node cross-reference table listing each node and all the elements connected to it. Each element is listed as element:term, where term identifies the element terminal as follows.

| Device Type | Terminal identifiers |
| :--- | :--- |
| Diode | $+=$ anode |
|  | $-=$ diode |
|  | B $=$ base |
| C $=$ collector |  |
| E $=$ emitter |  |
|  | S $=$ substrate |
|  | B $=$ bulk |
| MOSFET or JFET | D $=$ drain |
|  | $\mathbf{S}=$ source |
|  | $\mathbf{G}=$ gate |
|  | $\mathbf{1}=$ terminal 1 |
| All other devices | $\mathbf{2}=$ terminal 2 |
|  | etc. |

## nomod

.options nomod = \{ true | false \}

## Default Value

true
Description

Suppresses printout of all model parameters.

## numdgt

.options numdgt $=$ numdgt $\quad$ where numdgt is a non-negative integer

## Default Value

4

## Description

Minimum number of digits after the decimal point to be printed to the output file for each requested (.print) output value.

## nutmeg

.options nutmeg $=\{$ true $\mid$ false $\}$

## Default Value

false

## Description

Generates output files in a format compatible with the Nutmeg graphics program.

## opts

```
.options opts = { true | false }
```


## Default Value

false

## Description

Prints the current settings of all control options. The default behavior (opts = false) is to list only those option values that have been changed.

## outputall

.options outputall = \{ true | false \}

## Default Value

## false

## Description

Causes all commands that list nodes, devices, or options to include internal listings. Internal nodes, devices, and options are normally hidden to the user.

The outputall option affects the following commands:

| .options node | Includes all internal nodes. |
| :--- | :--- |
| .options list | Includes all internal nodes and devices. |
| .options opts | Includes all hidden and undocumented options. |
| .print | Tests internal devces and nodes for wildcard matching. When .print <br> is used without arguments, includes all internal nodes and devices in <br> the output. |
| . probe | Tests internal nodes and devices for wildcard matching. When <br> .probe is used without arguments, includes all internal nodes and <br> devices in the output. |

## See Also

```
"node" (page 305), "xref" (page 317), "opts" (page 309), ".print" (page 119), ".probe" (page 133)
```


## pathnum

options pathnum $=\{$ true | false $\}$

## Default Value

false

## Description

The pathnum option converts all node and element names in the output listings so that the subcircuit pathname portion of each name is converted to a number. An accompanying cross-reference will be printed to show the correspondence of these numbers to the fully qualified subcircuit pathnames.

## prtdel

.options prtdel $=$ prtdel $\quad$ where prtdel $\geq 0.0$

## Default Value

0.0 s

## Description

Fixed time delay between output points in transient analysis. This does not affect the internal time step calculations needed to ensure solution accuracy.

## prtinterp

```
.options prtinterp = { true | false }
```


## Default Value

## false

## Description

When the prtdel option is set, prtinterp determines how solutions are calculated at the output time intervals.

- prtinterp=0-In addition to the internal time steps, the T-Spice simulator takes time steps at the output intervals and calculates those solutions directly.
- prtinterp=1-Output solutions are computed using linear interpolation of the T-Spice engine's internal time step solutions.


## statdelay

.options statdelay = statdelay

## Default Value

$$
0.5 \mathrm{~s}
$$

## Description

Minimum delay in real time between updates of status display in the T-Spice user interface (GUI).

## tabdelim

.options tabdelim = \{ true | false \}

## Default Value

false

## Description

Toggles tab-delimited output columns.

## verbose

.options verbose $=\{0|1| 2|3| 4\}$

## Default Value

1

## Description

Level of detail of circuit and simulation information printed to the Simulation Window.

0
1

2

3

4
Lists hidden or internal devices, nodes, and options (equivalent to outputall = true), and lists convergence residual statistics (equivalent to expert = true).
If the input file contains .alter statements, then all $\log$ (listing) printouts will be given for each alter section.

## See Also

"opts" (page 309), "acct" (page 294), "node" (page 305), "outputall" (page 310)

## xref

```
.options xref = { true | false }
```


## Default Value

## false

## Description

Generates extensive cross-referencing information listings about the input circuit and simulation commands. The information includes:

- A list of all subcirctuit instances;
- A tree outline of all conditional statements (.if () ... .endif);
- A listing of all parameters (.param definitions or subcircuit parameters) that are defined and used in the circuit.


## Probing Options

| "binaryoutput" (page 319) | "probei" (page 320) |
| :--- | :--- |
| "probeq" (page 321) | "probev" (page 322) |

"probefilename" (page 323)

## binaryoutput

```
    .options binaryoutput ={0|1|2|3}
```

Default Value

3

## Description

Specifies the form of binary output created with ".probe" (page 133).

0
1
2
3

Text format.
Binary format with no compression.
Binary format using constant waveform compression.
Binary format using linear extrapolation compression.

## probei

```
.options probei = { true | false }
```

Default Value

## false

## Description

Instructs T-Spice to include device terminal current values in the output data generated by .probe and .print (when used without arguments).

## probeq

```
.options probeq = { true | false }
```


## Default Value

## false

## Description

Instructs T-Spice to include device terminal charge values in the output data generated by .probe and .print (when used without arguments).

## probev

.options probev = \{ true | false \}

## Default Value

false

## Description

Instructs T-Spice to include node voltage values in the output data generated by .probe and .print (when used without arguments).

## probefilename

.options probefilename = filename

## Default Value

fname.dat, where fname is the text output filename.

## Description

Specifies the filename for binary output produced by the .probe command.

## Verilog-A Options

"vaverbose" (page 325)
"vacache" (page 327)
"vaopts" (page 329)
"vaexprtol" (page 331)
"vasearch" (page 326)
"vaalwayscompile" (page 328)
"vatimetol" (page 330)

## vaverbose

```
.option vaverbose [ = \(\{\) true |false | 1 | 0 \}]
```


## Default Value

0

## Description

Enables or disables verbose printing of Verilog-A compiler settings, search paths, loaded modules, etc. This information is displayed in the Simulation Status window.

Possible settings are:

0 or false
1 or true

Do not print information.
Print information.

## vasearch

.option vasearch = path1 [ ; path2 [ ; ... ]]

## Default Value

None

## Description

Adds directories to the search path for Verilog-A files. Pathnames containing spaces must be enclosed in quotes.

T-Spice looks for Verilog-A files in the following default order:

1. Current working directory (directory containing the T-Spice input file)
2. Path(s) specified in the Simulation Settings dialog
3. Path(s) specified by the .option vasearch command
4. . IverilogA\models subdirectory of the local T-Spice installation

## vacache

```
.option vacache [ = { true | false | 1| 0}]
```


## Default Value

0

## Description

Enables or disables the Verilog-A CML (compiled model library) file-caching mechanism.
Possible settings are:

0 or false Do not cache CML files.
1 or true Cache CML files.

Verilog-A modules are automatically compiled when loaded, and the CML files resulting from compilation are cached for future use.

When vacache is set to false or $\mathbf{0}$, CML files are placed in .lib.win32, a subdirectory of the current working directory (directory containing the T-Spice input file).

When vacache is set to true or 1, CML files are placed in C:\Documents and Settings $\backslash$ username\Application Data\Tanner EDAl.tanner-model-cache.

## See Also

"vaalwayscompile" (page 328)

## vaalwayscompile

```
.option vaalwayscompile [ = { true | false | 1| 0 }]
```


## Default Value

0

## Description

Enables or disables forced recompilation of each Verilog-A file, even when the CML (compiled model library) file is up-to-date.

Possible settings are:
$\mathbf{0}$ or false Do not recompile Verilog-A files when the CML file is up-to-date.
1 or true Always recompile Verilog-A files.

When vaalwayscompile is set to false or $\mathbf{0}$, a new simulation recompiles the Verilog-A module code only if (a) the code has changed, (b) the include files have changed, (c) the vacomp compiler version has changed, or (d) the CML cache directory or file has been deleted.

## See Also

> "vacache" (page 327)

## vaopts

## .option vaopts = "options"

## Default Value

None

## Description

Passes options to the vacomp compiler.
Note that the default vacomp options are adequate for almost all situations. The ability to set vacomp options with the .option vaopts command is provided for advanced users only, and should be used with caution.

Strings of multiple options must be enclosed in quotes. For example: .option vaopts="-strict -G".
The options are:

| -f | Disable run-time floating point checking |
| :--- | :--- |
| -o file | Specify compiled model library file name (defaults to inputfile.cmI) |
| -strict | Reject non-compliant language extensions |
| -B | Force state variable creation for named branches |
| -D $\boldsymbol{x}$ | Define preprocessor macro $\boldsymbol{x}$ with value 1 |
| -D $\boldsymbol{x}=\boldsymbol{y}$ | Define preprocessor macro $\boldsymbol{x}$ with value $\boldsymbol{y}$ |
| -E | Run preprocessor; output to stdout |
| -G | Make all variables available for output |
| -I directory | Prepend directory to include search path |
| -M | Generate dependency file |
| -N | Suppress banner reporting |
| -P file | Run preprocessor; output to file |
| -U depth | Unroll genvar loops to level depth (0 .. no unrolling) |
| -V level | Status message reporting level; level = $0 . .2$ (default 1 ) |
| -W level | Warning message reporting level; level = 0..2 (default 1 ) |

## vatimetol

.option vatimetol = tolerance

## Default Value

10 * mintimestep

## Description

Sets the default time tolerance (time_tol) for the Verilog-A cross(), timer(), and above() functions.

## See Also

mintimestep

## vaexprtol

.option vaexprtol = tolerance

## Default Value

absv

## Description

Sets the default expression tolerance (expr_tol) for the Verilog-A cross() and above() functions.

## See Also

"absv | vntol" (page 207)

## 8 Device Models

## Introduction

This chapter describes the predefined analytical device models. Original documentation from the developers of the models is provided with T-Spice for further reference, in the docs/models folder of the installation directory, and at Additional Model Documentation.

The T-Spice built-in device models are distributed as a collection of external dynamically linked libraries (DLLs) located in the tspicemodels subdirectory of the installation. This modularization improves the performance, quality and features of all built-in device models.

## BIPOLAR Level/Model Cross Reference

T-Spice supports a number of different bipolar models, which are selectable using the level parameter in the .model statement. The association between model levels and the model type is shown in the following table.

| Bipolar <br> level | Model | Further Documentation |
| :--- | :--- | :--- |
| $\mathbf{1}$ | Gummel-Poon | BJT Level 1 (Gummel-Poon) (page 338) |
| $\mathbf{6}$ | Philips Mextram | BJT Level 6 (Mextram) (page 358) |
| $\mathbf{9}$ | VBIC | BJT Level 9 (VBIC) (page 359) |
| $\mathbf{1 0}$ | Philips Modella Lateral PNP | BJT Level 10 (Modella) (page 364) |

## Diode Level/Model Cross Reference

The diode models which are supported by T-Spice, together with their model level associations, are shown in the follwowing table.
Diode Model Further Documentation
level

| Diode <br> level | Model | Further Document |
| :--- | :--- | :--- |
| $\mathbf{2}$ | Fowler-Nordheim | Diode (page 368) |
| $\mathbf{3}$ | Geometric Junction Diode | Diode (page 368) |
| $\mathbf{4}$ | Philips Juncap 2 | Diode (page 368) |
| $\mathbf{2 0 0}$ | Philips Advanced Diode | Diode (page 368) |

## JFET \& MESFET Level/Model Cross Reference

The diode models which are supported by T-Spice, together with their model level associations, are shown in the follwowing table.

| JFET/ <br> MESFET <br> level | Model | Further Documentation |
| :--- | :--- | :--- |
| $\mathbf{0}$ | Schichmann and Hodges JFET | JFET (page 382) |
| $\mathbf{1}$ | Curtice MESFET | MESFET (page 385) |
| $\mathbf{2}$ | Statz MESFET | MESFET (page 385) |
| $\mathbf{3}$ | Curtice GaAs MESFET | MESFET (page 385) |

## MOSFET Level/Model Cross Reference

Particular MOSFET models are selected by use of the level parameter in the .model statement. The association between model levels and the model type is shown in the following table.

Note:
Some models can be referenced using more than one level number. This does not imply that the models are different. It is usually the case that the additional level is added for compatibility of input files from other simulators (Berkeley SPICE, HSPICE ${ }^{\circledR}$, PSPICE ${ }^{\circledR}$, etc.). For example, the EKV model can be selected as either MOSFET level 44, for SmartSpice compatibility, or as level 55, for HSPICE compatibility.

## MOSFET Model

## Further documentation

level

| MOSFET <br> level | Model | Further documentation |
| :---: | :---: | :---: |
| 2 | SPICE level 2 | MOSFET Levels 1/2/3 (Berkeley SPICE 2G6) (page 395) |
| 3 | SPICE level 3 | MOSFET Levels 1/2/3 (Berkeley SPICE 2G6) (page 395) |
| 4 | BSIM1 | MOSFET Levels 4 and 13 (BSIM1) (page 412) |
| 5 | proprietary Maher-Mead model | MOSFET Level 5 (Maher-Mead) (page 416) |
| 8 | BSIM3 v3.3 - strict Berkeley implementation without extensions | MOSFET Levels 8, 49 and 53 (BSIM3 Revision 3.3) (page 418) |
| 9 | Philips MOS 9 (identical to level 50) | MOSFET Level 20 (Philips MOS 20) (page 439) |
| 11 | Philips MOS 11 (identical to level 63) | MOSFET Levels 11 and 63 (Philips MOS 11) (page 428) |
| 13 | BSIM1 | MOSFET Levels 4 and 13 (BSIM1) (page 412) |
| 14 | BSIM4 v4.5 (identical to level 54) | Variables for which equations are not given here are as follows. (page 426) |
| 15 | RPI Amorphous-Si TFT Model | MOSFET Levels 15 and 61 (RPI Amorphous-Si TFT Model) (page 432) |
| 16 | RPI Poly-Si TFT Model (equivalent to AimSpice level 16 PSIA2) | MOSFET Levels 16 and 62 (RPI Poly-Si TFT Model, 1.0 and 2.0) (page 435) |
| 20 | Philips MOS 20 | MOSFET Level 20 (Philips MOS 20) (page 439) |
| 28 | BSIM1 with extensions | MOSFET Level 28 (Extended BSIM1) (page 440) |
| 30 | Philips MOS 30 | MOSFET Level 40 (Philips MOS 40) (page 446) |
| 31 | Philips MOS 31 | MOSFET Level 31 (Philips MOS 31) (page 445) |
| 40 | Philips MOS 40 | MOSFET Level 40 (Philips MOS 40) (page 446) |
| 44 | EKV v2.6 (identical to level 55) | .MOSFET Levels 44 and 55 (EKV Revision 2.6) (page 447) |
| 47 | BSIM3 v2 | MOSFET Level 47 (BSIM3 Revision 2) (page 448) |
| 49 | BSIM3 v3.3 with HSPICE extensions | MOSFET Levels 8, 49 and 53 (BSIM3 Revision 3.3) (page 418) |
| 53 | BSIM3 v3.3 with limited HSPICE extension support (ACM, tnom, etc.) | MOSFET Levels 8, 49 and 53 (BSIM3 Revision 3.3) (page 418) |
| 54 | BSIM4 v4.5 (identical to level 14) | Variables for which equations are not given here are as follows. (page 426) |
| 55 | EKV v2.6 (identical to level 44) | MOSFET Levels 44 and 55 (EKV Revision 2.6) (page 447) |
| 57 | BSIM3SOI v3.2 | MOSFET Level 57 (BSIM3SOI) (page 453) |
| 100 | PSP | MOSFET Level 100 (Penn State \& Philips PSP Model) (page 456) |

## Philips Model Cross Reference

T-Spice supports most of the models that are available in the Philips SiMKit compact transistor model library. The SiMKit library contains a variety of diode, bipolar, and MOSFET models, and has been made freely available to the circuit and model design community.

## Note:

The Philips models do not support table-based model evaluation, or HSPICE extensions (ACM, HSPICE diodes, etc.)

In order to facilitate easy selection of Philips models, an additional parameter has been added to the .model statement: model=modelname. The modelname value will determine the Philips model which will be selected, and will override the level and version parameter values in the .model statement, if they are present. The possible values for modelname are listed in the following table. In this table, the $\mathbf{e} /$ $\mathbf{g}$ column notes whether the model is electrical or geometrical; the thermal column states whether the model includes self-heating equations; and the substrate column states whether it is a bipolar model which includes the substrate current and charge terms.

| Model | Type | Level | Modelname | $e / g$ | Ther <br> mal | Subs trate |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| Juncap Level 1 | d | 1 | juncap | e |  |  |
| Juncap2 Level 200 | d | 200 | juncap200 | e |  |  |
| Advanced Diode Level 500 | d | 500 | dio500 | e |  |  |
| Modella | pnp | 500 | bjt500 | e |  | yes |
|  |  |  | bjt500t | e | yes | yes |
| Mextram Level 503 | npn/pnp | 503 | bjt503 | e |  | yes |
|  |  |  | bjtd503 | e |  |  |
| Mextram Level 504 | npn/pnp | 504 | bjt504 | e |  | yes |
|  |  |  | bjt504t | e | yes | yes |
|  |  |  | bjtd504 | e |  |  |
|  |  |  | bjtd504t | e | yes |  |
| PSP Level 100.1 | nmos/pmos | 100 | psp100 or psp100e | e |  |  |
|  |  | 1000 | $\begin{aligned} & \text { psp1000 or } \\ & \text { psp100g } \end{aligned}$ | g |  |  |
| Mos 11 Level 1100 | nmos/pmos | 1100 | mos1100e | e |  |  |
|  |  |  | $\operatorname{mos} 1100$ | g |  |  |


| Model | Type | Level | Modelname | $e / g$ | Ther <br> mal | Subs <br> trate |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| Mos 11 Level 1101 | nmos/pmos | 1101 | mos1101e | e |  |  |
|  |  |  | mos1101et | e | yes |  |
|  |  | 11010 | mos11010 | g |  |  |
|  |  |  | mos11010t | g | yes |  |
|  | (binning) | 11011 | mos11011 | g |  |  |
|  |  |  | mos11011t | g | yes |  |
| Mos 11 Level 1102 | nmos/pmos | 1102 | mos1102e | e |  |  |
|  |  |  | mos1102et | e | yes |  |
|  |  |  | mos11020 | g |  |  |
|  |  |  | mos11020t | g | yes |  |
|  | (binning) | 11021 | mos11021 | g |  |  |
|  |  |  | mos11021t | g | yes |  |
| Mos 20 Level 2001 | nmos/pmos | 2001 | mos2001e | e |  |  |
|  |  |  | mos2001et | e | yes |  |
|  |  |  | mos2001 | g |  |  |
|  |  |  | mos2001t | g | yes |  |
| Mos 31 Level 3100 | nmos/pmos | 3100 | mos3100 | e |  |  |
|  |  |  | mos3100t | e | yes |  |
| Mos 40 Level 40 | nmos/pmos | 40 | mos40 | e |  |  |
|  |  |  | mos40t | e | yes |  |
| Mos 30 Level 3002 | nmos/pmos | 3002 | mos3002 | e |  |  |
| Mos 9 Level 902 | nmos/pmos | 902 | mos902e | e |  |  |
|  |  |  | mos902 | g |  |  |
| Mos 9 Level 903 | nmos/pmos | 903 | mos903e | e |  |  |
|  |  |  | mos903 | g |  |  |

## Model Descriptions

For each model class, the following information is typically given.

- The .model command to be used in the input file. The .model command initializes the model by specifying its name, type, level, and parameter values.
- The parameters that determine the model's characteristics. These are given in a table of parameter names (as used in the code), symbols (as used in the equations), descriptions, default values, and units.
- The circuit underlying the large-signal behavior of the model.
- The analytical equations that constitute the model.

The following abbreviations and conventions are employed.
| (Vertical bar.) In syntax paradigms, separates alternative values. In parameter tables, separates alternative names (aliases).
Computed. Indicates a parameter whose value is computed, not fixed or assigned.
[n] Indicates the NMOS value of a parameter.
[p] Indicates the PMOS value of a parameter.
Symbol for square.
DIBL Abbreviation for drain-induced barrier lowering.
LDD
Abbreviation for lightly-doped drain.

## Constants

The following physical constants are used in parameter and equation evaluation.

| Constant | Description | Value | Units |
| :---: | :---: | :---: | :---: |
| $\varepsilon 0$ | Dielectric permittivity of vacuum | $\begin{aligned} & 8.85421 \times \\ & 10^{-12} \end{aligned}$ | F/m |
| عox | Relative dielectric permittivity of $\mathrm{SiO}_{2}$ | 3.9 | - |
| Esi | Relative dielectric permittivity of silicon | 11.7 | - |
| $n i$ | Intrinsic carrier concentration at 300 K | $1.45 \times 10^{16}$ | $\mathrm{m}^{-3}$ |
| $q$ | Elementary electron charge | $\begin{aligned} & 1.6021918 \times \\ & 10^{-19} \end{aligned}$ | C |
| $\pi$ | Pi | 3.1415926 | - |
| $k$ | Boltzmann's constant | $\begin{aligned} & 1.3806226 \times \\ & 10^{-23} \end{aligned}$ | V•C/K |
| - | $0{ }^{\circ} \mathrm{C}$ | 273.15 | K |
| Tnom | Default nominal model temperature | Specified by .options tnom (default: 25) | ${ }^{\circ} \mathrm{C}$ |
| e | Base of natural logarithms | 2.7182818 | - |

## BJT Level 1 (Gummel-Poon)

The level 1 bipolar junction transistor model uses a modified version of the Gummel-Poon chargecontrol model that was implemented in the original SPICE. The model simplifies to the Ebers-Moll model when certain parameters are not specified. It also includes high-bias and temperature effects.

Note: $\quad$ Gummel-Poon is the default model which will be used for all bipolar models (type npn or pnp) which do not have the level model parameter set.

## Parameters

The BJT model uses the following syntax.
.model name npn|pnp [level=1] [parameters]
The following tables describe all of the Gummel-Poon BJT parameters that T-Spice supports. Parameters that are not specified in the Ebers-Moll model are marked with an asterisk (*).

## DC Current Parameters

| Parameter (alias) | Symbol | Description | Default | Units |
| :---: | :---: | :---: | :---: | :---: |
| level |  | Model selector | 1.0 | - |
| subs |  | Substrate connection selector | $\begin{aligned} & 1(\mathrm{npn}) ; \\ & -1(\mathrm{pnp}) \end{aligned}$ | - |
| update |  | Equation selector for base charge. | 0 | - |
| dcap |  | Equation selector for depletion capacitance. | 2 | - |
| bf | $\beta f$ | Ideal forward maximum current gain. | 100.0 | - |
| br | $\beta_{r}$ | Ideal reverse maximum current gain. | 1.0 | - |
| ibc | $\mathrm{I}_{\mathrm{bc}}$ | Reverse saturation current between base and collector. | 0.0 | A |
| ibe | $\mathrm{I}_{\text {be }}$ | Reverse saturation current between base and emitter. | 0.0 | A |
| iss | $\mathrm{I}_{\text {ss }}$ | Reverse saturation current between bulk and collector for vertical geometry, or between bulk and base for lateral geometry | 0.0 | A |
| is | $\mathrm{I}_{\text {s }}$ | Transport saturation current. | $1.0 \times 10^{-16}$ | A |
| c2 (jle) | $\mathrm{C}_{2}$ | Non-ideality factor for base-emitter leakage saturation current.* | 0.0 | - |
| c4 | $\mathrm{C}_{4}$ | Non-ideality factor for base-collector leakage saturation current.* |  | - |
| ise | $\mathrm{I}_{\text {se }}$ | Base-emitter leakage saturation current.* | c2xis | A |
| isc | $\mathrm{I}_{\text {sc }}$ | Base-collector leakage saturation current.* | c4×is | A |
| nf | $\eta_{\text {f }}$ | Forward current emission coefficient.* | 1.0 | - |
| nr | $\eta_{\mathrm{r}}$ | Reverse current emission coefficient.* | 1.0 | - |
| ns | $\eta_{\text {s }}$ | Substrate current emission coefficient. | 1.0 | - |
| nc (nic) | $\eta_{\text {c }}$ | Base-collector leakage emission coefficient.* | 2.0 | - |
| ne (nle) | $\eta_{\text {e }}$ | Base-emitter leakage emission coefficient.* | 1.5 | - |
| expli | EXPLI | Current explosion model parameter. The PN junction characteristics above the explosion current area are linear, with the slope at the explosion point. | $1.0 \times 10^{15}$ | A |

## Base Charge Parameters

Base charge parameters are not specified for the Ebers-Moll model.

| Parameter <br> (alias) | Symbol | Description | Default | Units |
| :---: | :---: | :---: | :---: | :---: |
| vaf (vbf) | Vaf | Forward early voltage.* | 0.0 (indicates <br> infinite <br> value) | V |
| var (vb, vbb) | $\mathrm{V}_{\mathrm{ar}}$ | Reverse early voltage.* | 0.0 (indicates infinite value) | V |
| $\begin{aligned} & \text { ikf, } \\ & \text { (ikf) } \end{aligned}$ | $\mathrm{I}_{\mathrm{kf}}$ | Corner for forward Beta high current roll-off.* | 0.0 (indicates infinite <br> value) | A |
| ikr (jbr) | $\mathrm{I}_{\mathrm{kr}}$ | Corner for reverse Beta high current roll-off.* | 0.0 (indicates infinite <br> value) | A |
| nkf | $\eta_{\text {kf }}$ | Exponent for high current Beta roll-off.* | 0.5 |  |

## Parasitic Resistor Parameters

| Parameter <br> (alias) | Symbol | Description | Default | Units |
| :--- | :--- | :--- | :--- | :--- |
| irb <br> (jrb,iob) | Irb | Base current, where base resistance falls <br> halfway between $r_{b}$ and $r b m .^{*}$ | 0.0 (indicates <br> infinite <br> value) | A |
| rb | $\mathrm{r}_{\mathrm{b}}$ | Base resistance.* | 0.0 | $\Omega$ |
| rbm | $\mathrm{r}_{\mathrm{bm}}$ | Minimum high current base resistance.* | rb | $\Omega$ |
| re | $\mathrm{r}_{\mathrm{e}}$ | Emitter resistance. | 0.0 | $\Omega$ |
| rc | $\mathrm{r}_{\mathrm{c}}$ | Collector resistance. | 0.0 | $\Omega$ |

## Parasitic Capacitance Parameters

Parasitic capacitances are only used in the direct evaluation method of circuit analysis. They do not contribute to analysis in table mode.

| Parameter | Symbol | Description | Default | Units |
| :--- | :--- | :--- | :--- | :--- |
| cbcp | $C B C P$ | External base-collector constant capacitance. | 0.0 | F |
| cbep | CBEP | External base-emitter constant capacitance. | 0.0 | $\Phi$ |
| $\boldsymbol{c c s p}$ | CCSP | External collector-substrate (vertical) or base- <br> substrate (lateral) constant capacitance. | 0.0 | $\Phi$ |

## Junction Capacitance Parameters

| Parameter (alias) | Symbol | Description | Default | Units |
| :---: | :---: | :---: | :---: | :---: |
| cjc | Cjc | Base-collector zero-bias depletion capacitance. | 0.0 | F |
| cje | $\mathrm{C}_{\text {je }}$ | Base-emitter zero-bias depletion capacitance. | 0.0 | Ф |
| cjs <br> (ccs, csub) | $\mathrm{C}_{\mathrm{j} \text { s }}$ | Zero-bias collector-substrate capacitance. | 0.0 | $\Phi$ |
| fc | FC | Coefficient for forward bias depletion capacitance. | 0.5 |  |
| mjc (mc) | $\mathrm{m}_{\mathrm{jc}}$ | Base-collector junction exponent (grading factor). | 0.33 |  |
| mje (me) | $\mathrm{m}_{\mathrm{je}}$ | Base-emitter junction exponent (grading factor). | 0.33 |  |
| mjs (esub) | $\mathrm{m}_{\mathrm{js}}$ | Substrate junction exponent (grading factor). | 0.5 |  |
| vjc (pc) | $\mathrm{V}_{\mathrm{jc}}$ | Base-collector built-in potential. | 0.75 | V |
| vje (pe) | $\mathrm{V}_{\mathrm{je}}$ | Base-emitter built-in potential. | 0.75 | V |
| vjs (psub) | $\mathrm{V}_{\mathrm{j}}$ | Substrate junction built-in potential. | 0.75 | V |
| xcjc (cdis) | $\mathrm{X}_{\text {cjc }}$ | Internal base fraction of base-collector depletion capacitance. | 1.0 |  |

Transit Time parameters

| Parameter <br> (alias) | Symbol | Description | Default | Units |
| :--- | :--- | :--- | :--- | :--- |
| $\mathbf{p t f}$ | $\mathrm{P}_{\mathrm{tf}}$ | Frequency multiplier to determine excess phase. | 0.0 | deg. |
| $\mathbf{t f}$ | $\tau_{\mathrm{f}}$ | Base forward transit time. | 0.0 | s |
| $\mathbf{t r}$ | $\tau_{\mathrm{r}}$ | Base reverse transit time. | 0.0 | s |
| $\mathbf{v t f}$ | $\mathrm{~V}_{\mathrm{tf}}$ | Voltage for $V_{b c}$ dependence of $\tau_{f}$ | 0.0 (indicates <br> infinite | s |
|  |  |  | value) |  |
| $\mathbf{x t f}$ | $\mathrm{X}_{\mathrm{tf}}$ | Coefficient for bias dependence of $\tau f$. | 0.0 |  |
| itf (jff) | $I t f$ | Parameter for high-current effect on $\tau_{f}$ | 0.0 | A |

## Noise Parameters

| Parameter | Symbol | Description | Default |
| :--- | :--- | :--- | :--- |
| af | $A F$ | Flick noise exponent. | 1.0 |
| kf | KF | Flick noise exponent. | 0.0 |

Temperature Effect Parameters

| Parameter (alias) | Symbol | Description | Default | Units |
| :---: | :---: | :---: | :---: | :---: |
| tnom <br> (tref) | $\mathrm{T}_{\text {nom }}$ | Nominal temperature | global tnom (25.0) | deg |
| tlev | tlev | Temperature equation selector | 0 |  |
| tlevc | tleve | Temperature equation selector for junction capacitances and potentials | 0 |  |
| bex | Bex | $V 0$ temperature exponent. (Level 2 only.) | 2.42 |  |
| bexv | $\mathrm{B}_{\text {exv }}$ | $R c$ temperature exponent. (tlev=2 only.) | 1.90 |  |
| ctc | $\mathrm{C}_{\text {tc }}$ | Temperature coefficient for zero-bias basecollector capacitance. | 0.0 | 1/deg |
| cte | $\mathrm{C}_{\text {te }}$ | Temperature coefficient for zero-bias baseemitter capacitance. | 0.0 | 1/deg |
| cts | $\mathrm{C}_{\text {ts }}$ | Temperature coefficient for zero-bias substrate capacitance. | 0.0 | $1 / \delta \varepsilon \gamma$ |
| eg | $\mathrm{Eg}_{\mathrm{g}}(0)$ | $\begin{aligned} & \text { Energy gap at } 0^{\circ} \mathrm{K} \\ & \text { for tlev }=\mathbf{2}(\text { default }) \\ & \text { for tlev }=\mathbf{0}, \mathbf{1} \text {, or } 3 \text { : } \end{aligned}$ | $\begin{aligned} & 1.16 \\ & 1.11 \end{aligned}$ | eV |
| gap1 | GAP1 | Coefficient in energy gap temperature equation | $7.02 \times 10^{-4}$ | eV/deg |
| gap2 | GAP2 | Coefficient in energy gap temperature equation | 1108.0 | deg |
| tbf1 <br> tbf2 | $\begin{aligned} & \mathrm{TBF}_{1} \\ & \mathrm{TBF}_{2} \end{aligned}$ | First order and second order temperature coefficients for $\beta_{f}$. | $\begin{aligned} & 0.0 \\ & 0.0 \end{aligned}$ | 1/deg $1 / \operatorname{deg}^{2}$ |
| tbr1 <br> tbr2 | $\begin{aligned} & \mathrm{TBR}_{1} \\ & \mathrm{TBR}_{2} \end{aligned}$ | First order and second order temperature coefficients for $\beta r$. | $\begin{aligned} & 0.0 \\ & 0.0 \end{aligned}$ | 1/deg $1 / \operatorname{deg}^{2}$ |
| tikf1 <br> tikf2 | TIKF $_{1}$ <br> $\mathrm{TIKF}_{2}$ | First order and second order temperature coefficients for $I k f$. | $\begin{aligned} & 0.0 \\ & 0.0 \end{aligned}$ | 1/deg $1 / \operatorname{deg}^{2}$ |
| tikr1 <br> tikr2 | TIKR $_{1}$ <br> $\mathrm{TIKR}_{2}$ | First order and second order temperature coefficients for $I k r$. | $\begin{aligned} & 0.0 \\ & 0.0 \end{aligned}$ | 1/deg $1 / \mathrm{deg}^{2}$ |
| tirb1 <br> tirb2 | $\begin{aligned} & \operatorname{TIRB}_{1} \\ & \operatorname{TIRB}_{2} \end{aligned}$ | First order and second order temperature coefficients for Irb. | $\begin{aligned} & 0.0 \\ & 0.0 \end{aligned}$ | 1/deg $1 / \operatorname{deg}^{2}$ |


| Parameter (alias) | Symbol | Description | Default | Units |
| :---: | :---: | :---: | :---: | :---: |
| tisc1 <br> tisc2 | $\begin{aligned} & \mathrm{TISC}_{1} \\ & \mathrm{TISC}_{2} \end{aligned}$ | First order and second order temperature coefficients for Isc. (tlev=3 only.) | $\begin{aligned} & 0.0 \\ & 0.0 \end{aligned}$ | 1/deg $1 / \mathrm{deg}^{2}$ |
| tis1 tis2 | $\begin{gathered} \mathrm{TIS}_{1} \\ \mathrm{TIS}_{2} \end{gathered}$ | First order and second order temperature coefficients for $I s$ or $I b e$ and $I b c$. (tlev=3 only). | $\begin{aligned} & 0.0 \\ & 0.0 \end{aligned}$ | 1/deg $1 / \mathrm{deg}^{2}$ |
| tise1 tise2 | TISE1 <br> TISE2 | First order and second order temperature coefficients for Ise. (tlev=3 only) | $\begin{aligned} & 0.0 \\ & 0.0 \end{aligned}$ | 1/deg $1 / \mathrm{deg}^{2}$ |
| tiss 1 <br> tiss2 | $\begin{aligned} & \operatorname{TISS}_{1} \\ & \mathrm{TISS}_{2} \end{aligned}$ | First order and second order temperature coefficients for Iss (tlev=3 only). | $\begin{aligned} & 0.0 \\ & 0.0 \end{aligned}$ | 1/deg $1 / \mathrm{deg}^{2}$ |
| titf1 <br> titf2 | $\begin{aligned} & \operatorname{TITF}_{1} \\ & \mathrm{TITF}_{2} \end{aligned}$ | First order and second order temperature coefficients for $I t f$. | $\begin{aligned} & 0.0 \\ & 0.0 \end{aligned}$ | 1/deg <br> $1 / \operatorname{deg}^{2}$ |
| $\begin{aligned} & \text { tmjc1 } \\ & \text { tmjc2 } \end{aligned}$ | $\begin{aligned} & \mathrm{TMJC}_{1} \\ & \mathrm{TMJC}_{2} \end{aligned}$ | First order and second order temperature coefficients for $m j c$. | $\begin{aligned} & 0.0 \\ & 0.0 \end{aligned}$ | 1/deg $1 / \mathrm{deg}^{2}$ |
| tmje1 <br> tmje2 | $\mathrm{TMJE}_{1}$ $\mathrm{TMJE}_{2}$ | First order and second order temperature coefficients for mje. | $\begin{aligned} & 0.0 \\ & 0.0 \end{aligned}$ | 1/deg $1 / \operatorname{deg}^{2}$ |
| $\begin{aligned} & \text { tmjs1 } \\ & \text { tmjs2 } \end{aligned}$ | $\mathrm{TMJS}_{1}$ $\mathrm{TMJS}_{2}$ | First order and second order temperature coefficient for $m j s$. | $\begin{aligned} & 0.0 \\ & 0.0 \end{aligned}$ | 1/deg <br> $1 / \operatorname{deg}^{2}$ |
| $\begin{aligned} & \text { tnc1 } \\ & \text { tnc2 } \end{aligned}$ | $\begin{aligned} & \mathrm{TNC}_{1} \\ & \mathrm{TNC}_{2} \end{aligned}$ | First order and second order temperature coefficients for $\eta c$. | $\begin{aligned} & 0.0 \\ & 0.0 \end{aligned}$ | 1/deg $1 / \operatorname{deg}^{2}$ |
| tne1 <br> tne2 | $\begin{aligned} & \mathrm{TNE}_{1} \\ & \mathrm{TNE}_{2} \end{aligned}$ | First order and second order temperature coefficients for $\eta e$. | $\begin{aligned} & 0.0 \\ & 0.0 \end{aligned}$ | 1/deg $1 / \operatorname{deg}^{2}$ |
| $\begin{aligned} & \text { tnf1 } \\ & \text { tnf2 } \end{aligned}$ | $\begin{aligned} & \mathrm{TNF}_{1} \\ & \mathrm{TNF}_{2} \end{aligned}$ | First order and second order temperature coefficients for $\eta_{f}$. | $\begin{aligned} & 0.0 \\ & 0.0 \end{aligned}$ | 1/deg <br> $1 / \operatorname{deg}^{2}$ |
| $\begin{aligned} & \text { tnr1 } \\ & \text { tnr2 } \end{aligned}$ | $\begin{aligned} & \mathrm{TNR}_{1} \\ & \mathrm{TNR}_{2} \end{aligned}$ | First order and second order temperature coefficients for $\eta r$. | $\begin{aligned} & 0.0 \\ & 0.0 \end{aligned}$ | 1/deg $1 / \operatorname{deg}^{2}$ |
| $\begin{aligned} & \text { tns1 } \\ & \text { tns2 } \end{aligned}$ | $\begin{aligned} & \mathrm{TNS}_{1} \\ & \mathrm{TNS}_{2} \end{aligned}$ | First order and second order temperature coefficients for $\eta s$. | $\begin{aligned} & 0.0 \\ & 0.0 \end{aligned}$ | 1/deg $1 / \mathrm{deg}^{2}$ |
| $\begin{aligned} & \text { trb1 } \\ & \text { trb2 } \end{aligned}$ | $\begin{aligned} & \mathrm{TRB}_{1} \\ & \mathrm{TRB}_{2} \end{aligned}$ | First order and second order temperature coefficients for $r b$. | $\begin{aligned} & 0.0 \\ & 0.0 \end{aligned}$ | 1/deg <br> $1 / \operatorname{deg}^{2}$ |
| $\begin{aligned} & \operatorname{trc} 1 \\ & \operatorname{trc} 2 \end{aligned}$ | $\begin{aligned} & \mathrm{TRC}_{1} \\ & \mathrm{TRC}_{2} \end{aligned}$ | First order and second order temperature coefficients for $r c$. | $\begin{aligned} & 0.0 \\ & 0.0 \end{aligned}$ | 1/deg $1 / \operatorname{deg}^{2}$ |
| tre1 <br> tre2 | $\begin{aligned} & \mathrm{TRE}_{1} \\ & \mathrm{TRE}_{2} \end{aligned}$ | First order and second order temperature coefficients for $r e$. | $\begin{aligned} & 0.0 \\ & 0.0 \end{aligned}$ | 1/deg $1 / \mathrm{deg}^{2}$ |
| $\begin{aligned} & \operatorname{trm} 1 \\ & \text { trm2 } \end{aligned}$ | $\begin{aligned} & \mathrm{TRM}_{1} \\ & \mathrm{TRM}_{2} \end{aligned}$ | First order and second order temperature coefficients for rbm. | $\begin{aligned} & \operatorname{trb} 1 \\ & \operatorname{trb} 2 \end{aligned}$ | 1/deg <br> $1 / \mathrm{deg}^{2}$ |
| $\begin{aligned} & \text { ttf1 } \\ & \text { ttf2 } \end{aligned}$ | $\begin{aligned} & \mathrm{TTF}_{1} \\ & \mathrm{TTF}_{2} \end{aligned}$ | First order and second order temperature coefficients for $\tau f$. | $\begin{aligned} & 0.0 \\ & 0.0 \end{aligned}$ | 1/deg <br> $1 / \mathrm{deg}^{2}$ |
| $\begin{aligned} & \mathrm{ttr} 1 \\ & \mathrm{ttr} 2 \end{aligned}$ | $\begin{aligned} & \mathrm{TTR}_{1} \\ & \mathrm{TTR}_{2} \end{aligned}$ | First order and second order temperature coefficients for $\tau r$. | $\begin{aligned} & 0.0 \\ & 0.0 \end{aligned}$ | 1/deg $1 / \mathrm{deg}^{2}$ |


| Parameter <br> (alias) | Symbol | Description | Default | Units |
| :---: | :---: | :---: | :---: | :---: |
| tvaf1 <br> tvaf2 | $\begin{aligned} & \mathrm{TVF}_{1} \\ & \mathrm{TVF}_{2} \end{aligned}$ | First order and second order temperature coefficients for Vaf. | $\begin{aligned} & 0.0 \\ & 0.0 \end{aligned}$ | 1/deg <br> $1 / \operatorname{deg}^{2}$ |
| tvar1 <br> tvar2 | $\begin{aligned} & \mathrm{TVR}_{1} \\ & \mathrm{TVR}_{2} \end{aligned}$ | First order and second order temperature coefficients for Var. | $\begin{aligned} & 0.0 \\ & 0.0 \end{aligned}$ | 1/deg $1 /$ deg $^{2}$ |
| tvjc | $\mathrm{T}_{\mathrm{vjc}}$ | Temperature coefficient for Vjc. | 0.0 | V/deg |
| tvje | $\mathrm{T}_{\mathrm{vje}}$ | Temperature coefficient for $V_{j e}$. | 0.0 | V/deg |
| tvjs | $\mathrm{T}_{\mathrm{vjs}}$ | Temperature coefficient for Vjs. | 0.0 | V/deg |
| xtb <br> (tb, tcb) | $\mathrm{X}_{\mathrm{tb}}$ | Forward and reverse Beta temperature exponent. | 0.0 |  |
| xti | $\mathrm{X}_{\text {ti }}$ | Saturation current temperature exponent. (Use $X t i=3.0$ for Silicon diffused junction, and $X t i=2.0$ for Schottky barrier diode.) | 3.0 |  |

## Large-Signal Model



## Equations

The Gummel-Poon model includes four "second-order" current effects:

- The low-current drop in current gain $\beta$ is due to extra components of base current $I B$. The parameters $I_{s e}, \eta_{e}$ (the low current drop in $\beta_{f}$ ) and $I_{s c}, \eta c$ (the low current drop in $\beta_{r}$ ) describe this effect, and two non-ideal diodes are included in the Large-Signal Model, above as shown.
- Base-width modulation, affecting the BJT output conductance, is described by $V_{a r}$ (reverse Early voltage) and $V_{a f}$ (forward Early voltage).
- High-level injection, modifying the slope of the $\log (I C)$ vs. $V_{b e}$ characteristic, is described by two "knee" currents, $I_{k f}$ and $I_{k r}$, for the forward and reverse regions of operation.
- Base resistance is current dependent and is modeled by a combination of $r_{b}, r_{b m}$, and $I_{r b}$.

The Gummel-Poon large-signal model for transient simulations is topologically identical to the EbersMoll large-signal model except for the inclusion of the distributed base-collector capacitance. In addition, the effect of $\tau_{f}$ modulation (transit time) is handled.

## Geometry Consideration

The BJT model has two geometric configurations based on physical layout: vertical and lateral. The geometric configuration is specified by the substrate connection selector parameter, subs. Set subs equal to 1 to specify vertical geometry or to -1 to specify lateral geometry. The default value of subs is 1 for npn transistors and -1 for pnp transistors.

The instance parameters area, areab, areac, and $\mathbf{M}$ specify geometric scaling for current and charge values in the Gummel-Poon BJT. (See "BJT (q)" on page 152 for more information about these parameters.)

## Scaling: Both Vertical and Lateral Geometry

$$
\begin{aligned}
I_{s_{e f f}} & =\operatorname{area} \cdot M \cdot I_{s} \\
I_{b e_{e f f}} & =\operatorname{area} \cdot M \cdot I_{b e} \\
I_{\text {sefff }} & =\operatorname{area} \cdot M \cdot I_{\text {se }} \\
I_{k f_{e f f}} & =\operatorname{area} \cdot M \cdot I_{k f} \\
I_{k r_{e f f}} & =\operatorname{area} \cdot M \cdot I_{k r} \\
I_{r b_{e f f}} & =\operatorname{area} \cdot M \cdot I_{r b} \\
I_{s s_{e f f}} & =\operatorname{area} \cdot M \cdot I_{s s} \quad \text { if both } I_{b e} \text { and } I_{b c} \text { are NOT specified } \\
I_{t f e f f} & =\operatorname{area} \cdot M \cdot I_{t f}
\end{aligned}
$$

$$
\begin{equation*}
E X P L I_{e f f}=\operatorname{area} \cdot M \cdot E X P L I \tag{0.54}
\end{equation*}
$$

$$
\begin{align*}
C_{b c p_{e f f}} & =\operatorname{area} \cdot M \cdot C_{b c p} \\
C_{b e p_{e f f}} & =\operatorname{area} \cdot M \cdot C_{b e p}  \tag{0.55}\\
C_{c s p_{e f f}} & =\operatorname{area} \cdot M \cdot C_{c s p} \\
C_{j e_{e f f}} & =\operatorname{area} \cdot M \cdot C_{j e}
\end{align*}
$$

$$
r_{b_{e f f}}=\frac{r_{b}}{\text { area } \cdot M}
$$

$$
\begin{equation*}
r_{b m_{e f f}}=\frac{r_{b m}}{\text { area } \cdot M} \tag{0.56}
\end{equation*}
$$

$$
r_{e_{e f f}}=\frac{r_{e}}{\text { area } \cdot M}
$$

$$
r_{c_{e f f}}=\frac{r_{c}}{\operatorname{area} \cdot M}
$$

Scaling: Vertical Geometry (subs=1)

$$
\begin{align*}
I_{b c_{e f f}} & =\operatorname{areab} \cdot M \cdot I_{b c} \\
I_{s c_{e f f}} & =\operatorname{areab} \cdot M \cdot I_{s c} \\
I_{s s_{e f f}} & =\operatorname{areab} \cdot M \cdot I_{s s} \quad \text { if both } I_{b e} \text { and } I_{b c} \text { are specified }  \tag{0.57}\\
C_{j s_{e f f}} & =\operatorname{areab} \cdot M \cdot C_{j s} \\
C_{j c_{e f f}} & =\operatorname{areab} \cdot M \cdot C_{j c}
\end{align*}
$$

## Scaling: Lateral Geometry (subs=-1)

$$
\begin{align*}
I_{b c_{e f f}} & =\operatorname{areac} \cdot M \cdot I_{b c} \\
I_{s c_{e f f}} & =\operatorname{areac} \cdot M \cdot I_{s c} \\
I_{s s_{e f f}} & =\operatorname{areac} \cdot M \cdot I_{s s} \quad \text { if both } I_{b e} \text { and } I_{b c} \text { are specified }  \tag{0.58}\\
C_{j s_{e f f}} & =\operatorname{areac} \cdot M \cdot C_{j s} \\
C_{j c_{e f f}} & =\operatorname{areac} \cdot M \cdot C_{j c}
\end{align*}
$$

## Current Equations (Level 1)

The following current equations are used when level=1, specifying that either the Gummel-Poon or Ebers-Moll model will be used. T-Spice chooses appropriate current equations according to which parameters were specified. The reverse saturation currents between base and collector and between base and emitter ( $I_{b c}$ and $I_{b e}$ ) are optional parameters. If they are not specified, T-Spice uses the transport saturation current $I_{s}$ in current equations.

There are no explicit switches between the different regions of device operation. Equations (0.59) through ( 0.71 ) describe currents in the normal active, inverse, saturation, and cut-off regions of operation. This means that the $\beta$ roll-off at high collector current is slightly less pronounced in T-Spice.

## Base Charge Equations

In order to determine BJT currents, T-Spice must first calculate base charge. There are two sets of base charge equations; you can specify which equations T-Spice will use by changing the model selector update.

The base charge $q_{b}$ is calculated from the following equation:

$$
\begin{equation*}
q_{b}=\frac{q_{1}}{2}\left(1+\left(1+4 q_{2}\right)^{\eta_{k f}}\right) \tag{0.59}
\end{equation*}
$$

where $q_{2}$ and $q_{1}$ are calculated as follows.

$$
\begin{equation*}
q_{2}=\frac{I_{s e_{e f f}}}{I_{k f_{e f f}}}\left(e^{\frac{V_{b e}}{\eta_{f} V_{t}}}-1\right)+\frac{I_{s e_{e f f}}}{I_{k r_{e f f}}}\left(e^{\frac{V_{b c}}{\eta_{r} V_{t}}}-1\right) \tag{0.60}
\end{equation*}
$$

The thermal voltage $V_{t}$ is defined as:

$$
\begin{equation*}
V_{t}=k T / q \tag{0.61}
\end{equation*}
$$

where $k$ is Boltzmann's constant, $T$ is temperature, and $q$ is the elementary electron charge.
If update $=1$ and $\frac{V_{b c}}{V_{a f}}+\frac{V_{b e}}{V_{a r}} \geq 0$, then

$$
\begin{equation*}
q_{1}=1+\frac{V_{b c}}{V_{a f}}+\frac{V_{b e}}{V_{a r}} . \tag{0.62}
\end{equation*}
$$

If update $=\mathbf{0}$ or $\frac{V_{b c}}{V_{a f}}+\frac{V_{b e}}{V_{a r}}<0$, then

$$
\begin{equation*}
q_{1}=\left(1-\frac{V_{b c}}{V_{a f}}-\frac{V_{b e}}{V_{a r}}\right)^{-1} \tag{0.63}
\end{equation*}
$$

## Collector and Base Current Equations

If only the saturation current $I_{s}$ is specified, T-Spice uses the following equations to calculate collector current $\left(I_{c}\right)$ and base current $\left(I_{b}\right)$ :

$$
\begin{gather*}
I_{c}=\frac{I_{s_{e f f}}}{q_{b}}\left(e^{\frac{V_{B E}}{\eta_{f} V_{t}}}\right)-\frac{I_{\text {seff }}}{q_{b}}\left(e^{\frac{V_{B C}}{\eta_{r} V_{t}}}\right)-\frac{I_{s_{e f f}}}{\beta_{r}}\left(e^{\frac{V_{b c}}{\eta_{r} V_{t}}}-1\right)-I_{s c_{e f f}}\left(e^{\frac{V_{b c}}{\eta_{c} V_{t}}}-1\right)  \tag{0.64}\\
I_{b}=\frac{I_{s_{e f f}}}{\beta_{f}}\left(e^{\frac{V_{b e}}{\eta_{f} V_{t}}}-1\right)-\frac{I_{s_{e f f}}}{\beta_{r}}\left(e^{\frac{V_{b c}}{\eta_{r} V_{t}}}-1\right)+I_{s e_{e f f}}\left(e^{\frac{V_{b e}}{\eta_{e} V_{t}}}-1\right)+I_{s c_{e f f}}\left(e^{\frac{V_{b c}}{\eta_{c} V_{t}}}-1\right) \tag{0.65}
\end{gather*}
$$

If $I_{b e}$ and $I_{b c}$ are both specified, T-Spice uses the following current equations:

$$
\begin{align*}
& I_{c}=\frac{I_{b e_{e f f}}}{q_{b}}\left(e^{\frac{V_{b e}}{\eta_{f} V_{t}}}-1\right)-\frac{I_{b c_{e f f}}}{q_{b}}\left(e^{\frac{V_{b c}}{\eta_{r} V_{t}}}-1\right)-\frac{I_{b c_{e f f}}}{\beta_{r}}\left(e^{\frac{V_{b c}}{\eta_{r} V_{t}}}-1\right)-I_{s c_{e f f}}\left(e^{\frac{V_{b c}}{\eta_{c} V_{t}}}-1\right)  \tag{0.66}\\
& I_{b}=\frac{I_{b e_{e f f}}}{\beta_{f}}\left(e^{\frac{V_{b e}}{\eta_{f} V_{t}}}-1\right)+\frac{I_{b c_{e f f}}}{\beta_{r}}\left(e^{\frac{V_{b c}}{\eta_{r} V_{t}}}-1\right)+I_{s e_{e f f}}\left(e^{\frac{V_{b e}}{\eta_{e} V_{t}}}-1\right)+I_{s c_{e f f}}\left(e^{\frac{V_{b c}}{\eta_{c} V_{t}}}-1\right) \tag{0.67}
\end{align*}
$$

where $q_{b}$ is the normalized base charge, $\beta_{\mathrm{r}}$ and $\beta_{\mathrm{f}}$ are the ideal maximum reverse and forward current gains, $\eta_{\mathrm{f}}$ and $\eta_{\mathrm{r}}$ are the forward and reverse current emission coefficients, and $\eta_{\mathrm{c}}$ and $\eta_{\mathrm{e}}$ are the basecollector and emitter-collector leakage emission coefficients.

The last two terms in the $I_{b}$ expression represent recombination in the base-emitter and base-collector surfaces and depletion regions. The last term in the $I_{c}$ expression represents recombination in the basecollector junction.

The emitter current, $I_{e}$, is simply the sum of base and collector currents:

$$
\begin{equation*}
I_{e}=I_{b}+I_{c} \tag{0.68}
\end{equation*}
$$

## Excess Phase Equation

Excess phase represents the extra degrees of phase delay introduced by the BJT as a function of frequency, due to the distributed phenomena in the base region. T-Spice calculates excess phase in AC and transient analyses of the BJT. At any given frequency, the phase multiplier parameter ptf determines the relationship between excess phase and the base forward transit time, $\mathbf{t f}$.

$$
\begin{equation*}
\text { excess phase }=\left(2 \pi \cdot P_{t f} \cdot \frac{\tau_{f}}{360}\right) \cdot 2 \pi f \tag{0.69}
\end{equation*}
$$

In AC analysis, T-Spice applies excess phase as a linear phase delay in the transconductance generator, $g_{m}$. See the small-signal reference for "BJT Level 1 (Gummel-Poon)" on page 473 for a description of $g_{m}$.

In transient analysis, excess phase affects how T-Spice calculates collector current $\left(I_{c}\right)$. When excess phase is present (i.e., $\mathbf{p t f}=\mathbf{0}$ ), T-Spice calculates the collector current as a cumulative function using time step dependent backward Euler integration. Otherwise, if ptf is not specified, collector current is simply a function of the current time step.

## Substrate Current Equations

Substrate current is defined according to the geometric configuration of the BJT. The substrate current flows from substrate to collector for vertical BJTs (subs=1) and from substrate to base for lateral BJTs (subs=-1).

For vertical transistors (subs=1),

$$
\begin{array}{ll}
I_{s c}=I_{s s_{e f f}}\left(e^{\frac{V_{s c}}{\eta_{s} V_{t}}}-1\right) & \text { when } V_{s c}>-10 \cdot \eta_{s} \cdot V_{t}  \tag{0.70}\\
I_{s c}=-I_{s s_{e f f}} & \text { when } V_{s c} \leq-10 \cdot \eta_{s} \cdot V_{t}
\end{array}
$$

where $I_{\text {sseff }}$ is the effective reverse saturation current between bulk and collector.
For lateral transistors (subs=-1),

$$
\begin{array}{ll}
I_{b s}=I_{s s_{e f f}}\left(e^{\frac{V_{b s}}{\eta_{s} V_{t}}}-1\right) & \text { when } V_{b s}>-10 \cdot \eta_{s} \cdot V_{t}  \tag{0.71}\\
I_{b s}=-I_{s s_{e f f}} & \text { when } V_{b s} \leq-10 \cdot \eta_{s} \cdot V_{t}
\end{array}
$$

where $I_{s s e f f}$ is the effective reverse saturation current between bulk and base.

## Variable Base Resistance Equations

The following equations describe the calculation of the base resistance, $r_{b b}$. Base resistance varies with current and depends on two parameters, the low-current maximum resistance $\left(r_{b}\right)$ and the high-current minimum resistance ( $r_{b m}$ ). There are two ways that T-Spice can calculate $r_{b b}$, either with or without the parameter $I_{r b} . I_{r b}$ is the base current that occurs when $r_{b b}$ is equal to $0.5 \times\left(r_{b}-r_{b m}\right)$, or the midpoint between minimum and maximum resistance values.

If Irb is not specified, T-Spice uses the following equation:

$$
\begin{equation*}
r_{b b}=r_{b m_{e f f}}+\frac{r_{b_{e f f}}-r_{b m_{e f f}}}{q_{b}} \tag{0.72}
\end{equation*}
$$

If $I_{r b}$ is specified,

$$
\begin{equation*}
r_{b b}=r_{b m_{e f f}}+3\left(r_{b_{e f f}}-r_{b m_{e f f}}\right) \frac{\tan (z)-z}{z \tan (z) \tan (z)}, \tag{0.73}
\end{equation*}
$$

where

$$
\begin{equation*}
z=\frac{-1+\sqrt{1+\frac{144 \cdot I_{b}}{\pi^{2} \cdot I_{r b_{e f f}}}}}{\frac{24}{\pi^{2}} \cdot \sqrt{\frac{I_{b}}{I_{r b_{e f f}}}}} \tag{0.74}
\end{equation*}
$$

## Capacitance Equations

## Base-Emitter Capacitance

The total base-emitter capacitance consists of contributions from diffusion capacitance and depletion capacitance:

$$
\begin{equation*}
C_{b e}=C_{b e_{d i f f}}+C_{b e_{d e p}} \tag{0.75}
\end{equation*}
$$

The diffusion capacitance is determined as follows:

$$
\begin{array}{ll}
C_{b e_{\text {diff }}}=\frac{\partial}{\partial V_{b e b}}\left(\tau_{f} \cdot \frac{i_{b e}}{q_{b}}\right) & \text { when } i_{b e} \leq 0  \tag{0.76}\\
C_{b e_{\text {diff }}}=\frac{\partial}{\partial V_{b e}}\left(\tau_{f} \cdot\left(1+\arg \tau_{f}\right) \cdot \frac{i_{b e}}{q_{b}}\right) & \text { when } i_{b e}>0
\end{array}
$$

where

$$
\begin{equation*}
\arg \tau_{f}=X_{t f}\left(\frac{i_{b e}}{i_{b e}+I_{t f}}\right)^{2} \cdot e^{\frac{V_{b c}}{1.44 \cdot V_{t f}}} \tag{0.77}
\end{equation*}
$$

and

$$
\begin{equation*}
i_{b e}=I_{s_{e f f}}\left(e^{\frac{q V_{b e}}{\eta_{f} k T}}-1\right) \tag{0.78}
\end{equation*}
$$

T-Spice supports two different models for depletion capacitance. You can specify the depletion capacitance equations using the dcap model selector.

If dcap $=1$,

$$
\begin{align*}
C_{b e_{d e p}} & =C_{j e_{e f f}}\left(1-\frac{V_{b e}}{V_{j e}}\right)^{-m_{j e}} \\
C_{b e_{d e p}} & =C_{j e_{e f f}} \cdot \frac{1-F C\left(1+m_{j e}\right)+m_{j e} \cdot \frac{V_{b e}}{V_{j e}}}{(1-F C)^{1+m_{j e}}} \text { when } V_{b e}<F C \cdot V_{j e} \tag{0.79}
\end{align*}
$$

If dcap=2 (default),

$$
\begin{array}{ll}
C_{b e_{d e p}}=C_{j e_{e f f}}\left(1-\frac{V_{b e}}{V_{j e}}\right)^{-m_{j e}} & \text { when } \quad V_{b e}<0  \tag{0.80}\\
C_{b e_{d e p}}=C_{j e_{e f f}}\left(1+m_{j e} \cdot \frac{V_{b e}}{V_{j e}}\right) & \text { when } \quad V_{b e} \geq 0
\end{array}
$$

## Base-Collector Capacitance

The total base-collector capacitance consists of contributions from diffusion capacitance and depletion capacitance:

$$
\begin{equation*}
C_{b c}=C_{b c_{d i f f}}+C_{b c_{d e p}} \tag{0.81}
\end{equation*}
$$

The base-collector diffusion capacitance is determined as follows:

$$
\begin{equation*}
C_{b c_{d i f f}}=\frac{\partial}{\partial V_{b c}}\left(\tau_{r} \cdot i_{b c}\right) \tag{0.82}
\end{equation*}
$$

where

$$
\begin{equation*}
i_{b c}=I_{s_{e f f}}\left(e^{\frac{V_{b c}}{\eta_{r} V_{t}}}-1\right) \tag{0.83}
\end{equation*}
$$

T-Spice offers two different models for base-collector depletion capacitance. Use dcap to select a set of equations.

For dcap=1:

$$
\begin{align*}
C_{b c_{d e p}} & =X_{c j c} \cdot C_{j c_{e f f}}\left(1-\frac{V_{b c}}{V_{j c}}\right)^{-m_{j c}} \\
C_{b c_{d e p}} & =X_{c j c} \cdot C_{j c_{e f f}} \cdot \frac{1-F C\left(1+m_{j c}\right)+m_{j c} \cdot \frac{V_{b c}}{V_{j c}}}{(1-F C)^{1+m_{j c}}} \text { when } V_{b c}<F C \cdot V_{j c} \tag{0.84}
\end{align*}
$$

For dcap=2:

$$
\begin{array}{ll}
C_{b c_{d e p}}=X_{c j c} \cdot C_{j c_{e f f}}\left(1-\frac{V_{b c}}{V_{j c}}\right)^{-m_{j c}} & \text { when } \\
V_{b c}<0  \tag{0.85}\\
C_{b c_{d e p}}=X_{c j c} \cdot C_{j c_{e f f}}\left(1+m_{j c} \cdot \frac{V_{b c}}{V_{j c}}\right) & \text { when } \quad V_{b c} \geq 0
\end{array}
$$

where $X c j c$ is the partition parameter specifying the ration of base-collector junction capacitance distribution between internal base-internal collector and external base-internal collector.

If $X c j c<1$, the external base-internal collector capacitance has to be considered:

## For dcap=1:

$$
\begin{array}{ll}
C_{b c x}=\left(1-X_{c j c}\right) \cdot C_{j c_{e f f}}\left(1-\frac{V_{b c x}}{V_{j c}}\right)^{-m_{j c}} & \text { when } V_{b c x}<F C \cdot V_{j c} \\
C_{b c x}=\left(1-X_{c j c}\right) \cdot C_{j c_{e f f}} \cdot \frac{1-F C\left(1+m_{j c}\right)+m_{j c} \cdot \frac{V_{b c x}}{V_{j c}}}{(1-F C)^{1+m_{j c}}} \text { when } V_{b c x} \geq F C \cdot V_{j c} \tag{0.86}
\end{array}
$$

For dcap=2:

$$
\begin{array}{ll}
C_{b c x}=\left(1-X_{c j c}\right) \cdot C_{j c_{e f f}}\left(1-\frac{V_{b c x}}{V_{j c}}\right)^{-m_{j c}} & \text { when } V_{b c x}<0 \\
C_{b c x}=\left(1-X_{c j c}\right) \cdot C_{j c_{e f f}}\left(1+m_{j c} \cdot \frac{V_{b c x}}{V_{j c}}\right) & \text { when } \quad V_{b c x} \geq 0 \tag{0.87}
\end{array}
$$

where $V b c x$ is the voltage between the external base node and the internal collector node.

## Substrate Capacitance

The definition of substrate capacitance varies with BJT geometry. For vertical transistors (subs=1), substrate capacitance is defined for the base to substrate diode. For lateral transistors (subs=-1), it is defined as the capacitance of the substrate to collector diode.

For vertical BJTs,

$$
\begin{array}{ll}
C_{s c}=C_{j s_{e f f}}\left(1-\frac{V_{s c}}{V_{j s}}\right)^{-m_{j s}} & \text { when } \quad V_{s c}<0  \tag{0.88}\\
C_{s c}=C_{j s_{e f f}}\left(1+m_{j s} \cdot \frac{V_{s c}}{V_{j s}}\right) & \text { when } \quad V_{s c} \geq 0
\end{array}
$$

For lateral BJTs,

$$
\begin{array}{ll}
C_{b s}=C_{j s_{e f f}}\left(1-\frac{V_{b s}}{V_{j s}}\right)^{-m_{j s}} & \text { when } \quad V_{b s}<0  \tag{0.89}\\
C_{b s}=C_{j s_{e f f}}\left(1+m_{j s} \cdot \frac{V_{b s}}{V_{j s}}\right) & \text { when } \quad V_{b s} \geq 0
\end{array}
$$

## Temperature Dependence

Below is a list of parameters that T-Spice modifies when one or more corresponding temperature coefficients are specified, regardless of TLEV values. When neither first nor second order coefficients
are specified for a given parameter, the TLEV-dependent equations in "Saturation Current and Beta" on page 354 take precedence.

Forward and reverse current
gain

$$
\begin{aligned}
& \beta_{f}(T)=\beta_{f} \cdot\left(1+T B F_{1} \cdot \Delta T+T B F_{2} \cdot \Delta T^{2}\right) \\
& \beta_{r}(T)=\beta_{r} \cdot\left(1+T B R_{1} \cdot \Delta T+T B R_{2} \cdot \Delta T^{2}\right)
\end{aligned}
$$

Voltage and current
parameters

$$
\begin{aligned}
V_{a f}(T) & =V_{a f} \cdot\left(1+T V A F_{1} \cdot \Delta T+T V A F_{2} \cdot \Delta T^{2}\right) \\
V_{a r}(T) & =V_{a r} \cdot\left(1+T V A R_{1} \cdot \Delta T+T V A R_{2} \cdot \Delta T^{2}\right) \\
I_{t f}(T) & =I_{t f} \cdot\left(1+T I T F_{1} \cdot \Delta T+T I T F_{2} \cdot \Delta T^{2}\right)
\end{aligned}
$$

Transit time parameters

$$
\begin{aligned}
\tau_{f}(T) & =\tau_{f} \cdot\left(1+T T F_{1} \cdot \Delta T+T T F_{2} \cdot \Delta T^{2}\right) \\
\tau_{r}(T) & =\tau_{r} \cdot\left(1+T T R_{1} \cdot \Delta T+T T R_{2} \cdot \Delta T^{2}\right)
\end{aligned}
$$

Emission coefficients

$$
\begin{aligned}
& \eta_{f}(T)=\eta_{f} \cdot\left(1+T N F_{1} \cdot \Delta T+T N F_{2} \cdot \Delta T^{2}\right) \\
& \eta_{r}(T)=\eta_{r} \cdot\left(1+T N R_{1} \cdot \Delta T+T N R_{2} \cdot \Delta T^{2}\right) \\
& \eta_{e}(T)=\eta_{e} \cdot\left(1+T N E_{1} \cdot \Delta T+T N E_{2} \cdot \Delta T^{2}\right) \\
& \eta_{c}(T)=\eta_{c} \cdot\left(1+T N C_{1} \cdot \Delta T+T N C_{2} \cdot \Delta T^{2}\right) \\
& \eta_{s}(T)=\eta_{s} \cdot\left(1+T N S_{1} \cdot \Delta T+T N S_{2} \cdot \Delta T^{2}\right)
\end{aligned}
$$

$$
\begin{aligned}
& m_{j e}(T)=m_{j e} \cdot\left(1+T M J E_{1} \cdot \Delta T+T M J E_{2} \cdot \Delta T^{2}\right) \\
& m_{j c}(T)=m_{j c} \cdot\left(1+T M J C_{1} \cdot \Delta T+T M J C_{2} \cdot \Delta T^{2}\right) \\
& m_{j s}(T)=m_{j s} \cdot\left(1+T M J S_{1} \cdot \Delta T+T M J S_{2} \cdot \Delta T^{2}\right)
\end{aligned}
$$

Parasitic resistor parameters

$$
\begin{aligned}
r_{e}(T) & =r_{e} \cdot\left(1+T R E_{1} \cdot \Delta T+T R E_{2} \cdot \Delta T^{2}\right) \\
r_{b}(T) & =r_{b} \cdot\left(1+T R B_{1} \cdot \Delta T+T R B_{2} \cdot \Delta T^{2}\right) \\
r_{b m}(T) & =r_{b m} \cdot\left(1+T R M_{1} \cdot \Delta T+T R M_{2} \cdot \Delta T^{2}\right) \\
r_{c}(T) & =r_{c} \cdot\left(1+T R C_{1} \cdot \Delta T+T R C_{2} \cdot \Delta T^{2}\right)
\end{aligned}
$$

## Energy Gap

The calculation of energy gap is dependent on TLEV. For TLEV=0, 1, or 3, energy gap is always calculated as follows:

$$
\begin{equation*}
E_{g}\left(T_{n o m}\right)=1.16-\left(7.02 \times 10^{4}\right) \frac{T_{n o m}^{2}}{T_{n o m}+1108.0} \tag{0.96}
\end{equation*}
$$

If TLEV=2, the energy gap is calculated as a function of model parameters $E_{g}(0), G A P 1$, and $G A P 2$ :

$$
\begin{equation*}
E_{g}\left(T_{n o m}\right)=E_{g}(0)-G A P 1 \cdot \frac{T_{n o m}^{2}}{T_{n o m}+G A P 2} \tag{0.97}
\end{equation*}
$$

## Saturation Current and Beta

The following equations show the temperature effects for transport saturation current, base-emitter reverse saturation current, and base-collector reverse saturation current.
$T L E V=0,1$, or 2
TLEV $=3$
$I_{s}(T)=$
$I_{b e}(T)=$

$$
I_{s}^{\left(1+T I S_{1} \Delta T+T I S_{2} \Delta T^{2}\right)}
$$

$$
I_{b e}^{\left(1+T I S_{1} \Delta T+T I S_{2} \Delta T^{2}\right)}
$$

$T L E V=0,1$, or 2
$T L E V=3$
$I_{b c}(T)=$

$$
I_{b c} \cdot e^{\frac{f a c L N}{\eta_{r}}}
$$

$$
I_{b c}^{\left(1+T I S_{1} \Delta T+T I S_{2} \Delta T^{2}\right)}
$$

$I_{k f}(T)=$

$$
I_{k f} \cdot\left(1+T I K F_{1} \Delta T+T I K F_{2} \Delta T^{2}\right) \quad I_{k f}^{\left(1+T I K F_{1} \Delta T+T I K F_{2} \Delta T^{2}\right)}
$$

$I_{k r}(T)=$
$I_{k r} \cdot\left(1+T I K R_{1} \Delta T+T I K R_{2} \Delta T^{2}\right)$
$I_{k r}^{\left(1+T I K R_{1} \Delta T+T I K R_{2} \Delta T^{2}\right)}$
$I_{r b}(T)=$

$$
I_{r b} \cdot\left(1+T I R B_{1} \Delta T+T I R B_{2} \Delta T^{2}\right)
$$

$$
I_{r b}^{\left(1+T I R B_{1} \Delta T+T I R B_{2} \Delta T^{2}\right)}
$$

Temperature-effect equations for leakage saturation currents, bulk-to-collector (or base) saturation current, and beta parameters are shown below.

## TLEV=0 or 2 <br> TLEV=1 <br> $T L E V=3$

$I_{s e}(T)=$

$$
\frac{I_{s e}}{\left(\frac{T}{T_{n o m}}\right)^{X_{t b}} \cdot e^{\frac{f a c L N}{\eta_{e}}}} \frac{I_{s e}}{1+X_{t b} \Delta T} \cdot e^{\frac{f a c L N}{\eta_{e}}} \quad I_{s e}^{\left(1+T I S E_{1} \Delta T+T I S E_{2} \Delta T^{2}\right)}
$$

$I_{s c}(T)=$
$I_{s s}(T)=$

$$
\begin{aligned}
& \frac{I_{s s}}{\left(\frac{T}{T_{n o m}}\right)^{X_{t b}}} \cdot e^{\frac{f a c L N}{\eta_{s}}} \\
& \frac{I_{s s}}{1+X_{t b} \Delta T} \cdot e^{\frac{f a c L N}{\eta_{s}}} \\
& I_{S S}^{\left(1+T I S S_{1} \Delta T+T I S S_{2} \Delta T^{2}\right)}
\end{aligned}
$$

$\beta_{f}(T)=$

$$
\beta_{f} \cdot\left(\frac{T}{T_{n o m}}\right)^{X_{t b}} \quad \beta_{f} \cdot\left(1+X_{t b} \Delta T\right) \quad \beta_{f} \cdot\left(\frac{T}{T_{n o m}}\right)^{X_{t b}}
$$

(if $T B F_{1}, T B F_{2}$ are not specified)
$\beta_{r}(T)=$

$$
\beta_{r} \cdot\left(\frac{T}{T_{n o m}}\right)^{X_{t b}} \quad \beta_{r} \cdot\left(1+X_{t b} \Delta T\right) \quad \beta_{r} \cdot\left(\frac{T}{T_{n o m}}\right)^{X_{t b}}
$$

(if $T B R_{1}, T B R_{2}$ are not specified)

For $T L E V=0$ and 1

$$
\begin{equation*}
\operatorname{facln}=\frac{E_{g}(0)}{V_{t}\left(T_{n o m}\right)}-\frac{E_{g}(0)}{V t(T)}+X T I \cdot \ln \left(\frac{T}{T_{\text {nom }}}\right) \tag{0.98}
\end{equation*}
$$

For $T L E V=2$

$$
\begin{equation*}
\text { facln }=\frac{E_{g}\left(T_{\text {nom }}\right)}{V_{t}\left(T_{\text {nom }}\right)}-\frac{E_{g}(T)}{V t(T)}+X T I \cdot \ln \left(\frac{T}{T_{\text {nom }}}\right) \tag{0.99}
\end{equation*}
$$

For $T L E V=3$

$$
\begin{equation*}
\text { facln }=\frac{V_{S B}}{V_{t}\left(T_{n o m}\right)}-\frac{V_{S B}}{V t(T)}+X T I \cdot \ln \left(\frac{T}{T_{n o m}}\right) \tag{0.100}
\end{equation*}
$$

Note: $\quad$ If $T B F_{1}$ or $T B F_{2}$ is specified, then $\beta_{f}$ will be calculated using the equation for tlev=3, regardless of the actual value of tlev. Similarly, the tlev=3 equation for $\beta_{r}$ will always take precedence if either $T B R_{1}$ or $T B R_{2}$ is specified.

## Capacitance

Capacitance equations are selected by the parameter TLEVC.
The following capacitance equations are used when TLEVC $=0$ :

$$
\begin{align*}
& C_{j e}(T)=C_{j e} \cdot\left\{1+m_{j e} \cdot\left(4.0 \times 10^{-4} \cdot \Delta T-\frac{V_{j e}(T)}{V_{j e}}+1\right)\right\} \\
& C_{j c}(T)=C_{j c} \cdot\left\{1+m_{j c} \cdot\left(4.0 \times 10^{-4} \cdot \Delta T-\frac{V_{j c}(T)}{V_{j c}}+1\right)\right\},  \tag{0.101}\\
& C_{j s}(T)=C_{j s} \cdot\left\{1+m_{j s} \cdot\left(4.0 \times 10^{-4} \cdot \Delta T-\frac{V_{j s}(T)}{V_{j s}}+1\right)\right\}
\end{align*}
$$

where contact voltages are determined by

$$
\begin{align*}
& V_{j e}(T)=V_{j e} \cdot\left(\frac{T}{T_{n o m}}\right)-V_{t}(T) \cdot\left\{3 \ln \left(\frac{T}{T_{\text {nom }}}\right)+\frac{E_{g}\left(T_{n o m}\right)}{V_{t}\left(T_{n o m}\right)}-\frac{E_{g}(T)}{V_{t}(T)}\right\} \\
& V_{j c}(T)=V_{j c} \cdot\left(\frac{T}{T_{n o m}}\right)-V_{t}(T) \cdot\left\{3 \ln \left(\frac{T}{T_{n o m}}\right)+\frac{E_{g}\left(T_{n o m}\right)}{V_{t}\left(T_{n o m}\right)}-\frac{E_{g}(T)}{V_{t}(T)}\right\}  \tag{0.102}\\
& V_{j s}(T)=V_{j s} \cdot\left(\frac{T}{T_{n o m}}\right)-V_{t}(T) \cdot\left\{3 \ln \left(\frac{T}{T_{n o m}}\right)+\frac{E_{g}\left(T_{n o m}\right)}{V_{t}\left(T_{n o m}\right)}-\frac{E_{g}(T)}{V_{t}(T)}\right\}
\end{align*}
$$

If TLEVC=1,

$$
\begin{align*}
C_{j e}(T) & =C_{j e} \cdot\left(1+C_{t e} \cdot \Delta T\right) \\
C_{j c}(T) & =C_{j c} \cdot\left(1+C_{t c} \cdot \Delta T\right)  \tag{0.103}\\
C_{j s}(T) & =C_{j s} \cdot\left(1+C_{t s} \cdot \Delta T\right)
\end{align*}
$$

and contact voltages are determined by

$$
\begin{align*}
V_{j e}(T) & =V_{j e}-T_{v j e} \cdot \Delta T \\
V_{j c}(T) & =V_{j c}-T_{v j c} \cdot \Delta T  \tag{0.104}\\
V_{j s}(T) & =V_{j s}-T_{v j s} \cdot \Delta T
\end{align*}
$$

If TLEVC=2,

$$
\begin{align*}
& C_{j e}(T)=C_{j e} \cdot\left(\frac{V_{j e}}{V_{j e}(T)}\right)^{m_{j e}} \\
& C_{j c}(T)=C_{j c} \cdot\left(\frac{V_{j c}}{V_{j c}(T)}\right)^{m_{j c}}  \tag{0.105}\\
& C_{j s}(T)=C_{j s} \cdot\left(\frac{V_{j s}}{V_{j s}(T)}\right)^{m_{j s}}
\end{align*}
$$

where

$$
\begin{align*}
V_{j e}(T) & =V_{j e}-T_{v j e} \cdot \Delta T \\
V_{j c}(T) & =V_{j c}-T_{v j c} \cdot \Delta T  \tag{0.106}\\
V_{j s}(T) & =V_{j s}-T_{v j s} \cdot \Delta T
\end{align*}
$$

## Note:

Use $m j e, m j c$, and $m j s$ instead of $m j e(T), m j c(T)$, and $m j s(T)$ in the above equations.

When TLEVC=3:

$$
\begin{align*}
& C_{j e}(T)=C_{j e} \cdot\left(1-0.5 \cdot d v j e d t \cdot \frac{\Delta T}{V_{j e}}\right) \\
& C_{j c}(T)=C_{j c} \cdot\left(1-0.5 \cdot d v j c d t \cdot \frac{\Delta T}{V_{j c}}\right)  \tag{0.107}\\
& C_{j s}(T)=C_{j s} \cdot\left(1-0.5 \cdot d v j s d t \cdot \frac{\Delta T}{V_{j s}}\right)
\end{align*}
$$

and

$$
\begin{align*}
V_{j e}(T) & =V_{j e}+d v j e d t \cdot \Delta T \\
V_{j c}(T) & =V_{j c}+d v j c d t \cdot \Delta T  \tag{0.108}\\
V_{j s}(T) & =V_{j s}+d v j s d t \cdot \Delta T
\end{align*}
$$

where

$$
\begin{array}{r}
d v j e d t=-\frac{E_{g}\left(T_{n o m}\right)+3 \cdot V_{t}\left(T_{n o m}\right)+\left[E_{g}(0)-E_{g}\left(T_{n o m}\right)\right] \cdot\left(2-\frac{T_{n o m}}{T_{n o m}+G A P 2}\right)-V_{j e}}{T_{n o m}} \\
d v j c d t=-\frac{E_{g}\left(T_{n o m}\right)+3 \cdot V_{t}\left(T_{n o m}\right)+\left[E_{g}(0)-E_{g}\left(T_{n o m}\right)\right] \cdot\left(2-\frac{T_{n o m}}{T_{n o m}+G A P 2}\right)-V_{j c}}{T_{n o m}} \tag{0.109}
\end{array}
$$

$$
d v j s d t=-\frac{E_{g}\left(T_{n o m}\right)+3 \cdot V_{t}\left(T_{n o m}\right)+\left[E_{g}(0)-E_{g}\left(T_{n o m}\right)\right] \cdot\left(2-\frac{T_{n o m}}{T_{n o m}+G A P 2}\right)-V_{j s}}{T_{n o m}}
$$

## BJT Level 6 (Mextram)

The level 6 bipolar junction transistor model is the Philips Mextram model.

## Parameters

The Mextram model uses the following syntax.
.model name npn|pnp level=[6|503|504] | model=modelname [parameters]
The Mextram model is fully described in the document Bipolar Transistor Level 504.
For additional detailed information about the Mextram model, please refer to the Philips Compact Model Webpage:

## [1] <br> http://www.semiconductors.philips.com/Philips Models/bipolar/mextram

T-Spice includes support for Mextram versions 503 and 504. The version 504 model provides optional support for modeling the extrinsic substrate and the self-heating effects. Selection of an appropriate model is accomplished by using the model=modelname parameter. If no specific model is specified via the model parameter, the bjt503 model will be selected when level=503 or version=503, otherwise the bjt504 model will be used.

The available modelname values for the Mextram model selection are:

| Modelname | Description |
| :--- | :--- |
| bjt503 | Mextram version 503 with substrate |
| bjtd503 | Mextram version 503 without substrate |
| bjt504 (default) | Mextram version 504 with substrate |
| bjtd504 | Mextram version 504 without substrate |
| bjt504t | Mextram version 504 with substrate, self-heating |
| bjtd504t | Mextram version 504 without substrate, self-heating |

## BJT Level 9 (VBIC)

In addition to the standard Gummel-Poon BJT model, T-Spice supports the Vertical Bipolar InterCompany model (VBIC) as the level 9 BJT.

Note: If you specify VBIC Level 4 in T-Spice it will use the VBIC 1999 version 1.2 model.

## Parameters

The VBIC model uses the following syntax.
.model name npn|pnp level=9 [parameters]
The T-Spice VBIC model is based upon release 1.2 of the VBIC code, and includes certain enhancements for improved convergence and stability.

The following tables describe all of the VBIC BJT parameter.

| Parameter <br> (alias) | Description | VBIC Model Parameters | Default |
| :--- | :--- | :--- | :--- | Units


| Parameter <br> (alias) | Description | DBIC Model Parameters | Defalt |
| :--- | :--- | :--- | :--- | Units


| Parameter (alias) | Description VBIC Model Parameters | Default | Units |
| :---: | :---: | :---: | :---: |
| ms | substrate-collector grading coefficient | 0.33 |  |
| nbbe | Base-Emitter breakdown emission coefficient | 1.0 |  |
| nci | ideal base-collector emission coefficient | 1.0 |  |
| ncip | ideal parasitic base-collector emission coefficient | 1.0 | A |
| nen | non-ideal base-collector emission coefficient | 2.0 |  |
| nenp | non-ideal parasitic base-collector emission coefficient | 2.0 |  |
| nei | ideal base-emitter emission coefficient | 1.0 |  |
| nen | non-ideal base-emitter emission coefficient | 2.0 |  |
| nf | forward emission coefficient | 1.0 |  |
| nfp | parasitic fwd emission coefficient | 1.0 |  |
| nkf | High current roll-off coefficient | 0.5 |  |
| nr | reverse emission coefficient | 1.0 |  |
| pc | base-collector built-in potential | 0.75 | V |
| pe | base-emitter built-in potential | 0.75 | V |
| ps | substrate-collector built-in potential | 0.75 | V |
| qbm | Selector for SGP qb formulation | 0 |  |
| qco (qc0) | epi charge parameter | 0.0 | C |
| qtf | variation of TF with base-width modulation | 0.0 | S |
| rbi | intrinsic base resistance | 0.0 | $\Omega$ |
| rbp | parasitic base resistance | 0.0 | $\Omega$ |
| rbx | extrinsic base resistance | 0.0 | $\Omega$ |
| rci | intrinsic collector resistance | 0.0 | $\Omega$ |
| rex | extrinsic collector resistance | 0.0 | $\Omega$ |
| re | emitter resistance | 0.0 | $\Omega$ |
| rs | substrate resistance | 0.0 | $\Omega$ |
| rth | thermal resistance | 0.0 | $\Omega$ |
| tave | temperature coefficient of AVC2 | 0.0 |  |
| td | forward excess-phase delay time | 0.0 | S |
| tf | forward transit time | 0.0 | S |
| tnbbe | Temperature coefficient of NBBE | 0 |  |
| tnf | temperature coefficient of NF | 0.0 |  |


| Parameter | Description | VBIC Model Parameters | Default |
| :--- | :--- | :--- | :--- |$\quad$ Units

The following VBIC model parameters are T-Spice extensions to the standard model.

| level | model selector | 4 | V |
| :--- | :--- | :--- | :--- |
| ismin | Minimum permissible value of IS | $1 \mathrm{e}-19$ | A |
| ispmin | Minimum permissible value of ISP | $1 \mathrm{e}-19$ | A |
| $\operatorname{mcmin}$ | Minimum permissible value of MC | .01 |  |
| $\operatorname{memin}$ | Minimum permissible value of ME | .01 |  |
| $\operatorname{msmin}$ | Minimum permissible value of MS | .01 |  |
| rbpmin | Minimum permissible value of RBP | .001 | $\Omega$ |

## Equations

For a thorough description of the VBIC model and equations, please refer to the following website:
http://www.designers-guide.org/VBIC/index.html

Note:
Please keep in mind that the default operating temperature and model reference temperature in T-Spice is 25 degrees Celsius, whereas many simulaters use 27 degrees.
When performing simulation comparisons against these simulators, you may want to set the default reference temperature option, "tnom" (page 275), and the operating temperature, ".temp" (page 145), to 27 .

## BJT Level 10 (Modella)

The level 10 bipolar junction transistor model is the Philips Modella model, a lateral PNP bipolar model.

## Parameters

The Modella model uses the following syntax.

```
.model name pnp level=[10|500] | model=modelname [parameters]
```

The complete user manual for the Modella model is located at Bipolar PNP Transistor Level 500.
For additional detailed information about the Modella model, please refer to the Philips Compact Model Webpage:

## http://www.semiconductors.philips.com/Philips Models/bipolar/modella

T-Spice includes support for the Modella model version 500 with and without self-heating effects. When the self-heating model is used, the device statement should include an additional temperature node following the substrate node name.

The available modelname values for the Modella model selection are:

| Modelname | Description |
| :--- | :--- |
| bjt500 (default) | Modella version 500 with substrate |
| bjt500t | Mextram version 500 with substrate, self-heating |

## Capacitor

Indicates the capacitance of a planar diffused region from geometric and process information.

## Parameters

| Parameter | Symbol | Description | Value | Unit |
| :---: | :---: | :---: | :---: | :---: |
| Cap | C0 | Capacitance | 0 | F |
| Capsw | Csw | Sidewall capacitance | 0 | F/m |
| Cox | Cox | Bottomwall capacitance | 0 | $\mathrm{F} / \mathrm{m}^{2}$ |
| Del | $\delta$ | Difference between drawn and actual widths or lengths | 0 | m |
| Di | $\kappa$ | Dielectric constant or relative permittivity | 0 | - |
| L | $L$ | Length of the capacitor | 0 | m |
| Shrink | Sshrink | Shrink factor | 1 | - |
| Tc1 | Tc1 | The first temperature coefficient for capacitance | 0 | 1/deg C |
| Tc2 | Tc2 | The second temperature coefficient for capacitance | 0 | 1/(deg $C)^{2}$ |
| Thick | $\tau$ | Insulator thickness | 0 | m |
| Tnom \| Tref | tref | Reference temperature | global tnom (25.0) | Deg C |
| W | W | Width of capacitor | 0 | m |

## Equations

The statement ".model" (page 96) must be associated with an element statement; see the third syntax example in "Capacitor (c)" (page 154).

$$
\begin{equation*}
C=M S_{\text {scale }}\left[1+\left(T_{c 1} \Delta T\right)+\left(T_{c 2} \Delta T\right)^{2}\right] C_{0} \tag{0.110}
\end{equation*}
$$

Note:
When the calculated capacitance is greater than $0.1 \mathrm{~F}, \mathrm{~T}$-Spice issues a warning message.

The user supplies the multiplicity factor $M$ and the scale factor Scale in the element statement. See "Capacitor" (page 365). The user can supply Tc1, Tc2, and Dtemp in the element statement, model statement, or both. In the last case, element values override model values. $C 0$ will be determined in one of 3 ways, which are listed in order of selection:
i) $C 0$ in the element statement.
ii) $C 0 x$ in the model statement; $C 0$ will be computed using equation 0.111 .
iii) $C 0$ in the model statement.

When COx is supplied in the model description, T-Spice would then compute $C 0$ as follows:

$$
\begin{equation*}
C_{0}=L_{e f f} W_{e f f} C_{o x}+2\left(L_{e f f}+W_{e f f}\right) C_{s w} \tag{0.111}
\end{equation*}
$$

where

$$
\begin{gather*}
L_{e f f}=L_{\text {scaled }}-2 \Delta_{\text {eff }}  \tag{0.112}\\
W_{e f f}=W_{\text {scaled }}-2 \Delta_{e f f} \tag{0.113}
\end{gather*}
$$

If $L$ is supplied in the element statement: $L_{\text {scaled }}=L S_{\text {shrink }} S^{\prime}{ }_{\text {scale }}$

If $L$ is supplied in the model statement: $L_{\text {scaled }}=L S_{\text {shrink }} S_{\text {scalm }}$

If $W$ is supplied in the element statement: $W_{\text {scaled }}=W S_{\text {shrink }} S_{\text {scale }}^{\prime}$

If $W$ is supplied in the model statement: $W_{\text {scaled }}=w S_{\text {shrink }} S_{\text {scale }}^{\prime}$
The user supplies $S^{\prime}{ }_{\text {scale }}$ and $S_{\text {scalm }}^{\prime}$ using .options scale or .options scalm. For further information, see ".options" (page 106).

$$
\begin{equation*}
\Delta=\delta S_{\text {scalm }}^{\prime} \tag{0.118}
\end{equation*}
$$

If $\tau$ is supplied, $T$-Spice would compute Cox from

$$
\begin{align*}
& \text { If } \kappa \neq 0: C_{o x}=\kappa\left(\varepsilon_{0} / \tau\right)  \tag{0.119}\\
& \text { If } \kappa=0: C_{o x}=\varepsilon_{0 x} / \tau \tag{0.120}
\end{align*}
$$

The quantities $\varepsilon_{0}, \varepsilon_{0} x$ are $8.8542149 \mathrm{e}-12$ and $3.453148 \mathrm{e}-11$, respectively. After this, T-Spice would compute $C 0$ using the formulas above. If $\tau$ is not supplied, T-Spice sets $C 0=0$.

## Examples



## Coupled Transmission Line (Level 1)

The coupled transmission line model employs variable electrical parameters.

## Parameters

```
.model name cpl level=1 [[r]={matrix}] [l]={matrix} [c]={matrix}
    [[g]={matrix}]
```

Matrices are entered as follows.

```
[r]={r11, r12, r13, ...
+ {r21, r22, r23, ...
+ {r31, r32, r33, ...
... }
```

| Parameter | Description | Default | Units |
| :--- | :--- | :--- | :--- |
| $[\mathbf{r}]$ | Optional per unit length resistance matrix. Must <br> be positive definite. | [Zero matrix] | $\Omega / \mathrm{m}$ |
| $\left[\begin{array}{ll}\text { Per unit length inductance matrix. Must be } \\ \text { positive definite. Off-diagonal elements must be } \\ \text { non-negative. } \mathbf{n} \text { and } \mathbf{p} \text { metric prefixes may be } \\ \text { used. }\end{array}\right.$ | [Zero matrix] | $\mathrm{H} / \mathrm{m}$ |  |
| $\left[\begin{array}{l}\text { Per unit length capacitance matrix. Must be } \\ \text { positive definite. Off-diagonal elements must be } \\ \text { zero or negative. } \mathbf{n} \text { and } \mathbf{p} \text { metric prefixes may be }\end{array}\right.$ | [Zero matrix] | $\mathrm{F} / \mathrm{m}$ |  |
| $\left[\begin{array}{l}\text { used. }\end{array}\right.$ |  |  |  |

## Example

An example using lossless symmetrical coupled lines:

```
.model exCPL CPL level=1
+ [l]={494.6n, 63,3n,
+ 63.3n, 494.6n }
+ [c]={62.8p, -4.94p,
+ -4.94p, 62.8p }
```


## Diode

There are five types of diode models in T-Spice.

- Level 1 describes the Non-Geometric Junction diode model. It is used to model discrete diode devices such as standard and Zener diodes.
- Level 2 describes the Fowler-Nordheim model that is generally used to characterize the tunneling current flow through thin insulator in nonvolatile memory devices.
- Level 3 describes the Geometric Junction diode model. It is used to model IC-based standard silicone-diffused diodes, Schottky barrier diodes and Zener diodes.
- Level 4 describes the Philips Juncap version 2 diode. Note - level 200 and level 9 are also the Juncap model, with different level numbers provided for compatibility with various simulators.
- Level 500 describes the Philips Advanced diode.


## Parameters

The Philips Juncap2 model is fully described in the document Philips Juncap.
The Philips Advanced Diode is fully described in the document Philips Diode 500.
The following model parameter and equation descriptions pertain to Diode levels 1-3.
.model name d [parameters]
Model Selectors

| Parameter | Symbol | Description | Default | Unit |
| :---: | :---: | :---: | :---: | :---: |
| level | level | Diode model selector | 1 | - |
| dcap | dcap | Capacitance model selector | 2 | - |
| tlev | tlev | Temperature equation selector (tlev $\equiv 3$ for Schottky barrier diode) | 0 | - |
| tlevc | tlevc | Temperature equation selector for junction capacitance and contact potential ( $\mathrm{tlevc}=1$ and 2 for Schottky barrier diode) | 0 | - |

## Geometric and Scaling Parameters

| Parameter | Symbol | Description | Default | Unit |
| :--- | :--- | :--- | :--- | :--- |
| area | area | Junction area (unitless in level=1) | 1.0 | $\mathrm{~m}^{2}$ |
| PJ | $P J$ | Junction periphery (unitless in level=1) | 0.0 | m |
| M | $M$ | Multiplier factor to simulate multiple diode in <br> parallel | 1 |  |
| SCALE | SCALE | Scaling factor for geometric parameters | 1 |  |
| SCALM | SCALM | Scaling factor for model parameters | 1 |  |


| Parameter | Symbol | Description | Default | Unit |
| :--- | :--- | :--- | :--- | :--- |
| SHRINK | SHRIN | Shrink factor | 1 |  |
|  | $K$ |  |  |  |
| L | $L$ | Length of diode | 0.0 | m |
| W | $W$ | Width of diode | 0.0 | m |
| XW | $X W$ | Masking and etching effects | 0.0 | m |
| LM | $L M$ | Length of metal capacitor | 0.0 | m |
| WM | $W M$ | Width of metal capacitor | 0.0 | m |
| XM | $X M$ | Masking and etching effects for $L M$ and $W M$ | 0.0 | m |
| LP | $L P$ | Length of polysilicon capacitor | 0.0 | m |
| WP | $W P$ | Width of polysilicon capacitor | 0.0 | m |
| XP | $X P$ | Masking and etching effects for $L P$ and $W P$ | 0.0 | m |

DC Parameters

| Parameter | Symbol | Description | Default | Unit |
| :---: | :---: | :---: | :---: | :---: |
| IS\|JS | $I S$ | Saturation current (per unit area). Use calculated $I S$ value for Schottky barrier diode if $I S$ is not specified; see "Application NotesSchottky Barrier Diodes" on page 380. | $1.0 \times 10^{-14}$ | A |
| JSW | JSW | Side wall saturation current (per unit length) | 0.0 | A |
| RS | RS | Ohmic resistance | 0.0 | $\Omega$ |
| N | $N$ | Emission coefficient ( $N \equiv$ 1for Schottky barrier diode) | 1.0 |  |
| BV\|VB|VA R|VRB | BV | Breakdown voltage | $\infty$ | V |
| IBV\|IB | IBV | Current at breakdown voltage | $1.0 \times 10^{-3}$ | A |
| IK\|IKF |IBF | IKF | Forward knee current (per unit area) | 0.0 | A |
| IKB\|IKR |IBR | $I K B$ | Reverse knee current (per unit area) | 0.0 | A |
| EXPLI | EXPLI | Current explosion model parameter. The PN junction characteristics above the explosion current area are linear, with the slope at the explosion point. | $1.0 \times 10^{-15}$ | A |

## Capacitance Parameters

| Parameter | Symbol | Description | Default | Unit |
| :--- | :--- | :--- | :--- | :--- |
| CJO\|CJ | $C j 0$ | Zero-bias bottom wall junction capacitance (per <br> unit area) | 0.0 | F |
| CJA |  | F |  |  |


| Parameter | Symbol | Description | Default | Unit |
| :---: | :---: | :---: | :---: | :---: |
| CJP\|CJSW | Cjp0 | Zero-bias side wall/periphery junction capacitance (per unit length) | 0.0 | F |
| FC | FC | Coefficient for forward-bias depletion area capacitance | 0.5 |  |
| FCS | FCS | Coefficient for forward-bias depletion periphery capacitance | 0.5 |  |
| MJ\|M|EXA | $m j$ | Area junction grading coefficient ( $m j \equiv 0.5$ for Schottky barrier diode) | 0.5 |  |
| MJSW\|EXP | mjsw | Periphery junction grading coefficient | 0.33 |  |
| PB\|PHI|VJ| PHA | $P B$ | Area junction contact potential. Use Schottky barrier height as default $P B$ value for Schottky barrier diode if PB is not specified. | 0.8 | V |
| PHP\|VJSW | PHP | Periphery junction contact potential | PB | V |
| TT | $\tau$ | Transit time (minority carrier storage time) ( $\tau \equiv 0$ for Schottky barrier diode) | 0.0 | s |
| XOI | XOP | Thickness of oxide contacted on polysilicon | $1.0 \times 10^{4}$ | A |
| хом | XOM | Thickness of oxide contacted on metal | $1.0 \times 10^{4}$ | A |

## Noise Parameters

| Parameter | Symbol | Description | Default | Unit |
| :--- | :--- | :--- | :--- | :--- |
| AF | $A F$ | Flick noise exponent | 1.0 |  |
| KF | $K F$ | Flick noise exponent | 0.0 |  |

## Temperature Parameters

| Parameter | Symbol | Description | Default | Unit |
| :---: | :---: | :---: | :---: | :---: |
| TNOM TREF | Tnom | Reference temperature | global tnom (25.0) | deg |
| EG | $E g(0)$ | $\begin{aligned} & \text { Energy gap at } 0^{\circ} \mathrm{K} \\ & \text { for tlev }=\mathbf{2}: \\ & \text { for } \operatorname{tlev}=\mathbf{0 , 1 , 3} \end{aligned}$ | $\begin{aligned} & 1.16 \\ & 1.11 \end{aligned}$ | eV |
| VSB | VSB | Schottky barrier height (tlev=3 only) | 0.8 | V |
| GAP1 | GAP1 | Coefficient in energy gap temperature equation (Si: $4.73 \times 10^{-4}$, Ge: $4.77 \times 10^{-4}$, and GaAs: $5.41 \times 10^{-4}$ ) | $7.02 \times 10^{-4}$ | eV/deg |
| GAP2 | $G A P 2$ | Coefficient in energy gap temperature equation (Si: 636, Ge: 235, and GaAs: 204) | 1108 | deg |
| TCV | TCV | Breakdown voltage temperature coefficient | 0.0 | 1/deg |


| Parameter | Symbol | Description | Default | Unit |
| :--- | :--- | :--- | :--- | :--- |
| TTT1 | $\tau t 1$ | First-order temperature coefficient for $\tau$ | 0.0 | $1 / \mathrm{deg}$ |
| TTT2 | $\tau t 2$ | Second-order temperature coefficient for $\tau$ | 0.0 | $1 / \mathrm{deg}^{2}$ |
| TPB | $T P B$ | Temperature coefficient for $P B$ | 0.0 | $1 / \mathrm{deg}$ |
| TPHP | $T P H P$ | Temperature coefficient for $P H P$ | 0.0 | $1 / \mathrm{deg}$ |
| CTA\|CTC | $C T A$ | Temperature coefficient for $C J$ | 0.0 | $1 / \mathrm{deg}$ |
| CTP | $C T P$ | Temperature coefficient for $C J P$ | 0.0 | $1 / \mathrm{deg}$ |
| TM1 | $T M 1$ | First order temperature coefficient for $m j$ <br> $(T M \equiv 1$ for Schottky barrier diode) | 0.0 | $1 / \mathrm{deg}$ |
| TM2 | $T M 2$ | Second order temperature coefficient for $m j s w$ <br> $(T M \equiv 2$ for Schottky barrier diode) | 0.0 | $1 / \mathrm{deg}^{2}$ |
| TRS | $T R S$ | Resistance temperature coefficient | $1 / \mathrm{deg}^{2}$ |  |
| XTI | $X T I$ | Saturation current temperature exponent <br> (for Schottky barrier diode) | 3.0 |  |
|  |  |  | 0.0 |  |

Fowler-Nordheim Model Parameters (level=2)

| Parameter | Symbol | Description | Default | Unit |
| :--- | :--- | :--- | :--- | :--- |
| EF | $E F$ | Forward critical electric field | $1.0 \times 10^{8}$ | $\mathrm{~V} / \mathrm{cm}$ |
| ER | $E R$ | Reverse critical electric field | $E F$ | $\mathrm{~V} / \mathrm{cm}$ |
| JF | $J F$ | Forward Fowler-Nordheim current coefficient | $1.0 \times 10^{-10}$ | $\mathrm{~A} / \mathrm{V}^{2}$ |
| JR | $J R$ | Reverse Fowler-Nordheim current coefficient | $J F$ | $\mathrm{~A} / \mathrm{V}^{2}$ |
| TOX | $\tau o x$ | Thickness of oxide layer | 100.0 | $\AA$ |
| L | $L$ | Length of diode | 0.0 | m |
| W | $W$ | Width of diode | 0.0 | m |
| XW | $X W$ | Masking and etching effects | 0.0 | m |

## Current Equations

## Level 1 and Level 3

In levels 1 and 3, the diodes are modeled in forward bias, reverse bias, and breakdown regions.
In forward and reverse bias regions: $V d>-B V e f f$,

$$
\begin{equation*}
I_{d}=I_{\text {seff }} \cdot\left(\exp \left(\frac{V_{d}}{N \cdot V_{t}}-1\right)\right) \tag{0.121}
\end{equation*}
$$

where where $V t$ is thermal voltage, $V t=k T n o m / q, V d$ is the voltage across the diode, $V d=$ VnodelVnode2, BVeff is the adjusted breakdown voltage, and $N$ is emission coefficient ( $N \equiv 1$ for Schottky barrier diode).
$B V e f f$ can be determined by

$$
\begin{equation*}
B V_{e f f}=B V-\left(N \cdot V_{t} \cdot I n\right)\left(\frac{I B V_{e f f}}{I_{b r e a k}}\right) \tag{0.122}
\end{equation*}
$$

when IBVeff>Ibreak.
and

$$
\begin{equation*}
I B V e f f=B V \text {, when } I B V e f f \leq \text { Ibreak. } \tag{0.123}
\end{equation*}
$$

where

$$
\begin{equation*}
I_{\text {break }}=-I_{\text {seff }} \cdot\left(\exp \left(\frac{B V}{N \cdot V_{t}}-1\right)\right) \tag{0.124}
\end{equation*}
$$

In breakdown region: $B V<-B V e f f$

$$
\begin{equation*}
I_{d}=I_{\text {seff }} \cdot\left(\exp \left(\frac{V_{d}+B V_{e f f}}{N \cdot V_{t}}\right)\right) \tag{0.125}
\end{equation*}
$$

In all the above equations we assume that the diode has a finite breakdown voltage, that is $B V \neq \infty$. When BV is not given, or the diode has an infinite breakdown voltage,

$$
\begin{equation*}
I_{d}=I_{\text {seff }} \cdot\left(\exp \left(\frac{V_{d}}{N \cdot V_{t}}-1\right)\right) \tag{0.126}
\end{equation*}
$$

$V d>0$ is the forward-bias region and $V d<0$ is the reverse-bias region. There is no breakdown region in this case.

If the high-level injection effects are considered, the current equations are in forward-bias region $(V d>0)$ :

$$
\begin{equation*}
I^{*}{ }_{d}=\frac{I_{d}}{1+\left(\frac{I_{d}}{I_{K F}}\right)^{\frac{1}{2}}} \tag{0.127}
\end{equation*}
$$

when $I K F \neq 0$.

$$
\begin{equation*}
I * D=I D \tag{0.128}
\end{equation*}
$$

when $I K F=0$.
and in reverse-bias region $(V d<0)$

$$
\begin{equation*}
I^{*}{ }_{d}=\frac{I_{d}}{1+\left(\frac{I_{d}}{I_{K R}}\right)^{\frac{1}{2}}} \tag{0.129}
\end{equation*}
$$

when $I K R \neq 0$.

$$
\begin{equation*}
I * D=I D \tag{0.130}
\end{equation*}
$$

when $I K R=0$.

## Diode Capacitance Equations

The diode capacitance $C D$ consists of the contributions from diffusion capacitance $C d$, junction capacitance (depletion capacitance) $C j$, metal (contact electrode) capacitance $C m$, and polysilicon (contact electrode) capacitance $C p$.

## Diffusion Capacitance

$$
\begin{equation*}
C_{d}=\pi \cdot \frac{\partial I_{d}}{\partial V_{d}} \tag{0.131}
\end{equation*}
$$

Note:
For Schottky barrier diodes, $C d=0(\pi=0)$ because the Schottky barrier diode is a majority carrier device and minority carrier effect can be ignored.

## Junction Capacitance (Depletion Capacitance)

The junction capacitance has two components: the junction bottom area capacitance Cja and the junction periphery capacitance Cjp.
$C j=C j a+C j p$.

There are two sets of junction capacitance equations selected by the parameter dcap.
For dcap=1, the junction bottom area capacitance is given by

$$
\begin{equation*}
C_{j a}=C_{j 0 e f f} \cdot\left(1-\frac{V_{d}}{P B}\right)^{-m_{j}} \tag{0.132}
\end{equation*}
$$

when $V d>F C \times P B$

$$
\begin{equation*}
C_{j a}=C_{j 0 e f f} \cdot \frac{1-F C \times\left(1+m_{j}\right)+m_{j} \times \frac{V_{d}}{P B}}{(1-F C)^{1+m_{j}}} \tag{0.133}
\end{equation*}
$$

when $V d>F C \times P B$

The junction periphery capacitance is given by

$$
\begin{equation*}
C_{j p}=C_{j p 0 e f f} \cdot\left(1-\frac{V_{d}}{P H P}\right)^{-m_{j s w}} \tag{0.134}
\end{equation*}
$$

when $V d>F C S \times P H P$

$$
\begin{equation*}
C_{j a}=C_{j 0 e f f} \cdot \frac{1-F C S \times\left(1+m_{j s w}\right)+m_{j s w} \times \frac{V_{d}}{P B}}{(1-F C S)^{1+m_{j s w}}} \tag{0.135}
\end{equation*}
$$

when $V d>F C S \times P H P$

The total junction capacitance is

$$
\begin{equation*}
C_{j}=C_{j a}+C_{j p} \tag{0.136}
\end{equation*}
$$

For dcap=2 (default), the total junction capacitance is given by

$$
\begin{equation*}
C_{j}=C_{j 0 e f f} \cdot\left(1-\frac{V_{d}}{P B}\right)^{-m_{j}}+C_{j p 0 e f f} \cdot\left(1-\frac{V_{d}}{P H P}\right)^{-m_{j s w}} \tag{0.137}
\end{equation*}
$$

when $V d<0$.

$$
\begin{equation*}
C_{j}=C_{j 0 e f f} \cdot\left(1+m_{j} \cdot \frac{V_{d}}{P B}\right)+C_{j p 0 e f f} \cdot\left(1+m_{s j w} \cdot \frac{V_{d}}{P H P}\right) \tag{0.138}
\end{equation*}
$$

when $V d>0$.

## Metal (Contact Electrode) Capacitance

For level=3 only

$$
\begin{equation*}
C_{m}=\frac{\varepsilon_{o x}}{X_{O M}} \cdot\left(W_{M e f f}+X_{M e f f}\right) \cdot\left(L_{M e f f}+X_{M e f f}\right) \tag{0.139}
\end{equation*}
$$

## Polysilicon (Contact Electrode) Capacitance

For level=3 only

$$
\begin{equation*}
C_{p}=\frac{\varepsilon_{o x}}{X_{O P}} \cdot\left(W_{P e f f}+X_{P e f f}\right) \cdot\left(L_{P e f f}+X_{P e f f}\right) \tag{0.140}
\end{equation*}
$$

## Geometric Scaling Effect

## Level 1

Scaling for level=1 involves the use of the junction area (area), junction periphery ( $P J$ ), and the dimensionless multiplier factor $(M)$ to simulate multiple diodes.

Geometric parameters include

$$
\begin{gather*}
\text { area }_{\text {eff }}=\operatorname{area} \cdot M  \tag{0.141}\\
P J_{e f f}=P J \cdot M \tag{0.142}
\end{gather*}
$$

Element and model parameters include:

$$
\begin{gather*}
I_{K E e f f}=I_{K F} \cdot \text { area }_{e f f}  \tag{0.143}\\
I_{K R E e f f}=I_{K R} \cdot \text { area }_{e f f}  \tag{0.144}\\
I B V_{e f f}=I B V \cdot \text { area }_{e f f}  \tag{0.145}\\
I_{S e f f}=I_{S} \cdot \text { area }_{e f f}+J S W \cdot P J_{e f f}  \tag{0.146}\\
J S W_{e f f}=J S W \cdot P J_{e f f}  \tag{0.147}\\
E X P L I=E X P L I \cdot a r e a_{e f f}  \tag{0.148}\\
C_{j 0 e f f}=C_{j 0} \cdot \text { area }_{e f f}  \tag{0.149}\\
C_{j p 0 e f f}=C_{j p 0} \cdot P J_{e f f}  \tag{0.150}\\
R_{S e f f}=R_{s} /\left(\text { area }_{e f f}\right) \tag{0.151}
\end{gather*}
$$

## Level 3

Level 3 model scaling is affected by the parameters SCALE, SCALM, SHRINK, and M.
When both $L$ and $W$ are specified, geometric parameters include

$$
\begin{gather*}
\text { area }_{e f f}=W_{e f f} \cdot L_{e f f} \cdot M  \tag{0.152}\\
P J_{e f f}=\left(2 \cdot W_{e f f}+2 \cdot L_{e f f}\right) \cdot M \tag{0.153}
\end{gather*}
$$

where

Weff $=W \times S C A L E \times S H R I N K+X W e f f$
$L e f f=L \times S C A L E \times S H R I N K+X W e f f$
and
$X W e f f=X W \times S C A L M$
otherwise
areaeff $=$ area $\times M \times S C A L E 2 \times$ SHRINK 2
$P J e f f=\mathrm{PJ} \times M \times S C A L E \times S H R I N K$
Geometric parameters for polysilicon and metal capacitance include

$$
\begin{aligned}
& L M e f f=L M \text { SCALE } \times \text { SHRINK } \\
& W M e f f=W M S C A L E \times S H R I N K \\
& X M e f f=X M \times S C A L M \\
& L P e f f=L P S C A L E \times S H R I N K \\
& W P e f f=W P S C A L E \times \text { SHRINK } \\
& X P e f f=X P \times S C A L M
\end{aligned}
$$

Element and model parameters include

$$
\begin{gather*}
I_{K E e f f}=I_{K F} \cdot \text { area }_{e f f}  \tag{0.154}\\
I_{K R E e f f}=I_{K R} \cdot \text { area }_{e f f}  \tag{0.155}\\
I B V_{e f f}=\left(I B V \cdot \text { area }_{e f f}\right) /\left(S C A L M^{2}\right)  \tag{0.156}\\
I_{S e f f}=I_{S} \cdot \text { area }_{e f f} / S C A L M^{2}+J S W \cdot P J_{e f f} / S C A L M  \tag{0.157}\\
J S W_{e f f}=\left(J S W \cdot P J_{e f f}\right) /(S C A L M)  \tag{0.158}\\
E X P L I=E X P L I \cdot \operatorname{area}_{e f f}  \tag{0.159}\\
R_{S e f f}=R_{s} /\left(\text { area }_{e f f} \cdot S C A L M^{2}\right)  \tag{0.160}\\
C_{j 0 e f f}=C_{j 0} \cdot \text { area }_{e f f} / S C A L M^{2}  \tag{0.161}\\
C_{j p 0 e f f}=C_{j p 0} \cdot P J_{e f f} /(S C A L M) \tag{0.162}
\end{gather*}
$$

## Temperature Effects

## Energy Gap

The calculation of energy gap is dependent on TLEV. For TLEV=0, 1, or 3, energy gap is always calculated as follows:

$$
\begin{equation*}
E_{g}\left(T_{n o m}\right)=1.16-\left(7.02 \times 10^{4}\right) \frac{T_{\text {nom }}^{2}}{T_{\text {nom }}+1108.0} \tag{0.163}
\end{equation*}
$$

If $\mathbf{T L E V}=\mathbf{2}$, the energy gap is calculated as a function of model parameters $E_{g}(0), G A P 1$, and $G A P 2$ :

$$
\begin{equation*}
E_{g}\left(T_{n o m}\right)=E_{g}(0)-G A P 1 \cdot \frac{T_{n o m}^{2}}{T_{n o m}+G A P 2} \tag{0.164}
\end{equation*}
$$

## Saturation Current

$$
\begin{align*}
I_{S}(T) & =I_{S} \cdot e^{\frac{f a c l n}{N}}  \tag{0.165}\\
J S W(T) & =J S W \cdot e^{\frac{f a c l n}{N}} \tag{0.166}
\end{align*}
$$

For $T L E V=0$ and 1

$$
\begin{equation*}
\text { facln }=\frac{E_{g}(0)}{V_{t}\left(T_{n o m}\right)}-\frac{E_{g}(0)}{V t(T)}+X T I \cdot \ln \left(\frac{T}{T_{n o m}}\right) \tag{0.167}
\end{equation*}
$$

For $T L E V=2$

$$
\begin{equation*}
\text { facln }=\frac{E_{g}\left(T_{\text {nom }}\right)}{V_{t}\left(T_{\text {nom }}\right)}-\frac{E_{g}(T)}{V t(T)}+X T I \cdot \ln \left(\frac{T}{T_{\text {nom }}}\right) \tag{0.168}
\end{equation*}
$$

For $T L E V=3$

$$
\begin{equation*}
\text { facln }=\frac{V_{S B}}{V_{t}\left(T_{n o m}\right)}-\frac{V_{S B}}{V t(T)}+X T I \cdot \ln \left(\frac{T}{T_{n o m}}\right) \tag{0.169}
\end{equation*}
$$

## Breakdown Voltage

For $T L E V=0$

$$
\begin{equation*}
B V(T)=B V-T C V \cdot \Delta T \tag{0.170}
\end{equation*}
$$

For $T L E V=1,2$, or 3

$$
\begin{equation*}
B V(T)=B V \cdot(1-T C V \cdot \Delta T) \tag{0.171}
\end{equation*}
$$

where $\Delta T=T$ - Tnom
Transit Time

$$
\begin{equation*}
\tau(T)=\tau \cdot\left(1+\tau_{t 1} \cdot \Delta T+\tau_{t 2} \cdot \Delta T^{2}\right) \tag{0.172}
\end{equation*}
$$

## Contact Potential

For $T L E V=0$

$$
\begin{gather*}
P B(T)=P B \cdot\left(\frac{T}{T_{n o m}}\right)-V_{t}(T) \cdot\left\{3 \cdot \ln \left(\frac{T}{T_{n o m}}\right)+\frac{E_{g}\left(T_{n o m}\right)}{V_{t}\left(T_{n o m}\right)}-\frac{E_{g}(T)}{V_{t}(T)}\right\}  \tag{0.173}\\
P H P(T)=P H P \cdot\left(\frac{T}{T_{n o m}}\right)-V_{t}(T) \cdot\left\{3 \cdot \ln \left(\frac{T}{T_{n o m}}\right)+\frac{E_{g}\left(T_{n o m}\right)}{V_{t}\left(T_{n o m}\right)}-\frac{E_{g}(T)}{V_{t}(T)}\right\} \tag{0.174}
\end{gather*}
$$

For $T L E V=1$ or 2

$$
\begin{gather*}
P B(T)=P B-T P B \times \Delta T  \tag{0.175}\\
P H P(T)=P H P-T P H P \times \Delta T \tag{0.176}
\end{gather*}
$$

For $T L E V=3$

$$
\begin{gather*}
P B(T)=P B+d p b d t \times \Delta T  \tag{0.177}\\
P H P(T)=P H P-d p h p d t \times \Delta T \tag{0.178}
\end{gather*}
$$

where
$T L E V=2$

$$
\begin{equation*}
d p b d t= \tag{0.179}
\end{equation*}
$$

$$
-\frac{E_{g}\left(T_{n o m}\right)+3 \cdot V_{t}\left(T_{n o m}\right)+\left[E_{g}(0)-E_{g}\left(T_{n o m}\right)\right] \cdot\left(2-\frac{T_{n o m}}{T_{n o m}+G A P 2}\right)-P B}{T_{n o m}}
$$

$d p h p d t=$

$$
\begin{equation*}
-\frac{E_{g}\left(T_{n o m}\right)+3 \cdot V_{t}\left(T_{n o m}\right)+\left[E_{g}(0)-E_{g}\left(T_{n o m}\right)\right] \cdot\left(2-\frac{T_{n o m}}{T_{n o m}+G A P 2}\right)-P H P}{T_{\text {nom }}} \tag{0.180}
\end{equation*}
$$

and
$T L E V=0$ or 1
$\operatorname{Eg}(0)$ and GAP2 take their default values in the above equations:
$E g(0)=1.16$
$G A P 2=1108.0$

## Junction Capacitance

$T L E V=0$

$$
\begin{align*}
C_{j}(T) & =C_{j 0} \cdot\left\{1+m_{j} \cdot\left(4.0 \times 10^{-4} \cdot \Delta T-\frac{P B(T)}{P B}+1\right)\right\}  \tag{0.181}\\
C_{j s w}(T) & =C_{j s w 0} \cdot\left\{1+m_{j} \cdot\left(4.0 \times 10^{-4} \cdot \Delta T-\frac{P H P(T)}{P H P}+1\right)\right\} \tag{0.182}
\end{align*}
$$

$T L E V=1$

$$
\begin{gather*}
C_{j}(T)=C_{j 0} \cdot(1+C T A \cdot \Delta T)  \tag{0.183}\\
C_{j s w}(T)=C_{j s w 0} \cdot(1+C T P \cdot \Delta T) \tag{0.184}
\end{gather*}
$$

$T L E V=2$

$$
\begin{gather*}
C_{j}(T)=C_{j 0} \cdot\left(\frac{P B}{P B(T)}\right)^{m_{j}}  \tag{0.185}\\
C_{j s w}(T)=C_{j s w 0} \cdot\left(\frac{P H P}{P H P(T)}\right)^{m_{j s w}} \tag{0.186}
\end{gather*}
$$

Note:
Use $m j$ instead of $m j(T)$ in the above equation.
$T L E V=3$

$$
\begin{gather*}
C_{j}(T)=C_{j 0} \cdot 1-0.5 \cdot d p b d t \cdot \frac{\Delta T}{P B}  \tag{0.187}\\
C_{j s w}(T)=C_{j s w 0} \cdot\left(1-0.5 \cdot d p h p d t \cdot \frac{\Delta T}{P H P}\right) \tag{0.188}
\end{gather*}
$$

Grading Coefficient

$$
\begin{equation*}
m_{j}(T)=m_{j} \cdot\left(1+T M 1 \cdot \Delta T+T M 2 \cdot \Delta T^{2}\right) \tag{0.189}
\end{equation*}
$$

Resistance

$$
\begin{equation*}
R_{S}(T)=R_{S} \cdot(1+T R S \cdot \Delta T) \tag{0.190}
\end{equation*}
$$

## Fowler-Nordheim Model (Level 2)

The Fowler-Nordheim model is used to characterize the tunneling current flow through thin insulators in nonvolatile memory devices such as the floating gate devices and the MIOS (metal-insulator-oxide-
semiconductor) devices. The insulators in these devices are sufficiently thin (about $100 \AA$ ) to permit tunneling of carriers.

Current Equations

$$
\begin{equation*}
I_{d}=\operatorname{area}_{e f f} \cdot J_{F} \cdot\left(\frac{v_{d}}{t_{o x}}\right)^{2} \cdot e^{-\frac{E_{F} \cdot t_{o x}}{V_{d}}} \tag{0.191}
\end{equation*}
$$

when $V d \geq 0$

$$
\begin{equation*}
I_{d}=-\operatorname{area}_{e f f} \cdot J_{R} \cdot\left(\frac{v_{d}}{t_{o x}}\right)^{2} \cdot e^{-\frac{E_{R} \cdot t_{o x}}{V_{d}}} \tag{0.192}
\end{equation*}
$$

when $V d<0$
where
areaeff $=$ Weff $\times$ Leff $\times M$
and
Weff $=W \times S C A L M \times S H R I N K+X W e f f$

Leff $=L \times S C A L M \times S H R I N K+X W e f f$
$X W e f f=X W \times S C A L M$
Capacitance

$$
\begin{equation*}
C_{D}=\operatorname{area}_{e f f} \cdot \frac{\varepsilon_{o x}}{t_{o x}} \tag{0.193}
\end{equation*}
$$

## Application Notes—Schottky Barrier Diodes

The Schottky barrier diode is not explicitly modeled in T-Spice, but it can be simulated using the PN junction diode model provided extra attention is paid to the differences between the PN junction diode and Schottky barrier diode.

Schottky barrier diodes and PN junction diodes have a similar I-V relation, but their saturation current expressions are quite different. For Schottky barrier diode, the saturation current is given by

$$
\begin{equation*}
I_{S}=A_{R C} \cdot K_{R C} \cdot T_{n o m}^{2} \cdot \exp \left(-\frac{V_{s b}}{V_{t}}\right) \tag{0.194}
\end{equation*}
$$

where $A_{R C}=1.2 \times 10^{6}\left(A \cdot \mathrm{~m}^{-2} \cdot K^{-2}\right)$ is the Richardson constant, $K R C$ is the ratio of the effective Richardson constant to the Richardson constant, VSB is the Schottky barrier height, and $V_{t}=\left(k T_{n o m}\right) / q$ is the thermal voltage. Use this calculated $I S$ value for Schottky barrier diode if $I S$ is not specified.

Some typical $K R C$ values are:

| Type | $\boldsymbol{S i}$ | $\boldsymbol{G e}$ | $\boldsymbol{G a A s}$ |
| :--- | :--- | :--- | :--- |
| p-type | 0.66 | 0.34 | 0.62 |
| n-type | - (111): 2.2 | - $(111): 1.11$ | 0.068 |
|  | - $(100): 2.1$ | • $(100): 1.19$ |  |

Some other parameter values intended for Schottky barrier diodes are indicated in the diode parameter list. Use these values instead of default in the simulation of Schottky barrier diode if these parameters are not specified.

## JFET

The junction field-effect transistor model uses the basic FET model of Schichmann and Hodges. The DC characteristics are modeled by the threshold voltage and the gain factor, and charge storage is modeled by two reverse-biased PN junctions. Source and drain series resistances are included. JFET models are always level 0 .

## Parameters

| .model name $\mathrm{njf} \mid \mathrm{pjf}$ | [parameters] |  |  |  |
| :--- | :--- | :--- | :--- | :--- |
| Parameter | Symbol | Description | Default | Units |
| vto | $V t 0$ | Threshold voltage | -2.0 | V |
| beta | $\beta$ | Transconductance parameter | $1.0 \times 10^{-4}$ | $\mathrm{~A} / \mathrm{N}^{2}$ |
| lambda | $\lambda$ | Channel length modulation parameter | 0.0 | $1 / \mathrm{N}$ |
| rd | $R d$ | Drain series resistance | 0.0 | $\Omega$ |
| rs | $R s$ | Source series resistance | 0.0 | $\Omega$ |
| cgs | $C g s$ | Zero-bias gate-source junction capacitance | 0.0 | F |
| cgd | $C g d$ | Zero-bias gate-drain junction capacitance | 0.0 | F |
| pb | $P B$ | Gate junction potential | 1.0 | V |
| is | $I S$ | Gate junction saturation current | $1.0 \times 10^{-14}$ | A |
| fc | $F C$ | Forward-bias depletion capacitance coefficient | 0.5 | - |

## Large-Signal Model



## Equations

## Currents

In the normal or forward region of operation, the DC currents are described by the following equations, based on the quadratic FET model of Shichmann and Hodges.

For $(V G S-V T O) \leq 0$,

$$
\begin{equation*}
I_{D S}=0 \tag{0.195}
\end{equation*}
$$

For $0<(V G S-V T O) \leq V D S$,

$$
\begin{equation*}
I_{D S}=\beta\left(V_{G S}-V_{T O}\right)^{2}\left(1+\lambda V_{D S}\right) \tag{0.196}
\end{equation*}
$$

For $0<V D S<(V G S-V T O)$,

$$
\begin{equation*}
I_{D S}=\beta V_{D S}\left[2\left(V_{G S}-V_{T O}\right)-V_{D S}\right]\left(1+\lambda V_{D S}\right) \tag{0.197}
\end{equation*}
$$

For the inverse or reverse region of operation where $V D S<0$, the same set of equations is used, with $V G S$ replaced by $V G D$ and the signs on the $V D S$ terms reversed.

For $(V G D-V T O) \leq 0$,

$$
\begin{equation*}
I_{D S}=0 \tag{0.198}
\end{equation*}
$$

For $0<(V G D-V T O) \leq V D S$,

$$
\begin{equation*}
I_{D S}=\beta\left(V_{G D}-V_{T O}\right)^{2}\left(1-\lambda V_{D S}\right) \tag{0.199}
\end{equation*}
$$

For $0<V D S<(V G D-V T O)$,

$$
\begin{equation*}
I_{D S}=\beta V_{D S}\left[2\left(V_{G D}-V_{T O}\right)-V_{D S}\right]\left(1-\lambda V_{D S}\right) \tag{0.200}
\end{equation*}
$$

The gate-to-drain and gate-to-source leakage currents are:

$$
\begin{align*}
& I_{G D}=I_{S} \cdot\left(e^{\frac{q V_{G D}}{k T}}-1\right)  \tag{0.201}\\
& I_{G S}=I_{S} \cdot\left(e^{\frac{q V_{G S}}{k T}}-1\right) \tag{0.202}
\end{align*}
$$

The total currents are then:

$$
\begin{gather*}
I_{D}=I_{D S}-I_{G D}  \tag{0.203}\\
I_{G}=I_{G D}+I_{G S}  \tag{0.204}\\
I_{S}=-\left(I_{D S}+I_{G S}\right) \tag{0.205}
\end{gather*}
$$

## Charges

The charge equations corresponding to $C G D$ and $C G S$ are based on reverse-biased $\mathrm{P}-\mathrm{N}$ step junctions.
For $V G X<F C \cdot P B$,

$$
\begin{equation*}
Q_{G X}=2 C_{G X} \cdot P B\left(1-\sqrt{1-\frac{V_{G X}}{P B}}\right) \tag{0.206}
\end{equation*}
$$

For $V G X \geq F C \cdot P B$,

$$
\begin{align*}
Q_{G X}= & \frac{C_{G X}\left[\left(1-\frac{3}{2} F C\right)\left(V_{G X}-F C \cdot P B\right)+\frac{1}{4 P B}\left(V_{G X}^{2}-(F C \cdot P B)^{2}\right)\right]}{(1-F C) \sqrt{1-F C}}+  \tag{0.207}\\
& C_{G X} \cdot P B \cdot(1-\sqrt{1-F C})
\end{align*}
$$

$X$ denotes either source $(S)$ or drain $(D)$. The junction charge equations are identical to those used by the BJT and MOSFET models, except that the grading coefficient has been fixed at 0.5 .

## MESFET

## Parameters

.model name nmf|pmf |njf|pjf [parameters]
For HSPICE compatibility, you can create a MESFET device in T-Spice using a name which begins with the letter j . The syntax for the MESFET device statement is exactly as documented in "MESFET (z)" on page 173, except that the device name is jname instead of zname.

Additionally, the MESFET model can use either the .model name [ $\mathbf{n m f} \mid \mathbf{p m f}$ ] naming convention or .model name [ $\mathbf{n j f} \mid \mathbf{~ p j f}$ ].

## Submodel Selectors

| Parameter | Symbol | Description | Default | Units |
| :--- | :--- | :--- | :--- | :---: |
| level | LEVEL | Level selector (1, 2 or 3) | 1 |  |
| sat | SAT | Model selector | 0 | - |
| capop | $C A P O P$ | Capacitance model selector | 0 | - |
| dcap | DCAP | Forward-biased diode equation selector <br> $(C A P O P=0)$ | 2 | - |
| tlev | $T L E V$ | Temperature model selector | 0 | - |
| tlevc | $T L E V C$ | Junction capacitance temperature model <br> selector | 0 | - |
| nlev | $N L E V$ | Channel thermal noise equation selector | 2 | - |
| DC Parameters |  |  |  |  |


| Parameter | Symbol | Description | Default | Units |
| :--- | :--- | :--- | :--- | :--- |
| alpha | $\alpha$ | Saturation voltage factor | 2.0 | $\mathrm{~V}^{-1}$ |
| b | $b$ | Doping tail extending parameter | 0.3 | $\mathrm{~V}^{-1}$ |
| beta | $\beta$ | Transconductance parameter | $2.5 \times 10^{-3}$ | $\mathrm{~A} / \mathrm{N}^{2}$ |
| d | $D$ | Channel dielectric constant | $11.7(\mathrm{Si})$ | - |
| gamma | $\gamma d s$ | Drain-induced VT0 lowering | 0.0 | A |
| gamds |  |  | $1.0 \times 10^{-14}$ | A |
| is | $I s a t$ | Gate saturation current | 0.0 | $\mathrm{~V}^{-1}$ |
| k1 | $k l$ | Body effect on VT0 | 0.0 | $\mathrm{~V}^{-1}$ |
| lambda | $\lambda$ | Channel length modulation parameter | $1.552 \times 10^{16}$ | $\mathrm{~cm}^{-3}$ |
| nchan | $N D$ | Channel doping concentration | 0.0 | $\Omega$ |
| rd | $R d$ | Drain ohmic resistance | 0.0 | $\Omega$ |
| rg | $R g$ | Gate resistance |  |  |


| Parameter | Symbol | Description | Default | Units |
| :--- | :--- | :--- | :--- | :--- |
| rs | $R s$ | Source ohmic resistance | 0.0 | $\Omega$ |
| rsh | $R s h$ | Source/drain sheet resistance | 0.0 | $\Omega / \mathrm{m}^{2}$ |
| rshg | $R s h g$ | Gate sheet resistance | 0.0 | $\Omega / \mathrm{m}^{2}$ |
| rshl | $R s h l$ | Channel sheet resistance | 0.0 | $\Omega / \mathrm{m}^{2}$ |
| satexp | $n v d s$ | Drain voltage exponent for sat=3 | 3.0 | - |
| ucrit | $E c$ | Critical mobility degradation field | 0.0 | $\mathrm{~V} / \mathrm{cm}$ |
| vbi | $V b i$ | Gate diode built-in voltage | 1.0 | V |
| vgexp | $n v g s t$ | Gate voltage exponent for sat=3 | 2.0 | - |
| vp | $V p$ | Channel pinch-off voltage | Computed. | V |
| vto | $V T 0$ | Threshold voltage | Computed. | V |

## Capacitance Parameters

| Parameter | Symbol | Description | Default | Units |
| :--- | :--- | :--- | :--- | :--- |
| cgs | $C g s$ | Zero bias G-S capacitance | 0.0 | F |
| cgd | $C g d$ | Zero bias G-D capacitance | 0.0 | F |
| crat | $C R A T$ | Source fraction of GCAP | 0.666 | - |
| fc | $F C$ | Forward bias depletion capacitance coefficient | 0.5 | - |
| gcap | $G C A P$ | Total zero bias gate capacitance | - | F |
| interr | $E i n t$ | Integration error bound $(C A P O P=1)$ | 0.01 | - |
| m | $m$ | Junction grading coefficient $(C A P O P=0)$ | 0.5 | - |
| pb | $\phi s 0$ | Gate junction potential | 0.8 | V |
| tt | $\tau$ | Transit time $(C A P O P=0)$ | 0.0 | s |
| vdel | $\delta$ | Transition width for $\operatorname{Vgs}(C A P O P=1)$ | 0.2 | V |
| vmax | $V m a x$ | $V n$ limiting value $(C A P O P=1)$ | 0.5 | V |

## Noise Parameters

| Parameter | Symbol | Description | Default | Units |
| :--- | :--- | :--- | :--- | :--- |
| af | Af | Flicker noise exponent | 1.0 | - |
| gdsnoi | $G D S N O$ | Thermal channel noise coefficient (NLEV=3) | 1.0 | - |
| kf | $I$ |  |  |  |
|  | $K f$ | Flicker noise coefficient | 0.0 | - |

## Geometry Parameters

| Parameter | Symbol | Description | Default | Units |
| :--- | :--- | :--- | :--- | :--- |
| acm | ACM | Area calculation method selector | 0 | - |
| align | ALIGN | Misalignment of gate | 0.0 | m |
| hdif | Hdif | Space between S/D contacts and junction | 0.0 | m |
| I | L | Default gate length | 0.0 | m |
| Idel | Ldel | Delta between drawn and optical gate length | 0.0 | m |
| Idif | Ldif | Distance from junction to gate edge | 0.0 | m |
| w | W | Default gate width | 0.0 | m |
| wdel | Wdel | Delta between drawn and optical gate width | 0.0 | m |

## Area Calculation Method (ACM) Parameters

|  | ACM $=0$ | ACM $=1$ |
| :---: | :---: | :---: |
| AREAeff | $\frac{W e f f}{L e f f} \cdot M$ | Weff $\cdot$ Leff $\cdot M$ |
| RDeff | $\frac{R D}{\text { AREAeff }}$ | If $\mathrm{RD}=\mathbf{0}$ : $\frac{R D}{M}$ <br> If $\mathrm{RD}=\mathbf{0}$ : |
|  |  | $\frac{D I F}{2 f f \cdot M}+R S H L \cdot \frac{L D I F+A L I G N}{W e f f \cdot M}$ |
| RSeff | $\frac{R S}{\text { AREAeff }}$ | $\begin{aligned} & \text { If } \mathrm{RS}=\mathbf{0} \text { : } \\ & \frac{R S}{M} \\ & \text { If } \mathrm{RS}=\mathbf{0} \text { : } \end{aligned}$ |
|  |  | $\begin{aligned} & \text { RSH } \cdot \frac{H D I F}{W e f f \cdot M} \\ & + \text { RSHL } \cdot \frac{L D I F-A L I G N}{W e f f \cdot M} \end{aligned}$ |
| RGeff | $R G \cdot \frac{A R E A e f f}{M^{2}}$ | If $\mathbf{R G}=\mathbf{0}$ : <br> $\frac{R G}{M}$ <br> If $\mathrm{RG}=0$ : |
|  |  | $R S H G \cdot \frac{W e f f}{L e f f \cdot M}$ |


|  | ACM=0 | ACM=1 |
| :--- | :--- | :--- |
| ISeff | $I S \cdot A R E A e f f$ | IS $\cdot$ AREAeff |
| CGSeff | $C G S \cdot$ AREAeff | CGS $\cdot$ AREAeff |
| CGDeff | $C G D \cdot$ AREAeff | CGD $\cdot$ AREAeff |
| BETAeff | BETA $\cdot \frac{\text { Weff }}{\text { Leff }} \cdot M$ | BETA $\cdot \frac{\text { Weff }}{\text { Leff }} \cdot M$ |

Note that the model parameters IS, CGS, and CGD are unitless when $\mathbf{A C M}=\mathbf{0}$ and per square meter when $\mathbf{A C M}=\mathbf{1}$. For example, when $\mathbf{A C M}=\mathbf{0}, C G S=5 \times 10^{-12}, C G D=1.4 \times 10^{-11}$, and $I S=1 \times 10^{-14}$; for $\mathbf{A C M}=1$, however, $C G S=5, C G D=14$, and $I S=1 \times 10^{-2}$.

## Temperature Dependence Parameters

| Parameter | Symbol | Description | Default | Units |
| :--- | :--- | :--- | :--- | :--- |
| bex | $B E X$ | Mobility temperature exponent | 0.0 | - |
| ctd | $C T D$ | Temperature coefficient for $C g d$ | 0.0 | $\mathrm{deg}^{-1}$ |
| cts | $C T S$ | Temperature coefficient for $C g s$ | 0.0 | $\mathrm{deg}^{-1}$ |
| eg | $E g$ | Energy gap for G-D and G-S diodes | 1.16 | eV |
| gap1 | $G A P 1$ | First-order bandgap correction | $7.02 \mathrm{e}-4$ | $\mathrm{eV} / \mathrm{deg}$ |
| gap2 | $G A P 2$ | Second-order bandgap correction | 1108 | deg |
| n | $N$ | G-S and G-D diode emission coefficient | 1.0 | - |
| tcv | $T C V$ | Temperature coefficient for $V T 0$ | 0.0 | $\mathrm{deg}^{-1}$ |
| tpb | $T P B$ | Temperature coefficient for $p b$ | 0.0 | $\mathrm{deg}^{-1}$ |
| trd | $T R D$ | Temperature coefficient for $R d$ | 0.0 | $\mathrm{deg}^{-1}$ |
| trg | $T R G$ | Temperature coefficient for $R g$ | 0.0 | $\mathrm{deg}^{-1}$ |
| trs | $T R S$ | Temperature coefficient for $R s$ | 0.0 | $\mathrm{deg}^{-1}$ |
| xti | $X T I$ | $I s a t$ temperature exponent | 0.0 | - |

## Large-Signal Model



## Equations

There are three levels of the T-Spice MESFET model.

- Level 1. The Curtice model-a diode-based capacitance model and a simplified Ids calculation.
- Level 2. The Statz model (Statz et al. 1987)—a revision of the Curtice model, with an improved capacitance model and a more sophisticated Ids calculation.
- Level 3. An HSPICE-compatible model—highly customizable.


## Currents

For all three levels,

$$
\begin{equation*}
I_{d s}=\beta \cdot \frac{\left(V_{g s t}\right)^{V G E X P}}{A} \cdot B \cdot\left(1+\lambda V_{d s}\right) \tag{0.208}
\end{equation*}
$$

where

$$
\begin{equation*}
V_{g s t}=V_{g s}-V_{T 0}-\gamma_{d s} \cdot V_{d s} \tag{0.209}
\end{equation*}
$$

$A$ is the doping profile extension factor. At level $1, A=0$; otherwise:

$$
\begin{equation*}
A=1+b V_{g s t} \tag{0.210}
\end{equation*}
$$

$V G E X P$ can be varied only at level 3 ; at levels 1 and 2 , it is fixed at 2.0 .
$B$ is the saturation term; its form depends on the value of $S A T$.
When $S A T=0$ :

$$
\begin{equation*}
B=\tanh \left(\alpha V_{d s}\right) \tag{0.211}
\end{equation*}
$$

This form is fixed (that is, SAT can only take a value of 0 ) at level 1.

When $S A T=1$ :

$$
\begin{equation*}
B=\tanh \left(\alpha \cdot \frac{V_{d s}}{V_{g s t}}\right) \tag{0.212}
\end{equation*}
$$

When $S A T=2$ :

$$
\begin{equation*}
B=1-\left(1-\alpha \cdot \frac{V_{d s}}{3}\right)^{3} \tag{0.213}
\end{equation*}
$$

When $V d s>3 / \alpha, B=1$. This form is fixed (that is, SAT can only take a value of 2 ) at level 2.
When $S A T=3$ and $V d s<S A T E X P / \alpha$ :

$$
\begin{equation*}
B=1-\left(1-\alpha \cdot \frac{V_{d s}}{S A T E X P}\right)^{\text {SATEXP }} \tag{0.214}
\end{equation*}
$$

Otherwise, $B=1$.

## Capacitances

There are two capacitance models, one at level 1 (a "diode-like" model) and one at level 2 (the Statz model). The CAPOP parameter selects between the models.

When $C A P O P=0$ :
When the junctions are reverse-biased $(V g d<F C \cdot \phi s O)$ :

$$
\begin{align*}
& C_{g d}=C_{g d}(0) \cdot\left(1-\frac{V_{g d}}{\phi_{s 0}}\right)^{-m}  \tag{0.215}\\
& C_{g s}=C_{g s}(0) \cdot\left(1-\frac{V_{g s}}{\phi_{s 0}}\right)^{-m} \tag{0.216}
\end{align*}
$$

When the junctions are forward-biased, two models are available; the $D C A P$ parameter selects between them. When $D C A P=1$ :

$$
\begin{align*}
C_{g d} & =\tau \cdot \frac{\partial I_{g d}}{\partial V_{g d}}+C_{g d}(0) \cdot \frac{1-F C(1+m)+m \frac{V_{g d}}{\phi_{s 0}}}{(1-F C)^{m+1}}  \tag{0.217}\\
C_{g s} & =\tau \cdot \frac{\partial I_{g s}}{\partial V_{g s}}+C_{g s}(0) \cdot \frac{1-F C(1+m)+m \frac{V_{g s}}{\phi_{s 0}}}{(1-F C)^{m+1}} \tag{0.218}
\end{align*}
$$

When $D C A P=2$ (default):

$$
\begin{gather*}
C_{g d}=\tau \cdot \frac{\partial I_{g d}}{\partial V_{g d}}+C_{g d}(0) \cdot\left(1+m \frac{V_{g d}}{\phi_{s 0}}\right)  \tag{0.219}\\
C_{g s}=\tau \cdot \frac{\partial I_{g s}}{\partial V_{g s}}+C_{g s}(0) \cdot\left(1+m \frac{V_{g s}}{\phi_{s 0}}\right) \tag{0.220}
\end{gather*}
$$

When $C A P O P=1$ :
The basic Statz capacitance equations are:

$$
\begin{aligned}
& C_{g s, g d}=\frac{1}{4} \frac{C_{g s}(0)}{\sqrt{1-\frac{V_{n}}{\phi_{s 0}}} \times\left[1+\frac{V_{e f f}-V_{T 0}}{\sqrt{\left(V_{e f f}-V_{T 0}\right)^{2}+\delta^{2}}}\right]\left[1 \pm \frac{V_{g s}-V_{g d}}{\sqrt{\left(V_{g s}-V_{g d}\right)^{2}+(\alpha)^{-2}}}\right]} \\
& +\frac{1}{2} \times C_{g d}(0)\left[1 \mp \frac{V_{g s}-V_{g d}}{\sqrt{\left(V_{g s}-V_{g d}\right)^{2}+(\alpha)^{-2}}}\right]
\end{aligned}
$$

where

$$
\begin{gather*}
V_{e f f}=\frac{1}{2}\left[V_{g s}+V_{g d}+\sqrt{\left(V_{g s}-V_{g d}\right)^{2}+(\alpha)^{-2}}\right]  \tag{0.222}\\
V_{n}=\frac{1}{2}\left[V_{e f f}+V_{T 0}+\sqrt{\left(V_{e f f}-V_{T 0}\right)^{2}+(\delta)^{2}}\right] \tag{0.223}
\end{gather*}
$$

If $V_{n}>V_{\max }$, then $V n$ is limited to $V m a x$. In the plus/minus signs $( \pm)$ above, the top signs hold for $C g s$, the bottom ones for $C g d$.

## Temperature Dependence Equations

In the following, $\Delta T=T-T_{r e f}$. $T_{r e f}$ is the temperature at which the user-supplied parameters are valid, which defaults to $25^{\circ} \mathrm{C}$. All temperatures in the following equations are assumed to be in Kelvin.
$E_{g}$ temperature dependence. For all values of TLEV, the energy gap $E_{g}$ at the reference and simulation temperatures is calculated using

$$
\begin{equation*}
E_{g}(T)=E G-G A P 1 \times \frac{T}{T+G A P 2} \tag{0.224}
\end{equation*}
$$

For TLEV 0 and 1, EG, GAP1, and GAP2 are held fixed at 1.16, $7.02 \times 10^{-4}$, and 1108.0, respectively, regardless of what values the user specifies for these parameters.

Saturation current temperature dependence. The saturation current temperature extrapolation is calculated by the following general equation:

$$
\begin{equation*}
I_{s}(T)=I S \cdot \exp \left\{\frac{e}{k_{B} N}\left(\frac{E_{g}\left(T_{r e f}\right)}{T_{r e f}}-\frac{E_{g}(T)}{T}+X T I \cdot \operatorname{In}\left(\frac{T}{T_{r e f}}\right)\right)\right\} \tag{0.225}
\end{equation*}
$$

For TLEV 0 and 1, the user-supplied $E G$ is used in place of $E_{g}(T)$ for all $T$. For TLEV=2, $E_{g}(T)=E_{g}(T)$, as calculated above.

Capacitance parameters temperature dependence. A separate selection parameter, TLEVC, is used to choose one of four methods of temperature-adjusting the gate capacitance values. This parameter also influences the temperature compensation of $\phi_{s 0}$.

For TLEVC $=0$, the gate junction potential $\left(\theta_{s 0}\right)$ is temperature-adjusted as follows:

$$
\begin{equation*}
\phi_{s 0}(T)=\Phi_{s 0} \cdot \frac{T}{T_{r e f}}-\frac{3 k_{B}}{e} T \ln \left(\frac{T}{T_{r e f}}\right)-E_{g}\left(T_{r e f}\right) \cdot \frac{T}{T_{r e f}}+E_{g}(T) \tag{0.226}
\end{equation*}
$$

The gate capacitances are calculated by

$$
\begin{align*}
& C_{g s}(T)=C_{g s} \cdot\left[1+m \cdot\left(4.0 \times 10^{-4} \cdot \Delta T-\frac{\phi_{s 0(T)}}{\phi_{s 0\left(T_{\text {ref }}\right)}}+1\right)\right]  \tag{0.227}\\
& C_{g d}(T)=C_{g s} \cdot\left[1+m \cdot\left(4.0 \times 10^{-4} \cdot \Delta T-\frac{\phi_{s 0(T)}}{\phi_{s 0\left(T_{\text {ref }}\right)}}+1\right)\right] \tag{0.228}
\end{align*}
$$

For TLEVC $=1$, the junction potential is temperature-adjusted with

$$
\begin{equation*}
\phi_{s 0}(T)=\phi_{s 0}-T P B \cdot \Delta T \tag{0.229}
\end{equation*}
$$

The gate capacitances are calculated by

$$
\begin{align*}
& C_{g s}(T)=C_{g s} \cdot(1+C T S+\Delta T)  \tag{0.230}\\
& C_{g d}(T)=C_{g d} \cdot(1+C T S \cdot \Delta T) \tag{0.231}
\end{align*}
$$

For TLEVC=2, the junction potential is calculated as it is for TLEVC=1. The gate capacitances are calculated by

$$
\begin{align*}
& C_{g s}(T)=C_{g s} \cdot\left(\frac{\phi_{s 0}}{\phi_{s 0^{T}}}\right)^{m}  \tag{0.232}\\
& C_{g s}(T)=C_{g d} \cdot\left(\frac{\phi_{s 0}}{\phi_{s 0^{T}}}\right)^{m} \tag{0.233}
\end{align*}
$$

For TLEVC $=3$, the junction potential calculation attempts to estimate the term $d \phi_{s 0} /(d T)(d p b d t)$ using the following equations, depending on TLEV.

For TLEV=0 or 1 ,

$$
\begin{equation*}
d p b d t=-\left(\frac{1}{T_{r e f}} E_{g}\left(T_{r e f}\right)+\frac{3 k_{B}}{e} T_{r e f}+\left(1.16-E_{g}\left(T_{r e f}\right)\right) \cdot\left(2-\frac{T_{r e f}}{T_{r e f}+1108}\right)\left(-\phi_{s 0}\right)\right) \tag{0.234}
\end{equation*}
$$

For TLEV=2,

$$
\begin{equation*}
d p b d t=-\left(\frac{1}{T_{r e f}} E_{g}\left(T_{r e f}\right)+\frac{3 k_{B}}{e} T_{r e f}+\left(E G-E_{g}\left(T_{r e f}\right)\right) \cdot\left(2-\frac{T_{r e f}}{T_{r e f}+G A P 2}\right)\left(-\phi_{s 0}\right)\right) \tag{0.235}
\end{equation*}
$$

The gate capacitances are then calculated by

$$
\begin{align*}
& C_{g s}(T)=C_{g s} \cdot\left(1-0.5 \cdot d p b d t \times \frac{\Delta T}{\phi_{s 0}}\right)  \tag{0.236}\\
& C_{g c}(T)=C_{g d} \cdot\left(1-0.5 \cdot d p b d t \times \frac{\Delta T}{\phi_{s 0}}\right) \tag{0.237}
\end{align*}
$$

Note that $C_{g s, g d}$ becomes what is referred to elsewhere as $C_{g s, g d}(0)$, the zero-bias gate capacitances. $V_{T O}$ temperature dependence. The threshold voltage is temperature-compensated with a simple linear model

$$
\begin{equation*}
V_{T O}(T)=V_{T O}-T C V \times \Delta T \tag{0.238}
\end{equation*}
$$

Transconductance temperature dependence. The temperature compensation of the transconductance factor $(\beta)$ is calculated as follows

$$
\begin{equation*}
\beta(T)=\beta \cdot\left(\frac{T}{T_{r e f}}\right)^{B E X} \tag{0.239}
\end{equation*}
$$

Parasitic resistance temperature dependence. The source, drain, and gate parasitic resistances are temperature-compensated by the following equations

$$
\begin{align*}
& R_{d}(T)=R_{d} \cdot(1+T R D \times \Delta T)  \tag{0.240}\\
& R_{s}(T)=R_{s} \cdot(1+T R S \times \Delta T)  \tag{0.241}\\
& R_{g}(T)=R_{g} \cdot(1+T R G \times \Delta T) \tag{0.242}
\end{align*}
$$

## MOSFET Levels 1/2/3 (Berkeley SPICE 2G6)

## Parameters

.model name nmos |pmos level=1|2|3 [parameters]
Also see "Additional MOSFET Parameters" on page 457.

| Parameter | Symbol | Description | Default | Units |  |
| :---: | :---: | :---: | :---: | :---: | :---: |
| level | LEVEL | Model selector | 1 | - | (1)23 |
| vto | Vt0 | Zero-bias threshold voltage | Computed | V | (1)23 |
| kp | $K P$ | MOSFET transconductance | Computed | A/V ${ }^{2}$ | (1)23 |
| gamma | $\gamma$ | Bulk threshold parameter | Computed | $\mathrm{V}^{1 / 2}$ | (1)23 |
| phi | $\phi$ | Surface potential | Computed | V | (1)23 |
| lambda | $\lambda$ | Channel length modulation | Computed | $\mathrm{V}^{-1}$ | (1) 2 |
| tox | Tox | Gate oxide thickness | Computed. | $\begin{aligned} & \text { If }<1, \mathrm{~m} \text {; } \\ & \text { if }>1, \AA \end{aligned}$ | (1)23 |
| $\begin{aligned} & \text { nsub \| } \\ & \text { dnb \|nb } \end{aligned}$ | Nsub | Bulk doping concentration | 0.0 | $\mathrm{cm}^{-3}$ | (1)23 |
| nss | NSS | Surface state density | 0.0 | $\mathrm{cm}^{-2}$ | 23 |
| nfs \| dnf | nf | dfs | NFS | Fast surface state density | Computed | $\mathrm{cm}^{-2}$ | (1)23 |
| xj | Xj | Junction depth | 0.0 | m | 1123 |
| Id | $L D$ | Lateral diffusion | $0.75 \times x j$ | m | (1)23 |
| wd | WD | Width diffusion | 0.0 | m | (1)23 |
| $\mathbf{x I}$ \| dI | Idel | Xl | Mask and etching length change | 0.0 | m | (1)23 |
| $\begin{aligned} & \text { xw }\|d w\| \\ & \text { wdel } \end{aligned}$ | Xw | Mask and etching width change | 0.0 | m | (1)23 |
| uo | $\mu 0$ | Electron or hole mobility | 600.0 | $\mathrm{cm}^{2} N \cdot \mathrm{~s}$ | (1)23 |
| ucrit | UCRIT | Critical field mobility degradation coefficient | $1.0 \times 10^{-4}$ | $\mathrm{V} / \mathrm{cm}$ | 2 |
| uexp | UEXP | Critical field mobility degradation exponent | 0.0 | - | 2 |
| vmax | VMAX | Maximum carrier drift velocity | 0.0 | $\mathrm{m} / \mathrm{s}$ | 23 |
| neff | NEFF | Total channel charge coefficient | 1.0 | - | (2) |
| delta | $\delta$ | Width effect on threshold voltage | 0.0 | - | 23 |
| tpg | $T P G$ | Type of gate material: <br> - Doping type same as source-drain (tpg=1) | 1 | - | 123 1123 |

[^23]| Parameter | Symbol | Description | Default | Units |  |
| :---: | :---: | :---: | :---: | :---: | :---: |
|  |  | - Aluminum gate ( $\mathbf{t p g}=0$ ) |  |  | (1) 23 |
| theta | $\theta$ | Mobility modulation | 0.0 | V-1 | 3 |
| eta | $\eta$ | Static feedback | 0.0 | - | 3 |
| kappa | $\kappa$ | Saturation field factor | 0.2 | - | 3 |
| del |  | Channel length reduction per side | 0.0 | m | (1) 23 |

## Large-Signal Model



This schematic represents the Level 2 model. The Level 1 model has the same configuration, without the junction diodes.

The terminals ( $G, D, S, B$ ) represent the gate, drain, source, and bulk connections, respectively, of the MOSFET. Id is the current flowing from the drain to the source as a function of ( $V g s, V d s, V b s$ ). The ohmic resistance of the drain and source diffusion junctions are represented by $R d$ and $R s$. A P-channel MOSFET can be modeled by reversing the polarity of ( $V g s, V d s, V b s$ ), the current source $I d$, and the junction diodes.

When nrs and nrd are not given as options on the MOSFET device statement, T-Spice computes them by calculating the number of squares from the geometry of the junction and then multiplying them by RSH to obtain the drain and source resistors $R d$ and $R s$.

## Level 1 Equations

The Level 1 model is included for SPICE compatibility, but it is inaccurate when simulating circuits with analog characteristics. The original intent of the model was to provide an approximation for digital circuits that could be evaluated quickly, reducing the simulation time by as much as a factor of two. However, T-Spice generally precalculates current and charge tables and does not gain from this speedup. The Level 1 model should be avoided for most circuits.

## Current

Current behavior is modeled by three equations, representing the three regions of MOSFET operation: cutoff, linear, and saturation.

Cutoff region: Vgs ð Vth

$$
\begin{equation*}
I_{d s}=0 \tag{0.243}
\end{equation*}
$$

Linear region: $V g s>V t h$ and $(V g s-V t h)>V d s$

$$
\begin{equation*}
I_{d s}=\frac{\beta}{2} V_{d s}\left(2\left(V_{g s}-V_{t h}\right)-V_{d s}\right)\left(1+\lambda V_{d s}\right) \tag{0.244}
\end{equation*}
$$

Saturation region: $V g s>V t h$ and $(V g s-V t h) \leq V d s$

$$
\begin{equation*}
I_{d s}=\frac{\beta}{2}\left(V_{g s}-V_{t h}\right)^{2}\left(1+\lambda V_{d s}\right) \tag{0.245}
\end{equation*}
$$

In equations (0.244) and (0.245),

$$
\begin{equation*}
\beta=\frac{W-(2 \cdot W D)}{L-(2 \cdot L D)} \cdot K P \tag{0.246}
\end{equation*}
$$

## Charge

$$
\begin{gather*}
Q_{g}=C_{g b} V_{g b}+C_{g d} V_{g d}+C_{g s} V_{g s}  \tag{0.247}\\
Q_{d}=C_{g d} V_{g d}+\int C_{d b}(v) d v  \tag{0.248}\\
Q_{s}=C_{g s} V_{g s}+\int C_{s b}(v) d v  \tag{0.249}\\
Q_{b}=-\left(Q_{g}+Q_{d}+Q_{s}\right) \tag{0.250}
\end{gather*}
$$

## Capacitance

The Meyer gate capacitance model was replaced by a simplified model that provides conservation of charge.

$$
\begin{equation*}
C_{g b}=C_{g s}=C_{g d}=\frac{1}{3} W L \frac{\varepsilon_{o x}}{T_{o x}} \tag{0.251}
\end{equation*}
$$

The junction capacitance for the drain and source is dependent on the drain-bulk and drain-source voltages.

$$
\begin{align*}
C_{d b} & =C_{p n}\left(V_{b d}, A D, P D\right)  \tag{0.252}\\
C_{s b} & =C_{p n}\left(V_{b s}, A S, P S\right) \tag{0.253}
\end{align*}
$$

For reverse bias $V p n<F C \cdot P B$,

$$
\begin{equation*}
C_{p n}\left(V_{p n}, A, P\right)=\left(C J \cdot \frac{A}{\left(1-\frac{V_{p n}}{P B}\right)^{M J}}\right)+\left(C J S W \cdot \frac{P}{\left(1-\frac{V_{p n}}{P B}\right)^{M J S W}}\right) \tag{0.254}
\end{equation*}
$$

For forward bias $V p n \geq F C \cdot P B$,

$$
\begin{align*}
C_{p n}\left(V_{p n}, A, P\right)= & C J\left(\frac{A}{(1-F C)^{(1+M J)}}\right)\left(1-F C 1+M J+\frac{V_{p n}}{P B} M J\right)+  \tag{0.255}\\
& C J\left(\frac{P}{(1-F C)^{(1+M J S W)}}\right)\left(1-F C 1+M J S W+\frac{V_{p n}}{P B} M J S W\right)
\end{align*}
$$

In equations (0.254) and (0.255), $A$ denotes area and $P$ denotes perimeter.
The charge can be calculated using

$$
\begin{equation*}
Q=\int C(V) d v \tag{0.256}
\end{equation*}
$$

## Threshold Voltage

An increase in the threshold voltage is due to a reverse bias from the gate to the substrate called the body effect, which causes degradation in the current drive of a transistor.

$$
\begin{gather*}
V_{t o}=V_{F B}+(\gamma \sqrt{\phi}+\phi)  \tag{0.257}\\
\gamma=\frac{\sqrt{2 \varepsilon_{0} \varepsilon_{s i} q N_{s u b}}}{C_{o x}}  \tag{0.258}\\
C_{o x}=\frac{\varepsilon_{0} \varepsilon_{o x}}{T_{o x}}  \tag{0.259}\\
K P=\mu_{0} C_{o x}  \tag{0.260}\\
V_{F B}=\left(-T P G \cdot \frac{E_{q}}{2}\right)-\frac{\phi}{2}-\frac{q N_{s s}}{C_{o x}} \tag{0.261}
\end{gather*}
$$

Equation (0.257) is dependent on $V b s$ and is implemented as follows:

$$
\begin{equation*}
V_{t h}=V_{t o}+\gamma\left(\text { bodyterm }-\sqrt{2 \phi_{F}}\right) \tag{0.262}
\end{equation*}
$$

When Vbs $\leq 0.0$,

$$
\begin{equation*}
\text { bodyterm }=\sqrt{2 \phi_{F}-V_{b s}} \tag{0.263}
\end{equation*}
$$

When $V b s>0.0$,

$$
\begin{equation*}
\text { bodyterm }=\max \left(\left(\sqrt{2 \phi_{F}}-\frac{V_{b s}}{2 \sqrt{2 \phi_{F}}}\right), 0\right) \tag{0.264}
\end{equation*}
$$

In Equations (0.262) through (0.264),

$$
\begin{equation*}
2 \phi_{F}=\phi=2 \frac{k T}{q} \ln \left(\frac{N_{s u b}}{n_{i}}\right) \tag{0.265}
\end{equation*}
$$

## Level 2 Equations

The Level 2 model uses two current equations. Since the MOSFET is not an ideal switch, the current begins to flow before the transistor reaches the turn-on voltage. This region is called weak inversion. As the voltage on the gate approaches the threshold voltage, it conducts current much more vigorously. At this point the channel is in the strong inversion region. The strong inversion region includes the linear and saturation regions. Many second-order effects that control the amount of current are calculated in the Level 2 model, including backgate bias and short and narrow channel effects. The Level 2 current equations are similar to the Grove equation for a MOSFET. These equations insure the continuity of current at Von (threshold point) through the transistor regions.

## Subthreshold Region

The weak inversion current equation is used when the transistor is in the subthreshold region, $V g s<$ Von.

$$
\begin{align*}
I_{d s}= & \beta\left(\left(V_{o n}-V_{b i n}-\frac{\eta V_{o n}}{2}\right) V_{o n}-\right.  \tag{0.266}\\
& \left.\frac{2}{3} \gamma_{s}\left(\left(2 \phi_{F}-V_{b s}+V_{o n}\right)^{3 / 2}-\left(2 \phi_{F}-V_{b s}\right)^{3 / 2}\right)\right) e^{\frac{q}{n k T}\left(V_{g s}-V_{o n}\right)}
\end{align*}
$$

The strong inversion current equation is used to calculate the current when $V g s \geq V o n$ :

$$
\begin{align*}
I_{d s}= & \beta\left(\left(V_{g s}-V_{b i n}-\frac{\eta V_{d s}}{2}\right) V_{d s}-\frac{2}{3} \gamma_{s}\left(\left(2 \phi_{F}-V_{b s}+V_{d s}\right)^{3 / 2}-\right.\right.  \tag{0.267}\\
& \left.\left.\left(2 \phi_{F}-V_{b s}\right)^{3 / 2}\right)\right)
\end{align*}
$$

where $V d s=V d s a t$ for $V d s>V d s a t$.

The voltages calculated to determined the second order effects of the transistor currents are defined as:

$$
\begin{gather*}
V_{t h}=V_{b i n}+\gamma_{s} \sqrt{2 \phi_{F}-V_{b s}}  \tag{0.268}\\
V_{b i n}=V_{b i}+\delta\left(\frac{\pi \varepsilon_{0} \varepsilon_{s i}}{4 C_{o x} W_{e f f}}\right)\left(2 \phi_{F}-V_{b s}\right)  \tag{0.269}\\
V_{b i}=V_{f b}+2 \phi_{F}  \tag{0.270}\\
2 \phi_{F}=\phi=2 \frac{k T}{q} \ln \left(\frac{N_{s u b}}{n_{i}}\right)  \tag{0.271}\\
V_{f b}=\phi_{m s}-\frac{q \cdot N S S}{C_{o x}} \tag{0.272}
\end{gather*}
$$

The voltage Von is used to switch between the weak and strong inversion model regions. When NFS is not specified,

$$
\begin{align*}
V_{o n} & =V_{t h}  \tag{0.273}\\
n & =\infty \tag{0.274}
\end{align*}
$$

However, a more accurate cut-on point can be modeled by using a curve fitting parameter NFS in the evaluation of Von:

$$
\begin{equation*}
V_{o n}=V_{t h}+\frac{n k T}{q} \tag{0.275}
\end{equation*}
$$

where

$$
\begin{gather*}
n=1+\frac{C_{F S}}{C_{o x}}+\frac{C_{D}}{C_{o x}}  \tag{0.276}\\
C_{F S}=q \cdot N F S  \tag{0.277}\\
C_{D}=\frac{\partial Q_{B}}{\partial V_{b s}}=C_{o x}\left(-\gamma_{s}\left(\frac{d \sqrt{2 \phi_{F}-V_{b s}}}{d V_{b s}}\right)\right.  \tag{0.278}\\
\left.-\left(\frac{\partial \gamma_{s}}{\partial V_{b s}}\right) \sqrt{2 \phi_{F}-V_{b s}}+\delta \frac{\pi \varepsilon_{0} \varepsilon_{s i}}{4 C_{o x} W_{e f f}}\right)
\end{gather*}
$$

Taking the partial derivatives and applying the chain rule yields

$$
\begin{align*}
C_{D}= & C_{o x}\left[\frac{1}{2} \gamma_{s} \frac{1}{\sqrt{2 \phi_{F}-V_{b s}}}-\gamma_{s} \sqrt{2 \phi_{F}-V_{b s}}\left(\frac{X_{D}}{4 L} \cdot \frac{1}{\left(1+\frac{2 X_{D} \sqrt{2 \phi_{F}-V_{b s}}}{X_{j}}\right)^{1 / 2}} \cdot \frac{1}{\sqrt{2 \phi_{F}-V_{b s}}}\right)\right]  \tag{0.279}\\
& +\left(\frac{X_{D}}{4 L} \cdot \frac{1}{\left(1+\frac{2 X_{D} \sqrt{2 \phi_{F}-V_{b s}+V_{d s}}}{X_{j}}\right)^{1 / 2}} \cdot \frac{1}{\sqrt{2 \phi_{F}-V_{b s}+V_{d s}}}\right)+\delta \frac{\pi \varepsilon_{0} \varepsilon_{s i}}{4 C_{o x} W_{e f f}}
\end{align*}
$$

Equation (0.279) assumes that $V b s$ is negative. When $V b s$ is positive, $\sqrt{2 \phi_{F}-V_{b s}}$ should be replaced with

$$
\begin{equation*}
\frac{\sqrt{2 \phi_{F}}}{1+\frac{V_{b s}}{4 \phi_{F}}} \tag{0.280}
\end{equation*}
$$

## Linear and Saturation Regions

The saturation voltage Vdsat can be computed with either of two methods. Which method is chosen depends on whether the input parameter VMAX has been defined.

Method 1. When VMAX is not defined, the model computes Vdsat assuming that the channel is pinched off at the drain:

$$
\begin{align*}
& V_{d s a t}  \tag{0.281}\\
& =\frac{V_{g s}-V_{b i n}}{\eta}+\frac{1}{2}\left(\frac{\gamma_{s}}{\eta}\right)^{2}\left(1-\sqrt{1+4\left(\frac{\eta}{\gamma_{s}}\right)^{2}\left(\frac{V_{g s}-V_{b i n}}{\eta}+2 \phi_{F}-V_{b s}\right)}\right)
\end{align*}
$$

If the parameter $\lambda$ is not defined while using the pinch-off method, then it can be computed as

$$
\begin{equation*}
\lambda=\frac{X_{D}}{L_{l} V_{d s}} \sqrt{\frac{V_{d s}-V_{d s a t}}{4}+\sqrt{1+\left(\frac{\left.V_{d s}-V_{d s a t}\right)^{2}}{4}\right.}} \tag{0.282}
\end{equation*}
$$

The channel length becomes smaller due to the pinch-off of the channel. The effective channel length is

$$
\begin{equation*}
L_{e f f}=L_{l}\left(1-\lambda V_{d s}\right) \tag{0.283}
\end{equation*}
$$

Method 2. When VMAX is defined as Vdsat and the channel length modulation is calculated using the carrier scattering limited velocity model, this method appropriately models saturation current for short-
channel MOSFETs as charge carriers reaching their maximum scattering limited velocity before the pinch-off effect comes into play.

$$
\begin{equation*}
V M A X=\frac{\mu_{s}\left(\left(V_{g s}-V_{b i n}-\frac{\eta V_{d s a t}}{2}\right) V_{d s a t}-\frac{2 \gamma_{s}}{3}\left(\left(V_{d s a t}+2 \phi_{F}-V_{b s}\right)^{3 / 2}-\left(2 \phi_{F}-V_{b s}\right)^{3 / 2}\right)\right)}{L_{e f f}\left(V_{g s}-V_{b i n}-\eta V_{d s a t}-\gamma \sqrt{V_{d s a t}+2 \phi_{F}-V_{b s}}\right)} \tag{0.284}
\end{equation*}
$$

The effective channel length is dependent on $V M A X$ and $V d s a t$ and computed as

$$
\begin{equation*}
L_{e f f}=L_{l}-X_{D}\left(\left(\frac{X_{D} V M A X}{2 \mu_{s}}\right)^{2}+\left(V_{d s}-V_{d s a t}\right)\right)^{1 / 2}+\frac{\left(X_{D}\right)^{2} V M A X}{2 \mu_{s}} \tag{0.285}
\end{equation*}
$$

Solving for Vdsat is difficult because it requires the simultaneous solution of the nonlinear equations ( 0.284 ) and ( 0.285 ). A less computationally expensive approach is desirable:

Assume that Leff and $L 1$ in equation (0.285) are equal. Then by selecting parameter NEFF, adjust the value of $X D$ to obtain a good fit to the I-V characteristics of the MOSFET.

$$
\begin{equation*}
X_{D}=\sqrt{\frac{2 \varepsilon_{0} \varepsilon_{s i}}{q N_{s u b} N E F F}} \tag{0.286}
\end{equation*}
$$

Equation (0.285) can be solved using Ferrari's method. There will be 2 or 4 real roots. The smallest positive real root is the correct value of Vdsat.

If $\lambda$ is not defined, then it can be computed using Vdsat and equations (0.284) and (0.287):

$$
\begin{equation*}
\lambda=\frac{X_{D}}{L_{l} V_{d s}}\left(\left(\left(\frac{X_{D} V M A X}{2 \mu_{s}}\right)^{2}+\left(V_{d s}-V_{d s a t}\right)\right)^{1 / 2}+\frac{X_{D} V M A X}{2 \mu_{s}}\right) \tag{0.287}
\end{equation*}
$$

Then Leff can be computed as

$$
\begin{equation*}
L_{e f f}=L_{l}\left(1-\lambda V_{d s}\right) \tag{0.288}
\end{equation*}
$$

Thus the value of Leff is available from either of the two current saturation methods-channel pinch-off or carrier scattering limited velocity. If Leff is smaller than the zero-bias depletion layer width $W B=$ $X D \sqrt{P B}$, then Leff must be recomputed as

$$
\begin{equation*}
L_{e f f}=\frac{W_{B}}{1+\frac{\Delta L-L_{\max }}{W_{B}}} \tag{0.289}
\end{equation*}
$$

where

$$
\begin{gather*}
\Delta L=\lambda V_{d s} L_{1}  \tag{0.290}\\
L_{\max }=L_{1}-W_{B} \tag{0.291}
\end{gather*}
$$

Equation (0.289) prevents numerical non-convergence, but does not model the punch-through effect.
The voltage $V d s a t$ is compared with $V d s$. If $V d s$ is greater than $V d s a t$, then $V d s$ is set equal to $V d s a t$, thus clamping the drain-to-source voltage to Vdsat in the saturation region.

The result is a potential drop ( $V d s$ ) across the saturated transistor and a smaller effective transistor gate length that increases the gain $(\beta)$.

$$
\begin{align*}
& \beta=\frac{W_{e f f}}{L_{e f f}} K P  \tag{0.292}\\
& K P=\mu_{s} C_{o x} \tag{0.293}
\end{align*}
$$

$K P$ is the transconductance of the MOSFET. If it is not specified, it will take the calculated value.

## Second-Order Effects

Other variables, coefficients, and modified input parameters that are used in the model are defined as follows:

$$
\begin{align*}
& \phi_{m s}=-\left(\frac{2 \phi_{F}}{2}+\frac{E_{g}}{2}\right)  \tag{0.294}\\
& C_{o x}=\frac{\varepsilon_{0} \varepsilon_{o x}}{T_{o x}}  \tag{0.295}\\
& L_{l}=L-(2 \cdot L D)  \tag{0.296}\\
& W_{e f f}=W-(2 \cdot W D)  \tag{0.297}\\
& \eta=1+\delta\left(\frac{\pi \varepsilon_{0} \varepsilon_{s i}}{4 C_{o x} W_{e f f}}\right)  \tag{0.298}\\
& \mu_{s}=U_{0}\left(\frac{U C R I T \varepsilon_{0} \varepsilon_{s i}}{C_{o x}\left(V_{g s}-V_{o n}\right)}\right)^{U E X P}  \tag{0.299}\\
& \gamma_{s}=\gamma\left(1-\alpha_{s}-\alpha_{d}\right)  \tag{0.300}\\
& \gamma=\frac{\sqrt{2 q \varepsilon_{0} \varepsilon_{s i} N_{s u b}}}{C_{o x}}  \tag{0.301}\\
& \alpha_{S}=\frac{1}{2} \cdot \frac{X_{j}}{L_{l}} \cdot\left(\sqrt{1+2 \frac{W_{S}}{X_{J}}}-1\right)  \tag{0.302}\\
& \alpha_{D}=\frac{1}{2} \cdot \frac{X_{j}}{L_{l}} \cdot\left(\sqrt{1+2 \frac{W_{D}}{X_{J}}}-1\right)  \tag{0.303}\\
& W_{S}=X_{D} \sqrt{2 \phi_{F}-V_{b s}}  \tag{0.304}\\
& W_{D}=X_{D} \sqrt{2 \phi_{F}-V_{b s}+V_{d s}}  \tag{0.305}\\
& X_{D}=\sqrt{\frac{2 \varepsilon_{0} \varepsilon_{s i}}{q N_{s u b}}} \tag{0.306}
\end{align*}
$$

## Ward-Dutton Charge Model

The Ward-Dutton charge model was used to replace the shortcomings of the Meyer capacitance model. It has been shown that assuming capacitance reciprocity leads to non-conservation of charge. This nonconservation of bogus charge can cause various charge-dependent circuits to be simulated incorrectly.

The Ward-Dutton model derives equations based on charge instead of capacitance and conserves charge through all regions of the transistor. This model applies to Level 2 and Level 3 MOSFET models only.

The following table lists the parameters used by the equations describing the Ward-Dutton charge model (see "MOSFET Levels 4 and 13 (BSIM1)" on page 412).

| Symbol | Description | Unit |
| :--- | :--- | :--- |
| $I d c$ | DC drain current | A |
| $V d$ | Drain voltage | V |
| $V g$ | Gate voltage | V |
| $V s$ | Source voltage | V |
| $V d s a t$ | Saturation voltage | V |
| $Q b$ | Total bulk charge | C |
| $Q g$ | Total gate charge | C |
| $Q s$ | Total source charge | C |
| $Q d$ | Total drain charge | C |
| $Q g i$ | Intrinsic gate charge | C |
| $Q s i$ | Intrinsic source charge | C |
| $Q d i$ | Intrinsic drain charge | C |
| $Q g o$ | Overlap gate charge | C |
| $Q s o$ | Overlap source charge | C |
| $Q d o$ | Overlap drain charge | C |
| $Q s j$ | Junction source charge | C |
| $Q d j$ | Junction drain charge | C |
| Qd |  |  |

The Ward-Dutton model defines these normalized voltages as:

$$
\begin{gather*}
V_{g}=V_{g s}-V_{b s}-V_{f b}  \tag{0.307}\\
V_{d}=V_{d s}-V_{b s}+2 \phi_{F}  \tag{0.308}\\
V_{s}=-V_{b s}+2 \phi_{F} \tag{0.309}
\end{gather*}
$$

The charge on the gate, drain, and source of a transistor is the total charge due to the overlap, junction, and intrinsic channel charge.

$$
\begin{gather*}
Q_{g}=Q_{g i}+Q_{g o}  \tag{0.310}\\
Q_{d}=Q_{d i}+Q_{d o}+Q_{d j}  \tag{0.311}\\
Q_{s}=Q_{s i}+Q_{s o}+Q_{s j} \tag{0.312}
\end{gather*}
$$

The overlap capacitors are due to the gate edges overlapping the substrate and diffusion junctions.

$$
\begin{gather*}
Q_{g o}=C_{g s o} W_{e f f} V_{g s}+C_{g s o} W_{e f f}\left(V_{g s}-V_{d s}\right)+2 C_{g b o} L_{l}\left(V_{g s}-V_{b s}\right)  \tag{0.313}\\
Q_{d o}=C_{g d o} W_{e f f}\left(V_{d s}-V_{g s}\right)  \tag{0.314}\\
Q_{s o}=-C_{g s o} W_{e f f} V_{g s} \tag{0.315}
\end{gather*}
$$

The Ward-Dutton model addresses only the intrinsic channel charge. Two sets of equations model the regions of transistor charge.

Cut-off region. The charge model is in the cut-off region when the gate voltage is less than the threshold voltage.

When $V g s<V t h$ and $(V g s-V b s)<V f b$,

$$
\begin{gather*}
Q_{d i}=0  \tag{0.316}\\
Q_{s i}=0  \tag{0.317}\\
Q_{g i}=C_{o x} W_{e f f} L_{l} V_{g} \tag{0.318}
\end{gather*}
$$

When $V g s<V t h$ and $(V g s-V b s)>V f b$,

$$
\begin{gather*}
Q_{d i}=0  \tag{0.319}\\
Q_{s i}=0  \tag{0.320}\\
Q_{g i}=C_{o x} W L_{l} \cdot \frac{1}{2} \gamma_{s} \sqrt{\gamma_{s}^{2}+4 V_{g}} \tag{0.321}
\end{gather*}
$$

Linear and saturation regions. The model uses the same equation for the linear and saturation regions. In the saturation region the voltage $V d$ is clamped at the saturation voltage $V d s a t$ when the following condition is true:

$$
\begin{equation*}
V_{d}+\gamma_{s} \sqrt{V_{d}} \geq V_{g} \tag{0.322}
\end{equation*}
$$

Then

$$
\begin{gather*}
2 \sqrt{V_{d s a t}}=-\gamma_{s}+\sqrt{\gamma_{s}^{2}+4 V_{g}}  \tag{0.323}\\
V_{d}=\left(\sqrt{V_{d s a t}}\right)^{2} \tag{0.324}
\end{gather*}
$$

The intrinsic charge for the linear or saturation region is computed as

$$
\begin{gather*}
Q_{s i}=\frac{3}{5} Q_{C S A T}+\frac{3}{10}\left(Q_{C}-Q_{C S A T}\right)  \tag{0.325}\\
Q_{d i}=\frac{23}{5} Q_{C S A T}+\frac{7}{10}\left(Q_{C}-Q_{C S A T}\right)  \tag{0.326}\\
Q_{C}=-\left(Q_{g i}+Q_{b i}\right)  \tag{0.327}\\
Q_{C S A T}=-\frac{2}{3} C_{o x} W_{e f f} L_{l}\left(V_{g}-V_{s}-\gamma_{s} \sqrt{V_{s}}\right)  \tag{0.328}\\
Q_{g i}=C_{o x} W_{e f f} L_{l}\left[V_{g}-\frac{1}{I_{d c}}\left(V_{g} \frac{1}{2}\left(V_{d}^{2}-V_{s}^{2}\right)-\frac{2}{5} \gamma_{s}\left(V_{d}^{5 / 2}-V_{s}^{5 / 2}\right)-\frac{1}{3}\left(V_{d}^{3}-V_{s}^{3}\right)\right)\right]  \tag{0.329}\\
Q_{b i}=-\frac{C_{o x} W_{e f f} L_{l}}{I_{d c}}\left[V_{g} \frac{2}{3} \gamma_{s}\left(V_{d}^{3 / 2}-V_{s}^{3 / 2}\right)-\gamma_{s}^{2} \frac{1}{2}\left(V_{d}^{2}-V_{s}^{2}\right)-\frac{2}{5} \gamma_{s}\left(V_{d}^{5 / 2}-V_{s}^{5 / 2}\right)\right]  \tag{0.330}\\
I_{d c}=V_{g}\left(V_{d}-V_{s}\right)-\frac{2}{3} \gamma_{s}\left(V_{d}^{3 / 2}-V_{s}^{3 / 2}\right)-\frac{1}{2}\left(V_{d}^{2}-V_{s}^{2}\right) \tag{0.331}
\end{gather*}
$$

The diffusion junction capacitance equations for the drain and source are the same as in the Level 1 model. The capacitance is dependent on the drain to bulk or drain to source voltage.

For reverse bias $V b s<F C \cdot P B$,

$$
\begin{equation*}
C_{b d}=C J\left(\frac{A S}{\left(1-\frac{V_{b s}}{P B}\right)^{M J}}\right)+C J S W\left(\frac{P S}{\left(1-\frac{V_{b s}}{P B}\right)^{M J S W}}\right) \tag{0.332}
\end{equation*}
$$

For forward bias $V b s>F C \cdot P B$,

$$
\begin{align*}
C_{b d}= & C J\left(\frac{A S}{(1-F C)^{(1+M J S W)}}\right)\left[1-F C(1+M J)+\frac{V_{b s}}{P B} M J\right]+  \tag{0.333}\\
& C J S W\left(\frac{P S}{(1-F C)^{(1+M J S W)}}\right)\left[1-F C(1+M J S W)+\frac{V_{b s}}{P B} M J S W\right]
\end{align*}
$$

To obtain the charge function at the junction of the drain or source, integrate the junction capacitance over the range of Vbs:

$$
\begin{equation*}
Q=\int C(v) d v \tag{0.334}
\end{equation*}
$$

Now integrate the reverse bias region from $V b s$ to $(F C \cdot P B)$.

For reverse bias $V b s<F C \cdot P B$,

$$
\begin{gather*}
Q_{D j}=\int_{V_{b s}}^{F C \cdot P B} C_{b d} V_{b s} d v  \tag{0.335}\\
Q_{D j}=(C J \cdot A S \cdot P B)\left(\left(\frac{1.0-V_{b s}}{P B}\right)^{(1-M J)}-\frac{(1.0-F C)^{(1-M J)}}{(1-M J)}\right)+  \tag{0.336}\\
(C J S W \cdot P S \cdot P B)\left(\left(\frac{1.0-V_{b s}}{P B}\right)^{(1-M J S W)}-\frac{(1.0-F C)^{(1-M J S W)}}{(1-M J S W)}\right)
\end{gather*}
$$

For forward bias $V b s>F C \cdot P B$,

$$
\begin{align*}
& Q_{D j}=\int_{F C \cdot P B}^{V_{b s}} C_{b d} V_{b s} d v  \tag{0.337}\\
& Q_{D j}= \frac{C J \cdot A S \cdot P B}{(10-F C)^{2-M J}} \cdot\left[\left(V_{b s}-(F C \cdot P B)\right)(1.0-F C(2-M J))+\right.  \tag{0.338}\\
&\left.\frac{1}{2}\left(\frac{V_{b s}^{2}}{P B}-F C^{2} P B\right)(1-M J)\right]- \\
& \frac{C J \cdot S W \cdot P S \cdot P B}{(1.0-F C)^{2+M J S W} \cdot\left[\left(V_{b s}-(F C \cdot P B)\right)(1.0-F C(2-M J S W))+\right.} \\
&\left.\frac{1}{2}\left(\frac{V_{b s}^{2}}{P B}-F C^{2} P B\right)(1-M J)\right]
\end{align*}
$$

## Level 3 Equations

The Level 3 MOSFET model is a semi-empirical model developed to handle small-geometry devices.
The drain current in the linear and saturation regions (for $V g s>V t h$ ) is calculated using

$$
\begin{equation*}
I_{d s}^{\prime}=\beta \cdot\left[\frac{1}{1+V_{d s}\left(\frac{\mu_{s} V_{\max }}{L_{1}}\right)}\right] \cdot\left[V_{g s}-V_{t h}-\left(\frac{1+F_{B}}{2}\right) V_{d s}\right] \cdot V_{d s} \tag{0.339}
\end{equation*}
$$

where $V d s=V d s a t$ for $V d s>V d s a t$ and $V d s a t$ is defined as follows:
If $\operatorname{Vmax} \leq 0.0$,

$$
\begin{equation*}
V_{d s a t}=\frac{V_{g s}-V_{t h}}{1+F_{B}} \tag{0.340}
\end{equation*}
$$

If $\operatorname{Vmax}>0.0$,

$$
\begin{equation*}
V_{d s a t}=\frac{V_{g s}-V_{t h}}{1+F_{B}}+\frac{V_{\max } \cdot L_{1}}{\mu_{s}}-\sqrt{\left(\frac{V_{g s}-V_{t h}}{1+F_{B}}\right)^{2}+\left(\frac{V_{\max } \cdot L_{l}}{\mu_{s}}\right)^{2}} \tag{0.341}
\end{equation*}
$$

and

$$
\begin{gather*}
\mu_{s}=\frac{\mu_{0}}{1+\theta\left(V_{g s}-V_{t h}\right)}  \tag{0.342}\\
\beta=\frac{W_{e f f}}{L_{l}} \mu_{s} C_{o x}  \tag{0.343}\\
F_{B}=\frac{\gamma F_{s}}{4 \sqrt{2 \phi_{F}-V_{b s}}}-F_{n}  \tag{0.344}\\
F_{s}=1-\frac{X_{j}}{L_{1}}\left(\frac{L D+W_{c}}{X_{j}} \sqrt{1-\left(\frac{W_{p}}{X_{j}+W_{p}}\right)^{2}}-\frac{L D}{X_{j}}\right)  \tag{0.345}\\
W_{p}=X_{d \sqrt{2}} \sqrt{2 \phi_{F}-V_{b s}}  \tag{0.346}\\
X_{d}=\sqrt{\frac{2 \varepsilon_{s i} \varepsilon_{0}}{q N_{A}}}  \tag{0.347}\\
\frac{W_{c}}{X_{j}}=0.0631353+0.8013292 \frac{W_{p}}{X_{j}}-0.01110777\left(\frac{W_{p}}{X_{j}}\right)^{2}  \tag{0.348}\\
F_{n}=\frac{\varepsilon_{s i} \varepsilon_{0} \delta \pi}{2 C_{o x} W_{e f f}}  \tag{0.349}\\
V_{t h}=V_{F B}+2 \phi_{F}-\sigma V_{d s}+\gamma F_{s} \sqrt{2 \phi_{F}-V_{b s}}+F_{n}\left(2 \phi_{F}-V_{b s}\right)  \tag{0.350}\\
\sigma=\eta \cdot \frac{8.15 \times 10^{-22}}{C_{o x} L_{l}} \tag{0.351}
\end{gather*}
$$

Channel length modulation is calculated for $V d s>V d s a t$ as follows:

$$
\begin{align*}
I_{d s a t} & =I_{d s}^{\prime}\left(V_{d s}=V_{d s a t}\right)  \tag{0.352}\\
G_{d s a t} & =\frac{\partial I_{d s}^{\prime}}{\partial V_{d s}}\left(V_{d s}=V_{d s a t}\right)  \tag{0.353}\\
I_{d s} & =\frac{I_{d s a t}}{1-\left(\frac{L_{1}-L^{\prime}}{L_{1}}\right)} \tag{0.354}
\end{align*}
$$

where

$$
\begin{gather*}
L_{1}-L^{\prime}=\sqrt{\left(\frac{E_{p} X_{D}^{2}}{2}\right)^{2}+K X_{D}^{2}\left(V_{d s}-V_{d s a t}\right)}-\left(\frac{E_{p} X_{D}^{2}}{2}\right)  \tag{0.355}\\
E_{p}=\frac{I_{d s a t}}{G_{d s a t} L_{1}} \tag{0.356}
\end{gather*}
$$

For Vgs < Von, Ids is modified to included the weak inversion component of the drain current.

$$
\begin{gather*}
V_{o n}=V_{t h}+\frac{k T}{q} \cdot N  \tag{0.357}\\
N=1+\frac{q}{C_{o x}}+\frac{\gamma F_{s} \sqrt{2 \phi_{F}-V_{b s}}+F_{n}\left(2 \phi_{F}-V_{b s}\right)}{2\left(2 \phi_{F}-V_{b s}\right)}  \tag{0.358}\\
I_{d s}^{\prime}=I_{d s} \cdot e^{\frac{q}{N k T} \cdot\left(V_{g s}-V_{o n}\right)} \tag{0.359}
\end{gather*}
$$

## Temperature Dependence

The MOSFET model at Levels 1, 2, and 3 contains temperature-dependent model parameters. If a new temperature is specified with the .temp command, then these parameters must be modified before they are used in the current equations. The default temperature is $25^{\circ} \mathrm{C}$, which is equivalent to 300.15 K . The parameters affected by temperature changes are: $\phi F$ (Fermi potential), $E g$ (energy gap), $P B$ (built-in potential of the drain and source), $\mu 0$ (mobility), and $I s$ (reverse current of the diffused junctions).

The energy gap between the conduction band and the valence band for polysilicon at Tref $=300.15 \mathrm{~K}$ and at the new temperature Tnew is:

$$
\begin{gather*}
E_{g, \text { ref }}=1.16-\left(\frac{7.02 \times 10^{-4} \cdot\left(T_{\text {ref }}\right)^{2}}{1108+T_{\text {ref }}}\right)  \tag{0.360}\\
E_{g, \text { new }}=1.16-\left(\frac{7.02 \times 10^{-4} \cdot\left(T_{\text {new }}\right)^{2}}{1108+T_{\text {new }}}\right) \tag{0.361}
\end{gather*}
$$

The intrinsic doping is adjusted by different equations depending whether the parameter PHI is defined. When PHI is not defined,

$$
\begin{equation*}
n_{i, \text { new }}=n_{i}\left(\frac{T_{\text {new }}}{T_{\text {ref }}}\right)^{3 / 2}\left(e^{\frac{q}{k}\left(\frac{E_{g, \text { ref }}}{T_{\text {ref }}} \frac{E_{\text {g.new }}}{T_{\text {new }}}\right)}\right)^{1 / 2} \tag{0.362}
\end{equation*}
$$

When PHI is defined,

$$
\begin{equation*}
n_{i, \text { new }}=N_{\text {sub }}\left(\frac{T_{\text {new }}}{T_{\text {ref }}}\right)^{3 / 2}\left(e^{\frac{q}{k}\left(\frac{E_{g \text { gref }}}{T_{\text {ref }}}-\frac{E_{\text {g.new }}}{T_{\text {new }}}-\frac{2 \phi_{F}}{T_{\text {ref }}}\right)}\right)^{1 / 2} \tag{0.363}
\end{equation*}
$$

PHI for the new temperature is computed using ni,new:

$$
\begin{equation*}
\phi_{\text {new }}=2 \phi_{F, \text { new }}=\left(\frac{2 k T_{\text {new }}}{q}\right) \ln \left(\frac{N_{\text {sub }}}{n_{i, \text { new }}}\right) \tag{0.364}
\end{equation*}
$$

The conduction factor $K P$ and the mobility vary with temperature as

$$
\begin{equation*}
\frac{\mu_{0, \text { new }}}{\mu_{0, \text { ref }}}=\left(\frac{T_{\text {new }}}{T_{\text {ref }}}\right)^{-3 / 2} \tag{0.365}
\end{equation*}
$$

The parameter $K P$ or $\beta$ contains the temperature adjustment when computed from $\mu 0$; however, when $K P$ is entered from the model statement, the value is modified as

$$
\begin{equation*}
\frac{\beta_{\text {new }}}{\beta_{\text {ref }}}=\left(\frac{T_{\text {new }}}{T_{\text {ref }}}\right)^{-3 / 2} \tag{0.366}
\end{equation*}
$$

The MOSFET substrate junction diode saturation current varies as

$$
\begin{equation*}
\frac{I_{s, n e w}}{I_{s, \text { ref }}}=\left(\frac{T_{\text {new }}}{T_{r e f}}\right)^{3}\left(e^{\frac{q}{k}\left(\frac{E_{\text {gref }}}{T_{\text {ref }}}-\frac{E_{g, \text { new }}}{T_{\text {new }}}\right)}\right) \tag{0.367}
\end{equation*}
$$

The built-in potential $P B$ is adjusted as

$$
\begin{equation*}
P B=P B\left(\frac{T_{n e w}}{T_{r e f}}\right)-\left(\frac{2 k T_{n e w}}{q}\right) \ln \left(\frac{T_{n e w}}{T_{r e f}}\right)^{3 / 2}+\left[\left(\frac{T_{n e w}}{T_{\text {ref }}}\right) E_{g, \text { ref }}-E_{g, n e w}\right] \tag{0.368}
\end{equation*}
$$

## MOSFET Levels 4 and 13 (BSIM1)

## Parameters

.model name nmos $\mid$ pmos level= 4|13 [parameters]
Based on the Berkeley short-channel IGFET model, © 1990 Regents of the University of California. Also see "Additional MOSFET Parameters" on page 457.

| Parameter | Description | Default | Units |
| :---: | :---: | :---: | :---: |
| vfb | Flat band voltage | -0.3 | V |
| Ivfb | Length sensitivity of vfb | 0.0 | $\mu \mathrm{m} \cdot \mathrm{V}$ |
| wvfb | Width sensitivity of vfb | 0.0 | $\mu \mathrm{m} \cdot \mathrm{V}$ |
| pvfb | $W L$-product sensitivity of vfb | 0.0 | $\mu \mathrm{m}^{2} \cdot \mathrm{~V}$ |
| phi | Surface potential (double the Fermi potential) | 0.7 | V |
| Iphi | Length sensitivity of phi | 0.0 | $\mu \mathrm{m} \cdot \mathrm{V}$ |
| wphi | Width sensitivity of phi | 0.0 | $\mu \mathrm{m} \cdot \mathrm{V}$ |
| pphi | $W L$-product sensitivity of phi | 0.0 | $\mu \mathrm{m}^{2} \cdot \mathrm{~V}$ |
| k1 | $\sqrt{V_{s b}}$ threshold coefficient | 0.5 | $\mathrm{V}^{1 / 2}$ |
| Ik1 | Length sensitivity of $\mathbf{k 1}$ | 0.0 | $\mu \mathrm{m} \cdot \mathrm{V}^{1 / 2}$ |
| wk1 | Width sensitivity of $\mathbf{k} \mathbf{1}$ | 0.0 | $\mu \mathrm{m} \cdot \mathrm{V}^{1 / 2}$ |
| pk1 | $W L$-product sensitivity of k1 | 0.0 | $\begin{aligned} & \mu \mathrm{m}^{2} . \\ & \mathrm{V}^{1 / 2} \end{aligned}$ |
| k2 | Linear Vsb threshold coefficient | 0.0 | - |
| Ik2 | Length sensitivity of $\mathbf{k 2}$ | 0.0 | $\mu \mathrm{m}$ |
| wk2 | Width sensitivity of k2 | 0.0 | $\mu \mathrm{m}$ |
| pk2 | $W L$-product sensitivity of k2 | 0.0 | $\mu \mathrm{m}^{2}$ |
| eta | Linear Vds threshold coefficient | 0.0 | - |
| leta | Length sensitivity of eta | 0.0 | $\mu \mathrm{m}$ |
| weta | Width sensitivity of eta | 0.0 | $\mu \mathrm{m}$ |
| peta | $W L$-product sensitivity of eta | 0.0 | $\mu \mathrm{m}^{2}$ |
| muz | Low drain field first-order mobility | 600 | $\begin{aligned} & \mathrm{cm}^{2} / \\ & (\mathrm{V} \cdot \mathrm{~s}) \end{aligned}$ |
| Imuz | Length sensitivity of muz | 0.0 | $\begin{aligned} & \mu \mathrm{m} \cdot \mathrm{~cm}^{2} \\ & /(\mathrm{V} \cdot \mathrm{~s}) \end{aligned}$ |
| wmuz | Width sensitivity of muz | 0.0 | $\begin{aligned} & \mu \mathrm{m} \cdot \mathrm{~cm}^{2} \\ & /(\mathrm{V} \cdot \mathrm{~s}) \end{aligned}$ |
| pmuz | $W L$-product sensitivity of muz | 0.0 | $\begin{aligned} & \mu \mathrm{m}^{2} \cdot \mathrm{~cm}^{2} \\ & /(\mathrm{V} \cdot \mathrm{~s}) \end{aligned}$ |


| Parameter | Description | Default | Units |
| :---: | :---: | :---: | :---: |
| dl | Channel length reduction | 0.0 | $\mu \mathrm{m}$ |
| dw | Channel width reduction | 0.0 | $\mu \mathrm{m}$ |
| u0 | Gate field mobility reduction | 0.0 | $1 N$ |
| lu0 | Length sensitivity of $\mathbf{u} \mathbf{0}$ | 0.0 | $\mu \mathrm{m} / \mathrm{N}$ |
| wu0 | Width sensitivity of u0 | 0.0 | $\mu \mathrm{m} / \mathrm{N}$ |
| pu0 | $W L$-product sensitivity of $\mathbf{u 0}$ | 0.0 | $\mu \mathrm{m}^{2} N$ |
| u1 | Drain field mobility reduction | 0.0 | $1 N$ |
| lu1 | Length sensitivity of $\mathbf{u 1}$ | 0.0 | $\mu \mathrm{m} / \mathrm{N}$ |
| wu1 | Width sensitivity of u1 | 0.0 | $\mu \mathrm{m} / N$ |
| pu1 | $W L$-product sensitivity of $\mathbf{u 1}$ | 0.0 | $\mu \mathrm{m}^{2} N$ |
| x2mz | $V s b$ correction to low-field 1st-order mobility | 0.0 | $\begin{aligned} & \mathrm{cm}^{2} / \\ & \left(\mathrm{V}^{2} \cdot \mathrm{~s}\right) \end{aligned}$ |
| Ix2mz | Length sensitivity of $\mathbf{x} \mathbf{2 m z}$ | 0.0 | $\begin{aligned} & \mu \mathrm{m} \cdot \mathrm{~cm}^{2} \\ & /\left(\mathrm{V}^{2} \cdot \mathrm{~s}\right) \end{aligned}$ |
| wx2mz | Width sensitivity of $\mathbf{x} \mathbf{2 m z}$ | 0.0 | $\begin{aligned} & \mu \mathrm{m} \cdot \mathrm{~cm}^{2} \\ & /\left(\mathrm{V}^{2} \cdot \mathrm{~s}\right) \end{aligned}$ |
| px2mz | $W L$-product sensitivity of $\mathbf{x} \mathbf{2 m z}$ | 0.0 | $\begin{aligned} & \mu \mathrm{m}^{2} \cdot \mathrm{~cm}^{2} \\ & /\left(\mathrm{V}^{2} \cdot \mathrm{~s}\right) \end{aligned}$ |
| x2e | Vsb correction to linear $V d s$ threshold coefficient | 0.0 | $1 N$ |
| Ix2e | Length sensitivity of $\mathbf{x} \mathbf{2 e}$ | 0.0 | $\mu \mathrm{m} / \mathrm{N}$ |
| wx2e | Width sensitivity of $\mathbf{x 2 e}$ | 0.0 | $\mu \mathrm{m} / \mathrm{N}$ |
| px2e | $W L$-product sensitivity of $\mathbf{x 2 e}$ | 0.0 | $\mu \mathrm{m}^{2} N$ |
| x3e | $V d s$ correction to linear $V d s$ threshold coefficient | 0.0 | $1 N$ |
| 1x3e | Length sensitivity of $\mathbf{x} 3 \mathbf{e}$ | 0.0 | $\mu \mathrm{m} / \mathrm{N}$ |
| wx3e | Width sensitivity of $\mathbf{x 3 e}$ | 0.0 | $\mu \mathrm{m} / \mathrm{N}$ |
| px3e | $W L$-product sensitivity of $\mathbf{x 3 e}$ | 0.0 | $\mu \mathrm{m}^{2} N$ |
| x2u0 | $V s b$ reduction to gate field mobility reduction | 0.0 | $1 N^{2}$ |
| Ix2u0 | Length sensitivity of $\mathbf{x} \mathbf{2 u 0}$ | 0.0 | $\mu \mathrm{m} / \mathrm{V}^{2}$ |
| wx2u0 | Width sensitivity of $\mathbf{x} \mathbf{2 u 0}$ | 0.0 | $\mu \mathrm{m} / \mathrm{V}^{2}$ |
| px2u0 | $W L$-product sensitivity of $\mathbf{x} 2 \mathbf{u 0}$ | 0.0 | $\mu \mathrm{m}^{2} N^{2}$ |
| x2u1 | $V s b$ reduction to drain field mobility reduction | 0.0 | $1 N^{2}$ |
| Ix2u1 | Length sensitivity of $\mathbf{x} \mathbf{2 u 1}$ | 0.0 | $\mu \mathrm{m} / V^{2}$ |
| wx2u1 | Width sensitivity of $\mathbf{x} \mathbf{2 u 1}$ | 0.0 | $\mu \mathrm{m} / \mathrm{V}^{2}$ |
| px2u1 | $W L$-product sensitivity of $\mathbf{x} \mathbf{2 u 1}$ | 0.0 | $\mu \mathrm{m}^{2} N^{2}$ |


| Parameter | Description | Default | Units |
| :---: | :---: | :---: | :---: |
| mus | High drain field mobility | 600 | $\begin{aligned} & \mathrm{cm}^{2} / \\ & (\mathrm{V} \cdot \mathrm{~s}) \end{aligned}$ |
| Imus | Length sensitivity of mus | 0.0 | $\begin{aligned} & \mu \mathrm{m} \cdot \mathrm{~cm}^{2} / \\ & (\mathrm{V} \cdot \mathrm{~s}) \end{aligned}$ |
| wmus | Width sensitivity of mus | 0.0 | $\begin{aligned} & \mu \mathrm{m} \cdot \mathrm{~cm}^{2} / \\ & (\mathrm{V} \cdot \mathrm{~s}) \end{aligned}$ |
| pmus | $W L$-product sensitivity of mus | 0.0 | $\begin{aligned} & \mu \mathrm{m} \cdot \mathrm{~cm}^{2} / \\ & (\mathrm{V} \cdot \mathrm{~s}) \end{aligned}$ |
| x2ms | Vbs reduction to high drain field mobility | 0.0 | $\begin{aligned} & \mathrm{cm}^{2} / \\ & \left(\mathrm{V}^{2} \cdot \mathrm{~s}\right) \end{aligned}$ |
| 1x2ms | Length sensitivity of x2ms | 0.0 | $\begin{aligned} & \mu \mathrm{m} \cdot \mathrm{~cm}^{2} / \\ & \left(\mathrm{V}^{2} \cdot \mathrm{~s}\right) \end{aligned}$ |
| wx2ms | Width sensitivity of $\mathbf{x} \mathbf{2 m s}$ | 0.0 | $\begin{aligned} & \mu \mathrm{m} \cdot \mathrm{~cm}^{2} / \\ & \left(\mathrm{V}^{2} \cdot \mathrm{~s}\right) \end{aligned}$ |
| px2ms | $W L$-product sensitivity of $\mathbf{x} \mathbf{2 m s}$ | 0.0 | $\begin{aligned} & \mu \mathrm{m} \cdot \mathrm{~cm}^{2} / \\ & (\mathrm{V} \cdot \mathrm{~s}) \end{aligned}$ |
| x3ms | $V d s$ reduction to high drain field mobility | 5.0 | $\begin{aligned} & \mathrm{cm}^{2} / \\ & \left(\mathrm{V}^{2} \cdot \mathrm{~s}\right) \end{aligned}$ |
| Ix3ms | Length sensitivity of x $\mathbf{3 m s}$ | 0.0 | $\begin{aligned} & \mu \mathrm{m} \cdot \mathrm{~cm}^{2} / \\ & \left(\mathrm{V}^{2} \cdot \mathrm{~s}\right) \end{aligned}$ |
| wx3ms | Width sensitivity of $\mathbf{x} \mathbf{3 m s}$ | 0.0 | $\begin{aligned} & \mu \mathrm{m} \cdot \mathrm{~cm}^{2} / \\ & \left(\mathrm{V}^{2} \cdot \mathrm{~s}\right) \end{aligned}$ |
| px3ms | WL-product sensitivity of $\mathbf{x} 3 \mathrm{~ms}$ | 0.0 | $\begin{aligned} & \mu \mathrm{m}^{2} \cdot \mathrm{~cm}^{2} \\ & /\left(\mathrm{V}^{2} \cdot \mathrm{~s}\right) \end{aligned}$ |
| x3u1 | $V d s$ reduction to drain field mobility reduction | 0.0 | $1 N^{2}$ |
| Ix3u1 | Length sensitivity of $\mathbf{x} 3 \mathbf{u} \mathbf{1}$ | 0.0 | $\mu \mathrm{m} / N^{2}$ |
| wx3u1 | Width sensitivity of x3u1 | 0.0 | $\mu \mathrm{m} / \mathrm{N}^{2}$ |
| px3u1 | $W L$-product sensitivity of $\mathbf{x} 3 \mathbf{u} \mathbf{1}$ | 0.0 | $\mu \mathrm{m}^{2} N^{2}$ |
| tox | Gate oxide thickness | 0.02 | $\underset{>1}{\mu \mathrm{~m} ; \AA \text { if }}$ |
| temp | Temperature | 25.0 | ${ }^{\circ} \mathrm{C}$ |
| vdd | Critical voltage for high drain field mobility reduction | 5.0 | V |
| cgdo | Gate/drain parasitic capacitance per unit channel width | $1.5 \times 10^{-9}$ | F/m |
| cgso | Gate/source parasitic capacitance per unit channel width | $1.5 \times 10^{-9}$ | F/m |
| cgbo | Gate/bulk parasitic capacitance per unit channel length | $2.0 \times 10^{-10}$ | F/m |
| xpart | Flag for channel charge partitioning | 1 | - |


| Parameter | Description | Default | Units |
| :---: | :---: | :---: | :---: |
| n0 | Low-field weak inversion gate drive coefficient. A value $\square \geq 200$ disables weak inversion calculation. | 0.5 | - |
| In0 | Length sensitivity of $\mathbf{n 0}$ | 0.0 | $\mu \mathrm{m}$ |
| wno | Width sensitivity of n0 | 0.0 | $\mu \mathrm{m}$ |
| pn0 | $W L$-product sensitivity of n0 | 0.0 | $\mu \mathrm{m}^{2}$ |
| nb | $V s b$ reduction to n0 | 0.0 | - |
| Inb | Length sensitivity of nb | 0.0 | $\mu \mathrm{m}$ |
| wnb | Width sensitivity of nb | 0.0 | $\mu \mathrm{m}$ |
| pnb | $W L$-product sensitivity of nb | 0.0 | $\mu \mathrm{m}^{2}$ |
| nd | $V d s$ reduction to n0 | 0.0 | - |
| Ind | Length sensitivity of nd | 0.0 | $\mu \mathrm{m}$ |
| wnd | Width sensitivity of nd | 0.0 | $\mu \mathrm{m}$ |
| pnd | $W L$-product sensitivity of nd | 0.0 | $\mu \mathrm{m}^{2}$ |
| $\mathbf{x I} \mid$ dl \| Idel | Mask and etching length change | 0.0 | m |
| $\begin{aligned} & \text { xw }\|d w\| \\ & \text { wdel } \end{aligned}$ | Mask and etching width change | 0.0 | m |

## MOSFET Level 5 (Maher-Mead)

The Maher-Mead MOSFET model is accurate, physically based, continuous over all transistor regions of operation, including subthreshold, and scales to submicron channel lengths.

## Parameters

| Parameter | Symbol | Description | Default | Unit |
| :---: | :---: | :---: | :---: | :---: |
| solver | solver | Nonlinear system solver selector: bisection: solver=0 secant: solver=1 | 1 | - |
| tox | Tox | Oxide thickness | $1.0 \mathrm{e}-7$ | m |
| vmax | Vmax | Saturated velocity of electrons or holes | 0 | $\mathrm{m} / \mathrm{s}$ |
| mu0 | $\mu 0$ | Zero gate field mobility | Computed. | $\mathrm{cm}^{2} N \cdot \mathrm{~s}$ |
| nsub | Nsub | Substrate doping | - | $\mathrm{cm}^{-3}$ |
| vfb | $V f b$ | Flat band voltage | 0.0 | V |
| eghalf | Eghalf | Electric field where mobility $=\mathbf{m u 0}$ | $1.0 \times 10^{10}$ | $\mathrm{V} / \mathrm{m}$ |
| Id | $L d$ | Length adjustment parameter | $0.75 \times x j$ | m |
| wd | Wd | Width adjustment parameter | 0.0 | m |
| $\mathbf{x l \| d I} \mid$ Idel | Xl | Mask and etching length change | 0.0 | m |
| $\begin{aligned} & \text { xw }\|d w\| \\ & \text { wdel } \end{aligned}$ | $X w$ | Mask and etching width change | 0.0 | m |
| xj | Xj | Junction depth | 0.0 | m |
| del | del | Channel length reduction per side | 0.0 | m |
| tnom \| tref | Tref | Reference temperature | global tnom (25.0) | ${ }^{\circ} \mathrm{C}$ |
| qstol | qstol | Tolerance for nonlinear solution of source charge | $1.0 \times 10^{-8}$ |  |
| qdtol | qdtol | Tolerance for nonlinear solution of drain charge | $1.0 \times 10^{-8}$ |  |
| qdmindydx |  | Lower bound on derivative in nonlinear solution of drain charge | 0.01 |  |

## Characteristics

The Maher-Mead model is a physically based, charge-controlled model for the DC current, the intrinsic terminal charges, and the transcapacitances in the MOSFET.

The model expresses the current in the MOSFET in terms of the mobile charge per unit area in the channel, and uses a complete set of natural units for velocity, voltage, length, charge, and current. The
current-flow equation for the transistor includes both a drift term and a diffusion term, so that the formulation applies equally over the subthreshold, saturation, and "ohmic" regions of transistor operation and includes the effect of velocity saturation.

The model uses physical parameters derived from the fabrication process by direct measurement and from the dimensions of the device. The model agrees closely with measurements on the scaling of current with channel length down to submicron channel lengths.

## MOSFET Levels 8, 49 and 53 (BSIM3 Revision 3.3)

## Parameters

.model name nmos $\mid$ pmos level=8|49|53 [parameters]
Levels 49 and 53 are based upon the 3.3 version of Berkeley SPICE. They contain the most commonly used HSPICE ACM, parasitic resistor, and parasitic diode extensions. These extensions are described in "Additional MOSFET Parameters" on page 457.

Level 8 is a strict Berkeley v3.30 implementation with the addition of the HSPICE Effective area and Perimeter calculations and parasitic resistor equations, but not the diode equations.

Refer to the Berkeley manual BSIM3v330.pdf for further model parameters and equations.
Model Selectors

| Parameter | Symbol | Description | Default |
| :--- | :--- | :--- | :--- |
| binflag | binflag | Flag for use of xwref and xlref parameters | 0 (Off) |
| capmod | capmod | Flag for short channel capacitance model | $1[\mathrm{v} 3.0]$ <br> $0[\mathrm{v} 3.1]$ <br> $3[\geq \mathrm{v} 3.2]$ |
| mobmod | mobmo <br> $d$ | Mobility model selector. | 1 |
| nqsmod | nqsmod | Flag for NQS model. This turns the non- <br> quasistatic model equations on or off, and <br> overrides the model parameter value. | 0 |
|  |  | Note: This option applies to BSIM3 v3.2 and <br> v3.3 only. | nqsmod is a device parameter as well as a <br> device statement. |
| version | version | Select version of Berkeley BSIM3: 3.0, 3.1.3.2, <br> or 3.3. | 3.3 |

Basic Model Parameters

| Parameter | Symbol | Description | Default | Units |
| :--- | :--- | :--- | :--- | :--- |
| a1 | Al | Non-saturation factor 1 | $0.0[\mathrm{n}]$ | $\mathrm{V}^{-1}$ |
|  |  |  | $0.23^{1}[\mathrm{p}]$ |  |
| a2 |  |  |  |  |
|  |  | Non-saturation factor 2 | $1.0[\mathrm{n}]$ | $0.08[\mathrm{p}]$ |
| ags | Ags | Gate bias coefficient of Abulk | 0.0 | $\mathrm{~V}^{-1}$ |
| alpha0 | $\alpha 0$ | 1st parameter of impact ionization current | 0 | mV |


| Parameter | Symbol | Description | Default | Units |
| :---: | :---: | :---: | :---: | :---: |
| b0 | B0 | Bulk charge effect coefficient for channel width | 0.0 | m |
| b1 | B1 | Bulk charge effect width offset | 0.0 | m |
| beta0 | $\beta 0$ | 2nd parameter of impact ionization current | 30 | V |
| cdsc | Cdsc | Drain/source and channel coupling capacitance | $2.4 \times 10^{-4}$ | $\mathrm{F} / \mathrm{m}^{2}$ |
| cdscb | Cdscb | Body effect coefficient of cdsc | 0.0 | $\mathrm{F} / \mathrm{V} \cdot \mathrm{m}^{2}$ |
| cdscd | Cdscd | Drain-bias sensitivity of cdsc | 0.0 | $\mathrm{F} / \mathrm{V} \cdot \mathrm{m}^{2}$ |
| cit | Cit | Interface state capacitance | 0.0 | $\mathrm{F} / \mathrm{m}^{2}$ |
| delta | $\delta$ | Effective Vds parameter | 0.01 | - |
| drout | DRout | DIBL effect on Rout coefficient | 0.56 | - |
| dsub | Dsub | DIBL effect coefficient in subthreshold region | drout |  |
| dvt0 | Dvt0 | Short channel effect coefficient 0 | 2.2 |  |
| dvt0w | DvtOw | 1st coefficient of narrow width effect on $\mathbf{v t h}$ at small $L$ | 0 |  |
| dvt1 | Dvtl | Short channel effect coefficient 1 | 0.53 |  |
| dvt1w | Dvtlw | 2nd coefficient of narrow width effect on vth at small $L$ | $5.3 \times 10^{6}$ | $\mathrm{m}^{-1}$ |
| dvt2 | Dvt2 | Short channel effect coefficient 2 | -0.032 | $\mathrm{V}^{-1}$ |
| dvt2w | Dvt2w | Body-bias coefficient of narrow width effect on vth at small $L$ | -0.032 | $\mathrm{V}^{-1}$ |
| eta0 | $\eta 0$ | Subthreshold region DIBL coefficient | 0.08 |  |
| etab | $\eta b$ | Subthreshold region DIBL coefficient | $-0.07 \mathrm{~V}^{-1}$ | $\mathrm{V}^{-1}$ |
| is | $\mathrm{I}_{\text {s }}$ | Bulk saturation current | $1.0 \times 10^{-14}$ | A |
| k1 | K1 | $1^{\text {st }}$ order bulk effect coefficient | 0.53 | $\mathrm{V}^{1 / 2}$ |
| k2 | K2 | $2^{\text {nd }}$ order bulk effect coefficient | -0.0186 |  |
| k3 | K3 | Narrow width effect coefficient | 80.0 |  |
| k3b | K3b | Body effect coefficient of $\mathbf{k} \mathbf{3}$ | 0.0 | $\mathrm{V}^{-1}$ |
| keta | $K_{\eta}$ | Body bias coefficient of non-uniform depletion width effect | -0.047 | $\mathrm{V}^{-1}$ |


| Parameter | Symbol | Description | Default | Units |
| :---: | :---: | :---: | :---: | :---: |
| nch \| npeak | Nch | Peak doping concentration | $1.7 \times 10^{17}$ | $\mathrm{cm}^{-3}$ <br> Note: <br> T-Spice assigns units of $\mathrm{m}^{-3}$ to values > $10^{23}$. |
| nfactor | Nfactor | Subthreshold swing coefficient | 1 | - |
| ngate | Ngate | Poly gate doping concentration | 0 | $\mathrm{cm}^{-3}$ |
| $n 1 \times$ | Nlx | Lateral non-uniform doping effect | $1.74 \times 10^{-7}$ | m |
| nsub | Nsub | Doping concentration | $6.0 \times 10^{16}$ | $\mathrm{cm}^{-3}$ <br> Note: <br> T-Spice assigns units of $\mathrm{m}^{-3}$ to values > $10^{23}$. |
| pclm | Pclm | Channel-length modulation effect coefficient | 1.3 | - |
| pdiblc1 | Pdiblcl | 1 st output resistance DIBL effect correction parameter | 0.39 | - |
| pdiblc2 | Pdiblc2 | 2nd output resistance DIBL effect correction parameter | 0.0086 | - |
| pdiblcb | Pdiblcb | Body effect coefficient of DIBL correction parameters | 0.0 | $\mathrm{V}^{-1}$ |
| prwb | Prwb | Body effect coefficient of rdsw | 0 | $\mathrm{V}^{1 / 2}$ |
| prwg | Prwg | Gate bias coefficient of rdsw | 0 | $\mathrm{V}^{-1}$ |
| pscbe1 | Pscbel | Substrate current body effect coefficient 1 | $4.24 \times 10^{8}$ | V/m |
| pscbe2 | Pscbe2 | Substrate current body effect coefficient 2 | $1.0 \times 10^{-5}$ | V/m |
| pvag | Pvag | $V g$ dependence of Rout coefficient | 0.0 | V |
| rdsw | $R d s w$ | Source/drain resistance per unit width | 0.0 | $\Omega / \mu \mathrm{m}$ |
| tox | Tox | Gate oxide thickness | $1.50 \times 10^{-8}$ | m |
| u0 | $\mu 0$ | Low-field mobility at tnom | $\begin{aligned} & 670[\mathrm{n}] \\ & 250[\mathrm{p}] \end{aligned}$ | $\begin{aligned} & \mathrm{cm}^{2} N \cdot \mathrm{~s} \\ & (\geq 1) \\ & \mathrm{m}^{2} N \cdot \mathrm{~s} \\ & (<1) \end{aligned}$ |


| Parameter | Symbol | Description | Default | Units |
| :---: | :---: | :---: | :---: | :---: |
| ua | $U a$ | Linear Vgs dependence of mobility | $2.25 \times 10^{-9}$ | mV |
| ub | $U b$ | Quadratic Vgs dependence of mobility | $5.87 \times 10^{-18}$ | $\mathrm{m}^{2} N^{2}$ |
| uc | Uc | Body-bias dependence of mobility | $-4.65 \times 10^{-11}$ | $\mathrm{V}^{-1}$ |
| vbm | Vbm | Maximum body voltage | $\begin{aligned} & \text { v3.0: }-5.0 \\ & \geq \text { v3.1: }-3.0 \end{aligned}$ | V |
| vfb | vfb | DC flatband voltage. | -1 | V |
| vfbcv | vfbcv | Flatband voltage used in charge/capacitance equations when vfbflag=1 and capmod=0. | -1 | V |
| vfbflag | vfbflag | Selects vfb for capmod=0. (Vers. 3.2+) | 0 | - |
| voff | Voff | Threshold voltage offset | -0.08 | V |
| voffcv | Voffcv | C-V parameter for weak to strong inversion transition | 0 | - |
| vsat | vsat | Saturation velocity at tnom | $8.0 \times 10^{4}$ | $\mathrm{m} / \mathrm{s}$ |
| vtho \| vth0 | Vth0 | Threshold voltage. | $\begin{aligned} & 0.7[\mathrm{n}] \\ & -0.7[\mathrm{p}] \end{aligned}$ | V |
| w0 | W0 | Narrow width effect coefficient | $2.5 \times 10^{-6}$ | m |
| wr | Wr | Width offset from Weff for Rds calculation | 1.0 | - |
| xj | Xj | Junction depth | $1.5 \times 10^{-7}$ | m |

## AC and Capacitance Parameters

| Parameter | Symbol | Description | Default | Units |
| :--- | :--- | :--- | :--- | :--- |
| cf | $C f$ | Fringing field capacitance | Computed, | $\mathrm{F} / \mathrm{m}$ |
| cgbo | $C g b o$ | Gate/bulk overlap capacitance per unit channel <br> length | 0.0 | $\mathrm{~F} / \mathrm{m}$ |
| cgdl | $C g d l$ | Light doped drain-gate region overlap <br> capacitance <br> Gate/drain overlap capacitance per unit channel <br> width | 0.0 | $\mathrm{~F} / \mathrm{m}$ |
| cgdo | $C g d o$ | $\mathrm{~F} / \mathrm{m}$ |  |  |
| cgsl | $C g s l$ | Light doped source-gate region overlap <br> capacitance | 0.0 | $\mathrm{~F} / \mathrm{m}$ |
| cgso | $C g s o$ | Gate/source overlap capacitance per unit <br> channel width | 0.0 | $\mathrm{~F} / \mathrm{m}$ |
| ckappa | $C \kappa$ | Coefficient for lightly doped region overlap <br> capacitance | 0.6 | $\mathrm{~F} / \mathrm{m}$ |
| clc | $C L C$ | Constant term for short-channel model | $0.1 \times 10^{-6}$ | m |
| cle | $C L E$ | Exponential term for short-channel model <br> xpart | $X p a r t$ | Flag for channel charge partitioning |

## Length and Width Parameters

| Parameter | Symbol | Description | Default |  |
| :---: | :---: | :---: | :---: | :---: |
| dlc | DLC | Length offset fitting parameter from C-V | lint | m |
| dwb | $d W b$ | Coefficient of Weff substrate body bias dependence | 0.0 | $(\mathrm{mV})^{1 / 2}$ |
| dwc | DWC | Width offset fitting parameter from C-V | wint | m |
| dwg | $d W g$ | Coefficient of Weff gate dependence | 0.0 | $\mathrm{m} V$ |
| lint | Lint | Length offset fitting parameter from I-V without bias | 0.0 | m |
| II | Ll | Coefficient of length dependence for length offset | 0.0 | $m^{l l n}$ |
| llc | Llc | Coefficient of length dependence for $\mathrm{C}-\mathrm{V}$ channel width offset | II | $m^{l n}$ |
| Iln | Lln | Power of length dependence for length offset | 1.0 | - |
| Iw | Lw | Coefficient of width dependence for length offset | 0.0 | $m^{l w n}$ |


| Parameter | Symbol | Description | Default |  |
| :---: | :---: | :---: | :---: | :---: |
| lwc | Lwc | Coefficient of width dependence for $\mathrm{C}-\mathrm{V}$ channel length offset | Iw | $m^{l w n}$ |
| IwI | Lwl | Coefficient of length and width cross terms for length offset | 0.0 | $m^{l n+l w n}$ |
| Iwlc | Lwlc | Coefficient of length and width cross terms for C-V channel length offset | Iwlc | $m^{l l n+l w n}$ |
| Iwn | Lwn | Power of width dependence for length offset | 1.0 | - |
| wint | Wint | Width offset fitting parameter from I-V without bias | 0.0 | m |
| wl | Wl | Coefficient of length dependence for width offset | 0.0 | $\mathrm{m}^{\text {wln }}$ |
| wlc | Wlc | Coefficient of length dependence for $\mathrm{C}-\mathrm{V}$ channel width offset | wl | $\mathrm{m}^{\text {wln }}$ |
| win | Wln | Power of length dependence for width offset | 1.0 | - |
| ww | Ww | Coefficient of width dependence for width offset | 0.0 | $m^{w w n}$ |
| wwc | Wwc | Coefficient of width dependence for $\mathrm{C}-\mathrm{V}$ channel width offset | ww | $m^{w w n}$ |
| wwl | Wwl | Coefficient of length and width cross terms for width offset | 0.0 | $m^{w w n+w l n}$ |
| wwlc | Wwlc | Coefficient of length and width cross terms for $\mathrm{C}-\mathrm{V}$ channel width offset | wwl | $m^{w w n+w l n}$ |
| wwn | Wwn | Power of width dependence for width offset | 1.0 | - |
| $\mathbf{x l \| ~ d I ~ \| ~ I d e l ~}$ | Xl | Mask and etching length change | 0.0 | m |
| $\mathbf{x w}$ \| $\mathbf{d w}$ \| wdel I | $X w$ | Mask and etching width change | 0.0 | m |

## Temperature Parameters.

| Parameter | Symbol | Description | Default |  |
| :--- | :--- | :--- | :--- | :--- |
| at | $A t$ | Temperature coefficient of vsat | $3.3 \times 10^{4}$ | $\mathrm{~m} / \mathrm{s}$ |
| CTA CTC | $C T A \mid$ <br> $C T C$ | Temperature coefficient for $C j$ | 0.0 | $\mathrm{deg}^{-1}$ |
| CTP | $C T P$ | Temperature coefficient for $C j s w$ | 0.0 | $\mathrm{deg}^{-1}$ |
| EG | $E g(0)$ | Energy gap at $0^{\circ} \mathrm{K}($ Si: 1.166, Ge: 0.74, and <br> GaAs: 1.52$)$ <br> GAP1 | $G A P 1$ | Coefficient in energy gap temperature equation <br> $\left(S i: 4.73 \times 10^{-4}\right.$, Ge: $4.77 \times 10^{-4}$, and GaAs: 5.41 <br> $\left.\times 10^{-4}\right)$ |


| Parameter | Symbol | Description | Default |  |
| :---: | :---: | :---: | :---: | :---: |
| GAP2 | $G A P 2$ | Coefficient in energy gap temperature equation (Si: 636, Ge: 235, and GaAs: 204 | 1108 | deg |
| kt1 | Kt1 | Temperature coefficient of Vth | -0.11 | V |
| kt1I | Kt1l | Channel length sensitivity of kt1 | 0.0 | $\mathrm{V} \cdot \mathrm{m}$ |
| kt2 | Kt2 | Body bias coefficient of kt1 | 0.022 | - |
| prt | Prt | Temperature coefficient for rdsw | 0.0 | $\Omega \cdot \mu \mathrm{m}$ |
| PTA | PTA | Temperature coefficient for $P b$ | 0.0 | $\mathrm{deg}^{-1}$ |
| PTP | PTP | Temperature coefficient for Pbsw | 0.0 | $\mathrm{deg}^{-1}$ |
| tlev | tlev | Temperature equation selector | 0 | - |
| tlevc | tlevc | Temperature equation selector for junction capacitance and contact potential | 0 | - |
| tnom \| tref | $\mathrm{T}_{\text {ref }}$ | Reference temperature | global tnom (25.0) | deg |
| TRD | TRD | Temperature coefficient for $R d$ | 0.0 | $\operatorname{deg}^{-1}$ |
| TRS | TRS | Temperature coefficient for $R s$ | 0.0 | $\mathrm{deg}^{-1}$ |
| ua1 | Ual | Temperature coefficient of ua | $4.31 \times 10^{-9}$ | mV |
| ub1 | Ubl | Temperature coefficient of ub | $-7.61 \times 10^{-18}$ | $\mathrm{m}^{2} N^{2}$ |
| uc1 | Uc1 | Temperature coefficient of uc | -5.6e-11 | $\mathrm{V}^{-1}$ |
| ute | $\mu t e$ | Temperature coefficient of mobility | -1.5 | - |
| XTI | XTI | Saturation current temperature exponent | 0.0 | - |

Bin Description Parameters.

| Parameter | Symbol | Description | Default |
| :--- | :--- | :--- | :--- |
| binunit | binunit | Bin unit selector | 1 |

## Process Parameters

| Parameter | Symbol | Description | Default | Units |
| :--- | :--- | :--- | :--- | :--- |
| em | $E m$ | Maximum electric field | $4.1 \times 10^{7}$ | $\mathrm{~V} / \mathrm{m}$ |


| Parameter | Symbol | Description | Default | Units |
| :--- | :--- | :--- | :--- | :--- |
| gamma1 | $\gamma 1$ | Vth coefficient 1 | Computed | $\mathrm{V}^{1 / 2}$ |
| gamma2 | $\gamma 2$ | Vth coefficient 2 | 0.0 | $\mathrm{~V}^{1 / 2}$ |
| vbx | $V b x$ | Vth transition body voltage | Computed | V |
| xt | $X t$ | Doping depth | $1.55 \times 10^{-7}$ | m |

## NonQuasi-Static Parameters

| Parameter | Symbol | Description | Default |
| :--- | :--- | :--- | :--- |
| elm | elm | Elmore constant | 5 |

## Equations

For the complete set of equations describing the Level 49 model, see the BSIM3v3 Manual (Ko et al. 1995).

## Drain Current

$$
\begin{equation*}
I_{d s}=\frac{I_{d s o\left(V_{d s e f f}\right)}}{1+\frac{R_{d s} I_{d s o\left(V_{d s, e f f}\right)}}{V_{d s, e f f}}}\left(1+\frac{V_{d s}-V_{d s, e f f}}{V_{A}}\right)\left(1+\frac{V_{d s}-V_{d s, e f f}}{V_{A S C B E}}\right) \tag{0.369}
\end{equation*}
$$

where

$$
\begin{gather*}
I_{d s o}=\frac{W_{e f f} \mu_{e f f} C_{o x} V_{g s t, e f f}\left(1-A_{\text {bulk }} \frac{V_{d s, e f f}}{2\left(V_{g s t, e f f}+2 v_{t}\right)}\right) V_{d s, e f f}}{L_{\text {eff }}\left(1+\frac{V_{\text {ds,eff }}}{E_{\text {sat }} L_{e f f}}\right)}  \tag{0.370}\\
V_{d s, e \text { eff }}=V_{d s a t}-\frac{1}{2}\left(V_{d s a t}-V_{d s}-\delta+\sqrt{\left(V_{d s a t}-V_{d s}-\delta\right)^{2}+4 \delta V_{d s a t}}\right)  \tag{0.371}\\
E_{\text {sat }}=\frac{2 v_{\text {sat }}}{\mu_{e f f}}  \tag{0.372}\\
v_{t}=\frac{k T}{q} \tag{0.373}
\end{gather*}
$$

Variables for which equations are not given here are as follows.
$V_{A} \quad$ Early voltage

| $V_{A S C B E}$ | Early voltage due to substrate current-induced body effect |
| :--- | :--- |
| $V_{g s t e f f}$ | Effective Vgs -Vth (Vth: effective threshold voltage) |
| $\mu_{e f f}$ | Effective mobility |
| $A_{b u l k}$ | Bulk charge effect factor |
| $V_{d s a t}$ | Drain saturation voltage |

## Gate Charge

$$
\begin{equation*}
Q_{g}=-\left(Q_{a c c}+Q_{\text {sub } 0}+\delta Q_{\text {sub }}+Q_{i n v}\right) \tag{0.374}
\end{equation*}
$$

Variables for which equations are not given here are as follows.
$Q_{a c c}$
$Q_{\text {sub } 0}$
$Q_{\text {sub }}$
$Q_{i n v}$

Channel majority or accumulation charge
Substrate charge at $V d s=0$
Non-uniform substrate charge in presence of drain bias
$Q s+Q d=$ channel minority or inversion charge

## MOSFET Levels 9 and 50 (Philips MOS 9)

Philips MOS Model 9 is a compact MOS-transistor model, intended for the simulation of circuit behaviour with emphasis on analog applications. The model gives a complete description of all transistor-action related quantities: nodal currents and charges, noise-power spectral densities and weak-avalanche currents. The equations describing these quantities are based on the gradual-channel approximation with a number of first-order corrections for small-size effects. The consistency is maintained by using the same carrier-density and electrical-field expressions in the calculation of all model quantities. MOS Model 9 only provides a model for the intrinsic transistor. Junction charges and leakage currents are not included. They are covered by the separate Juncap model.

The MOS 9 model is fully documented in Philips MOS 9.
For further detailed information about the MOS 9 model, please refer to the Philips Compact Model Webpage:

## Parameters

The MOS 9 model uses the following syntax.

```
.model name nmos|pmos level=[9|50] | model=modelname [parameters]
```

T-Spice includes support for MOS 9 versions 902 and 903, and for both geometrical and electrical based model parameter sets.

The available modelname values for the MOS 9 model selection are:

| Modelname | Description |
| :--- | :--- |
| mos902 | Mos 9 level 902, geometrical |
| mos902e | Mos 9 level 902, electrical |
| mos903 (default) | Mos 9 level 903, geometrical |
| $\operatorname{mos} 903 e$ | Mos 9 level 903, electrical |

## MOSFET Levels 11 and 63 (Philips MOS 11)

MOS Model 11 has been developed as the successor of MOS Model 9. It is a symmetrical, surface-potential-based model, giving an accurate physical description of the transition from weak to strong inversion. MOS 11 includes an accurate description of all physical effects important for modern and future CMOS technologies, such as:
mobility reduction
bias-dependent series resistance
velocity saturation
conductance effects (CLM, DIBL, etc.)
gate leakage current
gate-induced drain leakage
gate depletion
quantum-mechanical effects
bias-dependent overlap capacitances
The description of the source-bulk and drain-bulk junction diode is not included in MOS Model 11. The behaviour of these junction diodes is modelled by the Juncap model. This model has to be added between the source and bulk node and between the drain and bulk node. The MOS 11 model is fully documented in Philips MOS 11.

The MOS 11 model is fully documented in Philips MOS 11.
For further detailed information about the MOS 11 model, please refer to the Philips Compact Model Webpage:
http://www.semiconductors.philips.com/Philips Models/mos models/model11

## Parameters

The MOS 11 model uses the following syntax.
.model name nmos $\mid$ pmos level=[11|63] | model=modelname [parameters]
T-Spice includes support for Mos 11 versions 1100, 1101, and 1102. Each of these versions, in turn, offers a selection of electrical or geometrical based parameterization, modeling of self-heating effects, and model binning

The available modelname values for the Mos 11 model are:

| Modelname | Description |
| :---: | :---: |
| mos1100 | Mos 11 level 1100, geometrical |
| mos1100e | Mos 11 level 1100, electrical |
| mos1101 | Mos 11 level 1101, electrical |
| mos1101t | Mos 11 level 1101, electrical, self-heating |
| mos11010 | Mos 11 level 1101, geometrical |
| mos11010t | Mos 11 level 1101, geometrical, self-heating |
| mos11011 | Mos 11 level 1101, geometrical, binning |


| mos11011t | Mos 11 level 1101, geometrical, binning, self-heating |
| :--- | :--- |
| mos1102 | Mos 11 level 1102, electrical |
| mos1102t | Mos 11 level 1102, electrical, self-heating |
| mos11020 (default) | Mos 11 level 1102, geometrical |
| mos11020t | Mos 11 level 1102, geometrical, self-heating |
| mos11021 | Mos 11 level 1102, geometrical, binning |
| mos11021t | Mos 11 level 1102, geometrical, binning, self-heating |

## MOSFET Levels 14 and 54 (BSIM4 Revision 5)

## Parameters

.model name nmos |pmos level=14|54 [parameters]
Levels 14 and 54 are fully compliant with the original UC Berkeley release of BSIM4 Revision 5. For standard model parameters and equations, refer to the Berkeley manual BSIM450.pdf. Specific device instance statements and their parameters are shown in the following section.

## Syntax

General MOSFET device parameters (length, width, drain, source, etc.) are described in the device statement chapter under "MOSFET (m)" on page 174. In the case of device values which have corresponding model values, the device settings override the model settings.

Device instance parameters for BSIM4 are as follows:

| mname drain gate source <br> [ps=Ps] [nrd=Nrd] [ <br> [min=min] [nrd=nrd] <br> [rbpd=rbpd] [rbps=rb <br> [trnqsmod=trnqsmod] | bulk model [l=L] [w=W] [ad=Ad] [pd=Pd] [as=As] <br> nrs=Nrs] [M=M] [acnqsmod=acnqsmod] [geomod=geomod] <br> [nrs=nrs] [rbdb=rbdb] [rbodymod=rbodymod] [rbpb=rbpb] <br> bps] [rbsb=rbsb] [rgatemod=rgatemod] [rgeomod=rgeomod] <br> [sa=sa] [sb=sb] [sd=sd] |
| :---: | :---: |
| acnqsmod | AC small-signal NQS model selector |
| geomod | Geometry-dependent parasitics model selector - specifying how the end S/D diffusions are connected |
| min | Wheter to minimize the number of drain or source diffusions for even-number finger devices |
| nf | Number of device fingers |
| nrd | Number of drain diffusion squares |
| nrs | Number of source diffusion squares |
| rbdb | Resistance connected between dbNode and bNode |
| rbodymod | Substrate resistance network model selector |
| rbpb | Resistance connected between bNodePrime and bNode |
| rbpd | Resistance connected between bNodePrime and dbNode |
| rbps | Resistance connected between bNodePrime and sbNode |
| rbsb | Resistance connected between sbNode and bNode |
| rgatemod | Gate resistance model selector |
| rgeomod | Source/drain diffusion resistance and contact model selector specifying the end S/D contact type: point, wide or merged, and how S/D parasitics resistance is computed |
| trnqsmod | Transient NQS model selector |
| sa | Distance between OD edge to Poly from one side |

Distance between OD edge to Poly from other side
Distance between neighboring fingers

Note:
Table-based model analysis is not supported for BSIM4.

## MOSFET Levels 15 and 61 (RPI Amorphous-Si TFT Model)

Level 15 is a thin-film transistor (TFT) amorphous silicon (a-Si) model developed at Rensselaer Polytechnic Institute (RPI).

This model is based on the universal charge control concept, which allows for currents and the large and small-signal parameters to be written as continuous functions of the applied bias, providing smooth transitions between the different operating regimes. Interpolation techniques are applied to the equations to unify the model.

Note that contrary to devices such as SOI MOSFETs, self-heating in a-Si TFT leads to an increase in current, since the carrier mobility increases with the temperature.

Physical effects included in MOS Model 15 include:
Above threshold:
Modified charge control model; induced charge trapped in localized states
Field effect mobility becoming a function of gate bias
Band mobility dominated by lattice scattering
Below threshold:
Fermi level located in deep localized states
Relate position of Fermi level, including the deep DOS back to the gate bias Empirical expression for current at large negative gate biases for hole-induced leakage current. Interpolation techniques are applied to the equations to unify the model.

Note:
The T-Spice implementation of the RPI a-Si TFT model supports model binning. The additional model parameters for this are $\mathbf{I m i n}$, $\boldsymbol{I m a x}, \mathbf{w m i n}$, wmax, $\mathbf{x I}$, xIref, $\mathbf{x w}$, and $\mathbf{x w r e f}$, described in the section "Additional MOSFET Parameters" on page 457.

## Parameters

This is a 3-terminal model. Because no bulk node exists, no parasitic drain-bulk or source-build diodes are appended to the model. You can specify a fourth node but it will not affect simulation results. The drain and source areas and perimeters are not used either, since the model equation is based solely upon the width and length.

Device instance parameters for MOS level 15 are as follows:
mname drain gate source model [L=l] [W=w] [M=m][TEMP=t]
The parameter definitions ( $\mathrm{L}, \mathrm{W}$, and M ) are the MOSFET standards (see "MOSFET (m)" on page 174), and TEMP is the device temperature (C).

For further detailed information please refer to the Rensselaer Polytechnic Institute research papers in the T-Spice models folder.

| Parameter | Description | Default | Units |
| :--- | :--- | :--- | :--- |
| ALPHASAT | Saturation modulation parameter | 0.6 | - |
| CGDO | Gate-drain overlap capacitance per meter <br> channel width | 0.0 | $\mathrm{~F} / \mathrm{m}$ |


| Parameter | Description | Default | Units |
| :---: | :---: | :---: | :---: |
| CGSO | Gate-source overlap capacitance per meter channel width | 0.0 | F/m |
| DEFO | Dark Fermi level position | 0.6 | eV |
| DELTA | Transition width parameter | 5 | - |
| EL | Activation energy of the hole leakage current | . 35 | eV |
| EMU | Field effect mobility activation energy | 0.06 | eV |
| EPS | Relative dielectric constant of substrate | 11 | - |
| EPSI | Relative dielectric constant of gate insulator | 7.4 | - |
| GAMMA | Power law mobility parameter | 0.4 | - |
| $\begin{aligned} & \text { GMIN (GO, } \\ & \text { GO) } \end{aligned}$ | Minimum density of deep states | 1E23 | $\mathrm{m}^{-3} \mathrm{eV}^{-1}$ |
| IOL | Zero bias leakage current parameter | 3E-14 | A |
| KASAT | Temperature coefficient of ALPHASAT | 0.006 | $1 /{ }^{\circ} \mathrm{C}$ |
| KVT | Threshold voltage temperature coefficient | -0.036 | V/ ${ }^{\circ} \mathrm{C}$ |
| LAMBDA | Output conductance parameter | 0.0008 | 1/V |
| M (MSAT) | Knee shape parameter | 2.5 | - |
| MUBAND | Conduction band mobility | 0.001 | $\mathrm{m}^{2} / \mathrm{Vs}$ |
| RD | Drain resistance | 0.0 | $\mu$ |
| RS | Source resistance | 0.0 | $\mu$ |
| SIGMAO <br> (sigma0) | Minimum leakage current parameter | 1E-14 | A |
| TNOM (TREF) | Parameter measurement temperature | global Tnom | oC |
| TOX | Thin-oxide thickness | 1E-7 | m |
| V0 | Characteristic voltage for deep states | 0.12 | V |
| VAA | Characteristic voltage for field effect mobility | 7.5E3 | V |
| VDSL | Hole leakage current drain voltage parameter | 7 | V |
| VFB | Flat band voltage | -3 | V |
| VGSL (VGL) | Hole leakage current gate voltage parameter | 7 | V |
| VMIN | Convergence parameter | 0.3 | V |
| VTO (VTO) | Zero-bias threshold voltage | 0.0 | V |

## Equivalent Circuit



## MOSFET Levels 16 and 62 (RPI Poly-Si TFT Model, 1.0 and 2.0)

Level 16 is a thin-film transistor (TFT) poly-silicon (Poly-Si) model developed at Rensselaer Polytechnic Institute (RPI).

MOS level 16 improves on existing devices models by including the necessary dependencies to make it scalable from long-channel to short-channel devices.

This model accounts for some effects that are specific to poly-Si TFTs, including the kink effect, the increase of the field-effect mobility as the gate voltage is increased in moderate inversion, the offcurrent, the DIBL (Drain Induced Barrier Lowering) and velocity saturation effects, as well as series resistances. The DIBL effect is more pronounced in poly-Si TFTs than in crystalline MOSFETs and cannot be neglected even for long-channel devices.

More specifically,

- Field effect mobility becomes a function of gate bias
- Effective mobility that accounts for trap states, for low V gs using a power law, for high V gs a constant.
- A unified DC model that includes all four regimes for channel lengths down to 4 m -leakage (thermionic emission), subthreshold (diffusion-like model), above threshold (c-Si-like, with mFet) and kink (impact ionization with feedback).
- An AC model that accurately reproduces $\mathrm{C}_{\mathrm{gc}}$ frequency dispersion
- An automatic scaling of model parameters to accurately model a wide range of device geometries

Note:
The T-Spice implementation of the RPI Poly-Si TFT model supports model binning. The additional model parameters for this are Imin, Imax, wmin, wmax, $\mathbf{x I}$, xIref, xw, and xwref, described in the section "Additional MOSFET Parameters" on page 457.

## Parameters

This is a 3-terminal model. MOS level 16 does not use a bulk node; there are no corresponding drainbulk or source-bulk diodes to be modeled. You can specify a fourth node but it does it not affect simulation results.

Device instance parameters for MOS level 16 are as follows:

```
mname drain gate source model [L=l] [W=w] [NRS=nrs] [NRD=nrd] [M=m] [TEMP=t]
```

The parameter definitions (L, W, NRS, NRD, M, etc.) are the MOSFET standard ones (see "MOSFET (m)" on page 174). TEMP is the device temperature (C).

For further detailed information please refer to the Rensselaer Polytechnic Institute papers in the T-Spice models folder.

| Parameter | Description | Default | Units |
| :--- | :--- | :--- | :--- |
| ASAT | Proportionality constant of Vsat | 1 | - |
| AT | DIBL parameter 1 | $3 \mathrm{E}-8$ | $\mathrm{~m} / \mathrm{V}$ |


| Parameter | Description | Default | Units |
| :---: | :---: | :---: | :---: |
| BLK | Leakage barrier lowering constant | 0.001 | - |
| BT | DIBL parameter 2 | 1.9E-6 | $\mathrm{m} \cdot \mathrm{V}$ |
| CAPMOD | Capacitance model selector | 0 | - |
| CGDO | Gate-drain overlap capacitance per meter channel width | 0.0 | F/m |
| CGSO | Gate-source overlap capacitance per meter channel width | 0.0 | F/m |
| DASAT | Temperature coefficient of ASAT | 0 | $1 /{ }^{\circ} \mathrm{C}$ |
| DD | Vds field constant | 1400 Å | m |
| DELTA | Transition width parameter | 4.0 | - |
| DG | Vgs field constant | 2000 Å | m |
| DMU1 | Temperature coefficient of MU1 | 0 | $\mathrm{cm}^{2} / \mathrm{Vs}^{\circ} \mathrm{C}$ |
| DVT | The difference between VON and the threshold voltage | 0 | V |
| DVTO | Temperature coefficient of VTO | 0 | V/ ${ }^{\circ} \mathrm{C}$ |
| EB | Barrier height of diode | 0.68 | EV |
| ETA (ETAI) | Subthreshold ideality factor | 7 | - |
| ETACO | Capacitance subthreshold ideality factor at zero drain bias | ETA | - |
| ETAC00 | Capacitance subthreshold coefficient of drain bias | 0 | 1/V |
| 10 (CLK) | Leakage scaling constant | 6.0 | A/m |
| 100 | Reverse diode saturation current | 150 | A/m |
| LASAT | Coefficient for length dependence of ASAT | 0 | M |
| LKINK | Kink effect constant | 19E-6 | M |
| MC | Capacitance knee shape parameter | 3.0 | - |
| MK (MKINK) | Kink effect exponent | 1.3 | - |
| MMU (M) | Low field mobility exponent | 1.7 | - |
| MUO | High field mobility | 100 | $\mathrm{cm}^{2} / \mathrm{Vs}$ |
| MU1 | Low field mobility parameter | 0.0022 | $\mathrm{cm}^{2} / \mathrm{Vs}$ |
| MUS | Subthreshold mobility | 1.0 | $\mathrm{cm}^{2} / \mathrm{Vs}$ |
| RD | Drain resistance | 0.0 | W |
| RDX | Resistance in series with Cgd (RF) | 0 | W |
| RS | Source resistance | 0.0 | W |
| RSH | Sheet resistance | 0 | $\Omega / \mathrm{sq}$ |
| RSX (RI) | Resistance in series with Cgs | 0 | W |


| Parameter | Description | Default | Units |
| :--- | :--- | :--- | :--- |
| TNOM <br> (TREF) | Parameter measurement temperature | 27 | ${ }^{\circ} \mathrm{C}$ |
| TOX | Thin-oxide thickness | $1.0 \mathrm{e}-7$ | m |
| VFB | Flat band voltage | -0.1 | V |
| VKINK | Kink effect voltage | 9.1 | V |
| VON | On-voltage | 0 | V |
| VTO | Zero-bias threshold voltage | 0.0 | V |

## Version 2.0 Parameters

Version 1.0 is the standard release of the Poly-Si model, equivalent to the AimSpice level 16 PSIA2 model. Version 2.0 (selected using the model parameter VERSION=2.0) is a newer release, and includes an intrinsic resistance model, alternate channel length modulation equations, and DIBL (drain induced barrier lowering) equations.

| Parameter | Description | Default | Units |
| :--- | :--- | :--- | :--- |
| INTDSNOD | Extrinsic resistance mode selector | 0 | - |
| ISUBMOD | Channel length modulation equation selector | 0 | - |
| LAMBDA | Channel length modulation parameter | .048 | $\mathrm{~m} / \mathrm{V}$ |
| LS | Channel length modulation parameter | $35 \mathrm{e}-9$ | $\mathrm{~m} / \mathrm{V}$ |
| ME (MS) | Long channel saturation transition parameter | 2.5 | - |
| META | Eta floating body parameter | 1.0 | - |
| MSS | Vdse transition parameter | 1.5 | - |
| THETA | Mobility degradation parameter | 0 | $1 / \mathrm{V}$ |
| VMAX | Saturation velocity | 4 e 4 | $\mathrm{~m} / \mathrm{s}$ |
| VP | Channel length modulation parameter | 0.2 | V |
| VSIGMA | Above threshold DIBL parameter | 0.2 | V |
| VSIGMAT | Above threshold DIBL parameter | 1.7 | V |

## Equivalent Circuit



## MOSFET Level 20 (Philips MOS 20)

MOS Model 20 is a compact LDMOS model, which combines the MOSFET operation of the channel region with that of the drift region under the thin gate oxide. As such, it is aimed as a successor of MOS Model 9 in series with MOS Model 31. MOS Model 20 has especially been developed to improve the convergence behaviour during simulation, by having the voltage at the transition from the channel region to the drift region calculated inside the model itself.

The MOS 20 model is fully documented in Philips MOS 20.
For further detailed information about the MOS 20model, please refer to the Philips Compact Model Webpage:
http://www.semiconductors.philips.com/Philips_Models/high_voltage/model20

## Parameters

The MOS 20 model uses the following syntax.
.model name nmos|pmos level=20 | model=modelname [parameters]
T-Spice includes support for MOS 20 version 2001 with geometrical and electrical model parameterization, and self-heating effects.

The available modelname values for the MOS 20 model selection are:

Modelname
mos2001 (default)
mos2001e
mos2001et

## Description

Mos 20 level 2001, geometrical
Mos 20 level 2001, electrical
Mos 20 level 2001, electrical, self-heating

## MOSFET Level 28 (Extended BSIM1)

.model name nmos|pmos level=28 [parameters]
T-Spice supports MOSFET model level 28, based on the Berkeley short-channel IGFET models. The Extended BSIM1 level 28 model is a proprietary Tanner Research extension to the core BSIM1 model developed at Berkeley. The extensions attempt to fix many of the problems in the original model equations, including:

- Negative output conductance in the saturation region of operation.
- Discontinuities in the output conductance at the transition between the linear and saturation regions of operation.
- Discontinuities in the subthreshold current and transconductance characteristics near threshold.

In addition, the core equations have been enhanced to correct deficiencies in the original model equations:

- Temperature compensation equations have been added for proper handling of temperature effects.
- Effective length-width product scaling factors have been added for use with the BSIM3 revision 3 scaling equations.

Note:
T-Spice accepts BSIM1 model parameters entered in the level 13 and level 28 conventions used by HSPICE ${ }^{\text {TM }} *$.
Level 13 model parameters are translated to standard BSIM1 model (see "MOSFET Levels 4 and 13 (BSIM1)" on page 412.)
Level 28 model parameters are automatically translated to the extended BSIM1 model as shown below.

## Parameters

Following are the Tanner Extended BSIM1 MOSFET model parameters.

| Parameter | Description | Default | Units |
| :--- | :--- | :--- | :--- |
| tempmod | Temperature model selector. tempmod=0 <br> disables the temperature compensation <br> equation. tempmod>0 enables the temperature <br> compensation equation. | 0 | - |
| ute | Temperature exponent for mobility | 1.5 | - |
| lute | Length sensitivity of ute | 0.0 | - |
| wute | Width sensitivity of ute | 0.0 | - |
| pute | WL-product sensitivity of ute | 0.0 | - |
| kt1 | Temperature coefficient for flat band voltage | 0.0 | V |
| Ikt1 | Length sensitivity of $\mathbf{k t i}$ | 0.0 | $\mu \mathrm{~m} \cdot \mathrm{~V}$ |
| wkt1 | Width sensitivity of $\mathbf{k t i}$ | 0.0 | $\mu \mathrm{~m} \cdot \mathrm{~V}$ |
| pkt1 | WL-product sensitivity of $\mathbf{k t i}$ | 0.0 | $\mu \mathrm{~m}^{2} \cdot \mathrm{~V}$ |
| * |  |  |  |
| HSPICE(®) is a registered trademark of Synopsys, Inc. |  |  |  |


| Parameter | Description | Default | Units |
| :--- | :--- | :--- | :--- |
| submod | Subthreshold current model selector | 0 | - |
| voffset | Subthreshold offset voltage above threshold | 0.0 | V |
| Ivoffset | Length sensitivity of voffset | 0.0 | $\mu \mathrm{~m} \cdot \mathrm{~V}$ |
| wvoffset | Width sensitivity of voffset | 0.0 | $\mu \mathrm{~m} \cdot \mathrm{~V}$ |
| pvoffset | WL-product sensitivity of voffset | 0.0 | $\mu \mathrm{~m}^{2} \cdot \mathrm{~V}$ |
| iratio | Subthreshold current factor | $\mathrm{e}^{-2}$ | - |
| liratio | Length sensitivity of iratio | 0.0 | - |
| wiratio | Width sensitivity of iratio | 0.0 | - |
| piratio | WL-product sensitivity of iratio | 0.0 | - |
| satmod | Saturated drain current model selector | 0 | - |
| alpha | Saturated drain current knee parameter | 1.0 | - |
| lalpha | Length sensitivity of alpha | 0.0 | - |
| walpha | Width sensitivity of alpha | 0.0 | - |
| palpha | WL-product sensitivity of alpha | 0.0 | - |
| gamma | Saturated drain current output conductance | 0.0 | - |
| lgamma | parameter | 0.0 | - |
| wgamma | Length sensitivity of gamma | 0.0 | - |
| pgamma | Width sensitivity of gamma | 1.0 | - |
| xj | WL-product sensitivity of gamma | - | - |
| wmit | Width shrink factor |  | - |

## Equations

## Process Parameters

Process parameters express the sensitivity of the BSIM1 electrical parameters to device length, width, and the product of length and width ( $W L$-product). The SPICE names of process parameters are derived from the related electrical parameter names by prefixing the letters $\mathbf{I}, \mathbf{w}$, and $\mathbf{p}$.

The actual value of an electrical parameter $P$ is

$$
\begin{equation*}
P=P_{0}+\frac{P_{L}}{L_{i}-\Delta L}+\frac{P_{W}}{W_{i}-\Delta W}+\frac{P_{P}}{\left(L_{i}-\Delta L\right)\left(W_{i}-\Delta W\right)} \tag{0.375}
\end{equation*}
$$

where $P L, P W$, and $P P$ denote $P$ 's length, width, and product sensitivity parameters, respectively.

## Drain Current

Drain current is modeled by three equations, representing the three regions of MOSFET operation: cutoff, linear, and saturation.

Cutoff region: Vgs $\leq$ Vth

$$
\begin{equation*}
I_{d s}=0 \tag{0.376}
\end{equation*}
$$

Linear region: Vgs $>V t h$ and $0<V d s<V d$,sat

$$
\begin{equation*}
I_{d s}=\frac{\mu_{0}}{1+U_{0}\left(V_{g s}-V_{t h}\right)} \cdot \frac{C_{o x}^{\prime} \frac{W_{e f f}}{L_{e f f}}}{\left(1+\frac{U_{1}}{L_{e f f}} V_{d s}\right)} \cdot\left[\left(V_{g s}-V_{t h}\right) V_{d s}-\frac{a}{2} V_{d s}^{2}\right] \tag{0.377}
\end{equation*}
$$

where

$$
\begin{equation*}
a=\frac{1+g K_{1}}{2 \sqrt{\phi_{s}-V_{b s}}}>1 \tag{0.378}
\end{equation*}
$$

and

$$
\begin{equation*}
g=1-\frac{1}{1.744+0.8364\left(\phi_{s}-V_{b s}\right)} \tag{0.379}
\end{equation*}
$$

Saturation region: Vgs $>V t h$ and $V d s \geq V d$,sat

$$
\begin{equation*}
I_{d s}=\frac{\mu_{0}}{1+U_{0}\left(V_{g s}-V_{t h}\right)} \cdot \frac{C_{o x}^{\prime} \frac{W_{e f f}}{L_{e f f}}}{2 a K} \cdot\left(V_{g s}-V_{t h}\right)^{2} \tag{0.380}
\end{equation*}
$$

where

$$
\begin{equation*}
K=\frac{1+v_{c}+\sqrt{1+2 v_{c}}}{2} \tag{0.381}
\end{equation*}
$$

and

$$
\begin{equation*}
v_{c}=\frac{U_{1}}{L_{e f f}} \cdot \frac{\left(V_{g s}-V_{t h}\right)}{a} \tag{0.382}
\end{equation*}
$$

In the linear and saturation regions,

$$
\begin{gather*}
V_{d, s a t}=\frac{V_{g s}-V_{t h}}{a \sqrt{K}}  \tag{0.383}\\
U_{0}\left(V_{d s}, V_{b s}\right)=U_{0 z}+U_{0 b} V_{b s}  \tag{0.384}\\
U_{l}\left(V_{d s}, V_{b s}\right)=U_{1 z}+U_{1 b} V_{b s}+U_{1 d}\left(V_{d s}-V_{d d}\right) \tag{0.385}
\end{gather*}
$$

$\mu 0$ is computed by quadratic interpolation given three conditions:

$$
\begin{gather*}
\mu_{0}\left(V_{d s}=0\right)=\mu_{z}+\mu_{z b} V_{b s}  \tag{0.386}\\
\mu_{0}\left(V_{d s}=V_{d d}\right)=\mu_{s}+\mu_{s b} V_{b s} \tag{0.387}
\end{gather*}
$$

and the sensitivity of $\mu 0$ to the drain bias at $V d s=V d d$.

## Subthreshold Current

The total drain current is modeled as the sum of two components: the strong inversion component $I d s, s$, equivalent to the drain current modeled in equations (0.376) through (0.387), and the weak inversion component $I d s, w$ :

$$
\begin{equation*}
I_{d s, w}=\frac{I_{\exp } I_{\text {limit }}}{I_{\text {exp }}+I_{\text {limit }}} \tag{0.388}
\end{equation*}
$$

where

$$
\begin{equation*}
I_{e x p}=\mu_{0} C_{o x}^{\prime} \frac{W_{e f f}}{L_{e f f}}\left(\frac{k T}{q}\right)^{2} e^{1.8} e^{q\left(V_{g s}-V_{t h}\right) / n k T}\left(1-e^{-q V_{d s} / k T}\right) \tag{0.389}
\end{equation*}
$$

and

$$
\begin{equation*}
I_{\text {limit }}=\frac{\mu_{0} C_{o x}^{\prime}}{2} \frac{W_{\text {eff }}}{L_{e f f}}\left(\frac{3 k T}{q}\right)^{2} \tag{0.390}
\end{equation*}
$$

The subthreshold parameter $n$ is modeled as

$$
\begin{equation*}
n\left(V_{d s}, V_{b s}\right)=n_{0}+n_{b} V_{b s}+n_{d} V_{d s}>0.5 \tag{0.391}
\end{equation*}
$$

## MOSFET Level 30 (Philips MOS 30)

MOS Model 30 is a long channel JFET/MOSFET model developed to describe the drift region of LDMOS, EPMOS and VDMOS devices.

Note:
MOS Model 30 has been replaced with the MOS 31 model, and is provided for historical and compatibility purposes only. It's use is not recommended.

The MOS 30 model is fully documented in Philips MOS 30.

## Parameters

The MOS 30 model uses the following syntax.
.model name nmos |pmos level=30 | model=mos3002 [parameters]
T-Spice includes support for MOS 30 version 3002 with electrical model parameterization.

## MOSFET Level 31 (Philips MOS 31)

MOS Model 31 is a physics based transistor model to be used in circuit simulation and IC-design of analog high-voltage applications. The model describes the electrical behaviour of a junction-isolated accumulation/depletion-type MOSFET. The model is used as the drain extension of high-voltage MOS devices, like the Lateral Double-diffused MOS (LDMOS), the Vertical Double-diffused MOS (VDMOS), and the Extended MOS transistors. Physical effects included in MOS Model 31:

Both accumulation and depletion underneath the gate oxide;
Depletion from the substrate (a pn-junction);
Pinch-off effects;
Velocity saturation; and Temperature scaling.

The MOS 31 model is fully documented in Philips MOS 31.
For further detailed information about the MOS 31 model, please refer to the Philips Compact Model Webpage:

## [1] <br> http://www.semiconductors.philips.com/Philips Models/high voltage/model31

## Parameters

The MOS 31 model uses the following syntax.
.model name nmos $\mid$ pmos level=31 | model=modelname [parameters]
T-Spice includes support for MOS 31 version 3100 with and without self-heating effects.
The available modelname values for the MOS 31 model selection are:

Modelname
mos3100 (default)
$\operatorname{mos} 3100 t$

## Description

Mos 31 level 3100, electrical
Mos 31 level 3100, electrical, self-heating

## MOSFET Level 40 (Philips MOS 40)

MOS Model 40 is a physics based transistor model to be used in circuit simulation and IC-design of analogue high-voltage applications processed in Silicon-on-Insulator (SOI). The model describes the electrical behavior of an accumulation/depletion-type MOSFET in SOI. The model is used as drain extension of high-voltage MOS devices, like the Lateral Double-diffused MOS (LDMOS), the Vertical Double-diffused MOS (VDMOS), and the Extended MOS transistors.
Physical effects in MOS Model 40 include:
Both accumulation and depletion underneath the gate oxide;
Both accumulation and depletion from the substrate (an oxide layer);
Pinch-off effects;
Velocity saturation; and
Temperature scaling.
The MOS 40 model is fully documented in Philips MOS 40.
For further detailed information about the MOS 40 model, please refer to the Philips Compact Model Webpage:
http://www.semiconductors.philips.com/Philips_Models/high_voltage/model40

## Parameters

The MOS 40 model uses the following syntax.
.model name nmos|pmos level=40 | model=modelname [parameters]
T-Spice includes support for MOS 40 version 40 with and without self-heating effects.
The available modelname values for the MOS 40 model selection are:

Modelname
mos40 (default)
mos40t

## Description

Mos 40 level 40, electrical
Mos 40 level 40, electrical, self-heating

## MOSFET Levels 44 and 55 (EKV Revision 2.6)

## Parameters

.model name nmos $\mid$ pmos level=44|55 [parameters]
For model parameters, model equations and device instance statements and their parameters, refer to the Swiss Federal Institute of Technology manual EKV_v262.pdf.

Note:
Table-based model analysis is not supported for EKV.

## MOSFET Level 47 (BSIM3 Revision 2)

## Parameters

.model name nmos $\mid$ pmos level=47 [parameters]
Based on the Berkeley short-channel IGFET model, © 1990 Regents of the University of California.] Also see "Additional MOSFET Parameters" on page 457.

| Parameter | Symbol | Description | Default | Units |
| :---: | :---: | :---: | :---: | :---: |
| subthmod | subthmo <br> $d$ | Subthreshold model selector | 2 | - |
| satmod | satmod | Saturation model selector | 2 | - |
| bulkmod | bulkmo <br> $d$ | Bulk charge effect model selector | $\begin{aligned} & 1[\mathrm{n}] \\ & 2[\mathrm{p}] \end{aligned}$ | - |
| mobmod | mobmo <br> $d$ | Mobility model selector | 1 | - |
| tox | Tox | Gate oxide thickness | $1.50 \times 10^{-8}$ | m |
| cdsc | Cdsc | Drain/source and channel coupling capacitance | $2.4 \times 10^{-4}$ | $\mathrm{F} / \mathrm{m}^{2}$ |
| cdscb | Cdscb | Body effect coefficient of cdsc | 0.0 | $\mathrm{F} / \mathrm{V} \cdot \mathrm{m}^{2}$ |
| cit | Cit | Interface state capacitance | 0.0 | $\mathrm{F} / \mathrm{m}^{2}$ |
| nfactor | Nfactor | Swing coefficient | 1 | - |
| xj | Xj | Junction depth | $1.50 \mathrm{e}-7$ | m |
| vsat | vsat | Saturation velocity at tnom | $8.0 \times 10^{-6}$ | $\mathrm{cm} / \mathrm{s}$ |
| at | At | Temperature coefficient of vsat | $3.3 \times 10^{-4}$ | $\mathrm{m} / \mathrm{s}$ |
| a0 | AO | Non-uniform depletion width effect coefficient | $\begin{aligned} & 1.0 \\ & {[\text { bulkmod=1] }} \\ & 4.4 \\ & {[\text { bulkmod }=2]} \end{aligned}$ | - |
| a1 | Al | Non-saturation factor 1 | $\begin{aligned} & 0.0[\mathrm{n}] \\ & 0.23[\mathrm{p}] \end{aligned}$ | 1/V |
| a2 | A2 | Non-saturation factor 2 | $\begin{aligned} & 1.0[\mathrm{n}] \\ & 0.08[\mathrm{p}] \end{aligned}$ | - |
| keta | Keta | Body bias coefficient of non-uniform depletion width effect | -0.047 | 1/V |
| vghigh | Vghigh | High bound of transition region | 0.12 | V |
| vglow | Vglow | Low bound of transition region | -0.12 | V |
| nsub | Nsub | Doping concentration | $6.0 \times 10^{16}$ | $\begin{aligned} & \mathrm{cm}^{-3} \\ & \left(\leq 10^{20}\right) \\ & \mathrm{m}^{-3} \\ & \left(>10^{20}\right) \end{aligned}$ |


| Parameter | Symbol | Description | Default | Units |
| :---: | :---: | :---: | :---: | :---: |
| nch \| npeak | Npeak | Peak doping concentration | $1.7 \times 10^{17}$ | $\begin{aligned} & \mathrm{cm}^{-3} \\ & \left(\leq 10^{23}\right) \\ & \mathrm{m}^{-3} \\ & \left(>10^{23}\right) \end{aligned}$ |
| ngate | Ngate | Gate doping concentration | 0.0 | $\mathrm{cm}^{-3}$ |
| gamma1 | $\gamma 1$ | $V$ th coefficient | 0.0 | $\mathrm{V}^{1 / 2}$ |
| gamma2 | $\gamma 2$ | $V t h$ coefficient 2 | 0.0 | $\mathrm{V}^{1 / 2}$ |
| vbx | $V b x$ | $V t h$ transition body voltage | 0.0 | V |
| vbi | Vbi | Drain/source junction built-in potential | 0.0 | V |
| vbm | Vbm | Maximum body voltage | -5.0 | V |
| xt | Xt | Doping depth | $1.55 \times 10^{-7}$ | m |
| phi | $\phi$ | Strong inversion surface potential | Computed | V |
| litl | Litl | Depth of current path | 0.0 | m |
| em | Em | Maximum electric field | $4.1 \times 10^{7}$ | $\mathrm{V} / \mathrm{m}$ |
| k1 | K1 | Bulk effect coefficient 1 | 0.0 | $\mathrm{V}^{1 / 2}$ |
| kt1 | Kt1 | Temperature coefficient of Vth | -0.11 | V |
| kt1I | Kt1l | Channel length sensitivity of kt1 | 0.0 | $\mathrm{V} \cdot \mathrm{m}$ |
| kt2 | Kt2 | Body bias coefficient of kt1 | 0.022 | - |
| k2 | K2 | Bulk effect coefficient 2 | 0.0 | - |
| k3 | K3 | Narrow width effect coefficient | 80.0 | - |
| k3b | K3b | Body effect coefficient of k3 | 0.0 | $1 N$ |
| w0 | W0 | Narrow width effect coefficient | $2.5 \times 10^{-6}$ | m |
| nlx | Nlx | Lateral non-uniform doping effect | $1.74 \times 10^{-7}$ | m |
| dvt0 | Dvt0 | Short channel effect coefficient 0 | 2.2 | - |
| dvt1 | Dvtl | Short channel effect coefficient 1 | 0.53 | - |
| dvt2 | Dvt2 | Short channel effect coefficient 2 | -0.032 | $1 N$ |
| drout | DRout | DIBL effect on Rout coefficient | 0.56 | - |
| dsub | Dsub | DIBL effect coefficient in subthreshold region | drout | - |
| vtho \| vth0 | Vth | Threshold voltage | $\begin{aligned} & 0.7[\mathrm{n}] \\ & -0.7[\mathrm{p}] \end{aligned}$ | V |
| ua | Ua | Linear Vgs dependence of mobility | $2.25 \times 10^{-9}$ | $\mathrm{m} / N$ |
| ua1 | Ua1 | Temperature coefficient of ua | $4.31 \times 10^{-9}$ | $\mathrm{m} / N$ |
| ub | Ub | Quadratic Vgs dependence of mobility | $5.87 \times 10^{-19}$ | $\mathrm{m}^{2} N^{2}$ |
| ub1 | Ub1 | Temperature coefficient of ub | $-7.61 \times 10^{-18}$ | $\mathrm{m}^{2} N^{2}$ |
| uc | Uc | Body-bias dependence of mobility | 0.0465 | $1 N$ |
| uc0 | Uc0 | Mobility coefficient | 0.0 | $\mathrm{V}^{2} / \mathrm{m}^{2}$ |


| Parameter | Symbol | Description | Default | Units |
| :---: | :---: | :---: | :---: | :---: |
| uc1 | Uc1 | Temperature coefficient of uc | -0.056 | $1 N$ |
| u0 | $\mu 0$ | Low-field mobility at tnom | $\begin{aligned} & 670.0[\mathrm{n}] \\ & 250.0[\mathrm{p}] \end{aligned}$ | $\begin{aligned} & \mathrm{cm}^{2} N \cdot \mathrm{~s} \\ & (\geq 1) \\ & \mathrm{m}^{2} N \cdot \mathrm{~s} \\ & (<1) \end{aligned}$ |
| ute | $\mu t e$ | Temperature coefficient of mobility | -1.5 | - |
| voff | Voff | Threshold voltage offset | -0.11 | V |
| vfb | $V f b$ | Flat band voltage | -1.0 | V |
| dl \| Id | $D l$ | Channel length reduction | 0.0 | m |
| dw \| wd | Dw | Channel width reduction | 0.0 | m |
| Imlt | Lmlt | Length shrink factor | 1.0 | - |
| wmit | Wmlt | Width shrink factor | 1.0 | - |
| $\mathbf{x l \| d I} \mid$ Idel | Xl | Mask and etching length reduction factor | 0.0 | - |
| $\begin{aligned} & \text { xw }\|d w\| \\ & \text { wdel } \end{aligned}$ | $X w$ | Mask and etching width reduction factor | 0.0 | - |
| tnom \| tref | Tnom | Temperature | 25.0 | ${ }^{\circ} \mathrm{C}$ |
| cgso cgsom | Cgso | Gate/source overlap capacitance per unit channel width | 0.0 | F/m |
| cgdo cgdom | Cgdo | Gate/drain overlap capacitance per unit channel width | 0.0 | F/m |
| cgbo cgbom | Cgbo | Gate/bulk overlap capacitance per unit channel length | 0.0 | F/m |
| xpart | Xpart | Flag for channel charge partitioning | 0.0 | - |
| rdsw | Rdsw | Source/drain resistance per unit width | 0.0 | $\Omega \cdot \mu \mathrm{m}$ |
| rds0 | $R d s 0$ | Source/drain contact resistance | 0.0 | $\Omega$ |
| Idd | $L D D$ | Total source/drain LDD region length | 0.0 | m |
| eta | Eta | Effective drain voltage coefficient | 0.3 | - |
| eta0 | Eta0 | Subthreshold region DIBL coefficient | 0.08 | - |
| etab | Etab | Subthreshold region DIBL coefficient | -0.07 | $1 N$ |
| pclm | Pclm | Channel-length modulation effect coefficient | 1.3 | - |
| pdibl1 | Pdibll | DIBL effect coefficient 1 | 0.39 | - |
| pdibl2 | Pdibl2 | DIBL effect coefficient 2 | 0.0086 | - |
| pscbe1 | Pscbel | Substrate current body effect coefficient 1 | $4.24 \times 10^{8}$ | $\mathrm{V} / \mathrm{m}$ |
| pscbe2 | Pscbe2 | Substrate current body effect coefficient 2 | $1.0 \times 10^{-5}$ | $\mathrm{m} / N$ |
| pvag | Pvag | $V g$ dependence of Rout coefficient | 0.0 | - |

## Equations

For the complete equations describing the Level 47 model, refer to J. H. Huang, Z. H. Liu, M. C. Jeng, K. Hui, M. Chan, P. K. Ko, and C. Hu, BSIM3 Manual (Version 2.0). Berkeley, CA: University of California, 1994.).

## Drain Current

In the linear region:

$$
\begin{equation*}
I_{d s}=\frac{I_{d s \operatorname{lin} 0}}{1+\frac{R_{d s} I_{d s \operatorname{lin} 0}}{V_{d s}}} \tag{0.392}
\end{equation*}
$$

where

$$
\begin{equation*}
I_{d s l i n 0}=\mu_{e f f} C_{o x}\left(\frac{W}{L}\right)\left(\frac{1}{1+\frac{V_{d s}}{E_{s a t} L}}\right)\left(V_{g s t}-A_{b u l k} \frac{V_{d s}}{2}\right) V_{d s} \tag{0.393}
\end{equation*}
$$

In the saturation region:

$$
\begin{equation*}
I_{d s}=I_{d s a t}\left(1+\frac{V_{d s}-V_{d s a t}}{V_{A}}\right)\left(1+\frac{V_{d s}-V_{d s a t}}{V_{A S C B E}}\right) \tag{0.394}
\end{equation*}
$$

where

$$
\begin{equation*}
I_{d s a t}=W v_{s a t} C_{o x}\left(V_{g s t}-A_{b u l k} V_{d s a t}\right) \tag{0.395}
\end{equation*}
$$

In the subthreshold region:
If subthmod $=0$ :

$$
\begin{equation*}
I_{d s}=0 \tag{0.396}
\end{equation*}
$$

If subthmod $=1$ :

$$
\begin{equation*}
I_{d s}=\frac{I_{\text {limit }} I_{\text {exp }}}{I_{\text {limit }}+I_{\text {exp }}}\left(1-e^{-V_{d s} / V_{t m}}\right) \tag{0.397}
\end{equation*}
$$

where

$$
\begin{gather*}
I_{l i m i t}=\frac{9}{2} \mu_{0} C_{d e p}\left(\frac{W}{L}\right) V_{t m}^{2} \cdot e^{\left(\frac{\left(E_{t a 0}+E_{t a b} \cdot V_{b s}\right) \theta_{\text {dibl }} V_{d s}}{n V_{t m}}\right)}  \tag{0.398}\\
I_{\text {exp }}=\mu_{0} C_{d e p}\left(\frac{W}{L}\right) V_{t m}^{2} \cdot e^{\left(\frac{\left.V_{s s}-V_{t h}-V_{o f f}+\left(E_{t a 0}+E_{t a b} \cdot V_{b s}\right) \theta_{d i b l} V_{d s}\right)}{n V_{t m}}\right)} \tag{0.399}
\end{gather*}
$$

If subthmod $=2$ :

$$
\begin{equation*}
I_{d s}=I_{s 0}\left(1-e^{-V_{d s} / V_{t m}}\right) \cdot e^{\left(\frac{V_{g s t}-V_{o f f}+\left(E_{t a 0}+E_{t a b} \cdot V_{b s}\right) \theta_{d i b l} V_{d s}}{n V_{t m}}\right)} \tag{0.400}
\end{equation*}
$$

where

$$
\begin{equation*}
I_{s 0}=\mu_{0} \frac{W}{L} \sqrt{\frac{q \varepsilon_{s i} N_{p e a k}}{2 \phi_{s}}} \cdot V_{t m}^{2} \tag{0.401}
\end{equation*}
$$

In the transition region:

$$
\begin{equation*}
I_{d s}=(1-t)^{2} I_{d s l o w}+2(1-t) t I_{p}+t^{2} I_{d s h i g h} \tag{0.402}
\end{equation*}
$$

where

$$
\begin{align*}
& t=\left(\frac{V_{p}-V_{g s l o w}}{V_{g s l o w}-2 V_{p}+V_{g s h i g h}}\right) \times  \tag{0.403}\\
& \left(\sqrt{1+\frac{\left(V_{g s l o w}-2 V_{p}+V_{g s h i g h}\right)\left(V_{g s t}-V_{g s l o w}\right)}{\left(V_{p}-V_{g s l o w}\right)^{2}}}-1\right)
\end{align*}
$$

Variables for which equations are not given here are as follows.

| $V A$ | Early voltage |
| :--- | :--- |
| $V A S C B E$ | Early voltage due to substrate current-induced body effect |
| $\mu e f f$ | Effective mobility |
| Abulk | Bulk charge effect factor |
| Vdsat | Drain saturation voltage |

## MOSFET Level 57 (BSIM3SOI)

BSIMSOI is an international standard model for silicon-on-insulator (SOI) circuit design, adjunct to the BSIM3v3 framework.

## Parameters

.model name nmos $\mid$ pmos level=57 [parameters]
For standard model parameters and equations, refer to the Berkeley manuals BSIMSOI3p1.pdf and BSIMSOI3p2.pdf. Specific device instance statements and their parameters are shown in the following section.

## Syntax

General MOSFET device parameters (length, width, drain, source, etc.) are described in the device statement chapter under "MOSFET (m)" on page 174. In the case of device values which have corresponding model values, the device settings override the model settings.

Device instance parameters for the BSIMSOI MOSFET model are as follows:

| mname [ | ```t] model [L=l] [W=w] [P=p] [B=b] [T=t] [AD=ad] =ps] [NRS=nrs] [NRD=nrd] [NRB=nrb] [M=M] [IC=ds gs bs es ps initial voltages] [RTHO=rth0 c] [NSEG=nseg] [PDBCP=pdbcp] [PSBCP=psbcp] P=aebcp] [VBSUSR=vbsusr] [TNODEOUT] [SOIMOD=soimod] [FRBODY=frbody]``` |
| :---: | :---: |
| d | Drain node |
| g | Front gate node |
| s | Source node |
| e | Back gate or substrate node |
| p | Optional external body contact node |
| b | Optional internal body node |
| t | Optional temperature node |
| ad | Drain diffusion area |
| aebcp | Parasitic gate-to-body overlap area for body contact |
| agbcp | Parasitic perimeter length for body contact at drain side |
| as | Source diffusion area |
| bjtoff | Turn off BJT current if equal to 1 |
| cth0 | Thermal capacitance per unit width: <br> - if not specified, CTH0 is extracted from model card <br> - f specified, it will override the one in model card |
| frbody | Layout-dependent body resistance coefficient |



## SOI Modes

There are three modes in BSIMSOI, soimod $=0,1$ or 2 . BSIMPD ( $\operatorname{soimod}=0$ ) can be used to model the PD SOI device, where the body potential is independent of DVbi (VBS > DVbi). Therefore the calculation of DVbi is skipped in this mode. On the other hand, the ideal FD model (soimod $=2$ ) is for the FD device with body potential equal to DVbi. Hence the calculation of body current/charge, which is essential to the PD model, is skipped. For the unified SOI model (soimod = 1), however, both DVbi and body current/charge are calculated to capture the floating-body behavior exhibited in FD devices. This unified model covers both BSIMPD and the ideal FD model.

## Body and Temperature Nodes

There are three optional nodes, P, B and T nodes. Nodes P and B are used for body contact devices. If the TNODEOUT flag is not set, when you specify four nodes, this element is a four terminal device, i.e., floating body. If you specify five nodes, the fifth node represents the external body contact node $(\mathrm{P})$. There is a body resistance between the internal body node and the P node. In both these cases, an internal body node is created, but it is not accessible in the circuit deck. However, if you specify six nodes, the fifth node will represent the P node and the sixth node will represent the internal body node (B). This configuration is useful for distributed body resistance simulation.

If the TNODEOUT flag is set, the last node is interpreted as the temperature node. In this case, when you specify five nodes, it is a floating body. If you specify six nodes, it is a body-contacted case. Finally, if you specify seven nodes, it is a body-contacted case with an accessible internal body node. The temperature node is useful for thermal coupling simulation.

Note:
Table-based model analysis is not supported for BSIMSOI.

## MOSFET Level 100 (Penn State \& Philips PSP Model)

The PSP model is a new compact MOSFET model, which has been jointly developed by Philips Research and Penn State University, and is able to accurately model present-day and upcoming deepsubmicron bulk CMOS technologies.

The PSP model is a symmetrical, surface-potential-based model, giving an accurate physical description of the transition from weak to strong inversion. The PSP model includes an accurate description of all physical effects important for modern and future CMOS technologies, such as:
mobility reduction
bias-dependent series resistance
velocity saturation
conductance effects (CLM, DIBL, etc.)
lateral doping gradient effect
mechanical stress related to STI
gate leakage current
gate-induced drain leakage
gate depletion
quantum-mechanical effects bias-dependent overlap capacitances
In addition, it gives an accurate description of charges and currents and their first-order derivatives (transconductance, conductance, capacitances), but also of their higher-order derivatives. In other words, it gives an accurate description of MOSFET distortion behaviour, and as such the PSP model is suitable for digital, analog as well as RF circuit design.

The PSP model is fully documented in Penn State \& Philips PSP Model.
For further detailed information about the PSP model, please refer to the Philips Compact Model Webpage:
http://www.semiconductors.philips.com/Philips Models/high voltage/model40

## Parameters

The PSP model uses the following syntax.

```
.model name nmos|pmos level=100|1000 | model=modelname [parameters]
```

T-Spice includes support for PSP version 100.1 with both electrical and geometrical model parameterization.

The available modelname values for the PSP model selection are:

## Modelname

psp100 or psp100e (default)
psp1000 or psp100g

## Description

PSP model version 100.1, electrical

PSP model version 100.1, geometrical

## Additional MOSFET Parameters

This section describes additional parameters, including parasitics, used by the equations describing MOSFET levels 1-3 and BSIM (levels 1, 2, 3, 14, 28, 47, 49, 53, and 54).

## Parameters

| Parameter | Symbol | Description | Default | Units |
| :---: | :---: | :---: | :---: | :---: |
| acm | ACM | Source/drain area calculation method | 0 | - |
| cj \| cjm | Cj | Source/drain bottom junction capacitance | $\begin{aligned} & 5.7911 \times 10^{-4} \\ & {[\text { level 49] }} \\ & 5.0 \times 10^{-4} \\ & {[\text { else] }} \end{aligned}$ | $\mathrm{F} / \mathrm{m}^{2}$ |
| cjgate | Cj,gate | Zero-bias gate edge sidewall junction capacitance | 0.0 | F/m |
| cjsw \| cjw | Cjsw | Source/drain sidewall junction capacitance | 0.0 | F/m |
| expli | EXPLI | Current limit | $1.0 \times 10^{15}$ | A |
| hdif | Hdif | Length of heavily doped diffusion from contact to lightly doped region | 0.0 | m |
| is | Is | Bulk saturation current | $\begin{aligned} & 0.0 \text { [level 49] } \\ & 1.0 \times 10^{-14} \\ & \text { [else] } \end{aligned}$ | A |
| js \| ijs | $J_{S}$ | Source/drain junction reverse saturation current density | 0.0 | A/m ${ }^{2}$ |
| jsw \| jssw | Jsw | Source/drain sidewall junction reverse saturation current density | 0.0 | A/m |
| Id \|dlat latd | Ld | Lateral diffusion into channel from source/drain diffusion | $0.75 \cdot \mathbf{x j}$ | - |
| Idif | Ldif | Length of lightly doped diffusion adjacent to gate | 0.0 | m |
| Imax | Lmax | Maximum channel length | 0.0 | m |
| Imin | Lmin | Minimum channel length | 0.0 | m |
| meto | Meto | Fringing field factor for overlap capacitance calculation | 0.0 | m |
| mj \| mjo | Mj | Source/drain bottom junction capacitance grading coefficient | 0.5 | - |
| mjsw \| mjw | Mjsw | Source/drain sidewall junction capacitance grading coefficient | 0.33 | - |
| n | $N$ | Emission coefficient | 1.0 | - |


| Parameter | Symbol | Description | Default | Units |
| :---: | :---: | :---: | :---: | :---: |
| nds | $N d s$ | Reverse bias slope coefficient | 1.0 | - |
| pb \| $\mathbf{p j}$ | Pb | Source/drain junction built-in potential | 0.8 [level 49] <br> 1.0 [else] | V |
| pbsw <br> pjw \| php | Pbsw | Source/drain sidewall junction capacitance built-in potential | pb | V |
| prdt | Prdt | Drain resistance temperature coefficient | 0.0 | - |
| prst | Prst | Source resistance temperature coefficient | 0.0 | - |
| rd | $R d$ | Drain resistance (rsh override) | 0.0 | $\Omega$ |
| rdc | Rdc | Drain contact resistance | 0.0 | $\Omega$ |
| rs | Rs | Source resistance (rsh override) | 0.0 | $\Omega$ |
| rsc | Rsc | Source contact resistance | 0.0 | $\Omega$ |
| rsh \| rshm | Rsh | Source/drain sheet resistance | 0.0 | $\Omega \square$ |
| vnds | $V n, d s$ | Reverse diode current transition point | -1 | V |
| wmax | Wmax | Maximum channel width | 1.0 | m |
| wmin | Wmin | Minimum channel width | 0.0 | m |
| wmit | Wmlt | Width diffusion layer shrink reduction factor | 1.0 | - |
| xI | Xl | Difference between the drawn and the actual length | 0.0 | m |
| xIref | Xlref | Difference between physical and drawn reference channel length | 0.0 | m |
| xw | Xw | Difference between the drawn and the actual width | 0.0 | m |
| xwref | Xwref | Difference between physical and drawn reference channel width | 0.0 | m |

## Equations

## Parasitic Resistances

MOSFET parasitics are simulated as resistances in series with the source $\left(R_{S_{e f f}}\right)$ and drain $\left(R_{d_{e f f}}\right)$. How these resistances are computed depends on the area calculation method (acm) specified.
acm
rseff
rdeff

0,10

$$
\begin{array}{llll}
R_{s_{e f f}}=N_{r s} \cdot R_{s h}+R_{s c} & \text { if } N_{r s} \cdot R_{s h} \neq 0 & R_{d_{e f f}}=N_{r d} \cdot R_{s h}+R_{d c} & \text { if } N_{r d} \cdot R_{s h} \neq 0 \\
R_{s_{e f f}}=R_{s}+R_{s c} & \text { otherwise } & R_{d_{e f f}}=R_{s}+R_{d c} & \text { otherwise }
\end{array}
$$

1, 11

$$
R_{s_{e f f}}=\frac{\left(L_{d}+L_{d i f}\right) \cdot R_{s}}{W_{e f f}}+N_{r s} \cdot R_{s h}+R_{s c} \quad R_{d_{e f f}}=\frac{\left(L_{d}+L_{d i f}\right) \cdot R_{d}}{W_{e f f}}+N_{r d} \cdot R_{s h}+R_{d c}
$$

2, 3, 12, 13
If $N_{r s}$ is specified:
If $N_{r d}$ is specified:

$$
R_{s_{e f f}}=\frac{\left(L_{d}+L_{d i f}\right) \cdot R_{s}}{W_{e f f}}+N_{r s} \cdot R_{s h}+R_{s c} \quad R_{d_{e f f}}=\frac{\left(L_{d}+L_{d i f}\right) \cdot R_{d}}{W_{e f f}}+N_{r d} \cdot R_{s h}+R_{d c}
$$

Otherwise:
Otherwise:

$$
R_{s_{e f f}}=\frac{\left(L_{d}+L_{d i f}\right) \cdot R_{s}+R_{s h} \cdot H_{d i f_{e f f}}}{W_{e f f}} \quad R_{d_{e f f}}=\frac{\left(L_{d}+L_{d i f}\right) \cdot R_{d}+R_{s h} \cdot H_{d i f_{e f f}}}{W_{e f f}}
$$

## Parasitic Diodes

Parasitic diodes are added for each MOSFET that uses direct model evaluation, and for all MOSFETs if the mosparasitics option is on.

One diode is placed between the MOSFET's bulk and source terminals, and the other between the bulk and drain.

Diode characteristics are determined by the device parameters as, ad, pd, ps, and geo, as well as the model parameters acm, cj, cjsw, cjgate, js, jsw, is, $\mathbf{n}$, nds, vnds, and hdif. The quantity weff also plays a role in determining default values for source and drain areas and perimeters for some values of acm.

If the MOSFET bulk-source voltage vbs is positive (the bulk-source diode is forward biased), then the bulk-source DC current ibs is

$$
\begin{equation*}
\text { ibs }=\text { isatbs } \cdot \exp (\mathbf{v b s} /(\mathbf{n} \cdot \mathbf{v t})-1) \tag{0.404}
\end{equation*}
$$

where $\mathbf{v t}=k T / q$ (the thermal voltage), and isatbs is the saturation current:

$$
\begin{equation*}
\text { isatbs }=\text { js } \cdot \text { aseff }+j s w \cdot p s e f f \tag{0.405}
\end{equation*}
$$

aseff and pseff are described below.
If this computed value of isatbs is zero, then isatbs will be set to the is parameter value.
If the MOSFET bulk-drain voltage vds is positive (the bulk-drain diode is forward biased), then the bulk-drain DC current is

$$
\begin{equation*}
\mathbf{i b d}=\mathbf{i s a t b d} \cdot \exp (\mathbf{v b d} /(\mathbf{n} \cdot \mathbf{v t})-1) \tag{0.406}
\end{equation*}
$$

where isatbd is the saturation current:

$$
\begin{equation*}
\text { isatbd }=\text { js } \cdot \text { adeff }+ \text { jsw } \cdot \text { pdeff } \tag{0.407}
\end{equation*}
$$

adeff and pdeff are described below.
If this computed value of isatbd is zero, then isatbd will be set to the is parameter value.
The exponential function in both diodes is replaced by a linear extension when the current is larger than the value of expli. The linear extension is chosen such that the diode current function is continuously differentiable at the transition point where the diode current equals expli.

When a MOSFET parasitic diode with saturation current isat is reverse-biased with a negative voltage vdi, then its current idi behaves as follows.

If $0>\mathbf{v d i}>\mathbf{v n d s}$, then

$$
\begin{equation*}
\text { idi }=\text { isat } \cdot v d i \tag{0.408}
\end{equation*}
$$

If vdi < vnds, then

$$
\begin{equation*}
\text { idi }=\text { isat } \cdot(\mathbf{v n d s}+(\mathbf{v d i}-\mathbf{v n d s}) / \mathbf{n d s}) \tag{0.409}
\end{equation*}
$$

## Effective Areas and Perimeters

Effective source and drain areas and perimeters depend on the value of parameter acm (and, if acm $=3$, on parameter geo). The parameter names are:

```
aseff
Effective source area
Effective drain area
```

```
pseff
Effective source perimeter
pdeff
Effective drain perimeter
```

The values of geo are:

| 0 | Drain and source not shared by other devices (default) |
| :--- | :--- |
| 1 | Drain shared with another device |
| 2 | Source shared with another device |
| 3 | Drain and source shared with other devices |

The area and perimeter values are computed as follows. The first table lists the equations used when $\mathbf{a c m}=\mathbf{0}, \mathbf{1}, \mathbf{2}$, or $\mathbf{3}$. The second table lists equations for $\mathbf{a c m}=\mathbf{1 0}, \mathbf{1 1}, \mathbf{1 2}$, or $\mathbf{1 3}$. The parameter CALCACM can only be invoked when $\mathbf{a c m}=12$. The values of defas, defad, and moscap are specified with the .options command.

|  | acm=0 or 10 <br> with as | acm=0 <br> without as |  | acm=10 <br> without as |
| :---: | :---: | :---: | :---: | :---: |
| $A_{s_{\text {eff }}}$ | $A_{s} \cdot\left(W_{m l t}\right)^{2}$ | 1•w <br> defas | if moscap=1 otherwise | 0 |
| $A_{d_{e f f}}$ | $A_{d}\left(W_{m l t}\right)^{2}$ | l-w <br> defad | if moscap=1 otherwise | 0 |
| $P_{s_{e f f}}$ | $P_{s} \cdot W_{m l t}$ | $\begin{aligned} & 2 \cdot(l+w) \\ & 0 \end{aligned}$ | if moscap=1 otherwise | 0 |
| $P_{d_{e f f}}$ | $P_{d} \cdot W_{m l t}$ | $\begin{aligned} & 2 \cdot(l+w) \\ & 0 \end{aligned}$ | if moscap=1 otherwise | 0 |

For $\mathrm{acm}=1$ or 11:

|  | acm=1 or 11 <br> with as | acm=1 <br> without as | acm=11 <br> without as |
| :--- | :--- | :--- | :--- |
| $A_{s_{\text {eff }}}$ | $W_{\text {eff }} W_{m l t}$ | $W_{e f f} W_{m l t}$ | $W_{e f f} W_{m l t}$ |
| $A_{d_{\text {eff }}}$ | $W_{\text {eff }} W_{m l t}$ | $W_{e f f} W_{m l t}$ | $W_{\text {eff }} W_{m l t}$ |
| $P_{S_{\text {eff }}}$ | $\mathrm{W}_{\text {eff }}$ | $\mathrm{W}_{\text {eff }}$ | $\mathrm{W}_{\text {eff }}$ |
| $P_{d_{e f f}}$ | $\mathrm{~W}_{\text {eff }}$ | $\mathrm{W}_{\text {eff }}$ | $\mathrm{W}_{\text {eff }}$ |

For $\mathrm{acm}=2$ or 12:

|  | acm=2 or 12 <br> with as | acm=2 <br> without as | acm=12 <br> without as |  |
| :--- | :--- | :--- | :--- | :--- |
| $A_{s_{\text {eff }}}$ | $A_{s} \cdot\left(W_{m l t}\right)^{2}$ | $2 \cdot H_{d i f_{e f f}} \cdot W_{e f f}$ | $2 \cdot H_{d i f_{e f f}} \cdot W_{e f f}$ <br> 0 | if calcacm=1 <br> otherwise |


|  | acm=2 or 12 <br> with as | acm=2 <br> without as | acm=12 <br> without as |  |
| :---: | :---: | :---: | :---: | :---: |
| $A_{d_{e f f}}$ | $A_{d}\left(W_{m l t}\right)^{2}$ | $2 \cdot H_{d i f_{e f f}} \cdot W_{e f f}$ | $\begin{aligned} & 2 \cdot H_{d i f_{e f f}} \cdot W_{e f f} \\ & 0 \end{aligned}$ | if calcacm=1 otherwise |
| $P_{S_{e f f}}$ | $P_{s} \cdot W_{m l t}$ | $4 \cdot H_{d i f_{e f f}}+2 \cdot W_{e f f}$ | $\begin{aligned} & 4 \cdot H_{d i f_{e f f}}+2 \cdot W_{e f f} \\ & 0 \end{aligned}$ | if calcacm=1 otherwise |
| $P_{d_{e f f}}$ | $P_{d} \cdot W_{m l t}$ | $4 \cdot H_{d i f_{e f f}}+2 \cdot W_{e f f}$ | $\begin{aligned} & 4 \cdot H_{d i f_{e f f}}+2 \cdot W_{e f f} \\ & 0 \end{aligned}$ | if calcacm=1 otherwise |

For $\mathrm{acm}=3$ or 13:

|  | acm=3 or 13 with as | acm=3 <br> without as |  | acm=13 <br> without as |
| :---: | :---: | :---: | :---: | :---: |
| $A_{s_{\text {eff }}}$ | $A_{s} \cdot\left(W_{m l t}\right)^{2}$ | $\begin{aligned} & 2 \cdot H_{d i f_{e f t}} \cdot W_{e f f} \\ & H_{d i f_{e f f}} \cdot W_{e f f} \end{aligned}$ | if geo $=\mathbf{0}$ or $\mathbf{1}$ otherwise | 0 |
| $A_{d_{e f f}}$ | $A_{d}\left(W_{m l t}\right)^{2}$ | $\begin{aligned} & 2 \cdot H_{d i f_{e f t}} \cdot W_{e f f} \\ & H_{d i f_{e f f}} \cdot W_{e f f} \end{aligned}$ | if $\mathbf{g e o}=0$ or 1 otherwise | 0 |
| $P_{s_{e f f}}$ | $P_{s} \cdot W_{m l t}$ | $\begin{aligned} & 4 \cdot H_{d i f_{e f f}}+W_{e f f} \\ & 2 \cdot H_{d i f_{e f f}}+W_{e f f} \end{aligned}$ | if geo=0 or 1 otherwise | 0 |
| $P_{d_{e f f}}$ | $P_{d} \cdot W_{m l t}$ | $\begin{aligned} & 4 \cdot H_{d i f_{e f f}}+W_{e f f} \\ & 2 \cdot H_{d i f_{e f f}}+W_{e f f} \end{aligned}$ | if geo=0 or 1 otherwise | 0 |

## Resistor

## Parameters

| Parameter | Description | Default | Units |
| :---: | :---: | :---: | :---: |
| bulk | Name of the node used as the bulk node for capacitance. | Gnd |  |
| cap | Default capacitance. | 0 | F |
| capsw | Sidewall fringing capacitance. | 0 | F/m |
| cratio | Specifies how capacitance is distributed between input and output nodes. The capacitor between node1 and the bulk node has the value cratio $\times$ Ceff, while the capacitor between node 2 and the bulk node has the value (1-cratio) $\times$ Ceff. Ceff is the effective capacitance as described below. | 0.5 |  |
| cox | Bottomwall capacitance. | 0 | F/m |
| di | Relative dielectric constant. | 0 |  |
| dir | Difference between the drawn resistor length and its actual length. Multiplied by .options scalm. For further information, see ".options" (page 106). | 0 | m |
| dw | Difference between the drawn resistor width and its actual width. Multiplied by .options scalm. For further information, see ".options" (page 106). | 0 | m |
| I | Default length. Multiplied by shrink and .options scalm to obtain the scaled length. For further information, see ".options" (page 106). | 0 | m |
| level | Model selector-not used. |  |  |
| noise | Default noise multiplier. | 1 |  |
| rac | Default AC resistance. | DC resistance | Ohm |
| res | Default resistance. | 0 | Ohm |
| rsh | Sheet resistance per square. | 0 |  |
| shrink | Shrink factor. | 1 |  |
| tc1c | First-order temperature coefficient for capacitance. | 0 | $d e g^{-1}$ |
| tc2c | Second-order temperature coefficient for capacitance. | 0 | $d e g^{-2}$ |
| tc1r | First-order temperature coefficient for resistance. | 0 | $d e g^{-1}$ |


| Parameter | Description | Default | Units |
| :--- | :--- | :--- | :--- |
| tc2r | Second-order temperature coefficient for <br> resistance. | 0 | $\mathrm{deg}^{-2}$ |
| thick | Dielectric thickness. | 0 | m |
| tnom \| tref | Reference temperature for temperature <br> compensation. | global tnom <br> $(25.0)$ | deg |
| w | Default width. Multiplied by shrink and <br> .options scalm to obtain the scaled width. For <br> further information, see ".options" (page 106). | 0 | m |
|  |  |  |  |

## Large-Signal Model



## Equations

## Resistance

Effective length is calculated as

$$
\begin{equation*}
L_{e f f}=L_{\text {scaled }}-(2 \cdot d l r \cdot \text { scalm }) \tag{0.410}
\end{equation*}
$$

Effective width is calculated as

$$
\begin{equation*}
W_{\text {eff }}=W_{\text {scaled }}-(2 \cdot d w \cdot \text { scalm }) \tag{0.411}
\end{equation*}
$$

If element resistance is specified, the effective resistance is

$$
\begin{equation*}
R_{e f f}=\text { resis } \tan c e \times \text { devscale } \tag{0.412}
\end{equation*}
$$

Otherwise, if $W_{e f f} \cdot L_{e f f} \cdot r s h=0$, then $R_{e f f}=r e s \cdot d e v s c a l e$.
Or if $W_{e f f} \cdot L_{e f f} \cdot r s h \neq 0$, then $R_{e f f}=L_{e f f} \cdot r s h \cdot($ devscale $) / W_{e f f}$.
In AC analysis, the device's resistance is

$$
\begin{equation*}
R A C_{e f f}=\text { acres } \cdot \text { devscale } \tag{0.413}
\end{equation*}
$$

if acres is given.

$$
\begin{equation*}
R A C_{e f f}=r a c \cdot d e v s c a l e \tag{0.414}
\end{equation*}
$$

if acres is not given and model parameter rac is given.

$$
\begin{equation*}
R A C_{e f f}=R_{e f f} \tag{0.415}
\end{equation*}
$$

if neither acres nor rac is given.

Note:

$$
\begin{equation*}
L_{e f f}=L_{\text {scaled }}-(2 \cdot d l r \cdot \text { scalm }) \tag{0.416}
\end{equation*}
$$

Effective width is calculated as

$$
\begin{equation*}
W_{e f f}=W_{\text {scaled }}-(2 \cdot d w \cdot \text { scalm }) \tag{0.417}
\end{equation*}
$$

If element capacitance is specified, the effective capacitance is

$$
\begin{equation*}
C_{e f f}=c \times \text { devscale } \tag{0.418}
\end{equation*}
$$

If cap is the only model parameter specified

$$
\begin{equation*}
C_{e f f}=c a p \cdot \text { devscale } \tag{0.419}
\end{equation*}
$$

Otherwise,

$$
\begin{equation*}
C_{e f f}=\text { devscale } \cdot\left(\text { Leff } \cdot \text { Weff } \cdot \operatorname{cox}+2\left(L_{e f f}+W_{e f f}\right) \times \text { capsw }\right) \tag{0.420}
\end{equation*}
$$

If cox is not specified, it is computed in one of two ways.

$$
\begin{align*}
& \text { If di is specified: } \operatorname{cox}=d i \cdot \frac{8.8542149 \cdot 10^{-12}}{\text { thick }}  \tag{0.421}\\
& \text { If If di is not specified: } \operatorname{cox}=\frac{3.453148 \cdot 10^{-11}}{\text { thick }} \tag{0.422}
\end{align*}
$$

## Note:

## Switch

A current- or voltage-controlled switch.
Syntax

| Name | Model | Description | Default | Unit |
| :---: | :---: | :---: | :---: | :---: |
| $v t$ | sw | Threshold voltage | 0 | V |
| it | csw | Threshold current | 0 | A |
| $v h$ | sw | Hysteresis voltage | 0 | V |
| ih | csw | Hysteresis current | 0 | A |
| ron | sw, csw | ON resistance | 1 | Ohm |
| roff | sw, csw | OFF resistance | 1 e 12 | Ohm |
| $d v$ | SW | Threshold transition width | 0.01 | V |
| di | csw | Threshold transition width | $1 \mathrm{e}-8$ | A |
| hdt | sw, csw | Threshold transition time | $1 \mathrm{e}-10$ | S |

The T-Spice switch is essentially a controlled resistor. The resistance is ron when the switch is on, and roff when the switch is off. The switch changes state between on and off when the controlling voltage or current is at its threshold value.

The following figure shows the resistance of the switch as a function of the controlling variable:


The T-Spice switch elements can display hysteresis, so that the threshold value is different when the control voltage/current is increasing than when it is decreasing. For a voltage-controlled switch, the threshold voltage is $\boldsymbol{v} \boldsymbol{t}$ when v (controll, control2) is increasing, and $\boldsymbol{v} \boldsymbol{t}$ - $\boldsymbol{v} \boldsymbol{h}$ when v (controll, control2) is decreasing. For a current-controlled switch, the threshold current is it when i (vsource_name) is increasing, and it-ih when i (vsource_name) is decreasing. The switch is on when the control voltage or current is greater than the threshold value.

The $\boldsymbol{d} \boldsymbol{v}$ and $\boldsymbol{d i}$ parameters define a small interval around the threshold in which a smooth transition between ron and roff is made.

## Examples

The following example creates a voltage-controlled switch:
.model swmod sw vt=0.7 dv=0.1

The following example creates a current-controlled switch:

```
.model swmod csw it=0.7 di=0.1
```


## Transmission Line

T-Spice supports two transmission line models:

- Lossless line, defined by characteristic impedance and delay. This model is described by Branin 1967.
- Lossy line, defined by RLCG parameters. This model is described here.


## Equations

The lossy transmission line is modeled with equivalent circuits consisting of cascaded cells or lumps, typically comprising discrete resistors, inductors, and capacitors. Lumps essentially discretize the transmission line wave equations over the length of the line. Distributed RLCG values are converted to non-distributed (lumped element) values:

$$
\begin{align*}
& \text { Rlump }=R \cdot l / n  \tag{0.423}\\
& \text { Llump }=L \cdot l / n  \tag{0.424}\\
& \text { Clump }=C \cdot l / n  \tag{0.425}\\
& \text { Glump }=G \cdot l / n \tag{0.426}
\end{align*}
$$

where $l$ is the physical length of the transmission line and $n$ is the number of lumps.

Typically, many lumps are needed to model a transmission line accurately. The number of lumps is specified by the lumps parameter on the device statement. A cascade ladder network-the iterative ladder circuit-is constructed with the specified number of lumps.


The "gamma" lump type is the most common implementation.


The "tee" lump type is a symmetrical alternative that includes an additional series resistance and inductance per lump.


The "pi" lump type is formed by adding identical shunt elements at the input and output of each lump.


Low-loss transmission lines need not be modeled with RLCG lumps. An alternative approach is to use lossless transmission line sections separated by lumped resistances and conductances. The "hybrid RGT" lump type consists of an ideal transmission line section with series resistances and shunt conductances at input and output. This equivalent circuit defaults to the lossless transmission line when $R$ and $G$ values are zero, and is therefore the default lumptype option.


## Introduction

## Small-Signal Models

The linear small-signal models for diodes, BJTs, JFETs, MESFETs, and MOSFETs described in this chapter are derived from T-Spice's nonlinear device representations.

Instead of using simplified equations to compute the small-signal model parameters, which can introduce errors at low and high frequencies, T-Spice generates linearized small-signal models directly from the device equations, with the most accurate small-signal results available.

Small-signal parameters are evaluated at the DC operating point. The currents and voltages appearing in the equations in this chapter are all DC values. In addition, the voltages are measured at the "intrinsic" terminals, inside the parasitic resistances connected to the external terminals.

Small-signal data are available with the ".acmodel" (page 63) command.

## Noise Models

The following parameters are used by many of T-Spice's noise models.

| Parameter | Symbol | Description | Default | Unit |
| :--- | :--- | :--- | :--- | :--- |
| noiselevel \| nlev | - | Noise equation selector <br> (JFET, MESFET, <br> MOSFET only) | 2 | - |
| gdsnoise \| gdsnoi | GDSn | Channel noise <br> coefficient (JFET, <br> MESFET, MOSFET <br> only) | 1.0 | - |
| af | $A f$ | Flicker noise exponent | 1.0 | - |
| kf | $K f$ | Flicker noise coefficient | 0.0 | - |

Noise models add RMS noise current sources to small signal models in order to simulate noise power densities (NPDs) in the device. The NPDs are calculated from model parameter values and DC operating point conditions.

For example, each of the resistors in a circuit, including the parasitic resistances in models, generates thermal noise, whose NPD is inversely proportional to the resistance:

$$
\begin{equation*}
\overline{\left|i_{t h}\right|^{2}}=\frac{4 k T}{R} \cdot \Delta f \tag{0.427}
\end{equation*}
$$

where $k$ is Boltzmann's constant, $T$ is the temperature in Kelvins, $R$ is the resistance, and $\Delta f$ is the width of the frequency band over which the noise is measured ( 1 Hz in T -Spice). The corresponding noise current source has a magnitude of $\sqrt{\left|i_{t h}\right|^{2}}$ and units of $A / \sqrt{H z}$, and is placed in parallel with the resistor.

The following sections show the NPD calculation for intrinsic noise sources in the models. These sources represent shot and/or flicker noise.

Shot noise is typically computed as

$$
\begin{equation*}
\overline{\left|i_{\text {shot }}\right|^{2}}=2 q\left|I_{x}\right| \cdot \Delta f \tag{0.428}
\end{equation*}
$$

where $q$ is the electron charge and $I x$ is the DC current into terminal $x$ at the operating point of the device.

Flicker noise is usually modeled by

$$
\begin{equation*}
\overline{\left|i_{\text {flicker }}\right|^{2}}=\frac{K_{f}\left|I_{x}\right|^{A_{f}}}{f} \cdot \Delta f \tag{0.429}
\end{equation*}
$$

where $f$ is the center frequency of the band over which the noise is being measured.
Where appropriate, alternate formulations for shot and flicker noise are presented for individual models.
 in the noise model.

## Diode

## Small-Signal Model



The conductance $g D$ is the partial derivative of the forward current $I D$ with respect to the voltage $V D$ across the intrinsic diode.

$$
\begin{equation*}
g_{D}=\left.\frac{\partial I_{D}}{\partial V_{D}}\right|_{\mathrm{op}} \tag{0.430}
\end{equation*}
$$

The small-signal capacitance $C D$ across the diode is

$$
\begin{equation*}
C_{D}=\left.\frac{\partial Q_{D}}{\partial V_{D}}\right|_{\mathrm{op}} \tag{0.431}
\end{equation*}
$$

$r D$ models the diode's linear parasitic resistance.
Noise Model

In addition to the thermal noise associated with $r D$, this model includes a PN junction noise source that includes shot and flicker noise:

$$
\begin{equation*}
\overline{\left|i_{A B_{n}}\right|^{2}}=2 q I_{A} \cdot \Delta f+\frac{K_{f}\left|I_{A}\right|^{A_{f}}}{f} \cdot \Delta f \tag{0.432}
\end{equation*}
$$

## BJT Level 1 (Gummel-Poon)

## Small-Signal Model



The bipolar conductances are denoted by $g m, g o, g_{\pi}$, and $g_{\mu}$.

$$
\begin{gather*}
g_{m}=\left.\frac{\partial I_{C}}{\partial V_{B E}}\right|_{\mathrm{op}}  \tag{0.433}\\
g_{o}=\frac{1}{r_{o}}=\left.\frac{\partial I_{C}}{\partial V_{C E}}\right|_{\mathrm{op}}  \tag{0.434}\\
g_{\pi}=\frac{1}{r_{\pi}}=\left.\frac{\partial I_{B}}{\partial V_{B E}}\right|_{\mathrm{op}}  \tag{0.435}\\
g_{\mu}=\frac{1}{r_{\mu}}=\left.\frac{\partial I_{B}}{\partial V_{B C}}\right|_{\mathrm{op}} \tag{0.436}
\end{gather*}
$$

The capacitances $C B E$ and $C B C$ are denoted by $C_{\pi}$ and $C_{\mu}$ respectively.

$$
\begin{align*}
& C_{\pi}=\left.\frac{\partial Q_{B}}{\partial V_{B E}}\right|_{\mathrm{op}}  \tag{0.437}\\
& C_{\mu}=\left.\frac{\partial Q_{B}}{\partial V_{B C}}\right|_{\mathrm{op}} \tag{0.438}
\end{align*}
$$

Other parameters computed are the transistor gain at DC operating point $\beta D C$, the AC signal gain $\beta A C$, and the gain-band-width product $f T$.

$$
\begin{gather*}
\beta_{D C}=\left.\frac{I_{C}}{I_{B}}\right|_{\mathrm{op}}  \tag{0.439}\\
\beta_{A C}=\left.\frac{\partial I_{C}}{\partial I_{B}}\right|_{\mathrm{op}}=g_{m} r_{\pi}  \tag{0.440}\\
f_{T}=\left.\frac{g_{m}}{2 \pi\left(C_{\pi}+C_{\mu}\right)}\right|_{\mathrm{op}} \tag{0.441}
\end{gather*}
$$

## Gummel-Poon Noise Model

T-Spice uses the equations in this section to simulate thermal, shot, and flicker noise power densities in the BJT Gummel-Poon device model.

## Thermal Noise

T-Spice uses the following equations to calculate thermal noise power density ( $n d_{t h e r m}$ ) of the base resistor $\left(r_{b}\right)$, collector resistor $\left(r_{c}\right)$, and emitter resistor $\left(r_{e}\right)$ noise currents, respectively:

$$
\begin{align*}
n d_{\text {therm }}\left(r_{b}\right) & =\frac{4 k T}{r_{b b}} \\
n d_{\text {therm }}\left(r_{c}\right) & =\frac{4 k T}{r_{c_{e f f}}},  \tag{0.442}\\
n d_{\text {therm }}\left(r_{e}\right) & =\frac{4 k T}{r_{e_{e f f}}}
\end{align*}
$$

where $k$ is Boltzmann's constant, $T$ is temperature, and $r_{b b}, r_{c e f f}$, and $r_{e e f f}$ are the effective base, collector, and emitter resistances.

## Shot Noise

The following equations give the shot noise density $\left(n d_{s h o t}\right)$ of the base current $\left(I_{b}\right)$ and collector current $\left(I_{c}\right)$, respectively:

$$
\begin{align*}
& n d_{\text {shot }}\left(I_{b}\right)=2 q I_{b} \\
& n d_{\text {shot }}\left(I_{c}\right)=2 q I_{c} \tag{0.443}
\end{align*}
$$

where $q$ is the elementary electron charge.

## Flicker Noise

The flicker noise density $\left(n d_{f l i c k}\right)$ of the base current $\left(I_{b}\right)$ is:

$$
\begin{equation*}
n d_{f l i c k}\left(I_{b}\right)=\frac{K F \cdot\left(I_{b}\right)^{A F}}{f}, \tag{0.444}
\end{equation*}
$$

where $f$ represents frequency.

## JFET/MESFET

## Small-Signal Model



The transconductance is denoted by $g m$ and the output conductance by $g D S$.

$$
\begin{align*}
& g_{m}=\left.\frac{\partial I_{D}}{\partial V_{G S}}\right|_{\mathrm{op}}  \tag{0.445}\\
& g_{D S}=\left.\frac{\partial I_{D}}{\partial V_{D S}}\right|_{\mathrm{op}} \tag{0.446}
\end{align*}
$$

The gate junction conductances are denoted by $g G S$ and $g G D$. These are usually very small, since the junctions are reverse-biased in normal operation.

$$
\begin{align*}
& g_{G S}=\left.\frac{\partial I_{G S}}{\partial V_{G S}}\right|_{\mathrm{op}}  \tag{0.447}\\
& g_{G D}=\left.\frac{\partial I_{G D}}{\partial V_{G D}}\right|_{\mathrm{op}} \tag{0.448}
\end{align*}
$$

The gate junction capacitances are denoted by $C G S$ and $C G D$.

$$
\begin{gather*}
C_{G S}=\left.\frac{\partial Q_{G}}{\partial V_{G S}}\right|_{\mathrm{op}}  \tag{0.449}\\
C_{G D}=\left.\frac{\partial Q_{G}}{\partial V_{G D}}\right|_{\mathrm{op}} \tag{0.450}
\end{gather*}
$$

$r D$ and $r S$ are constant linear resistances.

## Noise Model

In addition to the thermal noise associated with $r D, r S$, and $r G$, this model includes the intrinsic noise source

$$
\begin{equation*}
\overline{\left|i_{D S_{n}}\right|^{2}}=\overline{\left|i_{c h}\right|^{2}}+\frac{K_{f}\left|I_{D}\right|^{A_{f}}}{f} \cdot \Delta f \tag{0.451}
\end{equation*}
$$

where $I D$ is the DC operating point drain current.
Channel noise is modeled in two ways, depending on the parameter noiselevel. When noiselevel < 3,

$$
\begin{equation*}
\overline{\left|i_{c h}\right|^{2}}=\frac{8}{3} k T g_{m} \cdot \Delta f \tag{0.452}
\end{equation*}
$$

When noiselevel $=3$,

$$
\begin{equation*}
\overline{\left|i_{c h}\right|^{2}}=\frac{8}{3} k T \beta \cdot\left(V_{G S}-V_{t 0}\right) \cdot G_{D S_{n}} \cdot\left(\frac{1+\alpha+\alpha^{2}}{1+\alpha}\right) \cdot \Delta f \tag{0.453}
\end{equation*}
$$

where $k$ is Boltzmann's constant, $T$ is the current temperature in Kelvins, $g m$ is the transconductance, $\beta$ is the gain at the operating point, and

$$
\alpha= \begin{cases}1-\frac{V_{D S}}{V_{G S}-V_{t 0}} & \text { (linear region) }  \tag{0.454}\\ 0 & \text { (saturation region) }\end{cases}
$$

## MOSFET

## Small-Signal Model



The MOSFET conductances are denoted by $g m, g D S$, and $g m b s$.

$$
\begin{align*}
& g_{m}=\left.\frac{\partial I_{D S}}{\partial V_{G S}}\right|_{\mathrm{op}}  \tag{0.455}\\
& g_{D S}=\left.\frac{\partial I_{D S}}{\partial V_{D S}}\right|_{\mathrm{op}}  \tag{0.456}\\
& g_{m b s}=\left.\frac{\partial I_{D S}}{\partial V_{B S}}\right|_{\mathrm{op}} \tag{0.457}
\end{align*}
$$

The gate junction conductances are denoted by $g B D$ and $g B S$. These are usually very small, since the junctions are reverse-biased in normal operation.

$$
\begin{gather*}
g_{B D}=\left.\frac{\partial I_{B D}}{\partial V_{B D}}\right|_{\mathrm{op}}  \tag{0.458}\\
g_{B S}=\left.\frac{\partial I_{B S}}{\partial V_{B S}}\right|_{\mathrm{op}} \tag{0.459}
\end{gather*}
$$

The bulk junction capacitances are denoted by $C B S$ and $C B D$.

$$
\begin{align*}
C_{B D} & =\left.\frac{\partial Q_{B}}{\partial V_{B D}}\right|_{\mathrm{op}}  \tag{0.460}\\
C_{B S} & =\left.\frac{\partial Q_{B}}{\partial V_{B S}}\right|_{\mathrm{op}} \tag{0.461}
\end{align*}
$$

The gate-to-junction and gate-to-bulk capacitances are denoted by $C G S, C G D$, and $C G B$.

$$
\begin{align*}
& C_{G S}=\left.\frac{\partial Q_{G}}{\partial V_{G S}}\right|_{\mathrm{op}}  \tag{0.462}\\
& C_{G D}=\left.\frac{\partial Q_{G}}{\partial V_{G D}}\right|_{\mathrm{op}}  \tag{0.463}\\
& C_{G B}=\left.\frac{\partial Q_{G}}{\partial V_{G B}}\right|_{\mathrm{op}} \tag{0.464}
\end{align*}
$$

Since these parameters are computed directly from the MOSFET equations, the model is valid for lowand high-frequency simulations.

## Noise Model

In addition to the thermal noise associated with $r D$ and $r S$, this model includes channel and flicker noise sources.

$$
\begin{equation*}
\overline{\left|i_{D S_{n}}\right|^{2}}=\overline{\left|i_{c h}\right|^{2}}+\overline{\left|i_{\text {flicker }}\right|^{2}} \tag{0.465}
\end{equation*}
$$

Channel noise is modeled in two ways, depending on the parameter noiselevel. When noiselevel < 3,

$$
\begin{equation*}
\overline{\left|i_{c h}\right|^{2}}=\frac{8}{3} k T g_{m} \cdot \Delta f \tag{0.466}
\end{equation*}
$$

When noiselevel $=3$,

$$
\begin{equation*}
\overline{\left|i_{c h}\right|^{2}}=\frac{8}{3} k T \beta \cdot\left(V_{G S}-V_{t h}\right) \cdot G_{D S_{n}} \cdot\left(\frac{1+\alpha+\alpha^{2}}{1+\alpha}\right) \cdot \Delta f \tag{0.467}
\end{equation*}
$$

where $\beta$ is the gain at the operating point and

$$
\alpha= \begin{cases}1-\frac{V_{D S}}{V_{D s a t}} & \text { (linear region) }  \tag{0.468}\\ 0 & \text { (saturation region) }\end{cases}
$$

Flicker noise is modeled in three ways, depending on noiselevel. When noiselevel $=0$,

$$
\begin{equation*}
\overline{\left|i_{\text {flicker }}\right|^{2}}=\frac{K_{f} \cdot\left(i_{D S}\right)^{A_{f}}}{C_{o x} L_{e f f f}^{2} f} \cdot \Delta f \tag{0.469}
\end{equation*}
$$

When noiselevel $=1$,

$$
\begin{equation*}
\overline{\left|i_{f l i c k e r}\right|^{2}}=\frac{K_{f} \cdot\left(i_{D S}\right)^{A_{f}}}{f C_{o x} L_{e f f} W_{e f f}} \cdot \Delta f \tag{0.470}
\end{equation*}
$$

When noiselevel $=2$ or noiselevel $=3$,

$$
\begin{equation*}
\overline{\left|i_{\text {ficker }}\right|^{2}}=\frac{K_{f} \cdot g_{m}^{2}}{f^{A^{f} C_{o x} L_{e f f} W_{e f f}}} \cdot \Delta f \tag{0.471}
\end{equation*}
$$

## References

L. W. Nagel, SPICE2: A Computer Program to Simulate Semiconductor Circuits. Electronics Research Laboratory Memorandum ERL-M520. Berkeley, CA: University of California, 1975.
P. Antognetti and G. Massobrio (eds.), Semiconductor Device Modeling with SPICE, 2nd ed. New York: McGraw-Hill, 1993.
Y. P. Tsivids, Operation and Modeling of the MOS Transistor. New York: McGraw-Hill, 1987.

## Introduction

The devices that are components of circuits simulated by T-Spice are described by device models. In essence, models are mathematical functions that evaluate a device's terminal currents and charges, given its terminal voltages (and in some cases other state variables).

While many "hard-coded" models are included with T-Spice, representing a wide range of devices commonly used in circuit design, the need may arise for special models not already available. Such models may represent improvements over existing models for standard devices (such as transistors), or they may describe devices not included in T-Spice (such as mechanical devices used by MEMS designers, or macro-devices to be described in a behavioral way).

The user-defined external model feature allows users to code custom-designed device models using C or C++. The code can be compiled into DLLs (Windows) or shared objects (Unix) and then dynamically linked to T-Spice simulations. Alternatively, the raw code can be interpreted by T-Spice during simulation, eliminating the compilation step with faster turnaround time for writing and debugging, at the expense of slower performance.

## Creating External Models

## Templates

T-Spice simulates user-defined external models with information from either of two sources:

- DLL (dynamically linked library) or shared object files, generated before T-Spice is run by compiling C program files. (See "Compiling External Models" on page 483.)
- Uncompiled C program files, interpreted by T-Spice at runtime.

The original C code must be written in any case. A basic framework for this code can be found in the file template.c. This file contains comment lines describing the functions and actions required of the code for a typical external model.

The heart of the code is the ExternalModelMain() function. This function is called whenever information about the external model is required during simulation-both for initializing and instancing a model and for evaluating devices that are instances of the model. (See "Initializing the Definition" on page 485 and "Instancing a Device" on page 485.)

ExternalModelMain() typically consists of a call to the GetModelInfo() function-to specify the device and/or model and the information required-and a switch(action) statement-to call other functions based on the value of action (see "External Model Actions" on page 491).

## Examples

Five example external models are provided. Each example consists of three commented files: a C program (.c) file, a DLL (.dII) file, and a T-Spice input (.sp) file illustrating the use of the model (see "Using External Models" on page 484).

## Model description

diode
mos1
resist
switch
vco

A model incorporating most of the features of the standard SPICE diode model, with parameters analogous to those of T-Spice's internal diode model.

An implementation of the level 1 MOSFET model, with parasitic diodes and resistors, noise models, and support for table-based calculation.

A simple linear resistor model.
A switch model implemented as a voltage-controlled resistor with a hysteresis loop. This model is an extension of the SPICE3 voltagecontrolled switch.

A voltage-controlled oscillator (VCO) model.

## Compiling External Models

To be used in DLL or shared object form, external models must be compiled from the original C code.
The (required) C compiler and (provided) make file, make script, and object file names for each supported platform are as follows.

| Platform | Compiler | Make file | Make script | Object file |
| :--- | :--- | :--- | :--- | :--- |
| Windows | Visual C++4.0 or <br> later | model.mak | makemodl.bat | tspmodel.lib |
| Solaris | gcc | Makefile | makemodel_sol | tspmodel_sol.o |

Example files and instructions for these platforms are also provided.
To compile from a DOS command line, you must first configure your DOS environment for Microsoft Visual C++. Visual C++ includes a batch file that you can execute from autoexec.bat. This will establish the environment variables needed to run the C tools from the DOS command prompt. Generally, you can set up this environment by adding the following line to your autoexec.bat file:

C: \Progra~1\Micros~1\VC98\Bin\vcvars32.bat
To compile from the command line (Unix or DOS), type the following at the prompt:
script model
where script is the name of the appropriate make script (e.g., mademodel.bat on Windows) and model is the base name of the C file that contains the external model (for example, resistor for a model contained in resistor.c).

## Using Microsoft Developer

To compile an external model using Microsoft Visual C++ Developer:

- With Visual C++ Developer launched, use the File > New command to create a new project: in the dialog, select Projects. Select Win32 Dynamic Link Library. Give the project a name and choose a location: use the file browser to navigate to the directory if it already exists; if not, then a new directory will be created. Click OK.
- When asked What kind of DLL would you like to create?, choose An empty DLL project. Click Finish. When the New Project Information dialog displays, click OK.
- Use the File > New command to create a program file: in the dialog, select C++ Source File. Choose a file name and click OK.

Note:
The file name you choose must be either a C file (*.c) or a C++ file (*.cpp). If you choose a C++ file, you will have to wrap all T-Spice interface declarations with extern "C"\{...\}.

- Copy the text of program template.c and paste it into the editing space. Save the file.
- Use the Tools > Options command to add search paths to the T-Spice external C header and library files: in the dialog, click the Directories tab.
- In the Show directories for pull-down menu, select Include files. In the Directories: list, enter the fully qualified path to the extmod $\backslash$ win32 directory. (If you used the default installation of T-Spice Pro, this will be C:\Tanner\TSpice70lextmod\win32.)
- In the Show directories for pull-down menu, select Library files. In the Directories: list, enter the same path as in the previous step.
- Use the Project > Settings command and perform the following actions:
- Set Settings for to All Configurations.
- Click the Debug tab. In the field Executable for debug session, enter the fully qualified path to tspice.exe. (C:ITanner\TSpice91\tspice.exe by default.)
- In the Working directory field, enter the path to your T-Spice netlist.
- In the Program arguments field, enter the name of your T-Spice netlist. You can now compile and debug your external C model.
- Click the C/C++ tab. From the Category pull-down menu, select Code Generation. Set processor to Blend. Set Calling convention to __cdecl. Set Struct member alignment to 8 bytes.
- From the Category pull-down menu, select Preprocessor. Add MAKE_DLL to the Preprocessor definitions list. Set Setting for to both the Win32 Debug and Win32 Release versions.
- Click the Link tab. Make sure that Object/library modules includes tspmodel.lib.
- Click OK.
- Use the Build >project.dIl command to compile the DLL.


## Using External Models

After a user-defined external model has been created and compiled (if it is to be used in DLL or shared object form), it can be used in a simulation. This involves two procedures: initializing the model definition and instancing a device using the model.

## Initializing the Definition

An external model definition is initialized from within a T-Spice input file by means of the ".model" (page 96) command with the external keyword:
.model name external ([parameter=value [...]])
name is the string by which the model will be identified in the input file.
Within the parentheses, predefined parameters are assigned values (as many as necessary) to tune the model's characteristics. Values may be numbers or strings; string values are enclosed in double quotes. Parameter/value pairs are separated by spaces, and are passed to the external model as model parameters.

One of the parameter assignments must indicate the name of the file containing the model code (in either raw or compiled form). The name of this parameter depends on the platform:

## Platform

## Parameter

| Windows | winfile |
| :--- | :--- |
| Solaris | solfile |

The value of this parameter is the name of the file containing the model code. T-Spice will attempt to interpret (that is, treat as raw C code) any file whose name has a .c extension. Any other file will be assumed to be already compiled. Compiled files (DLLs or shared objects) typically have extension .dII or .sl.

## Instancing a Device

An actual instance of a device using an external model is created within a T-Spice input file using the "Instance (x)" (page 170) statement, in the same way that subcircuit instances are created:

```
xname nodel [node2 [...]]] modelname [parameter=value [parameter=value
    [...]]]
```

Here, modelname must match the modelname specified by the corresponding ".model" (page 96) command. Because the $\mathbf{x}$ key letter is also used for subcircuit instances, modelname should not conflict with any subcircuit definition name.

As with model initialization, parameters can be assigned values to tune the instantiated device's characteristics. Values may be numbers or strings; string values are enclosed in double quotes. Parameter/value pairs are separated by spaces, and are passed to the external model as device parameters.

When interpreted (C) files are used, a path must be set to the directory containing the header files. This is done in either of two ways:

- At the operating system level, set the environment variable LUPI_INCLUDE to the appropriate path.
- Include the following command in the input file: ".options" (page 106) cpath=path, where path is the appropriate path.


## External Model Features

Simple external models may only require the "EVALUATE_DEVICE" (page 496) and "EVALUATE_DERIVATIVES" (page 497) actions. More complex models may need to take advantage of advanced features, a number of which are described in this section:

- "User-Defined Model and Device Parameters," below
- "Error Handling" on page 486
- "Automatic Model Selection" on page 487
- "Parasitic Effects and Internal Nodes" on page 487
" "Tables" on page 488
- "Noise Analysis" on page 489
- "Current-Controlled Devices" on page 489
" "Voltage Sources" on page 490


## User-Defined Model and Device Parameters

When T-Spice parses a ".model" (page 96) command of type external, or a device statement instancing an external model, the model and device parameter names and values are stored for later interpretation.

The model's "PARSE_MODEL_PARAMETERS" (page 492) and "PRECOMPUTE_DEVICE_PARAMETERS" (page 494) actions may use the LookupParameter functions to find specific parameter names and their associated values. These are then typically stored in a model-specific structure.

For example, a resistor model may contain the following type declaration:

```
typedef struct ResistorDevice
{
    double resistance;
    double mult;
} ResistorDevice;
```

The code for the "PRECOMPUTE_DEVICE_PARAMETERS" (page 494) action might be as follows:

```
ResistorDevice *r;
TspBoolean pf;
r = (ResistorDevice *)malloc(sizeof(ResistorDevice));
device->info = (void *)r;
r->resistance = LookupParameterDouble(device->parameter_list, "r|res",
    "O.0", &pf);
r->mult = LookupParameterDouble(device->parameter_list, "m", "1.0", &pf);
```

No error handling is performed in this code: if malloc() returns NULL, then disaster follows.

## Error Handling

If an error occurs in the user-defined model code, T-Spice must be informed of this so that the simulation can be stopped. This is done by setting the error field in the ExternalModel or ExternalModelDevice structures to 1 . Whenever an external model action returns to T-Spice, those
error fields are checked, and the simulation is stopped if an error field is nonzero. For example, the following code might be inserted in the resistor example above, immediately below the call to malloc():

```
if (r==NULL)
{
    device->error = 1;
    return;
}
```


## Automatic Model Selection

T-Spice allows multiple ".model" (page 96) commands in one input file with the same model name and different extensions, such as nch.1, nch.2, etc., all of which match devices with the model name nch. The particular .model command actually used with a device is determined by the automatic model selector.

The automatic model selector compares certain device parameter values with model parameter values to determine which model matches the device. For example, T-Spice MOSFET model parameter sets can contain parameters wmin and wmax which specify a range of transistor widths over which the parameter set is valid. The automatic model selector selects a .model command for each device that ensures that the device width $\mathbf{w}$ falls within the model's width range.

The "MODEL_MATCHES_DEVICE" (page 493) action implements automatic model selection. This action is executed after the "PARSE_MODEL_PARAMETERS" (page 492) action, but before any device parameter parsing. It sets the model->model_matches_device flag to False if the model cannot be matched with the device.

If no model parameter set matches a device, then T-Spice exits with an error message. If multiple model parameters match, then T-Spice selects one of the matching sets.

The following example implements automatic model selection in the case of a MOSFET:

```
MosfetModel *m;
TspBoolean pf;
double w;
m = (MosfetModel *)model->info;
w = LookupParameterDouble(device->parameter_list, "w" , "0.0", &pf);
model->model_matches_device = True;
if (m->wmax_specified && pf)
    if (w > m->wmax)
                model->model_matches_device = False;
if (m->wmin_specified && pf)
    if (w < m->wmin)
                model->model_matches_device = False;
```


## Parasitic Effects and Internal Nodes

Many device models contain parasitic effects-effects that account for various phenomena inherent in the physical medium in which devices are used.

The "PARASITIC_SETUP" (page 495) action adds parasitic effects. Several predefined functions ("AddSeriesResistor()" (page 495), "AddParasiticDiode()" (page 495)) add simple standard parasitics. The "AddInternalNode()" (page 495) function adds custom parasitic elements by generating internal state variables. The "EVALUATE_DEVICE" (page 496) action adds the contributions of these elements.

For example, a $100 \Omega$ parasitic resistor could be added in series with terminal 0 of a device with the "AddSeriesResistor()" (page 495) function:

```
device->rs_id = AddSeriesResistor(device, 0, 100.0, "RS");
```

Alternatively, the "AddInternalNode()" (page 495) function could be used:

```
d->rs_terminal = AddInternalNode(device, "rs");
```

Using "AddSeriesResistor()" (page 495) is more convenient. However, "AddInternalNode()" (page 495) allows for the addition of arbitrary series parasitic devices.

In the case of the internal node method, the resistor's current would have to be accounted for by the "EVALUATE_DEVICE" (page 496) action as follows:

```
double irs = (device->voltage[0] - device->voltage[d->rs_terminal]) / 100.0;
device->current[0] += irs;
device->current[d->rs_terminal] -= irs;
```

In addition, the "EVALUATE_DERIVATIVES" (page 497) action would need to add the parasitic resistor's derivative (unless numerical derivatives were used):

```
device->current_deriv[0][0] += 1.0/100.0;
device->current_deriv[0][d->rs_terminal] -= 1.0/100.0;
device->current_deriv[d->rs_terminal][0] -= 1.0/100.0;
device->current_deriv[d->rs_terminal] [d->rs_terminal] += 1.0/100.0;
```

If thermal noise modeling for the resistor were desired, then the "NOISE_SETUP" (page 497) action would set up a noise source:

```
AddNoiseSource(device, "RS", 0, d->rs_terminal, 4.0*BOLTZMANN_CONSTANT*(1.0/
    100.0)*(model->sim_data[SIM_TEMPERATURE]+KELVIN));
```


## Tables

For devices with four or fewer terminals (counting internal nodes), tables can speed up simulation. Tables are "set up" at the beginning of simulation, but values are not filled in until needed. Thus, CPU time and memory are spent only on table entries that are actually used.

By default, external models do not use tables. To use tables, the "PRECOMPUTE_DEVICE_PARAMETERS" (page 494) action should set the device->table_mode flag to True.

Typically, a model sets the device->table_mode flag only if the deftables option model->sim_data[SIM_DEFTABLES] is set (nonzero). Devices may also specify device parameters which indicate whether or not tables are to be used. Devices with and without tables may be mixed in the same simulation.

Devices which share the same model may or may not be able to share the same table depending on the device parameters. For example, two MOSFETs can share a table only if they have the same length and width. If it is possible that devices may not be able to share a table, then the "TABLE_MATCHES_DEVICE" (page 494) action must be used.

The following example shows a typical "TABLE_MATCHES_DEVICE" (page 494) action:

```
MosfetDevice *d;
MosfetDevice *d_table;
```

```
d = (MosfetDevice *) device->info;
d_table = (MosfetDevice *)device->table->device->info;
if (d->width != d_table->width || d->length != d_table->length)
    model->table_matches_device = False;
```

If tables are used, then the model has control over table parameters by means of the "TABLE_SETUP" (page 495) action.

By default, the table grid will be uniformly spaced in all table dimensions, using the second terminal (terminal 1) as the reference node. The model can specify the number of grid points (default 10) and table ranges (default 5), which can be different for different table dimensions. If a non-uniform grid is to be used, the "TABLE_SETUP" (page 495) action should set up the grid.

## Noise Analysis

Noise analysis is performed in conjunction with an AC analysis frequency sweep. T-Spice's noise analysis computes the effect of "random" phenomena on the circuit output. Examples of such phenomena are resistor thermal noise and semiconductor shot and flicker noise.

Noise generators are modeled as current sources characterized by mean-square values in $\mathrm{A}^{2} / \mathrm{Hz}$. Instantaneous noise source values are not available, since the effects are considered random.

The "NOISE_SETUP" (page 497) action calls the "AddNoiseSource()" (page 497) function to add a noise current source of specified mean-square value between two device terminals.

The ".print" (page 119) command with the noise parameter can be used (in the T-Spice input file) with the noise source name to plot the effects of such noise sources on the circuit output.

The following example adds a typical thermal noise source for a resistor:

```
AddNoiseSource(device, "RS", 0, d->rs_terminal, 4.0*BOLTZMANN_CONSTANT*(1.0/
    100.0)*(model->sim_data[SIM_TEMPERATURE]+KELVIN));
```

The following T-Spice command outputs the effect of this noise source (assuming the input file contains ".noise" (page 101) and ".ac" (page 60) commands, and a device called $\mathbf{x} 1$ which uses the external model):
. print noise $d n(x 1, R S)$
If all noise sources are frequency independent, no more code needs to be written in the external model. Otherwise, the "NOISE_EVALUATE" (page 497) action can be used to set a noise source's mean-square value at each frequency point. This is done by calling the "SetNoiseSourceValue()" (page 498) function. The noise source is identified by the name given to it by the "AddNoiseSource()" (page 497) function.

The following example sets the flicker noise source value for a diode:

SetNoiseSourceValue(device, "FN", dm->kf * pow(fabs(device->current[0]), dm->af)/ device->model->sim_data[SIM_FREQUENCY]);

## Current-Controlled Devices

While most T-Spice models set terminal currents and charges as functions of terminal voltages, it is sometimes desirable to use devices which use a current (instead of a voltage) as an input state variable. An example of this is the standard SPICE current-controlled current source.

T-Spice's external models allow for current-controlled devices. The $\mathbf{x}$ device statement syntax allows on its pin list either node names or voltage source currents of the form $\mathbf{i}(\boldsymbol{v s o u r c e})$. For example, the declarations

```
x1 n1 n2 i(v1) mymodel
v1 n2 n3 0
```

generate a three-terminal device $\mathbf{x 1}$, with the third terminal representing the current through the voltage source $\mathbf{v 1}$.

The voltage source current can be accessed by device->voltage[2].
The device->terminal_type array can be examined to differentiate between node voltage and voltage source current type terminals. If terminal $\boldsymbol{i}$ is a node voltage, then device->terminal_type[i] equals TERMINAL_NODE_VOLTAGE; if it is a voltage source current, then device->terminal_type[i] equals TERMINAL_VSOURCE_CURRENT.

It is illegal to set the device->current and device->charge values of a TERMINAL_VSOURCE_CURRENT terminal.

## Voltage Sources

Voltage sources, instead of setting terminal currents and charges, specify the potential difference between two terminal nodes. The current through the device is computed internally. This requires the addition of an internal node which represents the voltage source current.

Voltage sources can be inserted between any two terminals. To set up such a voltage source, either of the "PRECOMPUTE_DEVICE_PARAMETERS" (page 494) or "PARASITIC_SETUP" (page 495) actions can call the "VoltageSource()" (page 494) function. This declares a voltage source, and internally creates the extra terminal needed to represent the voltage source current.

The following example creates a voltage source between the first two terminals:
d->vsid = VoltageSource(device, 0,1);
The return value is an identification number which is later used when setting the voltage source value. The first terminal is considered the positive terminal; that is, the voltage source value is defined to be the second terminal's voltage subtracted from the first terminal's voltage.

The "EVALUATE_DEVICE" (page 496) action sets the voltage source's value by calling the "SetVoltageSourceValue()" (page 497) function.

The following example sets a constant 5 V voltage source:

```
SetVoltageSourceValue(device, d->vsid, 5);
```

A voltage source may be controlled by other terminals' voltage (or current) values. The following example generates a linear voltage-controlled voltage source (VCVS):

```
SetVoltageSourceValue(device, d->vsid, d->k*(device->voltage[2]-
    device->voltage[3]));
```

Unless numerical differentiation is used, the "EVALUATE_DERIVATIVES" (page 497) action must calculate and set a voltage source's derivatives. For independent voltage sources, that derivative is always zero, so that no model code needs to be written. But for controlled voltage sources, such as the

VCVS above, the derivatives must be set. For the VCVS example above, the derivatives would be set by:

```
SetVoltageSourceDerivative(device, d->vsid, 2, d->k);
SetVoltageSourceDerivative(device, d->vsid, 3, -d->k);
```


## External Model Actions

Short descriptions of the predefined actions executed by ExternalModelMain() are given below. Each action is treated in more detail following. The actions are listed in the order in which they are executed. The actual code implementing each relevant action must, of course, be developed by the user.
"PARSE_MODEL_PARAMETERS" (page 492)
Read model parameter names and values and allocate memory.
"MODEL_MATCHES_DEVICE" (page 493)
Decide whether or not a requested model/device pair matches. Used in automatic model selection. (See "Automatic Model Selection" on page 487.)
"PRECOMPUTE_MODEL_PARAMETERS" (page 494)
Check model parameter names and values, precompute constant quantities to speed up model evaluations, and allocate memory.
"PRECOMPUTE_DEVICE_PARAMETERS" (page 494)
Check device parameter names and values, precompute constant quantities to speed up device evaluations, and allocate memory.
"TABLE_MATCHES_DEVICE" (page 494)
Decide whether or not a device may use a table which was set up for a different device.
"PARASITIC_SETUP" (page 495)
Add parasitics (typically series resistors, parallel diodes, or internal nodes).
"TABLE_SETUP" (page 495)
Compute table grid points and other parameters.
"EVALUATE_DEVICE" (page 496)
Given node voltages and state information, compute terminal currents and charges. This action is required.
"EVALUATE_DERIVATIVES" (page 497)
Compute all partial derivatives of the terminal currents and charges with respect to the terminal voltages. This action is required.
"NOISE_SETUP" (page 497)

Set up noise sources and make frequency-independent computations.
"NOISE_EVALUATE" (page 497)
Evaluate frequency-dependent noise sources at a particular frequency.
"PRINT_SMALL_SIGNAL_PARAMS" (page 498)
Compute and print small-signal parameter values.
"CLEANUP_DEVICE" (page 498)
Free memory associated with a device.
"CLEANUP_MODEL" (page 498)
Free memory associated with a model.

## PARSE_MODEL_PARAMETERS

The PARSE_MODEL_PARAMETERS action processes the parameter list specified by ".model" (page 96) in the input file.

The purpose of the .model command is to introduce a model into the simulation. At the code level, this means initializing a data structure of type ExternalModel.

Most parameter names and values from the .model command are stored in a linked list. The pointer to this list is the parameter_list member of the ExternalModel structure.

The values from parameter_list must be stored as separate items of data; they are typically placed in fields of a user-defined structure whose pointer is stored by the info member of the ExternalModel structure.

Thus, the code for PARSE_MODEL_PARAMETERS generally involves:

- Allocating the memory needed to store specific parameter values in the particular ExternalModel structure being initialized. This is typically done with malloc().
- Looking through (parsing) the parameter list to identify and store the specified parameter values in the appropriate locations. This is done with the LookupParameter...() functions.

LookupParameterDouble() Look up parameters of type double. The return value is a double.
LookupParameterInt() Look up parameters of type int. The return value is an int.
LookupParameterString() Look up parameters of type char. The return value is a char *, a pointer to the string array.

The LookupParameter...() functions all have the same arguments:

## Type <br> Argument

TspParamListElem *
paramlist

The pointer to the model's parameter list (the parameter_list member of the ExternalModel structure).

```
char *
char *
```


## TspBoolean *

parameter_name
The name(s) of the parameter to be extracted from the parameter list, enclosed in double quotes. The search is case-insensitive. Multiple names for the same parameter may be searched simultaneously by separating them with a vertical bar | in the parameter_name string.
default_value
The value assigned to the requested parameter if it is not found in parameter_list, enclosed in double quotes. If necessary, this string is converted to the appropriate numeric type using atoi() or atof(). The result becomes the function's return value.

## parameter_found

This Boolean, passed by reference, is set to True if the parameter was found, and False otherwise.

PARSE_MODEL_PARAMETERS is executed for each .model command in the input file, whether the model referred to is instanced as a device or not. This is to support automatic model selection, which requires that model parameter values be known before models and devices are matched. (See "Automatic Model Selection" on page 487.)

PARSE_MODEL_PARAMETERS acts on model parameter sets only. Thus, for this action, the device (d) passed to ExternalModelMain() is NULL.

If malloc() is used to allocate the memory pointed to by info, then the memory should be freed by the "CLEANUP_MODEL" (page 498) action.
"Unused" model parameters-items in parameter_list which were never looked up-can be listed by the "PRECOMPUTE_MODEL_PARAMETERS" (page 494) action.

For models that are actually instanced as devices, any remaining initialization tasks can be performed by the "PRECOMPUTE_MODEL_PARAMETERS" (page 494) action.

## MODEL_MATCHES_DEVICE

The MODEL_MATCHES_DEVICE action compares model and device parameter values to find a match.

- Model parameter values are looked up in model->info if they have been stored there (if the "PARSE_MODEL_PARAMETERS" (page 492) action has been performed already).
- Device parameter values have not been stored; they are found with the LookupParameter functions.

If the comparison fails, then the model_matches_device member of the ExternalModel structure is set to False.

MODEL_MATCHES_DEVICE supports automatic model selection. Several .model commands in one input file can specify the same model name (with different extensions), and a device can have its model chosen automatically. This is done by comparing parameters between the device and the candidate models. (See "Automatic Model Selection" on page 487.)

If automatic model selection is not used for a model, then MODEL_MATCHES_DEVICE can be omitted.

## PRECOMPUTE_MODEL_PARAMETERS

The PRECOMPUTE_MODEL_PARAMETERS action performs preparatory computations on a model parameter set.

PRECOMPUTE_MODEL_PARAMETERS can use the following function.

| PrintUnusedParameterMe | List "unused" model parameters—items in parameter_list which |
| :--- | :--- |
| ssage() | were never looked up. |

PARSE_MODEL_PARAMETERS acts on model parameter sets only. Thus, for this action, the device (d) passed to ExternalModelMain() is NULL.

## PRECOMPUTE_DEVICE_PARAMETERS

The PRECOMPUTE_DEVICE_PARAMETERS action parses and precomputes a device parameter set.
At this point, the device has been matched with a model, and that model is passed to ExternalModelMain(). (A pointer to the model is also available in the model field of the ExternalModelDevice structure.) Like ExternalModel, ExternalModelMain() has a parameter_list field and an info field, and their use is analogous to their ExternalModel counterparts.

PRECOMPUTE_DEVICE_PARAMETERS can use the following functions.

LookupParameter() Look up device parameter values.
PrintUnusedParameterMe List unused device parameters. ssage()

VoltageSource()
Set up voltage sources.

If the device is to be used in table mode, PRECOMPUTE_DEVICE_PARAMETERS should set device->table_mode to True. By default, device->table_mode is False.

PRECOMPUTE_DEVICE_PARAMETERS can also check model->sim_data[SIM_DEFTABLES] to determine the value of the deftables simulation option.

The maximum number of terminals for a device in table mode is four. If the device has more than four terminals, then table mode for that device is automatically turned off.

## TABLE_MATCHES_DEVICE

The TABLE_MATCHES_DEVICE action checks whether or not a device table can be reused on another device.

Before this action, the device->model->table field is temporarily assigned a table. TABLE_MATCHES_DEVICE must decide if that table can be used with the device. The device for which the table was originally made is device->model->table->device.

If the device->model->table->device and device cannot share the table, then TABLE_MATCHES_DEVICE should set model->table_matches_device to False.

## PARASITIC_SETUP

The PARASITIC_SETUP action adds parasitic devices and internal nodes.
Parasitic devices are added after all device and model parameters have been resolved. Standard MOSFET models require at least parasitic resistors and diodes.

Parasitic devices can be added in parallel (between existing nodes), or in series with a device's terminal (requiring the addition of a new node).

If the device is a MOSFET, one of T-Spice's standard MOSFET parasitic models may be used.
Care must be taken to ensure that ".print" (page 119) commands account for parasitics properly.
PARASITIC_SETUP can use the following functions.

| AddSeriesResistor() | Add a resistor in series with a given terminal. The return value is an <br> ID number which can be used later to refer to the resistor. The noise <br> modeling for series resistors is automatic if the noise_source_name <br> field is not NULL. |
| :--- | :--- |
| AddParasiticDiode() | Add a diode in parallel with two given terminals. The return value is <br> an ID number which can be used later to refer to the diode. A diode <br> model must be given as well, with a call to the <br> "NewParasiticDiodeModel()" (page 495) function. |
| NewParasiticDiodeModel() | Return a required diode model in conjunction with <br> "AddParasiticDiode()" (page 495), setting all parameters to typical <br> values. |
| The parameter values can be modified as needed before the call to <br> "AddParasiticDiode()" (page 495); they are the standard MOSFET <br> parasitic diode parameters (see "Additional MOSFET Parameters" <br> on page 457). |  |
| AddInternalNode() | Add a terminal to the device. The return value is the terminal number <br> of the new terminal. The new terminal can be used to hold internal <br> state information for the device. |
| For example, a series resistor can be created by AddInternalNode() <br> instead of "AddSeriesResistor()" (page 495) (see "Parasitic Effects |  |
| and Internal Nodes" on page 487). It is then the model's |  |
| responsibility to compute the resistor current. |  |

## TABLE_SETUP

The TABLE_SETUP action sets quantities for a device table.

If the device is used in table mode (restricted to devices with 4 or fewer terminals), a table grid is computed before simulation begins. A uniform grid may be chosen, which is based simply on the number of grid points and table range (set by this action). The table grid sizes and voltage ranges are under control of the model author, and may depend on model parameter values.

Table parameters, all fields of the device->table structure, include:
reference_termina
grid_type
number_of_points
max_voltage
grid
output_type
current_symmetry and charge_symmetry

Identifies the terminal used as the potential reference ( 1 by default). Terminals are numbered from 0 .

The table axes are the voltages at the remaining terminals with respect to the reference terminal voltage. An $n$-terminal device uses an ( $n-1$ ) dimensional table.

For example, a 4-terminal device with reference terminal 1 uses ( $v_{0}-$ $v_{1}, v_{2}-v_{1}, v_{3}-v_{1}$ ) as its independent variables for the table, where $v_{0}$, $v_{1}, v_{2}$, and $v_{3}$ are the voltages at terminals $0,1,2$, and 3 , respectively.

An array over the table dimensions (maximum 3) whose elements indicate what type of grid is to be used.

The options are GRIDTYPE_UNIFORM (uniform spacing) or GRIDTYPE_NONUNIFORM (non-uniform spacing, specified by the model).

An array over the table dimensions, each element indicating the number of table points used in the grid for a table dimension.

An array over the table dimensions, each element indicating the voltage range used in a uniform grid for a table dimension.

An array (double *) over the table dimensions containing pointers to the grid points for a non-uniform grid. If a non-uniform grid is computed, then the grid point values must be sorted in increasing order.

An array over the device terminals indicating which output variables need to be saved.

The options are OUTPUT_NORMAL (save outputs in table), OUTPUT_ALWAYS_ZERO (output is always zero, no need to save in table), and OUTPUT_COMPUTE (output variable is computed from other output variables).

Only one terminal can be of the OUTPUT_COMPUTE type: this terminal's current and charge is computed by assuming that all terminals' currents and charges must sum to zero.

Arrays over the table dimensions and terminals indicating which terminals' outputs have symmetry over which table dimensions. This information is used to save memory occupied by the table.

The options are SYMMETRY_NONE, SYMMETRY_ODD $(f(x)=-f(-$ $x)$ ), and SYMMETRY_EVEN $(f(x)=f(-x))$. To save memory in a given table dimension, all outputs (both currents and charges) of a device must have symmetry (although not necessarily of the same type).

## EVALUATE_DEVICE

The EVALUATE_DEVICE action evaluates a device's terminal currents and charges, given terminal voltage values.

The terminal voltages are stored in device->voltage. In the case of current-controlled sources, one of the device->voltage values actually represents the current through the controlling voltage source.

EVALUATE_DEVICE sets the contents of device->current and device->charge.
EVALUATE_DEVICE can use the following function.

SetVoltageSourceValue() Set the voltage value(s), if the device to be evaluated is or contains one or more voltage sources. One of the arguments is a voltage source ID number, which is the return value of a "VoltageSource()" (page 494) function call.

## EVALUATE_DERIVATIVES

The EVALUATE_DERIVATIVES action evaluates the partial derivatives of the device's terminal currents and charges, with respect to its terminal voltages.

EVALUATE_DERIVATIVES can use the following functions.

| ComputeNumericalDerivat <br> ives() | Compute derivatives by differences. <br> (Otherwise, if derivatives are available in analytic form, then they <br> can be directly assigned to the matrices device->current_deriv and <br> device->charge_deriv.) |
| :--- | :--- |
| SetVoltageSourceDerivati <br> ve() | Set the derivative of a voltage value with respect to a particular <br> device terminal voltage, if the device to be evaluated is or contains <br> one or more voltage sources. |

EVALUATE_DERIVATIVES may assume that the "EVALUATE_DEVICE" (page 496) action was performed just before with the same voltages.

If the device is in table mode, then EVALUATE_DERIVATIVES is never called.

## NOISE_SETUP

The NOISE_SETUP action performs one-time initializations for noise analysis.
NOISE_SETUP can use the following function.

AddNoiseSource() Define noise sources with assigned values.

The device's voltage, current, and charge fields contain the appropriate values at the operating point at which the noise analysis is to be performed.

At the beginning of a noise analysis, noise sources are identified for each device, and any one-time frequency-independent precomputations are performed.

NOISE_SETUP can be ignored if the model does not contain any noise source models.

## NOISE_EVALUATE

The NOISE_EVALUATE action re-evaluates frequency-dependent noise source contributions at each frequency point of a noise analysis.

NOISE_EVALUATE can use the following function.

SetNoiseSourceValue() Set a noise source's mean-square value.

Any frequency-dependent noise source values are set by NOISE_EVALUATE; if no such noise sources are present, then NOISE_EVALUATE can be omitted.

## PRINT_SMALL_SIGNAL_PARAMS

The PRINT_SMALL_SIGNAL_PARAMS action defines small-signal parameters to be printed with the ".acmodel" (page 63) command.

PRINT_SMALL_SIGNAL_PARAMS can use the SmallSignalParameter...() functions.

SmallSignalParameterStri Defines a string parameter (char*) for printing.
ng()
SmallSignalParameterDou Defines a floating point (double) parameter for printing.
ble()
SmallSignalParameterInt() Defines an integer parameter (int) for printing.

## CLEANUP_DEVICE

The CLEANUP_DEVICE action frees any memory that has been allocated for the device structure, such as the device->info field.

## CLEANUP_MODEL

The CLEANUP_MODEL action frees any memory that has been allocated for the model structure, such as the model->info field.

CLEANUP_MODEL is called after "CLEANUP_DEVICE" (page 498) has been performed for every instance of the model.

## 11 External Tables

## Introduction

Evaluation of device models in T-Spice is based by default on "internally" generated tables, which are computed and stored during a simulation and are discarded when the simulation is over.

It is also possible to use "externally" generated tables, which are created independently, instead of within a simulation run, and can be saved for later use.

For example, tables representing commonly simulated transistors can be created once and then used in the future without having to be regenerated during each simulation run.

External table-based evaluation, while not quite as accurate as direct model evaluation, can be significantly faster; and, while not as convenient as default (internal) table-based evaluation, can provide you with more freedom and flexibility in choosing sources for table data.

For example, a device for which no model is available, but only charge and current data based on experiments, can be simulated by means of an external table incorporating that data.

The commands related to the creation and manipulation of external tables have different Windows and DOS/Unix names.

| Function | Windows | DOS/Unix |
| :--- | :--- | :--- |
| Generate external tables | "Table $>$ Generate Table" (page "tv" (page 508) |  |
|  | 502 ) |  |
| Convert tables between | "Table > Convert Table" (page "table" (page 508) |  |
| ASCII and binary formats | 503) |  |
| Check table monotonicity | "Table $>$ <br> (page 503 Monotonicity Check" | "mc" (page 509) |

## Generating Tables From Presupplied Models

Where a presupplied device model is available, an external table is created with the Table > Generate Table command.

Generate Table takes a T-Spice input file in table-generating format and creates charge and current tables by (1) evaluating a model in terms of a representative device and (2) recording the results.

The table-generating input file contains information about the model and the representative device. For example, the tutorial file p125x3.sp looks like this:

```
* P-channel MOSFET model
.model penh pmos
+ Level=2 Ld=.03000000u Tox=225.000e-10
+ Nsub=6.575441e+16 Vto=-0.63025 Kp=2.635440E-05
+ Gamma=0.618101 Phi=.541111 Uo=361.941
+ Uexp=8.886957e-02 Ucrit=637449 Delta=0.0
+ Vmax=63253.3 Xj=0.112799u Lambda=0.0
+ Nfs=1.668437e+11 Neff=0.64354 Nss=3.000000E+10
+ Tpg=-1.00000 Rsh=150
+ Cgdo=3.35e-10 Cj=4.75e-04
+ Cjsw=2.23e-10 Mjsw=.307
md1 n1 n2 n3 n4 penh l=1.25u w=3.0u
```

This file reproduces the $p$-channel MOSFET model parameters contained in the model file $\mathbf{m 1 2 5 c n}$.md. The last line, beginning with the key letter $\mathbf{m}$, specifies the representative MOSFET device for which the tabular data will be computed and saved.

Generate Table, using p125x3.sp as input, creates charge and current tables for a $p$-channel MOSFET with a length of 1.25 microns and a width of 3 microns. (The tables for a 1.25 micron-long, 2 -micronwide $n$-channel MOSFET are created in an analogous manner; the table-generating input file in the tutorial directory is $\mathbf{n 1 2 5 x} \mathbf{2 . s p}$.) Devices that are of the same type but that differ in physical size (length or width) still require separate tables.

External tables are stored in either ASCII text (user-readable) or binary (machine-readable) format. The following chart compares the two formats.

| Format | Filename extensions | Advantages | Comments |
| :---: | :---: | :---: | :---: |
| ASCII text | .ftx (current) <br> .qtx (charge) | Portability across operating systems and platforms. | This is the default format for tables generated with the Table > Generate Table command. |
| Binary | .f (current) <br> . 9 (charge) | Smaller (less storage space required); fasterloading; more precise (floatingpoint numbers are not truncated). | This is the default format for tables generated with the tv utility program. |

To generate external tables from p125x3.sp:

## Windows

DOS/Unix

- Make sure p125x3.sp is

Type: open, active, and saved.

- Select Table > Generate

Table.
tv -o p125x3 -a p125x3.sp
The -a option generates ASCII files (the default is binary).

- The dialog suggests a table file basename, p125x3, which can be changed.
- Choose either ASCII Text (default) or Binary format.
- Press Return or click OK.

Tables can be converted between ASCII and binary formats with the Table > Convert Table command.

## Generating Tables From User-Supplied Data

External tables do not have to be generated from presupplied models. Table values can be user-supplied from various external sources:

- Experimentally measured charge and current data. If you do not have an analytical model for the device that you want to simulate, directly measuring the charge and current values across various voltage drops and constructing tables is the only solution.
- An analytical device model you have developed or acquired which may not have an equivalent in the presupplied model library. Charge and current tables can be generated by writing a short program which solves your model equations using your parameters, and outputs charge and current values.
- The results of a T-Spice simulation on a device or circuit that you would like to define as a macromodel in future simulations. Transfer analysis can be used to create charge and current tables. In future simulations, the device will be seen at a high level as a "box" with certain transfer characteristics, instead of at a low level as being composed of simpler, separately modeled elements such as transistors and capacitors.

User-supplied tables must conform to the required format (see "Table Format" on page 504).

## Using Tables

Input files using external tables differ slightly from those using internal tables. Internal tables are accessed by model names, while external tables are accessed by reference names.

For example, the MOSFET definition statements from the tutorial file invert1.sp are:

```
mt1 out in GND GND nenh l=1.25u w=2u
mt2 out in Vdd Vdd penh l=1.25u w=3u
```

These statements specify model names, nenh and penh, to be used in the generation of internal tables. External tables, which already exist when the simulation begins, are specified by reference names - for example, nmost and pmost (any legal names could be used). If invert1.sp were modified to use external tables, the corresponding lines would be:

```
mt1 out in GND GND nmost l=1.25u w=2u
mt2 out in Vdd Vdd pmost l=1.25u w=3u
```

Of course, T-Spice needs to know where to find the appropriate tabulated data when a particular reference name is given. This information is supplied by the .table command. The following lines would be added to the modified invert1.sp:
.table nmost $n 125 x 2$.ftx $n 125 x 2$. qtx
.table pmost p125x3.ftx p125x3.qtx
The .table command associates the reference names (nmost and pmost, used by the MOSFET device statements) with existing table files ( $\mathbf{n} 125 \times 2$.qtx, $\mathbf{n 1 2 5 x 2 . f t x}$, p125x3.qtx, and p125x3.ftx). The reference names need not resemble the file names. When the associations have been made, T-Spice searches the input file for device statements which call the same reference names, and so pairs specific devices with appropriate charge and current tables.

## Table Commands

## Table > Generate Table

Prompts for the basename of a set of external table files to be generated from the (active) input file.
The input file must contain at least one model and one device (MESFET, MOSFET, JFET, or diode) definition. It may also contain table control commands such as ".vrange" (page 150) and ".gridsize" (page 78), for customizing generated tables. The generated tables can be used with the ".table" (page 143) command as device models.

Table file basename

ASCII Text

Binary

A table file basename related to the input file name is automatically suggested.

Generate tables in ASCII (human-readable) format (.ftx, .qtx format).

Generate tables in binary (machine-readable) format (.f, .q format).

## Table > Evaluate Table

Prompts for terminal voltages to use when evaluating an external table generated from the (active) input file.

The input file must contain at least one model and one device (MESFET, MOSFET, JFET, or diode) definition. It may also contain table control commands such as ".vrange" (page 150) and ".gridsize"
(page 78), for customizing the generated table. The generated table is evaluated at the specified terminal voltages. Current and charge values corresponding to the specified voltages are reported in the Simulation Status window.

Terminal ... voltage Input voltages for each terminal.

## Table > Convert Table

Prompts for the name and path of an external table file to be converted from ASCII (.ftx, .qtx) to binary (.f, .q) format or vice versa. Files that have been converted are added to the Simulation Manager queue and can be viewed in the Simulation Status window.

| File name | The name of the table file to be converted. The wildcard character * <br> can be used. However, only one file can be converted at a time. The <br> scrolling window lists all files in the source directory. |
| :--- | :--- |
| Files of type | Select from the menu to limit the types of files displayed. |
| Open | The name of the table file to be converted. |

## Table > Monotonicity Check

Prompts for the name and path of an external table file to be checked for monotonicity. (Lack of monotonicity can cause severe convergence problems during simulation.)

| File name | The name of the table file to be checked. The wildcard character * <br> can be used. However, only one file can be checked at a time. The <br> scrolling window lists all files in the source directory. |
| :--- | :--- |
| Files of type | Select from the menu to limit the types of files displayed. |
| Open | The name of the table file to be checked. |

When you select a file for checking, T-Spice opens the Save Output to File dialog, prompting you for the name and path of an output file.

Output file name An output file name (with a .prt extension) based on the input file name is automatically suggested.

## Table > Print Table

Prompts for the name and path of an external table file to be printed to a .prt format file in user-readable form.

| File name | The name of the table file to be printed. The wildcard character * can <br> be used. However, only one file can be printed at a time. The <br> scrolling window lists all files in the source directory. |
| :--- | :--- |
| Files of type | Select from the menu to limit the types of files displayed. |

Open The name of the table file to be printed.

When you select a file for printing, T-Spice opens the Save Output to File dialog, prompting you for the name and path of an output file.

Output file name An output file name (with a .prt extension) based on the input file name is automatically suggested.

## Table Format

A T-Spice external device table lists either charge or current values which vary according to the different voltages between terminals on the device.

Tables have one or more input dimensions. Each input dimension consists of a set of voltages at one of the device terminals with respect to the reference terminal. (In the case of tables used in macromodeling, the reference terminal is the second terminal named on the Xinstance command.)

For example, the tables for a device with three terminals $\mathbf{a}, \mathbf{b}$, and $\mathbf{c}$, with $\mathbf{a}$ as the reference terminal, would have two input dimensions, corresponding to $V(\mathbf{b}, \mathbf{a})$ and $V(\mathbf{c}, \mathbf{a})$. Thus, one column in the charge table would list charges as a function of the voltage between $\mathbf{b}$ and $\mathbf{a}$; the other column, between $\mathbf{c}$ and $\mathbf{a}$ (and similarly for the current table).

Tables contain other information as well. The example below - the steady-state current table for a linear resistor - is followed by a detailed description of the format and order of entries in a table. Entries in the table are separated by spaces, tabs, or new lines.


Input dimensions [integer]. This must be the first entry. The number of input dimensions is the number of pairwise combinations of terminals with the reference terminal, or ( $n-1$ ) dimensions for an $n$ terminal device. (The reference terminal itself is not counted, since the corresponding voltage is always zero.)

Table resolutions [integer]. One resolution value is required for each dimension; it is the number of voltage (input) values, or grid points, the table will list in that dimension. (These entries are equivalent in function to the .gridsize command in input files.)

Output dimensions [integer]. The number of output dimensions is the number of distinct charge or current (output) values needed to characterize the device's behavior. This is usually one fewer than the number of terminals on the device, due to charge/current conservation: once ( $n-1$ ) currents or charges are known for an $n$-terminal device, the final terminal's values can be readily computed.

Table type [integer]. The table type indicates the device type, as follows:

| Table type | Device type | Description |
| :--- | :--- | :--- |
| 0 | MACRO | A device whose table is not <br> generated from a predefined <br> model but by some other means, <br> such as macromodeling. |
| 1 | NMOS | $N$-channel MOSFET |
| 2 | PMOS | $P$-channel MOSFET |
| 3 | D | Diode |
| 4 | NPN | npn |
| 5 | PNP | pnp |
| 6 | NJF | $N$-channel JFET |
| 7 | PJF | $P$-channel JFET |
| 10 | NMF | $N$-channel MESFET |
| 11 | PMF | $P$-channel MESFET |

Grid points [float]. The list of voltage (input) values used to determine the charge and current (output) values. The full set of grid points for the first input dimension is listed first, then the next, and so on. The total number of grid points is the sum of the table resolution values.

Table values [float]. The list of charge and current (output) values corresponding to the voltage (input) values. The table values are sorted into vertical columns, one column per output dimension. The order of the columns is specified in the input file by the device statement: the first terminal listed there uses the first (leftmost) column, the second terminal uses the second column, and so on. (The last terminal's charges and currents are computed, not tabulated.) Each column lists currents or charges as if the voltages were being swept through their grid ranges (see "Multiple Input Dimensions," below). The total number of table values per column is the product of the table resolutions.

## Grid Point Resolution

Grid points need not be evenly spaced. A higher density of grid points can be taken around areas where device behavior is non-linear, for higher accuracy.

## Table Value Monotonicity

For DC and transfer analyses, steady-state currents must be monotonic as a function of voltage. For transient analyses, charges must be monotonic in voltage as well.

The Table > Monotonicity Check command helps to locate areas of non-monotonicity. Monotonicity Check determines whether or not the table values for each combination of indices in each dimension are monotonic. Any non-monotonicities found are counted, and the table coordinates at which they were
found are reported (Windows: to a specified output file; DOS/Unix: to standard output unless redirected).

## Multiple Input Dimensions

In the case of more than one input dimension, the table values are listed as follows: Each output column lists table values as if the voltages were being swept through their ranges, so that a table value is given for each combination of voltages. For example, suppose that a device's table has three input dimensions (V1, V2, V3), each with two grid points (denoted by subscripts a and b). Then the currents in each column, computed from combinations of the three voltages, are listed in the following order:

```
I(V1a,V2a,V3a)
I(V1b,V2a,V3a)
I(V1a,V2b,V3a)
I(V1b,V2b,V3a)
I(V1a,V2a,V3b)
I(V1b,V2a,V3b)
I(V1a,V2b,V3b)
I(V1b,V2b,V3b)
```


## MOSFET Tables

The format for MOSFET tables is slightly different to reduce storage and access time.

- Only the drain and source steady-state currents are stored as table (output) values.
- Charge and current values are listed only for certain ranges of $V d s$ (voltage between drain and source). The drain and source terminals are defined arbitrarily, so it is redundant to store both positive and negative $V d s$ grid points.
- Only positive values for NMOS and negative values for PMOS are stored. The table type indicates whether the table is for a NMOS or a PMOS transistor.

Otherwise the format is standard. For example, NMOS charge tables take the following form, where $\boldsymbol{A}$, $\boldsymbol{B}, \boldsymbol{C}$ denote the numbers of grid points in the three input dimensions ( $V d s, V g s, V b s$, respectively), $\boldsymbol{V}$ denotes voltage, and $\boldsymbol{Q}$ denotes charge:

```
3 A B C
3 1
Vds,1 Vds,2 . . . Vds,A
Vgs,1 Vgs,2 . . . Vgs,B
Vbs,1 Vbs,2 . . . Vbs,C
Qd(Vds,1,Vgs,1,Vbs,1) Qs (Vds,1,Vgs,1,Vbs,1) Qg(Vds, 1, Vgs, 1, Vbs, 1)
Qd(Vds,2,Vgs,1,Vbs,1) Qs (Vds, 2,Vgs,1,Vbs,1) Qg(Vds, 2,Vgs,1,Vbs,1)
Qd(Vds,A,Vgs,B,Vbs,C)Qs(Vds,A,Vgs,B,Vbs,C) Qg(Vds,A,Vgs, B,Vbs, C)
```

The steady-state current file is similarly structured, except that the values for the gate are excluded and the number of output dimensions is two instead of three. The default input dimensions are: $\boldsymbol{A}(V d s)=9$, $\boldsymbol{B}(V g s)=15$, and $\boldsymbol{C}(V b s)=4$. These dimensions can be modified with the .gridsize command. The default voltage range is $[0.0,+5.0]$ for NMOS and $[-5.0,0.0]$ for PMOS. These ranges can also be modified with the .vrange command. Examples of PMOS and NMOS charge and current tables (p125x3.ftx, p125x3.qtx, n125x2.ftx, n125x2.qtx) are included.

The charge and current tables for a transistor should have the same grid points (to lower lookup times); if this is not the case, then the transistor will be treated as a general four-terminal device. T-Spice will
automatically reduce the dimensionality of a transistor table if the drain or source is connected to the bulk (to lower lookup and interpolation times).

The ordering of the nodes on a table Xinstance command corresponds to the ordering of the columns in the table. If a node has only zero values for all regions of operation - for example, if the current at a gate is zero - then the .ftx table should be modified as follows: (1) list the gate last; (2) reduce the number of output dimensions by one; (3) omit the table values for the gate.

## A Simple Example

The following example is the steady-state current table, res.ftx, for a linear resistor (10 kilohms).

```
1 2 1 0
-5.0 5.0
-.005
.005
```

The first line of the table contains the first four required entries.

- The number of input dimensions is $\mathbf{1}$, since a resistor has two terminals, and one is used as the reference. (In other words, the only voltage of interest is the one across the resistor's two terminals.)
- One table resolution value, corresponding to the single input dimension, is given: the table's first (and only) dimension contains $\mathbf{2}$ grid points.
- The number of output dimensions is $\mathbf{1}$, since currents need to be specified at only one terminal of the resistor (the current at the other terminal can be computed from the first).
- The table type, $\mathbf{0}$, indicates a device which is not represented in the T-Spice model library.

The grid points, $\mathbf{- 5 . 0}$ and $\mathbf{5 . 0}$ volts, establish fixed points from which the current at any other voltage can be computed by linear interpolation and extrapolation. The full set of grid points in the first input dimension is listed first, then the second (if there is a second input dimension), and so on.

Following the grid points is a column of table values. Two values are given, corresponding to the two input voltages in the first (and only) dimension, and representing the current at one of the terminals given those voltages.

The resistor's charge table is stored in another file, res.qtx. The resistor does not have charge associated with it, but a charge table is still required, one that contains zero values:

```
12 1 0
-5.0 5.0
0.0
0.0
```

Since the standard resistor device statement does not include an option for specifying an alternate model, this resistor would be implemented as a macromodel (see below) by including the .table command in the circuit description using the tabulated resistor. Then, an instance of a table device is created using the Xname subcircuit-device command.

```
.table myres res.ftx res.qtx
xr1 in out myres
```

where $\mathbf{~ x r} 1$ is the name of the resistor in the circuit, myres is the table reference name, and in and out are the resistor's two terminals.

## Utility Programs

Several utility programs are included with T-Spice; these aid in the creation and manipulation of external tables. Giving the name of any of the utility programs (tv, table, mc) without arguments at the command prompt produces a usage message.
tv
tv, a table generator, generates external charge and current tables from an input file consisting of a .model command with parameters and a statement specifying a representative device.

```
tv [-aEUV] -o output input
```

| Option | When on | When off (default) |
| :--- | :--- | :--- |
| -a | Generates tables in ASCII text <br> format. | Generates tables in binary format. |
| -E | Evaluation mode. Prompts for a <br> set of (input) terminal voltages, <br> and returns the (output) terminal <br> charges and currents at those <br> voltages. |  |
| -U | Prints a usage message and quits <br> the program. |  |
| -V | Prints the version number and <br> acknowledgments and quits the <br> program. | - |
| -o output | Prints results to table files with <br> base name output. | [This argument is required.] |
| input | Uses file input to generate tables. | [This argument is required.] |
|  | Input files typically have the <br> extension .sp. |  |

## table

table, a table format converter, converts external charge and current tables between ASCII text (userreadable) and binary (machine-readable) formats.
table [-UV] input output

| Option | When on | When off (default) |
| :--- | :--- | :--- |
| -U | Prints a usage message and quits <br> the program. |  |
| -V | Prints the version number and <br> acknowledgments and quits the <br> program. |  |


| Option | When on | When off (default) |
| :--- | :--- | :--- |
| input | Looks in file input for the table to <br> be converted. ASCII table files <br> must have extension .ftx or .qtx; <br> binary table files must have <br> extension .f or .q. | [This argument is required.] |
| output | Writes the converted table to file <br> output. ASCII table files must <br> have extension .ftx or .qtx; binary <br> table files must have extension .f <br> or.q. |  |
|  | [This argument is required.] |  |

## mc

$\mathbf{m c}$, a monotonicity checker, determines for a table whether or not the table values for each combination of indices in each input dimension are monotonic. Any non-monotonicities found are counted, and the table coordinates at which they were found are reported to standard output (unless redirected).
mc [-cpuV] input

| Option | When on | When off (default) |
| :--- | :--- | :--- |
| -c | Continues checking (even if non- <br> monotonicity is found). | Stops checking as soon as non- <br> monotonicity is found. |
| -p | Prints out grid values along each <br> dimension instead of checking <br> for monotonicity. | - |
| -U | Prints a usage message and quits <br> the program. |  |
| -V | Prints the version number and <br> acknowledgments and quits the <br> program. |  |
| input | Looks in file input for the table to <br> be checked. ASCII table files | [This argument is required.] |
|  | must have extension .ftx or .qtx; <br> binary table files must have <br> extension .f or .9. |  |

## 12 Parametric Analysis

## Introduction

T-Spice is often required to study the effects of variations in parameter values on circuit performance. For example, parametric analysis can be used to evaluate multidimensional trends in the output over defined ranges of input values, or the sensitivity of circuit behavior to random fluctuations in fabrication conditions.

A large range of parameters may be systematically and automatically varied:

- External parameters (such as temperature)
- Simulation parameters (such as tolerances)
- Device parameters (such as input voltage level or transistor length)
- Model parameters (such as transistor threshold voltage)

Three types of parametric analysis are supported by T-Spice: parameter sweeping, Monte Carlo analysis, and optimization.

This chapter will guide the T-Spice Pro user through several tutorial problems in order to demonstrate some basic concepts of parametric analysis.

The example files for these tutorials can be found in the tspice91\exampleslinput subdirectory of the T-Spice Pro installation path.

## Output File Formats

Results produced by parameter sweeps and Monte Carlo analysis are easily read in T-Spice output files. You can open a T-Spice output file from the T-Spice Simulation Manager by clicking on the Show Output button. Alternatively, select File > Open and browse within the Open dialog to select the output filename. T-Spice output files are text files; they are also readable in the text editor of your choice.

Analysis results for parameter sweeps are reported in table format, with section headings that contain the current values of the swept parameters. For example, if a .step command invokes several transient analyses, each analysis produces its own output section, the header of which shows the parameter values for that analysis (e.g., TRANSIENT ANALYSIS - vdd=3).

Results obtained from .measure commands are listed at the end of each output section corresponding to a specific parameter value. These measurements are summarized at the end of the sweep in a table labeled TRANSFER ANALYSIS. The use of a .step command causes .measure results to be plotted in W-Edit, with the swept variable as the $x$-axis.

## Parameter Sweeps

In a parameter sweep, a specified parameter is held or initialized at a given value, all analyses requested by the input file are performed, and the results are recorded. Then the parameter is incremented by a set amount, and the same analyses are repeated. The cycle continues as the parameter is incremented through a defined range of values.

Parameter values may be swept linearly—in identical increments, typically through a limited range-or logarithmically-in exponential increments, typically through a range spanning multiple orders of magnitude. You can also specify a sweep over a list of values.

Parameter sweeping is performed by using the sweep option with one of the following commands:

- .ac (see ".ac" on page 60)
- .dc (see ".dc" on page 69)
- .step (see ".step" on page 138)
- .tran (see ".tran" on page 147)

Additionally, it is also possible to perform simultaneous parameter sweeps of several different variables using the command .data (see ".connect" on page 66).

Adding the sweep option to a .tran or .ac command instructs T-Spice to perform that analysis for all parameter values of the specified sweep. Using the sweep option with an analysis command is similar to using it with .step. A single .step command causes T-Spice to perform parameter sweeps for all analysis commands in the input file. If sweep is specified on an analysis command and a .step command is present, the sweep specified with the analysis command is nested inside the sweep specified with the .step command.

All input files listed for this chapter are in the directory <install_dir>|tutoriallinput.

## Example 1: Parametric Sweep

This example uses a ring oscillator to demonstrate the basic features of a parametric sweep.

| T-Spice Input | ring2.cir |
| :--- | :--- |
| Output | ring2.out |

## $T$-Spice Input

```
* Circuit: ring2.sp
*
.SUBCKT inv in out Gnd Vdd
c2 out Gnd cap
m1p out in Vdd Vdd pmos L=5u W=12u
mn1 out in Gnd Gnd nmos L=5u W=8u
.ENDS
* Main circuit: ring2
cinv1 a7 Gnd 400ff
.include ml2_125.md
Xinv1 a1 a2 Gnd Vdd inv
```

```
Xinv2 a2 a3 Gnd Vdd inv
Xinv3 a3 a4 Gnd Vdd inv
Xinv4 a4 a5 Gnd Vdd inv
Xinv5 a5 a6 Gnd Vdd inv
Xinv6 a6 a7 Gnd Vdd inv
Xinv7 a7 a1 Gnd Vdd inv
.measure tran period trig v(a2) val=3.0 fall=2 targ v(a2) val=3.0 fall=3
.measure tran pulsewidth trig v(a2) val=1.5 rise=2 targ v(a2) val=1.5 fall=2
.measure tran timedelay trig v(a2) val=3.0 fall=2 targ v(a1) val=3.0 fall=2
.param cap=800ff
.print tran a1
.step cap 200f 1000f 200f
.tran/powerup 1n 800n
vdd Vdd Gnd 3.0
* End of main circuit: ring2
```

In this example, instead of keeping the load capacitor in the inverter subcircuit constant, the capacitor is defined as a variable cap and T-Spice sweeps it over a range of 200fF to 1000fF. The .param statement sets a nominal value for cap and the .step command sweeps cap linearly from 200fF to 1000fF in increments of 200fF.

The .measure statement measures the period, time delay, and pulse width of the ring oscillator at the different values of capacitance. In this example, period is measured at $\mathbf{v}(\mathbf{a 2} \mathbf{2}=\mathbf{3 V}$ from its second falling edge to its third falling edge. Time delay is measured from the second falling edge of $\mathbf{v}(\mathbf{a} 2)$ at 3 V to the second falling edge of $\mathbf{v}(\mathbf{a} 1)$ at $\mathbf{3 V}$. Pulse width is measured from the second rising edge of $\mathbf{v}(\mathbf{a} \mathbf{2})$ at $\mathbf{1 . 5 V}$ to the second falling edge of $\mathbf{v}(\mathbf{a} 2)$ at $\mathbf{1 . 5 V}$.

## Output

T-Spice reports the transient analysis results in five sections for cap=200fF, 400fF, 600fF, 800fF, and 1000fF.

Following is part of the output section for cap=200fF.

```
TRANSIENT ANALYSIS - cap=2e-013
Time<s> v(a1)<V>
0.0000e+000 0.0000e+000
1.0876e-010 1.9456e-002
4.9424e-010 3.3521e-001
8.9842e-010 6.0502e-001
1.2047e-009 7.0183e-001
```

The measurement results are reported at the end of each section.

```
MEASUREMENT RESULTS - cap=2e-013
period = 9.9026e-008
    Trigger = 1.7549e-007
    Target = 2.7452e-007
pulsewidth = 4.8288e-008
    Trigger = 1.3217e-007
    Target = 1.8046e-007
timedelay = 4.1316e-008
    Trigger = 1.7549e-007
    Target = 2.1681e-007
```

Measurement results are summarized in a table at the end of the output file. Because the .step command was used, measurement results will be plotted against the parameter cap in W-Edit.

| TRANSFER ANALYSIS |  |  |  |
| ---: | ---: | :--- | :--- |
| cap<> | period<> | pulsewidth<> | timedelay<> |
| $2.0000 \mathrm{e}-013$ | $9.9026 \mathrm{e}-008$ | $4.8288 \mathrm{e}-008$ | $4.1316 \mathrm{e}-008$ |
| $4.0000 \mathrm{e}-013$ | $1.4248 \mathrm{e}-007$ | $6.9783 \mathrm{e}-008$ | $5.9662 \mathrm{e}-008$ |
| $6.0000 \mathrm{e}-013$ | $1.8579 \mathrm{e}-007$ | $9.1213 \mathrm{e}-008$ | $7.8093 \mathrm{e}-008$ |
| $8.0000 \mathrm{e}-013$ | $2.2913 \mathrm{e}-007$ | $1.1262 \mathrm{e}-007$ | $9.6608 \mathrm{e}-008$ |
| $1.0000 \mathrm{e}-012$ | $2.7235 \mathrm{e}-007$ | $1.3401 \mathrm{e}-007$ | $1.1505 \mathrm{e}-007$ |

## Waveform

The following two figures show the waveform output for this example. The first displays the output of the ring oscillator vs. time with different capacitance values; the second displays the period, time delay and pulse width in a single chart.

Ring oscillator versus time at different capacitances:


Period (blue), time delay (green) and pulse width (red) charted together:.
ring2


## Monte Carlo Analysis

In a Monte Carlo analysis, T-Spice performs simulation runs using randomly chosen parameter values. The parameter values for each run are chosen from probability distributions defined by the user.

T-Spice's Monte Carlo analysis will generate a summary output of all simulation run measurement results after all runs are completed. T-Spice will also report, for each Monte Carlo iteration, the values of all expressions evaluated using probability distributions.

Monte Carlo analysis can be invoked using the keywords sweep monte with one of the following commands:

- ".ac" (page 60)
- ".dc" (page 69)
- ".step" (page 138)
- ".tran" (page 147)

Syntax and options for the keyword sweep are defined in the section describing ".step" (page 138).
Probability distributions are assigned to parameters by use of the .param command. For a complete description of the syntax of this command, see ".param" (page 113).

## Example 2: Monte Carlo Analysis

This example demonstrates Monte Carlo Analysis on a CMOS inverter circuit.

```
Input
Output
    invert5.cir
    invert5.out
Input
* Main circuit: invert5
c2 out Gnd 800ff
.include ml2_125mc.md
m1n out in Gnd Gnd nmos L=5u W=8u
m1p out in Vdd Vdd pmos L=5u W=12u
.measure tran falltime trig v(out) val=2.8 fall=1 targ v(out) val=0.2 fall=1
.param vto_n=unif(0.622490, 0.5, 1) vto_p=unif(-0.63025, 0.5, 1)
.tran 2n 600n sweep monte=10
.print tran in out
vdd Vdd Gnd 3.0
vin in Gnd pwl (0ns OV 100ns 0V 105ns 3V 200ns 3V 205ns 0V 300ns
+ OV 305ns 3V 400ns 3V 405ns 0V 500ns 0V 505ns 3V 600ns 3V)
* End of main circuit: invert5
```

A Monte Carlo analysis sweeps parameter values that are chosen based on statistical variations. In this example, T -Spice varies the model parameter vto using random values chosen by probability distribution. In model file $\mathbf{m l 2} \mathbf{1 2 5 m c} . \mathbf{m d}$, the .model statement specifies the vto parameter as two variables: vto_n for an n-channel MOSFET and vto_p for a p-channel MOSFET.

The .param statement defines the probability distribution, where vto_n=unif(0.622490, 0.5, 1) and vto_p=unif( $-0.63025,0.5,1$ ) select uniform distributions centered at 0.622490 and -0.63025 with relative variation of $50 \%$. The keyword monte $=10$ in the .tran statement invokes Monte Carlo analysis with 10 runs. The .measure statement measures the falltime of the output pulse for different values of vto.

## Output

T-Spice reports the transient analysis results in ten sections for the ten Monte Carlo runs.

Following is part of the output section for the first run.

```
TRANSIENT ANALYSIS - Monte-Carlo-index=1
Time<s> v(in)<V> v(out)<V>
    0.0000e+000 0.0000e+000 2.9996e+000
    6.0000e-010 0.0000e+000 2.9996e+000
    2.6000e-009 0.0000e+000 2.9996e+000
    4.6000e-009 0.0000e+000 2.9996e+000
    6.6000e-009 0.0000e+000 2.9996e+000
    8.5999e-009 0.0000e+000 2.9996e+000
```

...

Measurement results are reported at the end of each section.

```
MEASUREMENT RESULTS - Monte-Carlo-index=1
```

```
falltime = 1.2278e-008
    Trigger = 1.0471e-007
    Target = 1.1699e-007
```

At the end of the output file, T-Spice reports the Monte Carlo values for each run The measurement results are summarized along with statistical results from the analysis (minimum, maximum, mean, average deviation, variance, and sigma).


## Waveform

The following figure displays families of output traces from a Monte Carlo analysis.


## Optimization

The T-Spice optimization feature allows circuit parameters to be tuned within given ranges to achieve the best possible circuit performance. T-Spice seeks to minimize the difference between performance measurements and a user-defined optimization goal. In order to specify an optimization, you must supply the following:
[1] A list of parameters which can be adjusted to optimize performance. Each parameter is assigned a nominal, minimum, and maximum value with .paramlimits. The nominal value serves as the initial guess in the optimization process. (For a complete description of the syntax of the .paramlimits command, see ".paramlimits" (page 117))
[2] An optimization goal defined in terms of .optgoal commands and .measure results. T-Spice attempts to minimize the deviation of .measure results from their respective goal values defined in .optgoal. If multiple .optgoal commands are used, each .optgoal parameter has a weight value to indicate its relative importance. (For a complete description of the syntaxes, see ".macro /.eom" (page 88) or ".optgoal" (page 103).)
[3] A .optimize command that invokes the optimization run. The optimization model and analysis name are specified using the .optimize command. (For a complete description of the .optimize command syntax, see ".optimize" (page 104).)
[4] A .model command which defines the optimization algorithm, as well as optimization algorithm parameters and tolerances. (For a complete description of the .model command syntax, see ".model" (page 96).)

## Defining Optimization Parameters

Any parameter defined using .param can be used as an optimization parameter. Use the .paramlimits command to associate such a parameter with an optimization run, so that T-Spice can vary it during the optimization. There is no limit on how many optimization parameters an optimization run can have, but the optimization will be much faster with fewer parameters. The precise syntax for this keyword is described in ".paramlimits" (page 117).

## Defining Optimization Goals

Optimization goals are defined using .optgoal. The function of the .optgoal command is to link a .measure result to an optimization run and to specify a goal value for the measurement. During each optimization run, T -Spice calculates an optimization function based on the differences between measurements and their corresponding optimization goals. T-Spice uses this calculation to find parameter values that minimize the deviation of measurement results from goal values.

An optimization run can have multiple .optgoal commands, each of which is assigned a weight. The value of the optimization function for each run is obtained by summing the weighted individual goals: each .optgoal contributes a term of the form weight $\times($ goal-result $) /$ goal.

Curve-fit optimization can be performed by using the error function measurements available on the .measure command.

For more information on the relevant commands, see ".macro /.eom" (page 88) and ".optgoal" (page 103).

## Invoking Optimization

A .optimize command invokes an optimization run using the parameters and goals specified by .paramlimits and .optgoal when these commands use a matching optimization run name. Only those parameters for which the run name matches are varied during the optimization run. The model keyword defines an optimization model, which is specified using a .model command with optimization algorithm parameters such as iteration count limits and convergence tolerances. The analysisname option identifies the .step, .ac, .dc, or .tran analysis that will be performed to evaluate the measurements for the optimization.

After an optimization, the optimized parameter values are used in all subsequent analyses specified in the same input file. This allows for incremental optimization: some parameters can be optimized while others are held fixed; other parameters can then be optimized based on the results of the first optimization. DC analyses are performed first, followed by AC analyses, and then transient analyses. Multiple analyses of the same type are performed in the order in which they are found in the input file.

The T-Spice wizard-style user interface will guide you in setting up optimization commands.

## Example 3: Optimization

```
Input A
    opamp_ac.cir
Input B
Output
myopamp.cir
myopamp.out
```

This tutorial will demonstrate the procedures to be followed in setting up an optimization command. We use the operational amplifier introduced in Example 4 to show how you can optimize output by varying
the output transistor's lengths and widths. We can use the existing netlist by adding optimization commands to the netlist.

This exercise uses the input file opamp_ac.cir as a base file to which we will add optimization commands in the course of the tutorial. The modified input file that you create will be named myopamp.cir. For reference, we have included a file called opamp4.cir, which represents what myopamp.cir should look like at the end of the tutorial.
$\square \quad$ Open opamp.cir and choose File > Save As to rename the file. Name the file myopamp.cir.
$\checkmark \quad$ For simplicity, remove the statements .print ac vp(out) and .acmodel opamp1m.out (*) in the original netlist.
$\checkmark \quad$ Place the cursor at the beginning of any line, such as the line above the .include statement. Choose Edit > Insert Command or click the Insert Command icon in the Command toolbar:


च In the left-hand pane of the Command Tool, click Settings. In the right-hand pane, click the Parameters button.
$\checkmark \quad$ With Parameter type set to General, enter the following values. For each value pair that you add, click Add. T-Spice will add the parameter to the list.

Parameter name
Parameter value

| 13 | $6 u$ |
| :--- | :--- |
| w3 | $20 u$ |
| 14 | $10 u$ |
| w4 | $6 u$ |

When you have finished, the Command Tool will look like this:

$\boxtimes \quad$ Click Insert Command. T-Spice will insert the following line into the netlist:

$$
\text { . param } 13=6 u \text { w } 3=20 u \quad 14=10 u \text { w } 4=6 u
$$

$\square \quad$ Next, edit the lengths and widths of output transistors mp3 and mn4 to optimize the results. For mp3, replace the existing length and width values with parameter names $\mathbf{I} \mathbf{3}$ and $\mathbf{w} 3$, respectively. Enclose these parameter names in single quotes ('). For mn4, replace the existing length and width values with parameter names $\mathbf{1 4}$ and $\mathbf{w 4}$, respectively.
$\boxtimes \quad$ Next, add a .measure command. Place the cursor at the beginning of any line and choose Edit > Insert Command or click the Insert Command icon. Double-click Output, then click Measure under Output (or click the Measure button). The Command Tool will appear in a form suitable for entering a .measure command. Type or select the following values:

| Field | Value |
| :--- | :--- |
| Analysis type: | AC |
| Measurement result name | gain |
| Measurement type | Signal statistics |
| Type of measurement | Maximum |
| Measured signal | vdb(out) |

च Leave all other fields blank. The Command Tool dialog will look like this:


च Click Insert Command to insert the command in the netlist. T-Spice inserts the following line in the netlist:

```
.measure ac gain max vdb(out)
```

$\square \quad$ For the bandwidth measurement, repeat the last step, using the following values:

| Field | Value |
| :--- | :--- |
| Analysis type | AC |
| Measurement result name | bandwidth |
| Measurement type | Find-when |
| Find | x-value |
| When | Signal |
| Signal (name) | vdb(out) |
| equals value | 15 |

$\square \quad$ Leave all other fields blank. The Command Tool dialog will look like this:


■ Click Insert Command. T-Spice inserts the following line in the netlist:

```
.measure ac bandwidth when vdb(out)=15 cross=1
```

$\checkmark \quad$ Now, run the simulation. Choose Simulation $>$ Run Simulation, press F5, or click the Run Simulation icon in the Simulation toolbar. T-Spice displays the Run Simulation dialog.

$\square \quad$ Under Waveform options, select Show during, then click Start Simulation. T-Spice will simulate the circuit, then invoke W-Edit to display the following waveform:


Note that the amplifier has a gain of 43.1 dB and a bandwidth of 11.4 kHz . In the following procedure, we will use the T-Spice optimization feature to modify this design to achieve a gain of 20 dB while maximizing bandwidth.
$\boxtimes \quad$ Switch back to T-Spice. Choose Edit > Insert Command again. T-Spice displays the T-Spice Command Tool. In the left-hand tree, double-click Optimization; the Wizard will appear underneath.

$\checkmark \quad$ Click Wizard (or the Wizard button) to go to the first dialog, Optimization setup. Type optsize in the Optimization name field and type or select First AC Analysis as the analysis name.

$\square \quad$ Click Continue to go to the next dialog, Set optimization goals. Enter gain for the first measurement name, with a target value of $\mathbf{2 0}(\mathrm{db})$ and a weight of $\mathbf{5}$. Click Add to add this in the List of optimization goals.
$\square \quad$ Repeat these steps to define the second measurement name bandwidth, target value 5 e 3 and weight 1, and add them to the List of optimization goals. The T-Spice Command Tool dialog will look like this:


च Click Continue to go to the next dialog, Set parameter limits. First set an optimization goal for I3, using the first column of values in the following table:

| Field | Values |  |  |  |
| :--- | :--- | :--- | :--- | :--- |
| Parameter name | I 3 | w 3 | 14 | w 4 |
| Minimum value | 1 u | 1 u | 1 u | 1 u |
| Maximum value | 20 u | 30 u | 20 u | 20 u |
| Delta | $\mathbf{0 . 5 \mathrm { u }}$ | 0.5 u | 0.5 u | 0.5 u |
| Guess value | 6 u | 20 u | 10 u | 6 u |

ஏ Click Add to add these values to the List of optimization goals. The optimization goals for w3, 14, and w4 can be set in the same way. When you finish, the T-Spice Command Tool dialog will look like this:

$\square \quad$ Click Continue to go to the next dialog, Set optimization algorithm. In the Name field, type optmod. For all other values, accept the defaults. The T-Spice Command Tool dialog will look like this:

$\nabla \quad$ Click Continue to go to the next dialog, Insert command. T-Spice displays your optimization commands in the dialog. Check them to make sure they are correct.

```
.optimize optsize model=optmod analysisname=ac
.paramlimits optsize l3 minval=1u maxval=20u delta=0.5u guess=6u
.paramlimits optsize w3 minval=1u maxval=30u delta=0.5u guess=20u
.paramlimits optsize l4 minval=1u maxval=20u delta=0.5u guess=10u
.paramlimits optsize w4 minval=1u maxval=20u delta=0.5u guess=6u
.optgoal optsize gain=20 minval=1e-12 weight=5
.optgoal optsize bandwidth=5e3 minval=1e-12 weight=1
.model optmod opt cendif=1e-9 close=0.001 cut=2 difsiz=1e-3 grad=1e-6
+ itropt =20 max =600000 parmin=0.1 relin=0.001 relout=0.001
```

$\square \quad$ If you need to change a line, click Back to make changes.
$\square \quad$ Click Insert Command. T-Spice inserts the optimization commands in the text editor.
$\square \quad$ Rerun the simulation. This time you will see the following waveform:


## Output

The list of optimization model parameters is summarized in the output file, followed by the optimization results and the optimized parameter values for $\mathbf{1 3}, \mathbf{w} 3, \mathbf{I 4}$, and w4.

```
* BEGIN NON-GRAPHICAL DATA
Optimization model parameters:
    Level=1
    cendif=1e-009
    close=0.001
    cut=2
    difsiz=0.001
    grad=1e-006
    itropt=20
    max=600000
    parmin=0.1
    relin=0.001
    relout=0.001
* END NON-GRAPHICAL DATA
* BEGIN NON-GRAPHICAL DATA
Optimization results:
                                    Residual = 0.359805
                            Gradient norm = 0.363615
            Marquardt parameter = 16.384
        Function evaluations = 45
        Number of iterations = 16
Optimized parameter values:
```

```
13=9.5000e-006
w3 = 1.9000e-006
14=3.5000e-006
w4 = 1.2000e-006
```

```
* END NON-GRAPHICAL DATA
```

```
* END NON-GRAPHICAL DATA
```

AC analysis results are reported in different sections for different optimization runs. In this example, only one optimization run-optsize-was performed.

```
AC ANALYSIS - OPTIMIZE=optsize
Frequency<Hz> vdb(out)<dB>
    1.00000e+000 2.0533e+001
    1.58489e+000 2.0533e+001
    2.51189e+000 2.0533e+001
    3.98107e+000 2.0533e+001
    6.30957e+000 2.10533e+001
```

The measurement results are reported at the end of each section. Because of the difference in relative weight, gain (weight=5) has higher priority in the optimization than bandwidth (weight=1), and gain is much closer to its optimization goal.

```
gain = 2.0533e+001
    At = 1.0000e+000
bandwidth = 1.4642e+003
```

T-Spice also supports HSPICE-compatible optimization commands, as the following example shows.

## Example 4: Optimization Using HSPICE-Compatible Commands

```
Input
Output
opamp5.cir
opamp5.out
Input
* Circuit: opamp5.sp
*
* Main circuit: opamp5
.ac DEC 5 1 10OMEG sweep optimize=optsize
+ results=gain bandwidth model=optmod
.model optmod opt level=1 itropt=20
.param l4=optsize(10u, 1u, 20u,0.5u) l3=optsize(6u, 1u, 20u,0.5u)
+ w4=optsize(6u, 1u, 20u,0.5u) w3=optsize(20u, 1u, 30u, 0.5u)
.measure ac gain max vdb(out) goal=20 weight=5
.measure ac bandwidth when vdb(out)=15 goal=5e3
ccomp vf1 out 2pF
cout out Gnd 2pF
mn1 vn1 vbias Gnd Gnd nmos L=10u W=6u
mn2 vm1 in1 vn1 Gnd nmos L=6u W=6u
mn3 vf1 in2 vn1 Gnd nmos L=6u W=6u
mn4 out vbias Gnd Gnd nmos l='l4' w='w4'
.include ml2_125.md
mp1 vm1 vm1 Vdd Vdd pmos L=6u W=6u
```

```
mp2 vf1 vm1 Vdd Vdd pmos L=6u W=6u
mp3 out vf1 Vdd Vdd pmos l='l3' w='w3'
.print ac vdb(out)
vbias vbias Gnd 0.8
Vdd Vdd Gnd 5.0
vdiff in2 in1 -0.0007 AC 1.0 90
vin1 in1 Gnd 2.0
* End of main circuit: opamp5
```


## Output

The output of this example is the same as the output "Example 3: Optimization" on page 518.

The following references may be consulted for further information on various aspects of circuit design, modeling, and simulation.
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[^0]:    "fast" (page 217), "precise" (page 232)

[^1]:    "dcstep" (page 215), "minsrcstep" (page 226), "gmindc" (page 219), "gramp" (page 220)

[^2]:    "precise" (page 232), "trextraiter[ations] | trnewtol" (page 254)

[^3]:    "gramp" (page 220), "dchomotopy" (page 212)

[^4]:    "gmindc" (page 219)

[^5]:    "mindcratio" (page 225), "numnx | itl2" (page 230)

[^6]:    "numns | itl6" (page 229), "dchomotopy" (page 212)

[^7]:    "dchomotopy" (page 212)

[^8]:    ".nodeset" (page 100)

[^9]:    "numnd | itl1" (page 227), "dchomotopy" (page 212)

[^10]:    "numnxramp" (page 231)

[^11]:    "absi | abstol" (page 206), "kcltest" (page 222)

[^12]:    "method" (page 245)

[^13]:    "method" (page 245)

[^14]:    "ft" (page 240)

[^15]:    "extraiter[ations] | newtol" (page 216), "precise" (page 232)

[^16]:    "absq | chgtol" (page 239), "relq | relchgtol" (page 252), "trtol" (page 255)

[^17]:    "BJT Level 1 (Gummel-Poon)" (page 338), "Diode" (page 368)

[^18]:    "modelmode" (page 270), "MOSFET (m)" (page 174)

[^19]:    "defl" (page 261), "defw" (page 267)

[^20]:    ".macro /.eom" (page 88), ".tran" (page 147)

[^21]:    "Multi-Threaded Processing" on page 37

[^22]:    ".print" (page 119), ".probe" (page 133)

[^23]:    1) 
